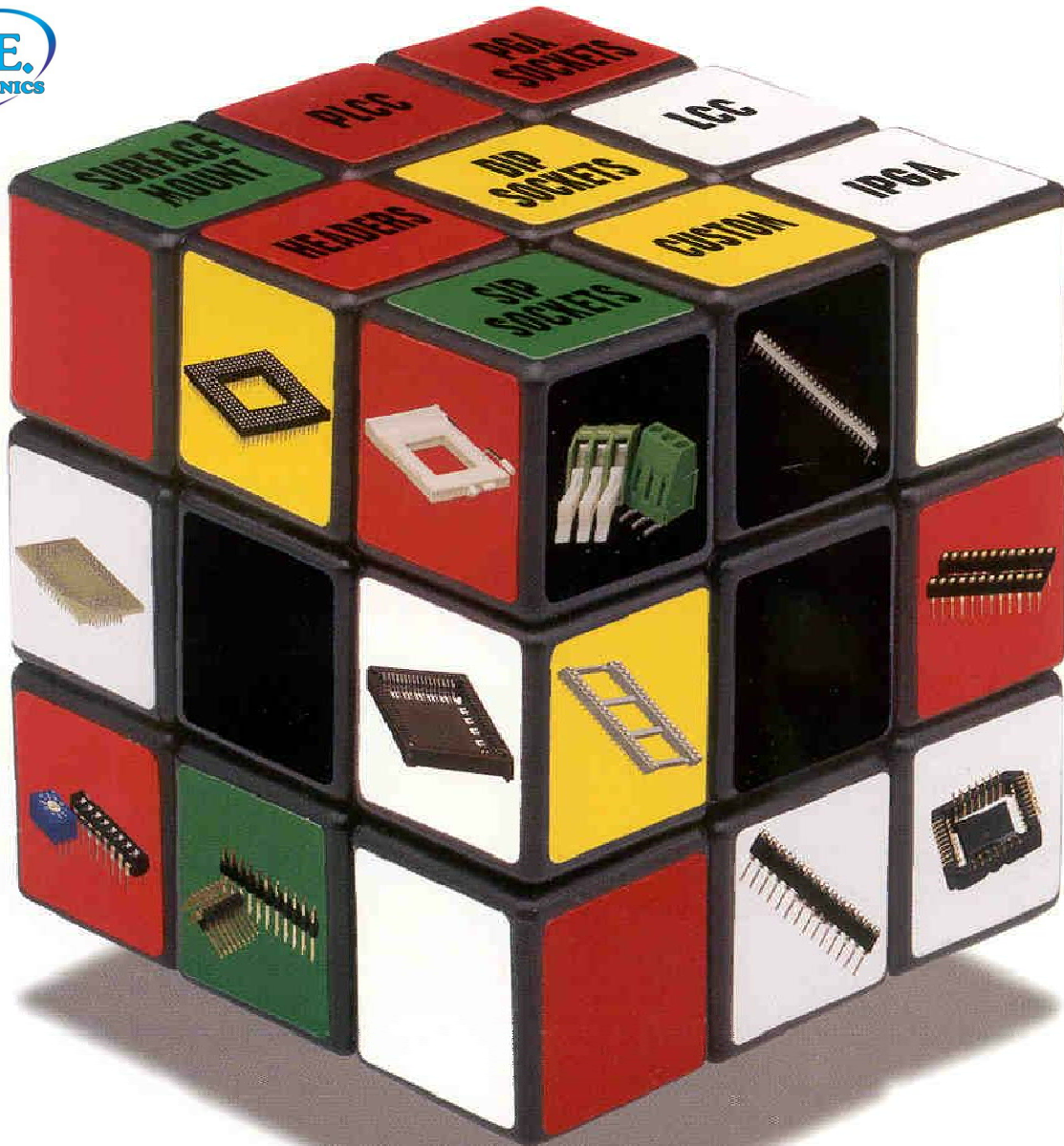


ANDON ELECTRONICS



THE PROBLEM SOLVER

CATALOG 2007

B.C.E. S.r.l. - Via Regina Pacis, 54/c - Sassuolo (MO) - I 41049 - Italy
Tel.: 0536 811616 - Fax: 0536 811500 - Web: www.bce.it - E-mail: bce@bce.it



ANDON®
INTERCONNECTION SPECIALISTS

ISO 9001:2000
CERTIFIED

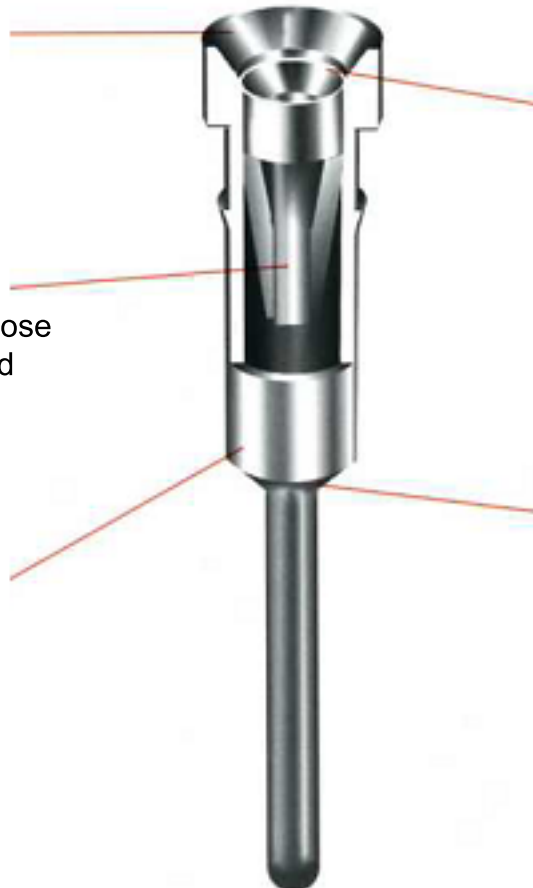


CUT-AWAY VIEW OF ANDON'S STANDARD HI-REL SOCKET

Largest possible tapered
entry funnel.

Short four finger contact
plated and assembled loose
in order to avoid unplated
cut-off areas.

Closed base eliminates
solder wicking.



Four finger, BeCu inner
contact with funnel entry
design allows for easy
insertion of IC lead.

Chamfer ensures perfect
alignment of terminal
on the PC board.

**THE ONE AND ONLY 1 OUNCE CONTACT
FOR IPGA AND PGA SOCKETS!**



TABLE OF CONTENTS

PRODUCT LINE SERIES NUMBERS

TABLE OF CONTENTS I-IV

OPEN FRAME SOCKETS

101: STANDARD OPEN FRAME DIP SOCKET..... 1

102: NO CROSS BAR 1

103: LOW PROFILE 2

104: ULTRA LOW PROFILE 2

105: ULTRA LOW PROFILE NO CROSS BAR 2

106: SURFACE MOUNT 3

107: SHRINK DIP 4

108: CRYSTAL & RELAY..... 5

109: DIP COMPONENT ADAPTER / HEADER 6

110: DIP HEADER / BOARD TO BOARD..... 7

111: DIP SOCKET – RAISED INTERCONNECT..... 8

CLOSED FRAME SOCKETS

201: STANDARD CLOSED FRAME DIP SOCKET 9

202: CLOSED FRAME WITHOUT MOUNTING HOLES 9

204: DIP SOCKET WITHOUT INDEX MARK..... 26

206: SURFACE MOUNT 3

207: SHRINK DIP 4

208: CRYSTAL & RELAY..... 5

209: DIP COMPONENT ADAPTER / HEADER 6

210: DIP HEADER / BOARD TO BOARD 7

211: DIP SOCKET – RAISED INTERCONNECT 8

212: LED SOCKET (VERTICLE)..... 10

213: LED SOCKET (HORIZONTAL) 10

214: ZIG – ZAG SOCKET..... 10

215: TRANSISTOR SOCKET 11

GULL-WING SURFACE MOUNT SOCKETS

217: CLOSED FRAME DIP SOCKET..... 12

218: BLUE LAMINATE DIP SOCKET 13

219: OPEN FRAME DIP SOCKET 14

220: "J" LEAD DIP SOCKET..... 12

221: "J" LEAD OSCILLATOR SOCKET 15

SIP SOCKETS

301: SNAP-OFF SINGLE IN-LINE PACKAGE 16

302: SOLID SIP 16

303: SNAP-OFF HEADS FLUSH..... 17

305: SIP COMPONENT ADAPTER, SNAP-OFF 18

306: SIP COMPONENT ADAPTER, SOLID 18

307: SIP HEADER / BOARD TO BOARD, SNAP-OFF..... 19

308: SIP HEADER / BOARD TO BOARD, SOLID..... 19

©COPYRIGHT 2007 ANDON ELECTRONICS CORP. ALL RIGHTS RESERVED.
 THIS MATERIAL IS PROTECTED BY U.S. AND OTHER COPYRIGHTS AND
 MAY NOT BE COPIED, SOLD OR REDISTRIBUTED IN ANY FORM
 WITHOUT THE WRITTEN PERMISSION OF ANDON ELECTRONICS CORP.

LAMINATE WAFER SOCKETS (NO CIRCUITRY)

204:	DIP SOCKET WITHOUT INDEX	26
401:	QUAD IN-LINE	27
402:	DIP SOCKET	27
403:	SHRINK DIP	4
404:	LOGIC MODULE.....	CONSULT FACTORY
405:	SIP	16
406:	DIP POLYIMIDE WITH STANDOFFS	28
407:	DIP POLYIMIDE WITHOUT STANDOFFS	28
408:	TWIN STRIP.....	CONSULT FACTORY
409:	TWIN STRIP COMPONENT ADAPTER	CONSULT FACTORY
410:	ELEVATED INTERCONNECT BURN-IN SOCKET... CONSULT FACTORY	
411:	POLYIMIDE SIP.....	16

CARRIER SOCKETS

9-:	PLASTIC CARRIER FRAME	31
	FUSE SOCKETS	33

FLOATING TERMINAL SOCKETS

	OPEN FRAME DIP SOCKET.....	34
	CLOSED FRAME DIP SOCKET.....	35
	PGA SOCKET.....	36

TERMINAL STYLES

OPTIONAL PLATINGS.....

PIN GRID ARRAY SOCKETS

510:	STANDARD PGA SOCKETS	45-46
540:	PGA SOCKET WITH STANDOFFS	46
550:	CARI-LOC PULL-OFF CARRIER PGA SOCKET WITH STANDOFFS..	46
575:	CUSTOM LAMINATE PGA SOCKETS	46
585:	INTERSTITIAL PGA SOCKETS	87
	PGA FOOTPRINTS.....	47-85
	PGA CUSTOM FOOTPRINTS.....	86
	IPGA FOOTPRINTS.....	87-94
	IPGA CUSTOM FOOTPRINTS.....	96

BALL GRID ARRAY SOCKETS AND MINI PGA SOCKETS

10:	BGA SOCKETS/ADAPTERS (.050" PITCH).....	97-98
11:	MPGA - MINI PGA SOCKETS (.050" PITCH)....	CONSULT FACTORY
	BGA - MPGA FOOTPRINTS	97-102
	BGA - MPGA CUSTOM FOOTPRINTS.....	103

PLCC & LCC ADAPTER AND CHIP CARRIER SOCKETS

601:	PLCC ADAPTER TYPE A	CONSULT FACTORY
602:	PLCC ADAPTER TYPE B, C, AND D.....	CONSULT FACTORY
610:	5.4 mm LCC SURFACE MOUNT	104
620:	2.85 mm LCC SURFACE MOUNT, AUTO INSERTION.....	105-106
621:	2.85 mm LCC SURFACE MOUNT, MANUAL INSERTION.....	106
700:	PLCC SOLDER TAIL & SURFACE MOUNT.....	107-110
710:	LCC: LEADLESS CHIP CARRIER SOCKETS	111
654:	COMMERCIAL PLCC SOLDER TAIL & SURFACE MOUNT.....	112

TEST SOCKETS/BATTERY SOCKETS

TS:	BGA & LGA TEST SOCKETS	113
TSR:	TEST SOCKET RECEPTACLE	114
BS:	PLUG-IN TYPE BATTERY SOCKETS / HOLDERS	115

SPECIFICATIONS

INSULATOR AND CONTACT SPECIFICATIONS	116
--	-----



SERIES 101 STANDARD DIP SOCKET (OPEN FRAME)
102 DIP SOCKET WITHOUT CROSSBARS (OPEN FRAME)

WAFER CHART			
	PIN	DIM "A"	
FIG. 1	6	.300 [7.62]	306
	8	.400 [10.16]	308
	10	.500 [12.70]	310
FIG. 2	14	.700 [17.78]	314
	16	.800 [20.32]	316
	18	.900 [22.86]	318
	20	1.000 [25.40]	320
	22	1.100 [27.94]	322
	24	1.200 [30.48]	324
FIG. 3	28	1.400 [35.56]	328
	16	.800 [20.32]	416
FIG. 4	22	1.100 [27.94]	422
	24	1.200 [30.48]	424
FIG. 5	24	1.200 [30.48]	624
	28	1.400 [35.56]	628
	30	1.500 [38.10]	630
	32	1.600 [40.64]	632
	36	1.800 [45.72]	636
	40	2.000 [50.80]	640
FIG. 6	48	2.400 [60.96]	648
	50	2.500 [63.50]	950
	52	2.600 [66.04]	952
	64	3.200 [81.28]	964

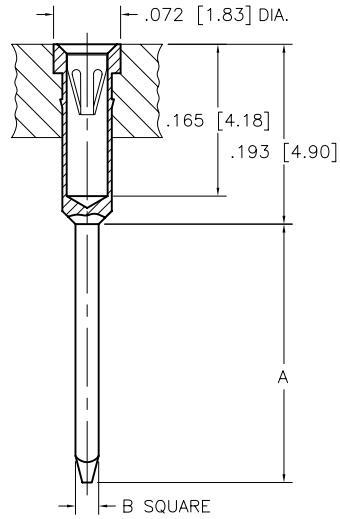


FIG. C

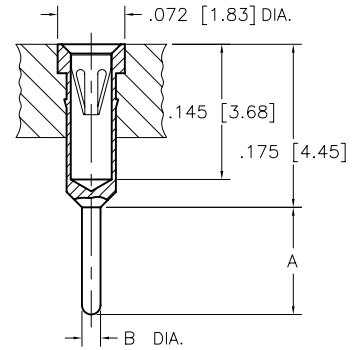
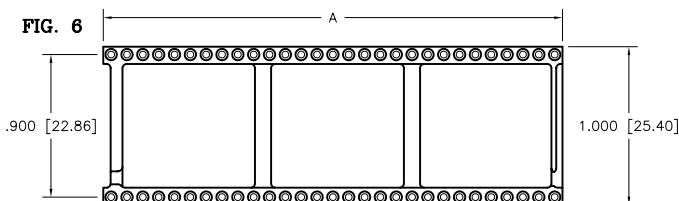
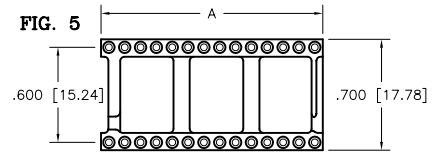
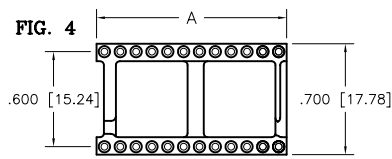
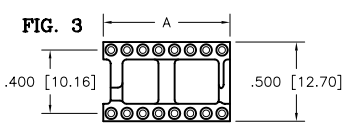
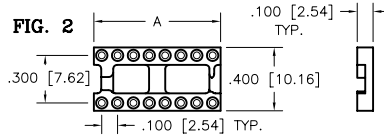
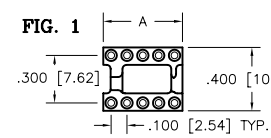


FIG. D

TERMINAL STYLE			
TERMINAL	FIG.	DIM "A"	DIM "B"
-01	D	.115 [2.92]	.020 [0.51]
-02	C	.370 [9.40]	.025 [0.64]
-03	C	.510 [12.95]	.025 [0.64]
-08	D	.170 [4.31]	.020 [0.51]
-09	D	.280 [7.11]	.020 [0.51]
-11	D	.135 [3.43]	.020 [0.51]
-94	D	.125 [3.17]	.018 [0.46]



CONTACT TYPE

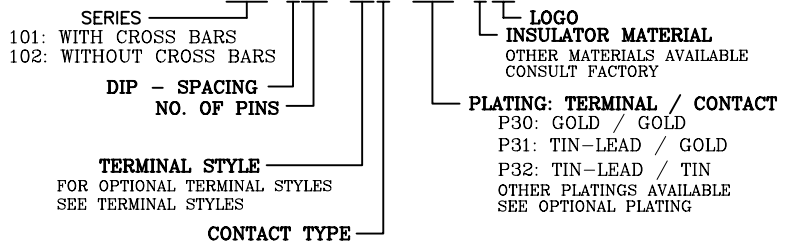
S: STANDARD DIP INSERTION FORCE 9.0 oz. AVG.
 WITHDRAWAL FORCE 2.0 oz. MIN.

TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR GLASS FILLED POLYESTER
 UL 94V-0 LISTED
TERMINAL CONTACT BRASS PER ASTM-B16
 BeCu PER ASTM-B194
OPERATING TEMP. -65°C TO +125°C

ORDERING INFORMATION

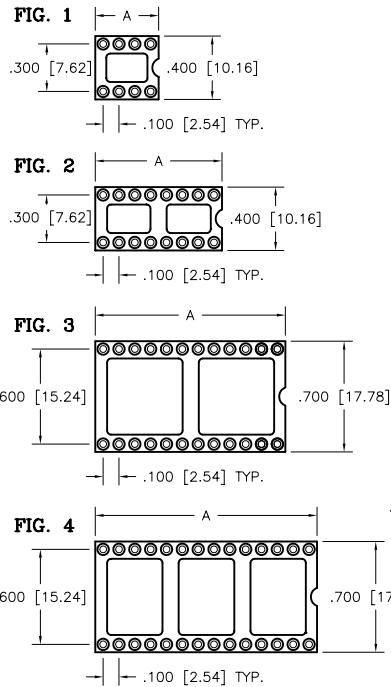
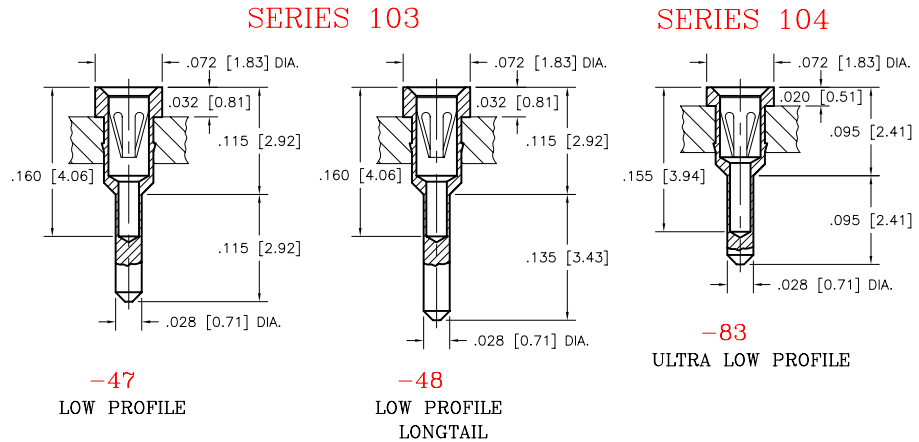
10X-XXX-XXX-PXX-B12



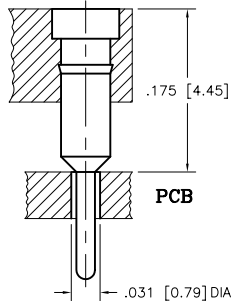


SERIES 103 LOW PROFILE DIP SOCKET (OPEN FRAME)
 SERIES 104 ULTRA LOW PROFILE DIP SOCKET (OPEN FRAME)
 SERIES 105 ULTRA LOW PROFILE DIP SOCKET (OPEN FRAME WITHOUT CROSSBARS)

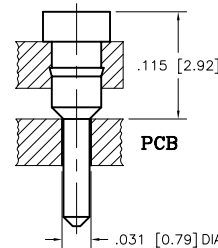
WAFER CHART			
	PIN	DIM "A"	
FIG. 1	6	.300 [7.62]	306
	8	.400 [10.16]	308
	14	.700 [17.78]	314
FIG. 2	16	.800 [20.32]	316
	18	.900 [22.86]	318
	20	1.000 [25.40]	320
	22	1.100 [27.94]	322
	24	1.200 [30.48]	324
FIG. 3	28	1.400 [35.56]	328
	24	1.200 [30.48]	624
FIG. 4	28	1.400 [35.56]	628
	30	1.500 [38.10]	630
	32	1.600 [40.64]	632
	36	1.800 [45.72]	636
	40	2.000 [50.80]	640



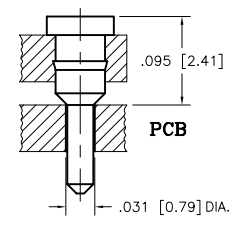
STANDARD HEIGHT ABOVE PCB WITH -01 TERMINAL



34% REDUCED HEIGHT WITH -47 TERMINAL



46% REDUCED HEIGHT WITH -83 TERMINAL



CONTACT TYPE

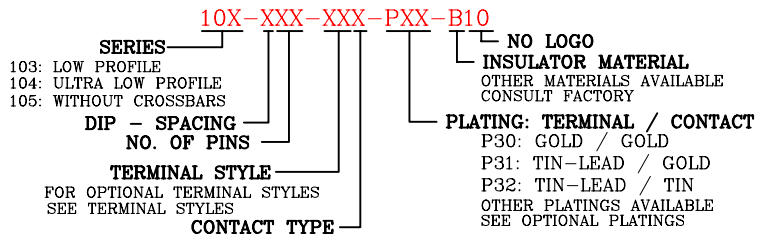
S: STANDARD DIP	INSERTION FORCE	9.0 oz. AVG.
	WITHDRAWAL FORCE	2.0 oz. MIN.
M: STANDARD PGA	INSERTION FORCE	1.6 oz. MAX.
	WITHDRAWAL FORCE	0.5 oz. MIN.
L: INTERSTITIAL PGA	INSERTION FORCE	1.0 oz. MAX.
	WITHDRAWAL FORCE	0.3 oz. MIN.
H: HIGH FORCE	INSERTION FORCE	18.3 oz. MAX.
	WITHDRAWAL FORCE	4.2 oz. MIN.

TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR GLASS FILLED POLYESTER
 UL 94V-0 LISTED
TERMINAL CONTACT BRASS PER ASTM-B16
 BeCu PER ASTM-B194
OPERATING TEMP. -65°C TO +125°C

CONTACT FORCES
INSERTION STANDARD 9 oz. AVG.
WITHDRAWAL STANDARD 2 oz. MIN.

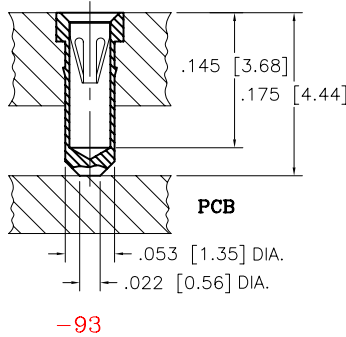
ORDERING INFORMATION



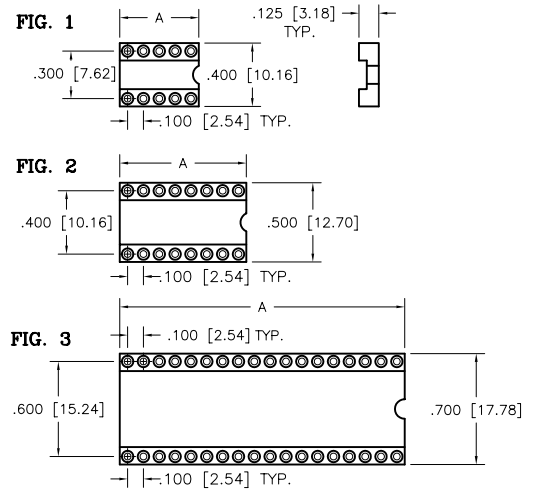
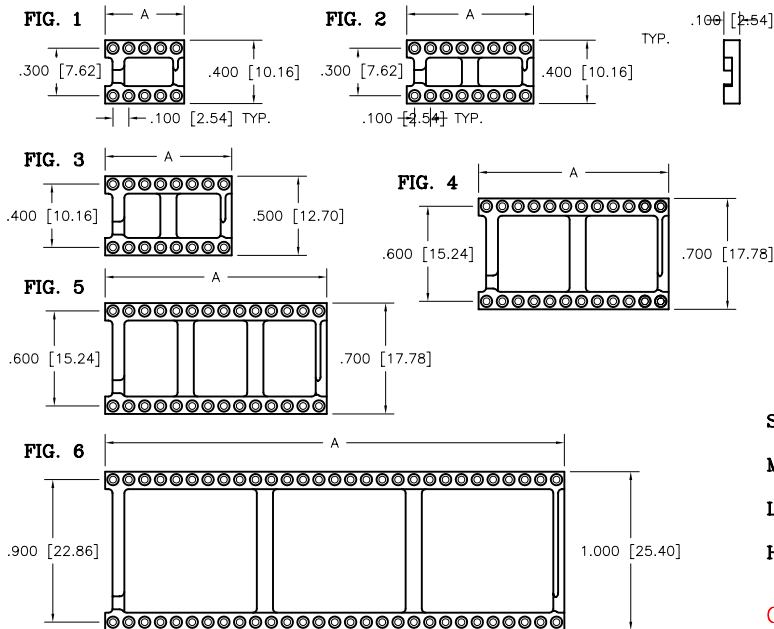


SERIES 106 HI-TEMP SURFACE MOUNT DIP SOCKET (OPEN FRAME)
SERIES 206 HI-TEMP SURFACE MOUNT DIP SOCKET (SOLID FRAME)

SERIES 106 OPEN FRAME WAFER CHART			
	PIN	DIM "A"	
FIG. 1	6	.300 [7.62]	306
	8	.400 [10.16]	308
	10	.500 [12.70]	310
FIG. 2	14	.700 [17.78]	314
	16	.800 [20.32]	316
	18	.900 [22.86]	318
	20	1.000 [25.40]	320
	22	1.100 [27.94]	322
	24	1.200 [30.48]	324
FIG. 3	28	1.400 [35.56]	328
	16	.800 [20.32]	416
	22	1.100 [27.94]	422
	24	1.200 [30.48]	424
FIG. 4	24	1.200 [30.48]	624
FIG. 5	28	1.400 [35.56]	628
	30	1.500 [38.10]	630
	32	1.600 [40.64]	632
	36	1.800 [45.72]	636
	40	2.000 [50.80]	640
	48	2.400 [60.96]	648
FIG. 6	50	2.500 [63.50]	950
	52	2.600 [66.04]	952
	64	3.200 [81.28]	964



SERIES 206 SOLID FRAME WAFER CHART				
	PIN	DIM "A"		
FIG. 1	6	.300 [7.62]	306	
	8	.400 [10.16]	308	
	10	.500 [12.70]	310	
	14	.700 [17.78]	314	
	16	.800 [20.32]	316	
	18	.900 [22.86]	318	
	20	1.000 [25.40]	320	
	24	1.200 [30.48]	324	
	FIG. 2	16	.800 [20.32]	416
		22	1.100 [27.94]	422
24		1.200 [30.48]	424	
24		1.200 [30.48]	624	
FIG. 3	28	1.400 [35.56]	628	
	30	1.500 [38.10]	630	
	32	1.600 [40.64]	632	
	36	1.800 [45.72]	636	
	40	2.000 [50.80]	640	



TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR GREY NYLON 46
 UL 94V-0 LISTED
TERMINAL CONTACT BRASS PER ASTM-B16
 BeCu PER ASTM-B194
OPERATING TEMP. -65°C TO +150°C

CONTACT FORCES
INSERTION STANDARD 9 oz. AVG.
WITHDRAWAL STANDARD 2 oz. MIN.

SERIES
 106: OPEN
 206: SOLID

DIP - SPACING
 NO. OF PINS

TERMINAL STYLE
 FOR OPTIONAL TERMINAL STYLES
 SEE TERMINAL STYLES

CONTACT TYPE

S: STANDARD DIP INSERTION FORCE 9.0 oz. AVG.
 WITHDRAWAL FORCE 2.0 oz. MIN.

M: STANDARD PGA INSERTION FORCE 1.6 oz. MAX.
 WITHDRAWAL FORCE 0.5 oz. MIN.

L: INTERSTITIAL PGA INSERTION FORCE 1.0 oz. MAX.
 WITHDRAWAL FORCE 0.3 oz. MIN.

H: HIGH FORCE INSERTION FORCE 18.3 oz. MAX.
 WITHDRAWAL FORCE 4.2 oz. MIN.

ORDERING INFORMATION

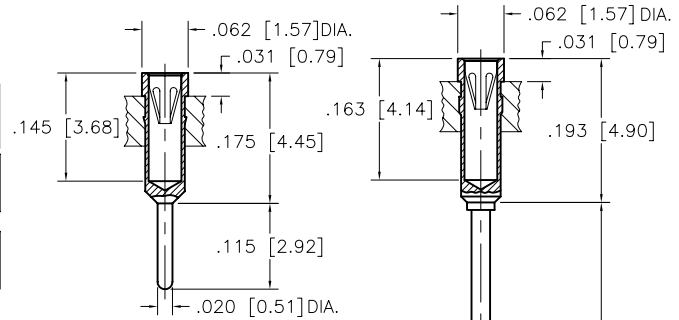
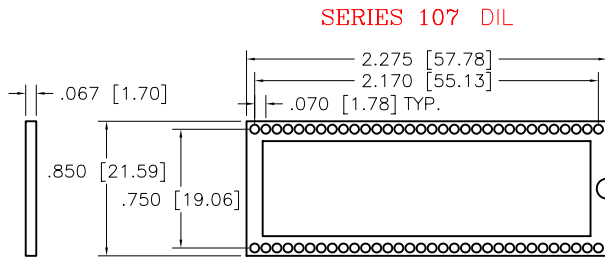
106-XXX-XXX-PXX-Y12
 206-XXX-XXX-PXX-Y10

LOGO
INSULATOR MATERIAL
 OTHER MATERIALS AVAILABLE
 CONSULT FACTORY

PLATING: TERMINAL / CONTACT
 P30: GOLD / GOLD
 P31: TIN-LEAD / GOLD
 P32: TIN-LEAD / TIN
 OTHER PLATINGS AVAILABLE
 SEE OPTIONAL PLATINGS

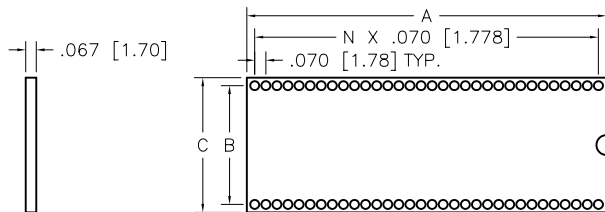


SERIES 107 SHRINK DIP (OPEN FRAME)
SERIES 207 SHRINK DIP (SOLID FRAME)
SERIES 403 SHRINK DIP (LAMINATE WAFER)



SERIES 207 DIL

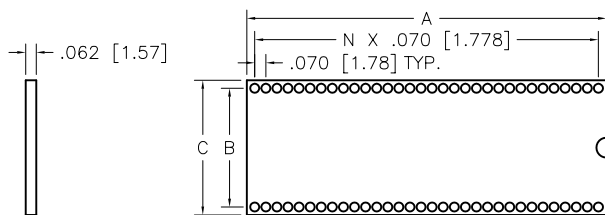
PIN	A	B	C
28	1.010 [25.65]	.600 [15.24]	.700 [17.78]
40	1.430 [36.32]	.600 [15.24]	.700 [17.78]
64	2.270 [57.66]	.750 [19.05]	.850 [21.59]



SERIES 403 DIL

PIN	A	B	C
28	1.010 [25.65]	.600 [15.24]	.700 [17.78]
40	1.430 [36.32]	.600 [15.24]	.700 [17.78]
64	2.270 [57.66]	.750 [19.05]	.850 [21.59]

NOTE: OTHER SOCKET SIZES AVAILABLE



TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR GLASS FILLED POLYESTER
 UL 94V-0 LISTED
TERMINAL CONTACT BRASS PER ASTM-B16
 BeCu PER ASTM-B194
OPERATING TEMP. -65°C TO +125°C

CONTACT FORCES

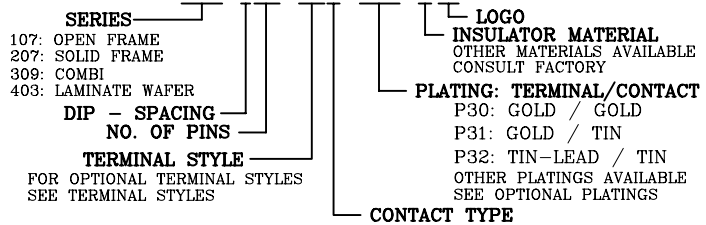
INSERTION STANDARD 9 oz. AVG.
WITHDRAWAL STANDARD 2 oz. MIN.

CONTACT TYPE

S: STANDARD DIP INSERTION FORCE 9.0 oz. AVG.
 WITHDRAWAL FORCE 2.0 oz. MIN.
M: STANDARD PGA INSERTION FORCE 1.6 oz. MAX.
 WITHDRAWAL FORCE 0.5 oz. MIN.
L: INTERSTITIAL PGA INSERTION FORCE 1.0 oz. MAX.
 WITHDRAWAL FORCE 0.3 oz. MIN.
H: HIGH FORCE INSERTION FORCE 18.3 oz. MAX.
 WITHDRAWAL FORCE 4.2 oz. MIN.

ORDERING INFORMATION

107-XXX-XXX-PXX-B10
 207-XXX-XXX-PXX-B10
 309-XXX-XXX-PXX-B10
 403-XXX-XXX-PXX-N10

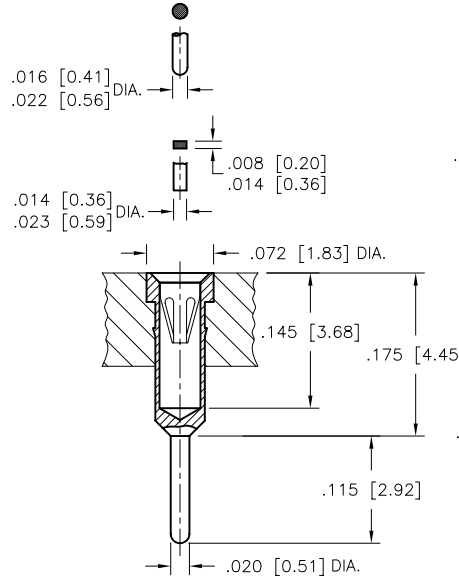
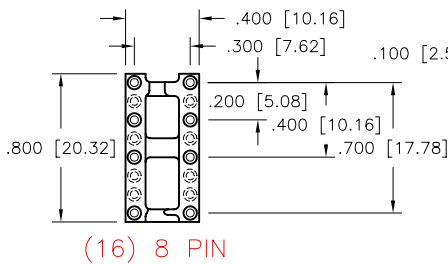
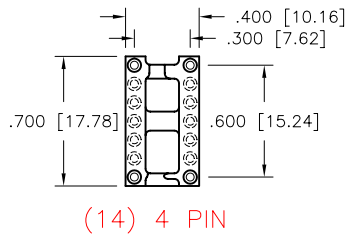
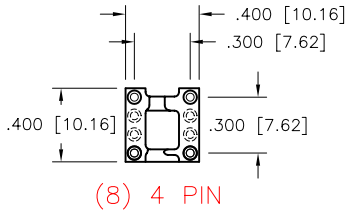


SERIES 403: INSULATOR: GLASS-EPOXY FR-4 UL 94V-0 HIGH TEMPERATURE OPERATION

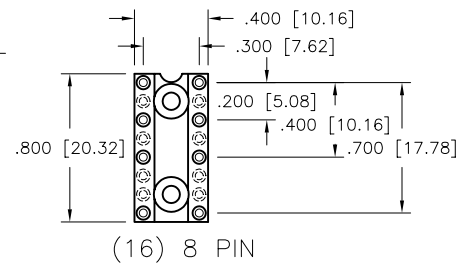
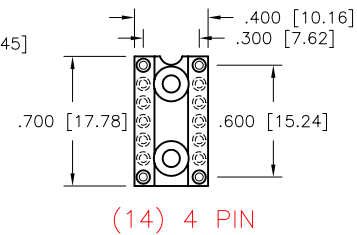
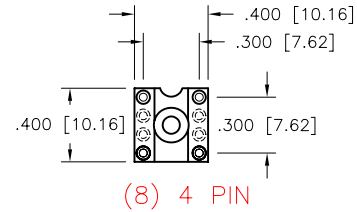


SERIES 108 CRYSTAL AND RELAY SOCKET (OPEN FRAME)
208 CRYSTAL AND RELAY SOCKET (SOLID FRAME)

SERIES 108



SERIES 208

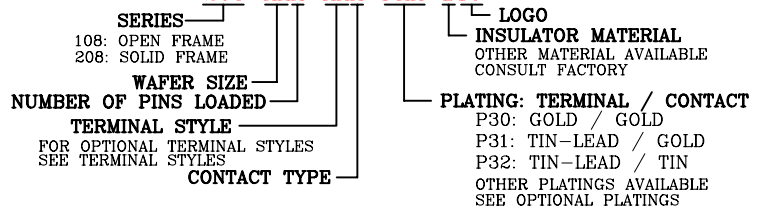


CONTACT TYPE

S: STANDARD DIP	INSERTION FORCE	9.0 oz. AVG.
	WITHDRAWAL FORCE	2.0 oz. MIN.
M: STANDARD PGA	INSERTION FORCE	1.6 oz. MAX.
	WITHDRAWAL FORCE	0.5 oz. MIN.
L: INTERSTITIAL PGA	INSERTION FORCE	1.0 oz. MAX.
	WITHDRAWAL FORCE	0.3 oz. MIN.
H: HIGH FORCE	INSERTION FORCE	18.3 oz. MAX.
	WITHDRAWAL FORCE	4.2 oz. MIN.

ORDERING INFORMATION

108-XXX-XXX-PXX-B12
 208-XXX-XXX-PXX-B10



**CUSTOM SOCKETS AVAILABLE
 CONSULT FACTORY**

TECHNICAL SPECIFICATIONS

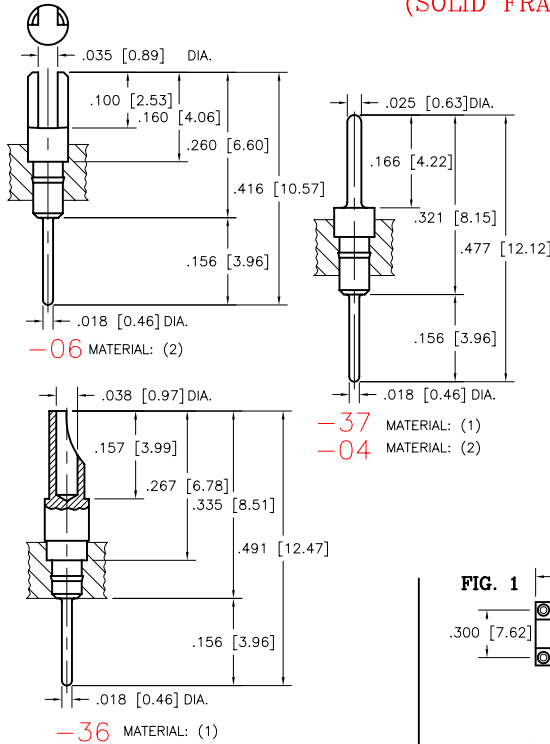
MATERIAL INSULATOR GLASS FILLED POLYESTER
 UL 94V-0 LISTED
TERMINAL CONTACT BRASS PER ASTM-B16
 BeCu PER ASTM-B194
OPERATING TEMP. -65°C TO +125°C

CONTACT FORCES
INSERTION STANDARD 9 oz. AVG.
WITHDRAWAL STANDARD 2 oz. MIN.

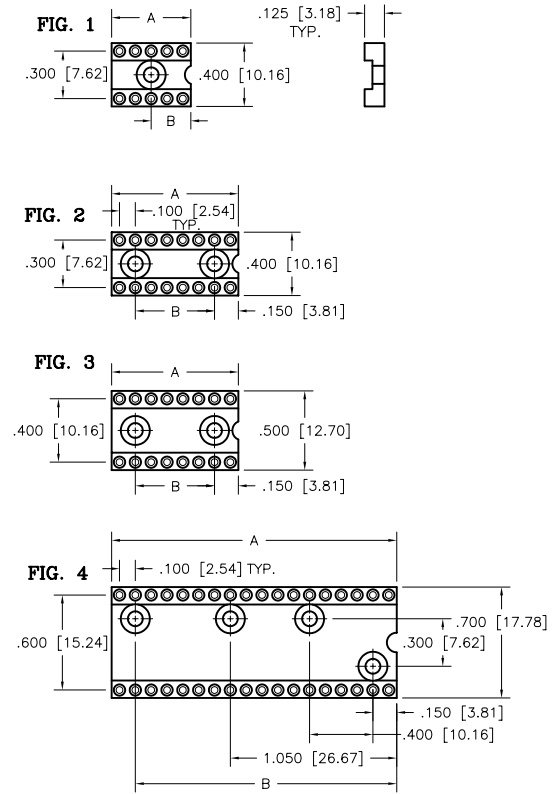
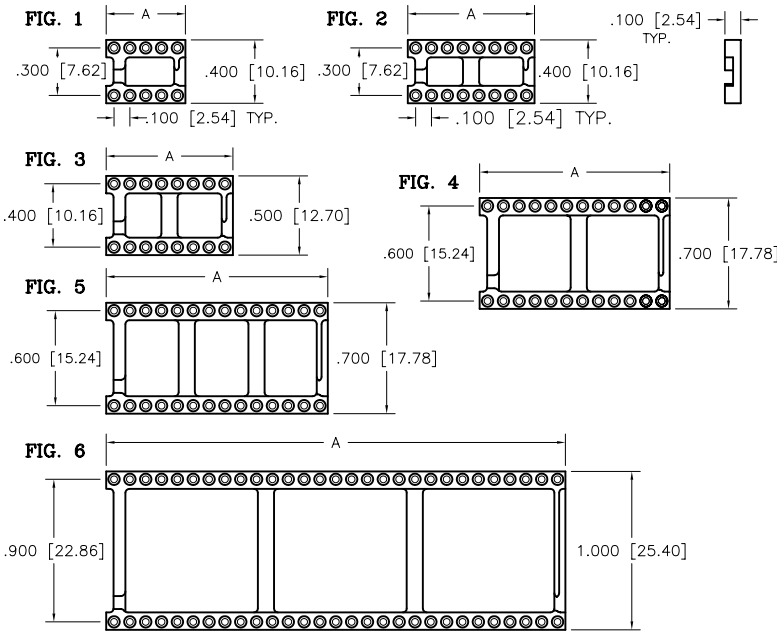


SERIES 109 DIP COMPONENT ADAPTERS/HEADERS (OPEN FRAME)
209 DIP COMPONENT ADAPTERS/HEADERS (SOLID FRAME)

SERIES 109 OPEN FRAME WAFER CHART			
	PIN	DIM "A"	
FIG. 1	6	.300 [7.62]	306
	8	.400 [10.16]	308
	10	.500 [12.70]	310
FIG. 2	14	.700 [17.78]	314
	16	.800 [20.32]	316
	18	.900 [22.86]	318
	20	1.000 [25.40]	320
	22	1.100 [27.94]	322
	24	1.200 [30.48]	324
FIG. 3	28	1.400 [35.56]	328
	16	.800 [20.32]	416
	22	1.100 [27.94]	422
	24	1.200 [30.48]	424
FIG. 4	24	1.200 [30.48]	624
FIG. 5	28	1.400 [35.56]	628
	30	1.500 [38.10]	630
	32	1.600 [40.64]	632
	36	1.800 [45.72]	636
	40	2.000 [50.80]	640
	48	2.400 [60.96]	648
FIG. 6	50	2.500 [63.50]	950
	52	2.600 [66.04]	952
	64	3.200 [81.28]	964



SERIES 209 SOLID FRAME WAFER CHART				
	PIN	DIM "A"	DIM "B"	
FIG. 1	6	.300 [7.62]	.150 [3.81]	306
	8	.400 [10.16]	.200 [5.08]	308
	10	.500 [12.70]	.250 [6.35]	310
FIG. 2	14	.700 [17.78]	.400 [10.16]	314
	16	.800 [20.32]	.500 [12.70]	316
	18	.900 [22.86]	.600 [15.24]	318
	20	1.000 [25.40]	.700 [17.78]	320
	24	1.200 [30.48]	.900 [22.86]	324
	16	.800 [20.32]	.500 [12.70]	416
FIG. 3	22	1.100 [27.94]	.800 [20.32]	422
	24	1.200 [30.48]	.900 [22.86]	424
	24	1.200 [30.48]		624
	28	1.400 [35.56]		628
FIG. 4	30	1.500 [38.10]		630
	32	1.600 [40.64]		632
	36	1.800 [45.72]	1.650 [41.91]	636
	40	2.000 [50.80]	1.650 [41.91]	640



TECHNICAL SPECIFICATIONS
MATERIAL INSULATOR GLASS FILLED POLYESTER
 UL 94V-0 LISTED
TERMINAL MATERIAL:(1) BRASS PER ASTM-B16
 MATERIAL:(2) PHOSPHOR BRONZE PER ASTM-B139
OPERATING TEMP. -65°C TO +125°C

ORDERING INFORMATION
 109-XXX-XX-XXX-B12
 209-XXX-XX-XXX-B10

SERIES
 109: OPEN
 209: SOLID
DIP - SPACING
NO. OF PINS
TERMINAL STYLE
 FOR OPTIONAL TERMINAL STYLES
 SEE TERMINAL STYLES

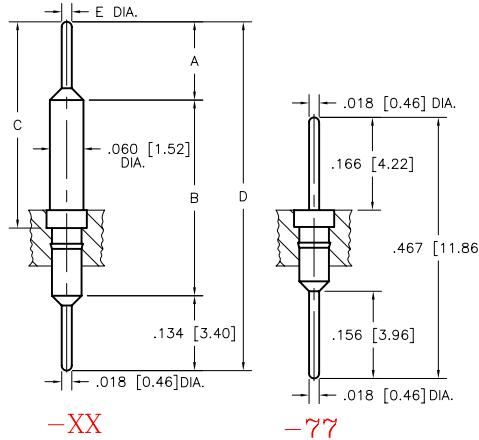
LOGO
INSULATOR MATERIAL
 OTHER MATERIALS AVAILABLE
 CONSULT FACTORY
PLATING: TERMINAL
 G04: GOLD
 T: TIN
 TL: TIN-LEAD



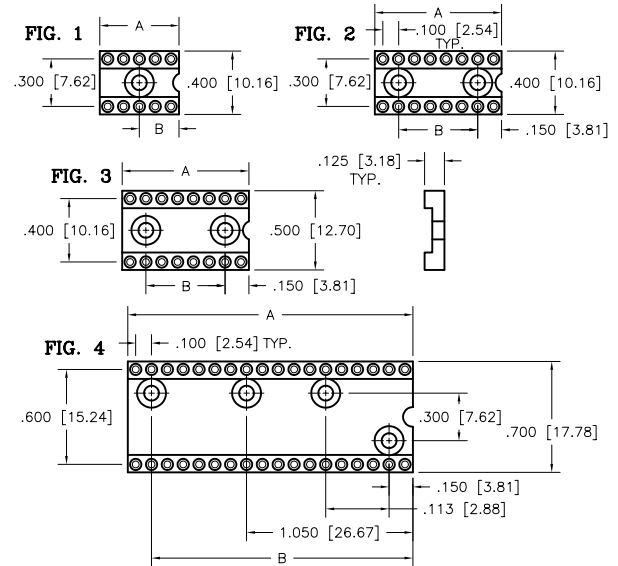
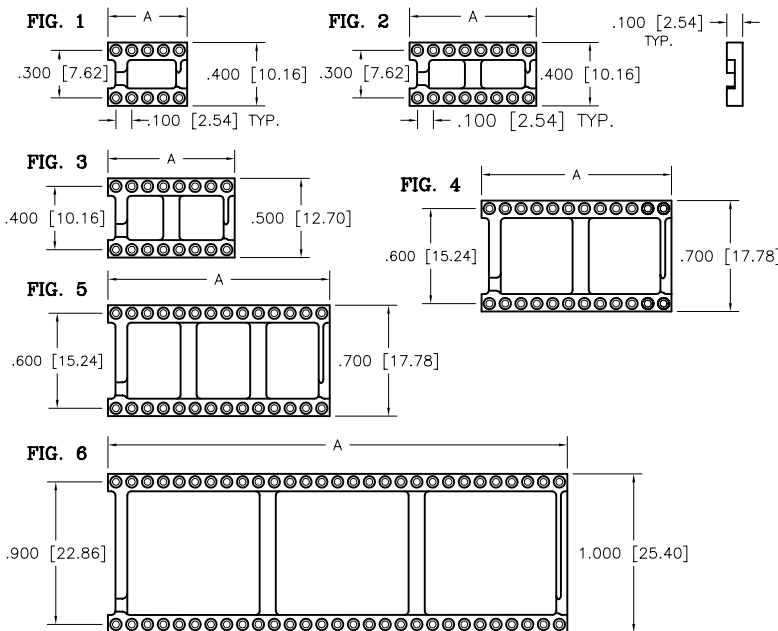
SERIES 110 DIP HEADER: BOARD TO BOARD CONNECTOR (OPEN FRAME)
210 DIP HEADER: BOARD TO BOARD CONNECTOR (SOLID FRAME)

SERIES 110 OPEN FRAME WAFER CHART			
	PIN	DIM "A"	
FIG. 1	6	.300 [7.62]	306
	8	.400 [10.16]	308
	10	.500 [12.70]	310
FIG. 2	14	.700 [17.78]	314
	16	.800 [20.32]	316
	18	.900 [22.86]	318
	20	1.000 [25.40]	320
	22	1.100 [27.94]	322
	24	1.200 [30.48]	324
FIG. 3	28	1.400 [35.56]	328
	16	.800 [20.32]	416
FIG. 4	22	1.100 [27.94]	422
	24	1.200 [30.48]	424
FIG. 5	28	1.400 [35.56]	628
	30	1.500 [38.10]	630
	32	1.600 [40.64]	632
	36	1.800 [45.72]	636
FIG. 6	40	2.000 [50.80]	640
	48	2.400 [60.96]	648
	50	2.500 [63.50]	950
	52	2.600 [66.04]	952
	64	3.200 [81.28]	964

TERM.	A	B	C	D	E
-56	.184 [4.68]	.583 [14.82]	.630 [16.00]	.902 [22.90]	.026 [0.65]
-58	.140 [3.56]	.350 [8.89]	.390 [9.91]	.624 [15.85]	.018 [0.46]
-59	.140 [3.56]	.457 [11.61]	.479 [12.17]	.731 [18.57]	.018 [0.46]



SERIES 210 SOLID FRAME WAFER CHART				
	PIN	DIM "A"	DIM "B"	
FIG. 1	6	.300 [7.62]	.150 [3.81]	306
	8	.400 [10.16]	.200 [5.08]	308
	10	.500 [12.70]	.250 [6.35]	310
FIG. 2	14	.700 [17.78]	.400 [10.16]	314
	16	.800 [20.32]	.500 [12.70]	316
	18	.900 [22.86]	.600 [15.24]	318
	20	1.000 [25.40]	.700 [17.78]	320
	24	1.200 [30.48]	.900 [22.86]	324
	16	.800 [20.32]	.500 [12.70]	416
FIG. 3	22	1.100 [27.94]	.800 [20.32]	422
	24	1.200 [30.48]	.900 [22.86]	424
FIG. 4	24	1.200 [30.48]		624
	28	1.400 [35.56]		628
	30	1.500 [38.10]		630
	32	1.600 [40.64]		632
	36	1.800 [45.72]	1.650 [41.91]	636
	40	2.000 [50.80]	1.650 [41.91]	640



TECHNICAL SPECIFICATIONS
MATERIAL
INSULATOR GLASS FILLED POLYESTER
 UL 94V-0 LISTED
TERMINAL BRASS PER ASTM-B16
OPERATING TEMP. -65°C TO +125°C

ORDERING INFORMATION

110-XXX-XX-XXX-B12
 210-XXX-XX-XXX-B10

SERIES
 110: OPEN
 210: SOLID

DIP - SPACING

NO. OF PINS

TERMINAL STYLE

LOGO
INSULATOR MATERIAL
 OTHER MATERIALS AVAILABLE
 CONSULT FACTORY

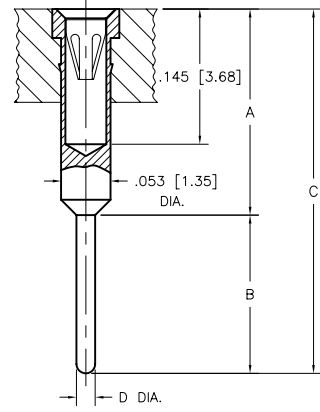
PLATING: TERMINAL
 G04: GOLD
 T: TIN
 TL: TIN-LEAD



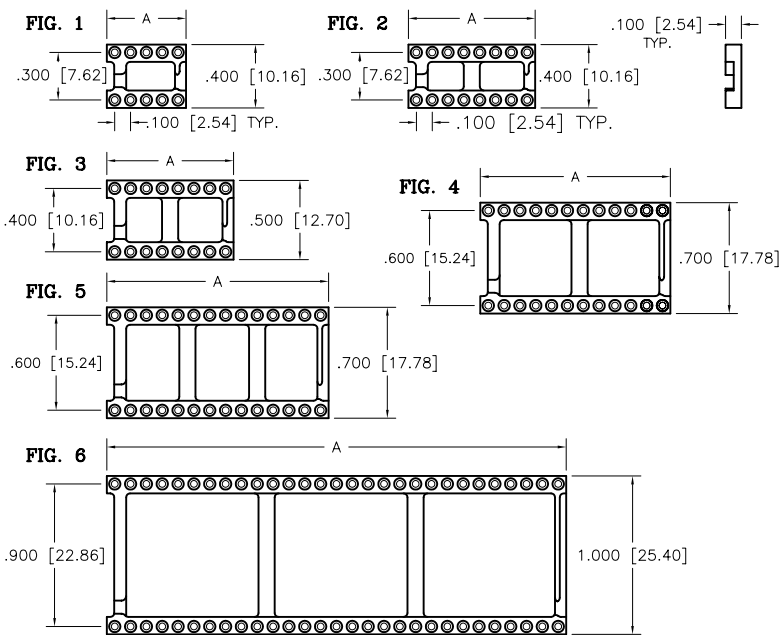
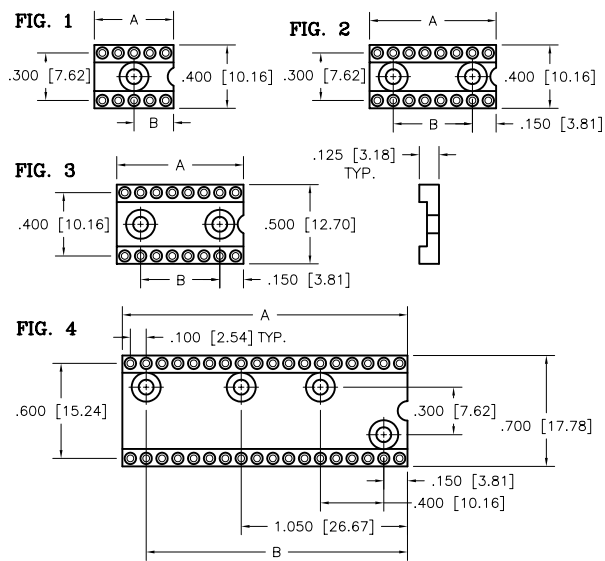
SERIES 111 RAISED INTERCONNECT DIP SOCKET (OPEN FRAME)
211 RAISED INTERCONNECT DIP SOCKET (SOLID FRAME)

SERIES 110 OPEN FRAME WAFER CHART			
	PIN	DIM "A"	
FIG. 1	6	.300 [7.62]	306
	8	.400 [10.16]	308
	10	.500 [12.70]	310
FIG. 2	14	.700 [17.78]	314
	16	.800 [20.32]	316
	18	.900 [22.86]	318
	20	1.000 [25.40]	320
	22	1.100 [27.94]	322
	24	1.200 [30.48]	324
FIG. 3	28	1.400 [35.56]	328
	16	.800 [20.32]	416
FIG. 4	22	1.100 [27.94]	422
	24	1.200 [30.48]	424
FIG. 5	28	1.400 [35.56]	628
	30	1.500 [38.10]	630
	32	1.600 [40.64]	632
	36	1.800 [45.72]	636
	40	2.000 [50.80]	640
	48	2.400 [60.96]	648
FIG. 6	50	2.500 [63.50]	950
	52	2.600 [66.04]	952
	64	3.200 [81.28]	964

TERMINAL	A	B	C	D
-60	.768 [19.50]	.118 [3.00]	.886 [22.50]	.028 [0.71]
-61	1.161 [29.50]	.118 [3.00]	1.280 [32.50]	.028 [0.71]
-62	.551 [14.00]	.118 [3.00]	.669 [17.00]	.020 [0.51]
-63	.807 [20.50]	.118 [3.00]	.925 [23.50]	.028 [0.71]
-65	.512 [13.00]	.118 [3.00]	.630 [16.00]	.018 [0.46]
-80	.236 [6.00]	.126 [3.20]	.362 [9.20]	.024 [0.60]
-82	1.004 [25.50]	.118 [3.00]	1.122 [28.50]	.018 [0.46]
-84	.307 [7.80]	.126 [3.20]	.433 [11.00]	.024 [0.60]
-85	.354 [9.00]	.126 [3.20]	.480 [12.20]	.024 [0.60]
-87	.433 [11.00]	.118 [3.00]	.551 [14.00]	.028 [0.71]



SERIES 211 SOLID FRAME WAFER CHART			
	PIN	DIM "A"	DIM "B"
FIG. 1	6	.300 [7.62]	.150 [3.81]
	8	.400 [10.16]	.200 [5.08]
	10	.500 [12.70]	.250 [6.35]
FIG. 2	14	.700 [17.78]	.400 [10.16]
	16	.800 [20.32]	.500 [12.70]
	18	.900 [22.86]	.600 [15.24]
	20	1.000 [25.40]	.700 [17.78]
	24	1.200 [30.48]	.900 [22.86]
	16	.800 [20.32]	.500 [12.70]
FIG. 3	22	1.100 [27.94]	.800 [20.32]
	24	1.200 [30.48]	.900 [22.86]
FIG. 4	24	1.200 [30.48]	.624
	28	1.400 [35.56]	.628
	30	1.500 [38.10]	.630
	32	1.600 [40.64]	.632
	36	1.800 [45.72]	.636
	40	2.000 [50.80]	.640



TECHNICAL SPECIFICATIONS

MATERIAL
INSULATOR GLASS FILLED POLYESTER
 UL 94V-0 LISTED
TERMINAL BRASS PER ASTM-B16
CONTACT BeCu PER ASTM-B194
OPERATING TEMP. -65°C TO +125°C

CONTACT FORCES
INSERTION STANDARD 9 oz. AVG.
WITHDRAWAL STANDARD 2 oz. MIN.

CONTACT TYPE

S: STANDARD DIP INSERTION FORCE 9.0 oz. AVG.
 WITHDRAWAL FORCE 2.0 oz. MIN.

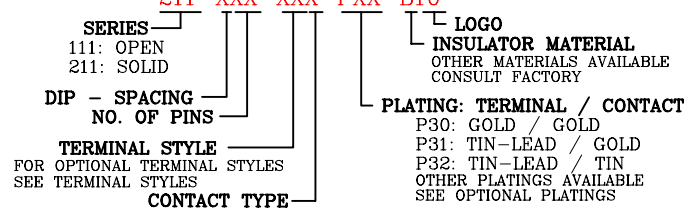
M: STANDARD PGA INSERTION FORCE 1.6 oz. MAX.
 WITHDRAWAL FORCE 0.5 oz. MIN.

L: INTERSTITIAL PGA INSERTION FORCE 1.0 oz. MAX.
 WITHDRAWAL FORCE 0.3 oz. MIN.

H: HIGH FORCE INSERTION FORCE 18.3 oz. MAX.
 WITHDRAWAL FORCE 4.2 oz. MIN.

ORDERING INFORMATION

111-XXX-XXX-PXX-B12
 211-XXX-XXX-PXX-B10



©ANDON 2007 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]. WE RESERVE THE RIGHT TO CHANGE SPECIFICATIONS WITHOUT NOTICE.



SERIES 201 STANDARD DIP SOCKET (SOLID FRAME)
202 STANDARD DIP SOCKET WITHOUT MOUNTING HOLES (SOLID FRAME)

WAFER CHART				
	PIN	DIM "A"	DIM "B"	
FIG. 1	6	.300 [7.62]	.150 [3.81]	306
	8	.400 [10.16]	.200 [5.08]	308
	10	.500 [12.70]	.250 [6.35]	310
FIG. 2	14	.700 [17.78]	.400 [10.16]	314
	16	.800 [20.32]	.500 [12.70]	316
	18	.900 [22.86]	.600 [15.24]	318
	20	1.000 [25.40]	.700 [17.78]	320
FIG. 3	24	1.200 [30.48]	.900 [22.86]	324
	16	.800 [20.32]	.500 [12.70]	416
	22	1.100 [27.94]	.800 [20.32]	422
	24	1.200 [30.48]	.900 [22.86]	424
FIG. 4	24	1.200 [30.48]		624
	28	1.400 [35.56]		628
	30	1.500 [38.10]		630
	32	1.600 [40.64]		632
	36	1.800 [45.72]	1.650 [41.91]	636
	40	2.000 [50.80]	1.650 [41.91]	640

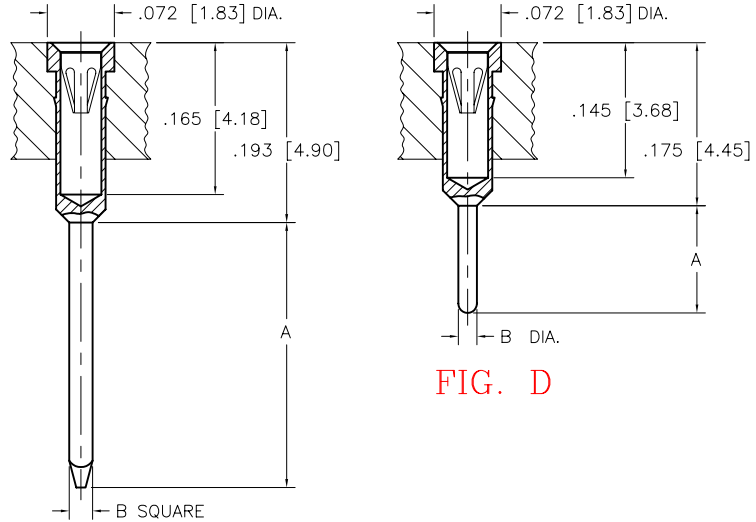
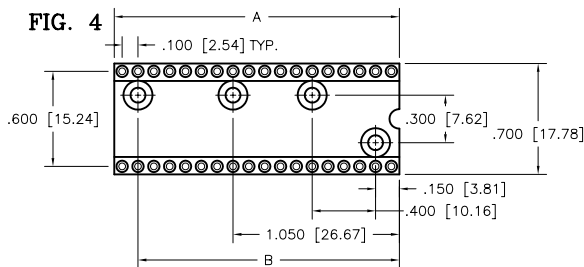
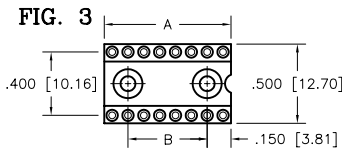
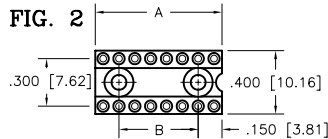
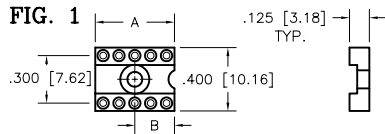


FIG. D



TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR GLASS FILLED POLYESTER
 UL 94V-0 LISTED
TERMINAL CONTACT BRASS PER ASTM-B16
 BeCu PER ASTM-B194
OPERATING TEMP. -65°C TO +125°C

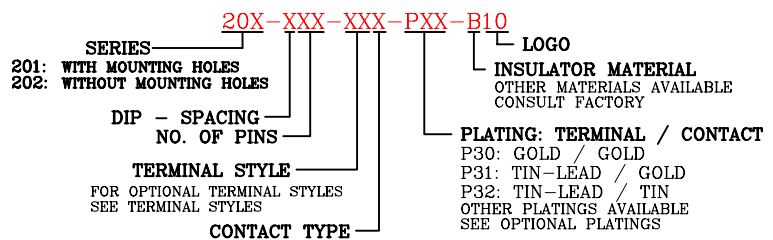
CONTACT FORCES
INSERTION STANDARD 9 oz. AVG.
WITHDRAWAL STANDARD 2 oz. MIN.

TERMINAL STYLE			
TERMINAL	FIG.	DIM "A"	DIM "B"
-01	D	.115 [2.92]	.020 [0.51]
-02	C	.370 [9.40]	.025 [0.64]
-03	C	.510 [12.95]	.025 [0.64]
-08	D	.170 [4.31]	.020 [0.51]
-09	D	.280 [7.11]	.020 [0.51]
-11	D	.135 [3.43]	.020 [0.51]
-94	D	.125 [3.17]	.018 [0.46]

CONTACT TYPE

S: STANDARD DIP INSERTION FORCE 9.0 oz. AVG.
 WITHDRAWAL FORCE 2.0 oz. MIN.
M: STANDARD PGA INSERTION FORCE 1.6 oz. MAX.
 WITHDRAWAL FORCE 0.5 oz. MIN.
L: INTERSTITIAL PGA INSERTION FORCE 1.0 oz. MAX.
 WITHDRAWAL FORCE 0.3 oz. MIN.
H: HIGH FORCE INSERTION FORCE 18.3 oz. MAX.
 WITHDRAWAL FORCE 4.2 oz. MIN.

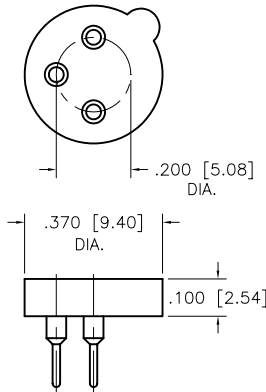
ORDERING INFORMATION



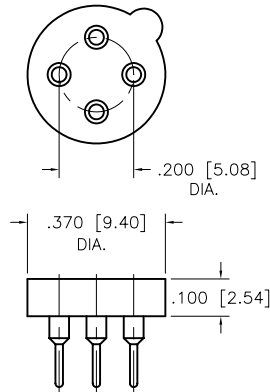
© ANDON 2007 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]. WE RESERVE THE RIGHT TO CHANGE SPECIFICATIONS WITHOUT NOTICE.



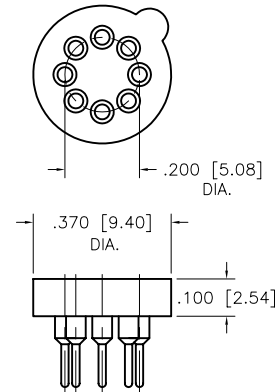
SERIES 215 TRANSISTOR SOCKET



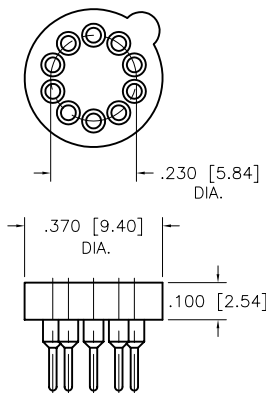
3 PIN



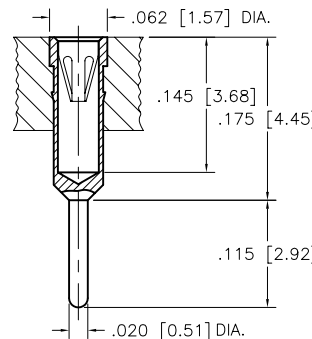
4 PIN



8 PIN



10 PIN



-75

CONTACT TYPE

S: STANDARD DIP	INSERTION FORCE	9.0 oz. AVG.
	WITHDRAWAL FORCE	2.0 oz. MIN.
M: STANDARD PGA	INSERTION FORCE	1.6 oz. MAX.
	WITHDRAWAL FORCE	0.5 oz. MIN.
L: INTERSTITIAL PGA	INSERTION FORCE	1.0 oz. MAX.
	WITHDRAWAL FORCE	0.3 oz. MIN.
H: HIGH FORCE	INSERTION FORCE	18.3 oz. MAX.
	WITHDRAWAL FORCE	4.2 oz. MIN.

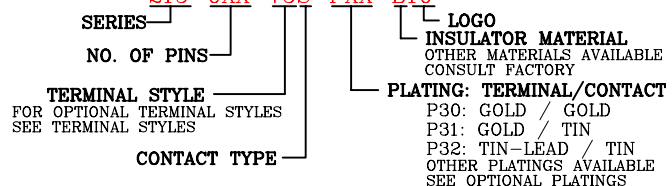
TECHNICAL SPECIFICATIONS

MATERIAL	
INSULATOR	GLASS FILLED POLYESTER UL 94V-0 LISTED
TERMINAL CONTACT	BRASS PER ASTM-B16 BeCu PER ASTM-B194
OPERATING TEMP.	-65°C TO +125°C

CONTACT FORCES	
INSERTION	STANDARD 9 oz. AVG.
WITHDRAWAL	STANDARD 2 oz. MIN.

ORDERING INFORMATION

215-OXX-75S-PXX-B10



© ANDON 2007 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]. WE RESERVE THE RIGHT TO CHANGE SPECIFICATIONS WITHOUT NOTICE.

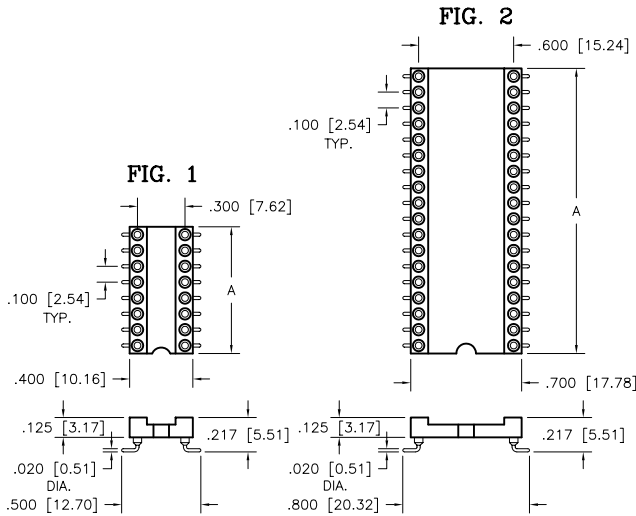


SERIES 217 SURFACE MOUNT GULLWING SOCKET (SOLID FRAME)

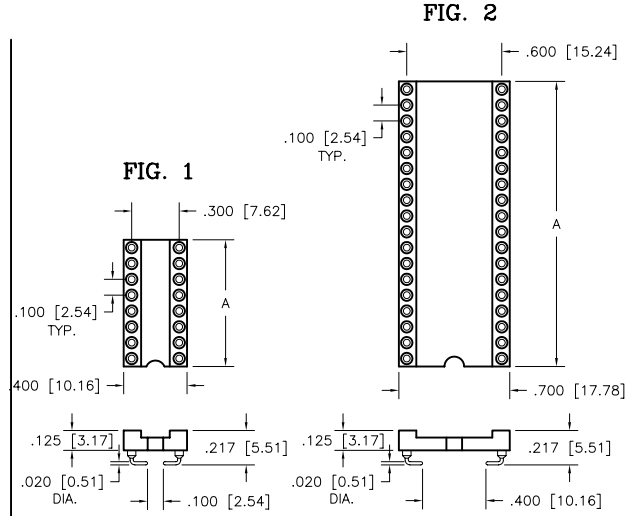
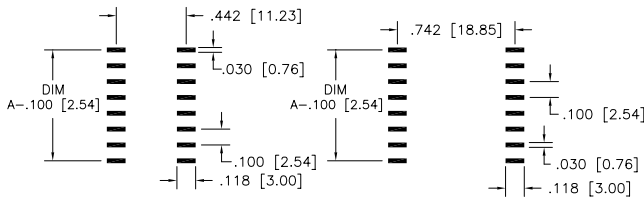
SERIES 220 SURFACE MOUNT "J" LEAD SOCKET (SOLID FRAME)

SERIES 217

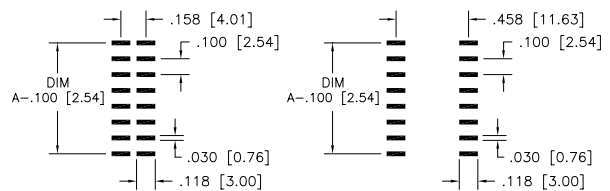
SERIES 220



P.C.B. FOOTPRINT



P.C.B. FOOTPRINT



WAFER CHART			
	PIN	DIM "A"	
FIG. 1	6	.300 [7.62]	
	8	.400 [10.16]	
	10	.500 [12.70]	
	14	.700 [17.78]	
	16	.800 [20.32]	
	18	.900 [22.86]	
	20	1.000 [25.40]	
	24	1.200 [30.48]	
FIG. 2	24	1.200 [30.48]	
	28	1.400 [35.56]	
	30	1.500 [38.10]	
	32	1.600 [40.64]	
	36	1.800 [45.72]	
	40	2.000 [50.80]	
			306
			308
		310	
		314	
		316	
		318	
		320	
		324	
		624	
		628	
		630	
		632	
		636	
		640	

TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR HIGH TEMP. GREY NYLON 46
 UL 94V-0

TERMINAL CONTACT BRASS PER ASTM-B16
 BeCu PER ASTM-B194

OPERATING TEMP. -65°C TO 150°C

CONTACT FORCES

INSERTION STANDARD 9 oz. AVG.
WITHDRAWAL STANDARD 2 oz. MIN.

ORDERING INFORMATION

2XX-XXX-232S-PXX-Y10

SERIES
 217: GULL WING
 220: "J" LEAD

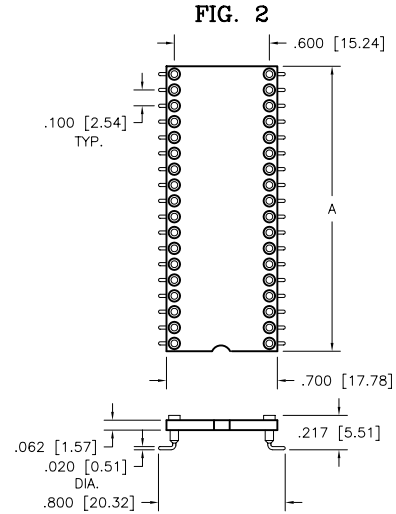
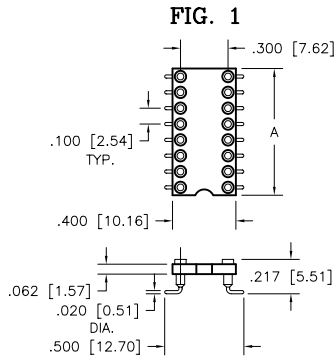
DIP - SPACING
NO. OF PINS

PLATING: TERMINAL / CONTACT
 P30: GOLD / GOLD
 P31: TIN-LEAD / GOLD
 P32: TIN-LEAD / TIN
 OTHER PLATINGS AVAILABLE
 SEE OPTIONAL PLATINGS

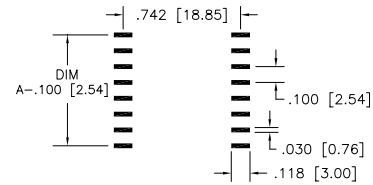
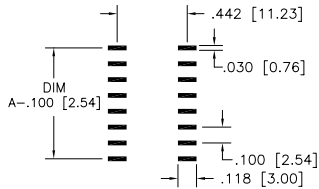
TERMINAL ASSEMBLY



SERIES 218 SURFACE MOUNT GULLWING SOCKET (BLUE LAMINATE)



P.C.B. FOOTPRINT



WAFER CHART			
	PIN	DIM "A"	
FIG. 1	6	.300 [7.62]	306
	8	.400 [10.16]	308
	10	.500 [12.70]	310
	14	.700 [17.78]	314
	16	.800 [20.32]	316
	18	.900 [22.86]	318
	20	1.000 [25.40]	320
	24	1.200 [30.48]	324
FIG. 2	24	1.200 [30.48]	624
	28	1.400 [35.56]	628
	30	1.500 [38.10]	630
	32	1.600 [40.64]	632
	36	1.800 [45.72]	636
	40	2.000 [50.80]	640

TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR HIGH TEMP. BLUE FR-4 EPOXY
UL 94V-0

TERMINAL CONTACT BRASS PER ASTM-B16
BeCu PER ASTM-B194

OPERATING TEMP. -65°C TO 150°C

CONTACT FORCES

INSERTION STANDARD 9 oz. AVG.
WITHDRAWAL STANDARD 2 oz. MIN.

ORDERING INFORMATION

218-XXX-232S-PXX-A10

SERIES

DIP - SPACING

NO. OF PINS

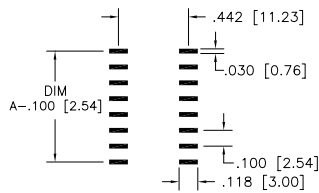
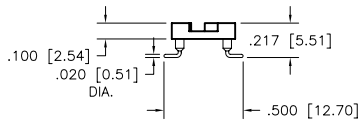
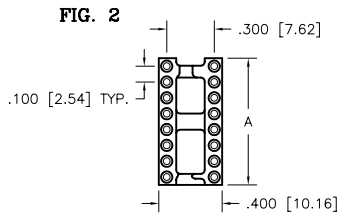
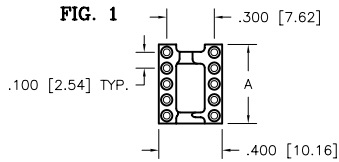
PLATING: TERMINAL / CONTACT
P30: GOLD / GOLD
P31: TIN-LEAD / GOLD
P32: TIN-LEAD / TIN
OTHER PLATINGS AVAILABLE
SEE OPTIONAL PLATINGS

TERMINAL ASSEMBLY

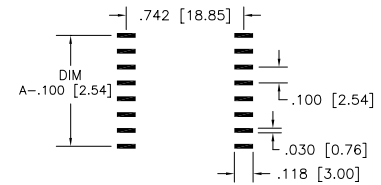
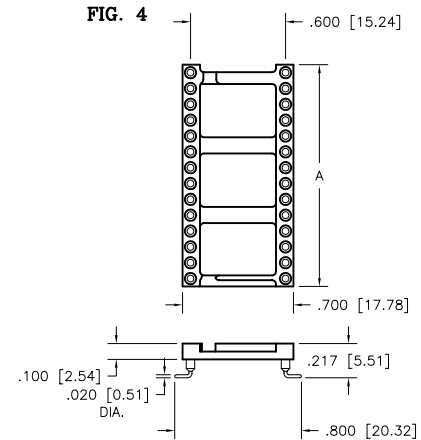
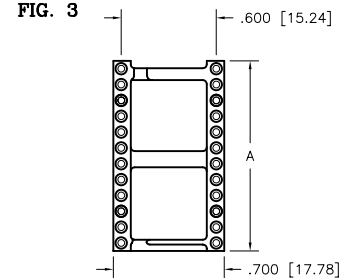
© ANDON 2007 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]. WE RESERVE THE RIGHT TO CHANGE SPECIFICATIONS WITHOUT NOTICE.



SERIES 219 SURFACE MOUNT GULLWING SOCKET (OPEN FRAME)



WAFER CHART			
	PIN	DIM "A"	
FIG. 1	6	.300 [7.62]	306
	8	.400 [10.16]	308
	10	.500 [12.70]	310
FIG. 2	14	.700 [17.78]	314
	16	.800 [20.32]	316
	18	.900 [22.86]	318
	20	1.000 [25.40]	320
	22	1.100 [27.94]	322
	24	1.200 [30.48]	324
	28	1.400 [35.56]	328
FIG. 3	24	1.200 [30.48]	624
FIG. 4	28	1.400 [35.56]	628
	30	1.500 [38.10]	630
	32	1.600 [40.64]	632
	36	1.800 [45.72]	636
	40	2.000 [50.80]	640
	48	2.400 [60.96]	648



P.C.B. FOOTPRINT

TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR HIGH TEMP. GREY NYLON 46
UL 94V-0

TERMINAL CONTACT BRASS PER ASTM-B16
BeCu PER ASTM-B194

OPERATING TEMP. -65° TO 150°

CONTACT FORCES

INSERTION STANDARD 9 oz. AVG.
WITHDRAWAL STANDARD 2 oz. MIN.

ORDERING INFORMATION

219-XXX-232S-PXX-Y10

SERIES | **PLATING: TERMINAL / CONTACT**

DIP - SPACING | P30: GOLD / GOLD

NO. OF PINS | P31: TIN-LEAD / GOLD

| P32: TIN-LEAD / TIN

| OTHER PLATINGS AVAILABLE

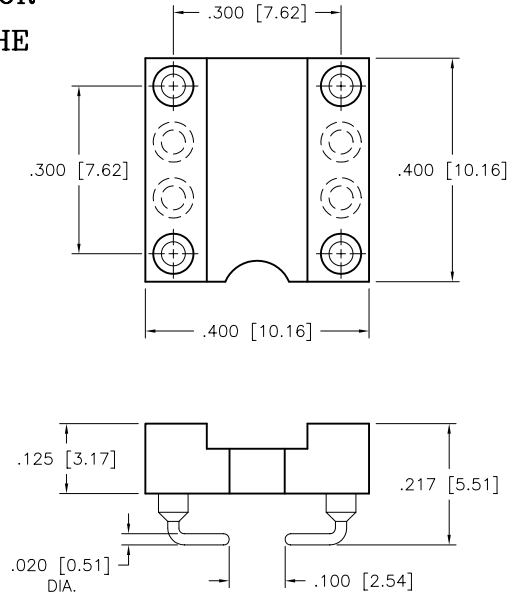
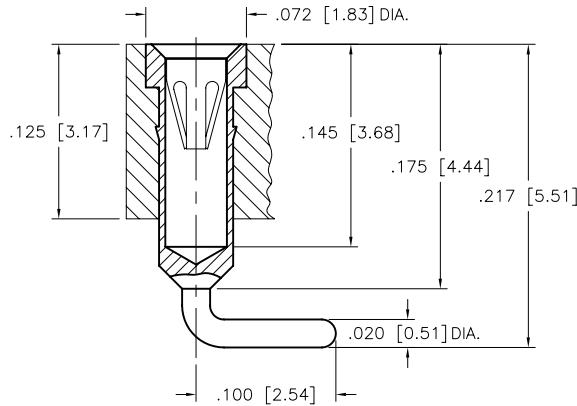
| SEE OPTIONAL PLATING

TERMINAL ASSEMBLY



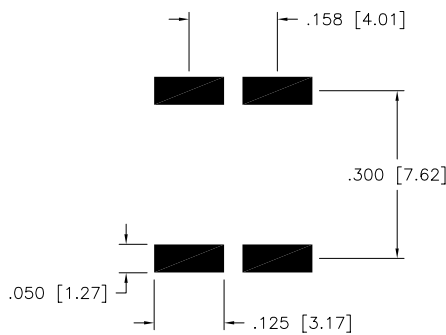
SERIES 221 "J" LEAD OSCILLATOR SOCKET (SOLID FRAME)

REPLACEMENT SOCKET FOR SMD OSCILLATOR TO REPLACE WITH LEADED DEVICES ON THE SAME FOOTPRINT

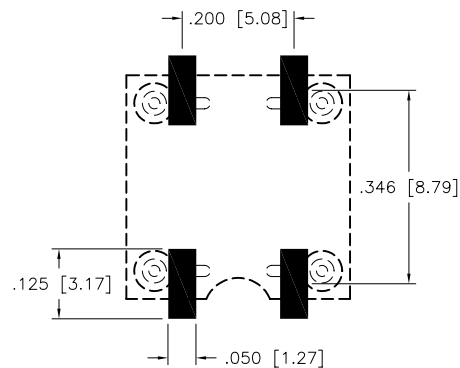


4 PIN REPLACEMENT SOCKET

STANDARD P.C.B. FOOTPRINT



REPLACEMENT P.C.B. FOOTPRINT



TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR	HIGH TEMP. GREY NYLON 46 UL 94V-0 LISTED
TERMINAL CONTACT	BRASS PER ASTM-B16 BeCu PER ASTM-B194
OPERATING TEMP.	-65° TO 150°
CONTACT FORCES	
INSERTION	STANDARD 9 oz. AVG.
WITHDRAWAL	STANDARD 2 oz. MIN.

ORDERING INFORMATION

SERIES	221-084-232S-PXX-Y10	PLATING: TERMINAL / CONTACT
WAFER SIZE		P30: GOLD / GOLD
NUMBER OF PINS LOADED		P31: TIN-LEAD / GOLD
TERMINAL ASSEMBLY		P32: TIN-LEAD / TIN
		OTHER PLATINGS AVAILABLE SEE OPTIONAL PLATINGS



SERIES 301 SIP SOCKET (SNAP)
SERIES 302 SIP SOCKET (SOLID)
SERIES 405 SIP SOCKET (LAMINATE WAFER)
SERIES 411 SIP SOCKET (POLYIMIDE WAFER)

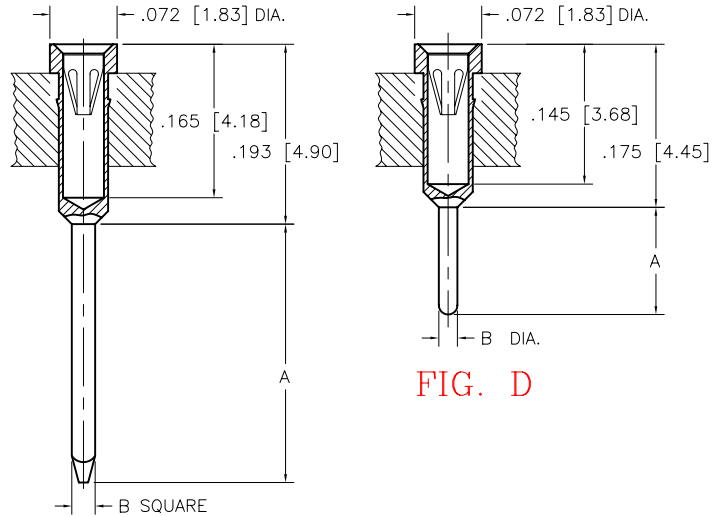
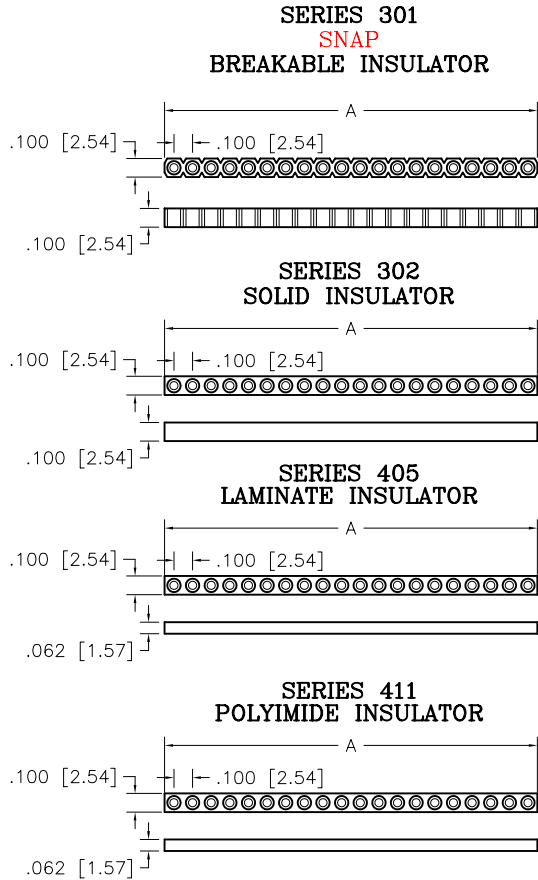


FIG. C

FIG. D

TERMINAL CHART			
TERMINAL	FIG.	DIM "A"	DIM "B"
-01	D	.115 [2.92]	.020 [0.51]
-02	C	.370 [9.40]	.025 [0.64]
-03	C	.510 [12.95]	.025 [0.64]
-08	D	.170 [4.31]	.020 [0.51]
-09	D	.280 [7.11]	.020 [0.51]
-11	D	.135 [3.43]	.020 [0.51]
-94	D	.125 [3.17]	.018 [0.46]

PIN	DIM "A"	
2	.200 [5.08]	002
3	.300 [7.62]	003
4	.400 [10.16]	004
5	.500 [12.70]	005
6	.600 [15.24]	006
7	.700 [17.78]	007
8	.800 [20.32]	008
9	.900 [22.86]	009
10	1.000 [25.40]	010
11	1.100 [27.94]	011
12	1.200 [30.48]	012
13	1.300 [33.02]	013
14	1.400 [35.56]	014
15	1.500 [38.10]	015
16	1.600 [40.64]	016

PIN	DIM "A"	
17	1.700 [43.18]	017
18	1.800 [45.72]	018
19	1.900 [48.26]	019
20	2.000 [50.80]	020
21	2.100 [53.34]	021
22	2.200 [55.88]	022
23	2.300 [58.42]	023
24	2.400 [60.96]	024
25	2.500 [63.50]	025
26	2.600 [66.04]	026
27	2.700 [68.58]	027
28	2.800 [71.12]	028
29	2.900 [73.66]	029
30	3.000 [76.20]	030
31	3.100 [78.74]	031
32	3.200 [81.28]	032

TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR GLASS FILLED POLYESTER
 UL 94V-0 LISTED

TERMINAL CONTACT BRASS PER ASTM-B16
 BeCu PER ASTM-B194

CONTACT FORCES

INSERTION STANDARD 9 oz. AVG.
WITHDRAWAL STANDARD 2 oz. MIN.

CONTACT TYPE

S: STANDARD DIP INSERTION FORCE 9.0 oz. AVG.
 WITHDRAWAL FORCE 2.0 oz. MIN.

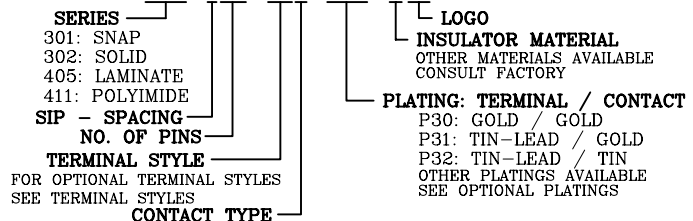
M: STANDARD PGA INSERTION FORCE 1.6 oz. MAX.
 WITHDRAWAL FORCE 0.5 oz. MIN.

L: INTERSTITIAL PGA INSERTION FORCE 1.0 oz. MAX.
 WITHDRAWAL FORCE 0.3 oz. MIN.

H: HIGH FORCE INSERTION FORCE 18.3 oz. MAX.
 WITHDRAWAL FORCE 4.2 oz. MIN.

ORDERING INFORMATION

301-OXX-XXX-PXX-B10
 302-OXX-XXX-PXX-B10
 405-OXX-XXX-PXX-N10
 411-OXX-XXX-PXX-H10





SERIES 303 SIP SOCKET (SNAP) HEAD FLUSH WITH INSULATOR

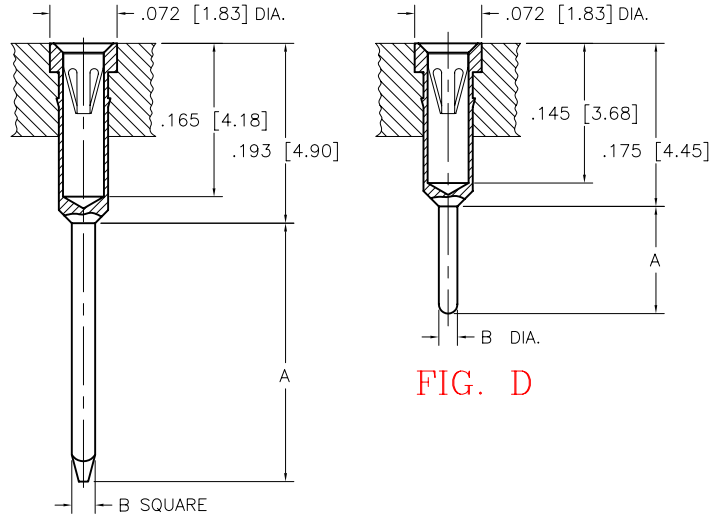
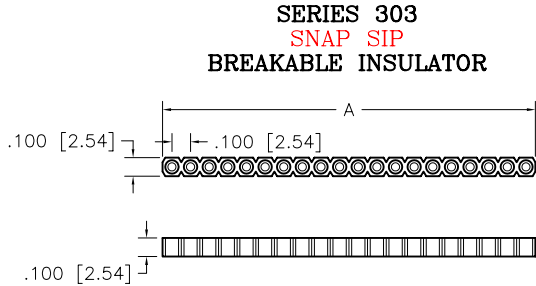


FIG. C

FIG. D

PIN	DIM "A"	
2	.200 [5.08]	002
3	.300 [7.62]	003
4	.400 [10.16]	004
5	.500 [12.70]	005
6	.600 [15.24]	006
7	.700 [17.78]	007
8	.800 [20.32]	008
9	.900 [22.86]	009
10	1.000 [25.40]	010
11	1.100 [27.94]	011
12	1.200 [30.48]	012
13	1.300 [33.02]	013
14	1.400 [35.56]	014
15	1.500 [38.10]	015
16	1.600 [40.64]	016

PIN	DIM "A"	
17	1.700 [43.18]	017
18	1.800 [45.72]	018
19	1.900 [48.26]	019
20	2.000 [50.80]	020
21	2.100 [53.34]	021
22	2.200 [55.88]	022
23	2.300 [58.42]	023
24	2.400 [60.96]	024
25	2.500 [63.50]	025
26	2.600 [66.04]	026
27	2.700 [68.58]	027
28	2.800 [71.12]	028
29	2.900 [73.66]	029
30	3.000 [76.20]	030
31	3.100 [78.74]	031
32	3.200 [81.28]	032

TERMINAL CHART			
TERMINAL	FIG.	DIM "A"	DIM "B"
-01	D	.115 [2.92]	.020 [0.51]
-02	C	.370 [9.40]	.025 [0.64]
-03	C	.510 [12.95]	.025 [0.64]
-08	D	.170 [4.31]	.020 [0.51]
-09	D	.280 [7.11]	.020 [0.51]
-11	D	.135 [3.43]	.020 [0.51]
-94	D	.125 [3.17]	.018 [0.46]

CONTACT TYPE

S: STANDARD DIP	INSERTION FORCE	9.0 oz. AVG.
	WITHDRAWAL FORCE	2.0 oz. MIN.
M: STANDARD PGA	INSERTION FORCE	1.6 oz. MAX.
	WITHDRAWAL FORCE	0.5 oz. MIN.
L: INTERSTITIAL PGA	INSERTION FORCE	1.0 oz. MAX.
	WITHDRAWAL FORCE	0.3 oz. MIN.
H: HIGH FORCE	INSERTION FORCE	18.3 oz. MAX.
	WITHDRAWAL FORCE	4.2 oz. MIN.

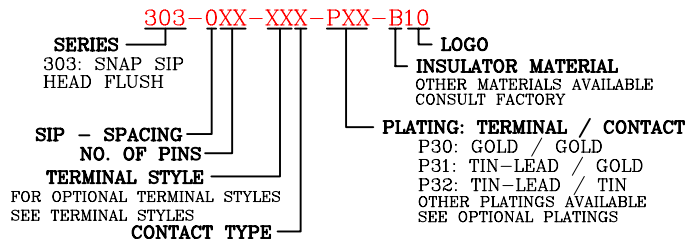
TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR	GLASS FILLED POLYESTER UL 94V-0 LISTED
TERMINAL CONTACT	BRASS PER ASTM-B16 BeCu PER ASTM-B194
OPERATING TEMP.	-65°C TO +125°C

CONTACT FORCES

INSERTION	STANDARD	9 oz. AVG.
WITHDRAWAL	STANDARD	2 oz. MIN.

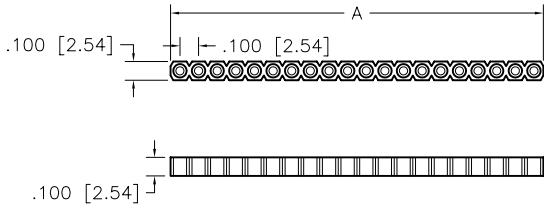
ORDERING INFORMATION



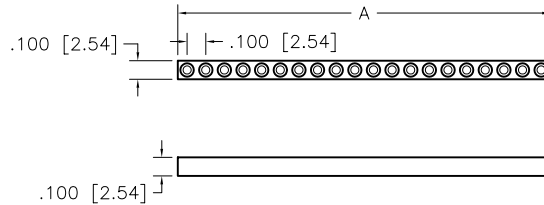


SERIES 305 SIP COMPONENT ADAPTER (SNAP)
SERIES 306 SIP COMPONENT ADAPTER (SOLID)

**SERIES 305
SNAP
BREAKABLE INSULATOR**

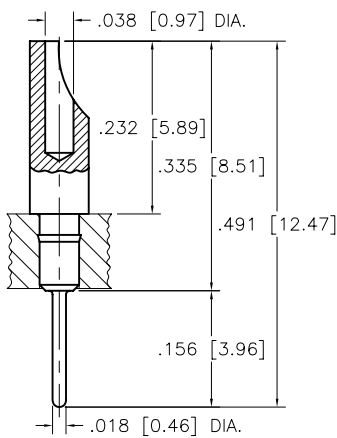


**SERIES 306
SOLID
SOLID INSULATOR**

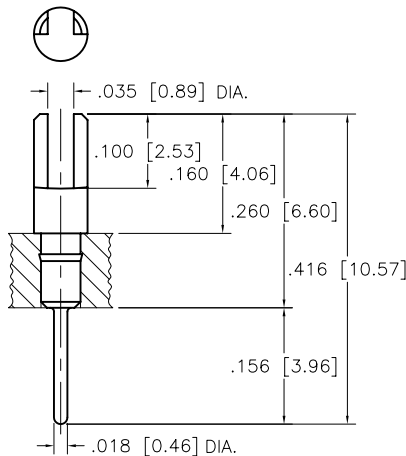


PIN	DIM "A"	
2	.200 [5.08]	002
3	.300 [7.62]	003
4	.400 [10.16]	004
5	.500 [12.70]	005
6	.600 [15.24]	006
7	.700 [17.78]	007
8	.800 [20.32]	008
9	.900 [22.86]	009
10	1.000 [25.40]	010
11	1.100 [27.94]	011
12	1.200 [30.48]	012
13	1.300 [33.02]	013
14	1.400 [35.56]	014
15	1.500 [38.10]	015
16	1.600 [40.64]	016

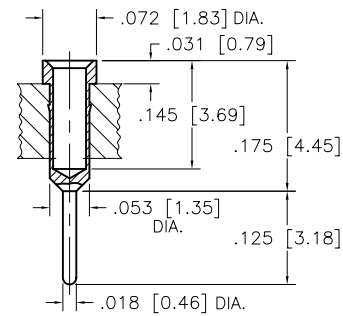
PIN	DIM "A"	
17	1.700 [43.18]	017
18	1.800 [45.72]	018
19	1.900 [48.26]	019
20	2.000 [50.80]	020
21	2.100 [53.34]	021
22	2.200 [55.88]	022
23	2.300 [58.42]	023
24	2.400 [60.96]	024
25	2.500 [63.50]	025
26	2.600 [66.04]	026
27	2.700 [68.58]	027
28	2.800 [71.12]	028
29	2.900 [73.66]	029
30	3.000 [76.20]	030
31	3.100 [78.74]	031
32	3.200 [81.28]	032



-05



-06



-07
HOLLOW
PHOSPHOR BRONZE

TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR GLASS FILLED POLYESTER
 UL 94V-0 LISTED
TERMINAL OPERATING TEMP. BRASS PER ASTM-B16
 -65°C TO +125°C

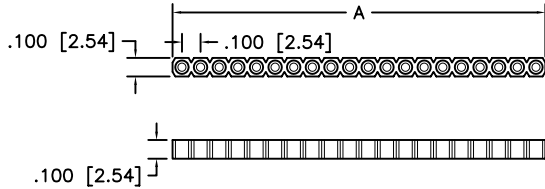
ORDERING INFORMATION

30X-OXX-XX-XXX-B10
 SERIES: 305: SNAP, 306: SOLID
 SPACING NO. OF PINS
 TERMINAL STYLE
 LOGO
 INSULATOR MATERIAL
 OTHER MATERIALS AVAILABLE
 CONSULT FACTORY
 PLATING: TERMINAL
 G04: GOLD
 T: TIN
 TL: TIN-LEAD

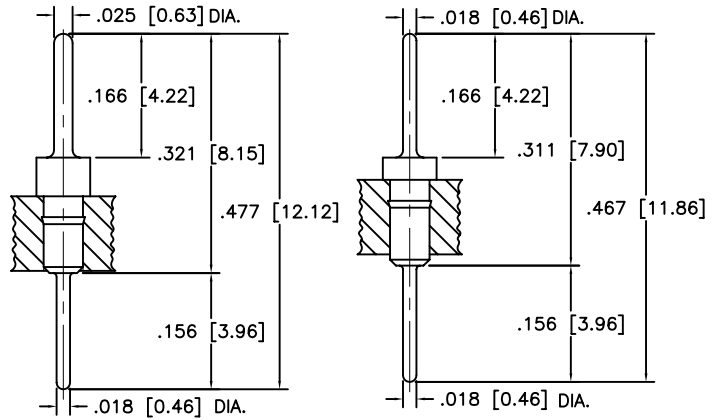
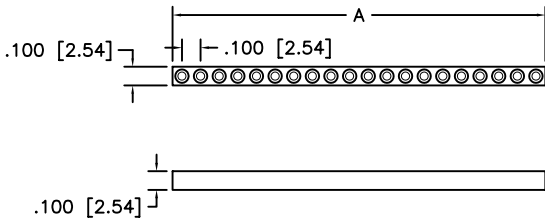


SERIES 307 SIP BOARD TO BOARD CONNECTOR (SNAP)
308 SIP BOARD TO BOARD CONNECTOR (SOLID)

**SERIES 307
SNAP
BREAKABLE INSULATOR**



**SERIES 308
SOLID
SOLID INSULATOR**

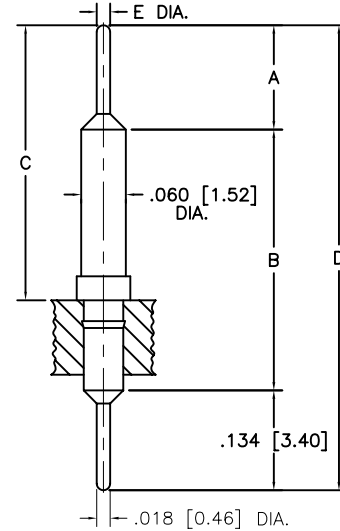


-37 MATERIAL: (1)
-04 MATERIAL: (2)
-77 MATERIAL: (2)

TERM.	A	B	C	D	E
-56	.184	4.68	.583	14.82	.630
-58	.140	3.56	.350	8.89	.390
-59	.140	3.56	.457	11.61	.479

PIN	DIM "A"	
2	.200 [5.08]	002
3	.300 [7.62]	003
4	.400 [10.16]	004
5	.500 [12.70]	005
6	.600 [15.24]	006
7	.700 [17.78]	007
8	.800 [20.32]	008
9	.900 [22.86]	009
10	1.000 [25.40]	010
11	1.100 [27.94]	011
12	1.200 [30.48]	012
13	1.300 [33.02]	013
14	1.400 [35.56]	014
15	1.500 [38.10]	015
16	1.600 [40.64]	016

PIN	DIM "A"	
17	1.700 [43.18]	017
18	1.800 [45.72]	018
19	1.900 [48.26]	019
20	2.000 [50.80]	020
21	2.100 [53.34]	021
22	2.200 [55.88]	022
23	2.300 [58.42]	023
24	2.400 [60.96]	024
25	2.500 [63.50]	025
26	2.600 [66.04]	026
27	2.700 [68.58]	027
28	2.800 [71.12]	028
29	2.900 [73.66]	029
30	3.000 [76.20]	030
31	3.100 [78.74]	031
32	3.200 [81.28]	032



-XX MATERIAL: (1)

TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR GLASS FILLED POLYESTER
 UL 94V-0 LISTED
TERMINAL MATERIAL: (1) BRASS PER ASTM-B16
 MATERIAL: (2) PHOSPHOR BRONZE PER ASTM-B139
CONTACT BeCu PER ASTM-B194
OPERATING TEMP. -65°C TO +125°C

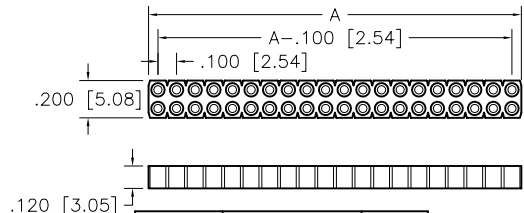
ORDERING INFORMATION

XXX-0XX-XX-XXX-B10
 SERIES 307: SNAP
 308: SOLID
 SIP - SPACING
 NO. OF PINS
 TERMINAL STYLE
 LOGO
 INSULATOR MATERIAL
 OTHER MATERIAL AVAILABLE
 CONSULT FACTORY
 PLATING: TERMINAL
 G04: GOLD
 T: TIN
 TL: TIN-LEAD



SERIES 351 TWIN STRIP SOCKET 355 TWIN STRIP COMPONENT ADAPTER

TWIN STRIP WAFER



PINS PER ROW	DIM "A"	ORDER CODE
5	.500 [12.70]	205
10	1.000 [25.40]	210
20	2.000 [50.80]	220
32	3.200 [81.28]	232
40	4.000 [101.60]	240

* OTHER PIN QUANTITIES AVAILABLE

SERIES 351 TERMINALS

TERMINAL CHART			
TERMINAL	FIG.	DIM "A"	DIM "B"
-01	D	.115 [2.92]	.020 [0.51]
-02	C	.370 [9.40]	.025 [0.64]
-03	C	.510 [12.95]	.025 [0.64]
-08	D	.170 [4.31]	.020 [0.51]
-09	D	.280 [7.11]	.020 [0.51]
-11	D	.135 [3.43]	.020 [0.51]
-94	D	.125 [3.17]	.018 [0.46]

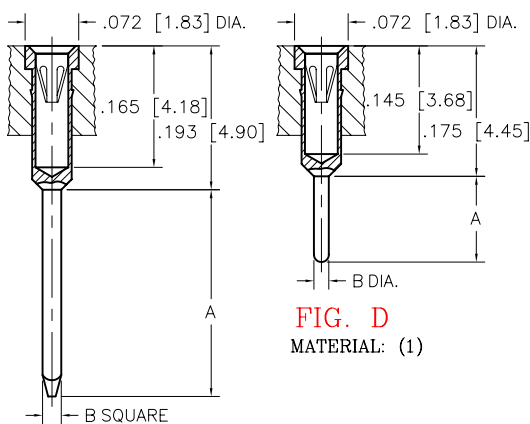


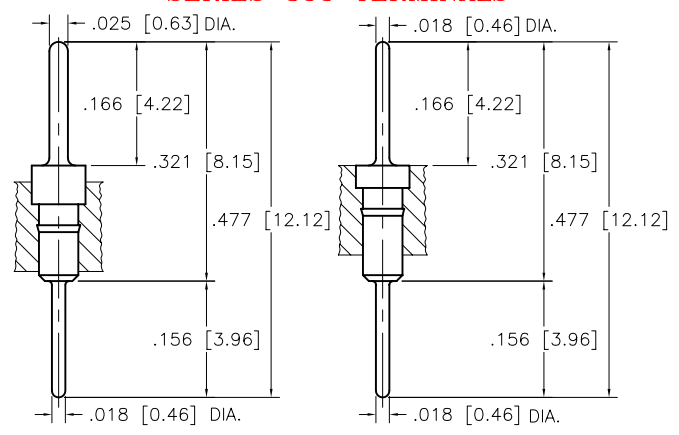
FIG. C MATERIAL: (1)

FIG. D MATERIAL: (1)

TECHNICAL SPECIFICATIONS

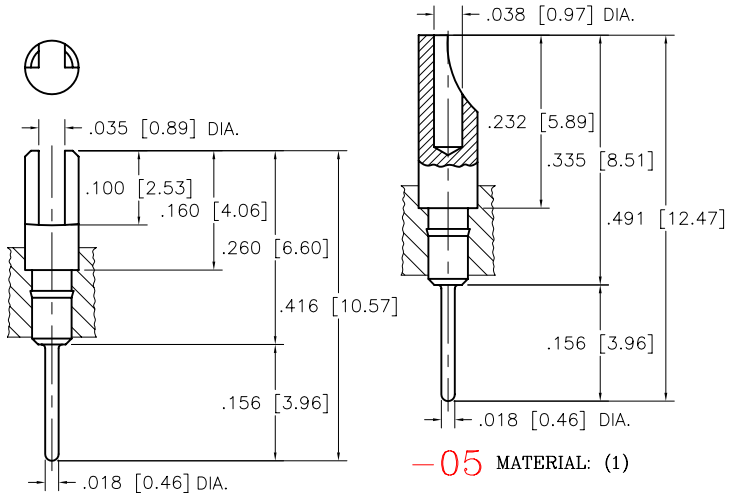
- MATERIAL INSULATOR:** GLASS FILLED POLYESTER UL 94V-0 LISTED
- TERMINAL MATERIAL:** (1) BRASS PER ASTM-B16; (2) PHOSPHOR BRONZE PER ASTM-B139
- CONTACT:** BeCu PER ASTM-B194
- OPERATING TEMP.:** -65°C TO +125°C
- CONTACT FORCES:**
 - INSERTION:** STANDARD 9 oz. AVG.
 - WITHDRAWAL:** STANDARD 2 oz. MIN.

SERIES 355 TERMINALS



-37 MATERIAL: (1)
-04 MATERIAL: (2)

-77 MATERIAL: (2)



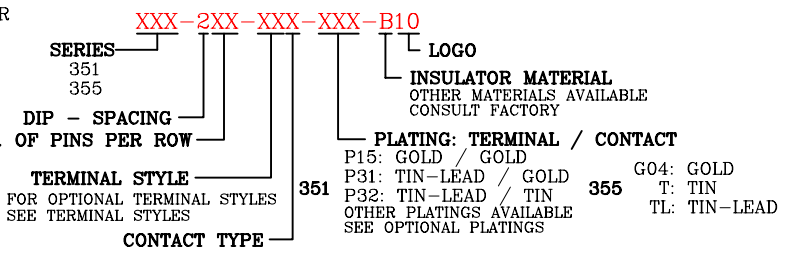
-06 MATERIAL: (2)

-05 MATERIAL: (1)

CONTACT TYPE

- S: STANDARD DIP** INSERTION FORCE 9.0 oz. AVG. WITHDRAWAL FORCE 2.0 oz. MIN.
- M: STANDARD PGA** INSERTION FORCE 1.6 oz. MAX. WITHDRAWAL FORCE 0.5 oz. MIN.
- L: INTERSTITIAL PGA** INSERTION FORCE 1.0 oz. MAX. WITHDRAWAL FORCE 0.3 oz. MIN.
- H: HIGH FORCE** INSERTION FORCE 18.3 oz. MAX. WITHDRAWAL FORCE 4.2 oz. MIN.

ORDERING INFORMATION



© ANDON 2007 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]. WE RESERVE THE RIGHT TO CHANGE SPECIFICATIONS WITHOUT NOTICE.



SERIES 360 PIN HEADER

.025 IN. [0.64 MM] SQ. POST
.100 IN. [2.54 MM] PITCH

TYPE
PSS
PSR
PDS
PDR

- .025 IN [0.64 MM] SQUARE POST ON .100 IN [2.54 MM] CENTERLINE PITCH
- MOLDED WITH STANDOFFS
- UP TO 40 PIN POSITIONS AVAILABLE SINGLE IN LINE AND 80 POSITIONS DUAL IN LINE
- X/Y STACKABLE

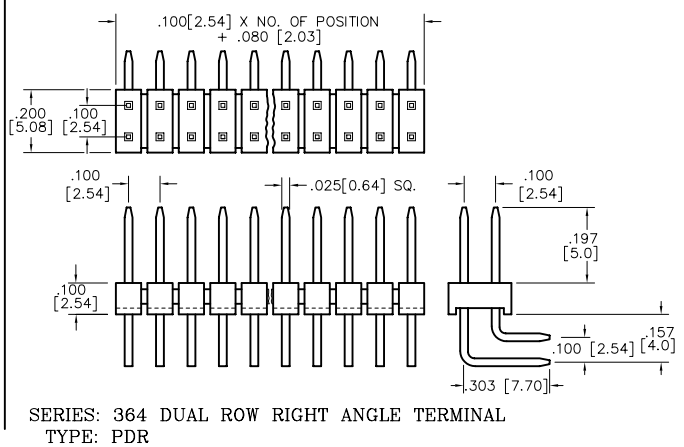
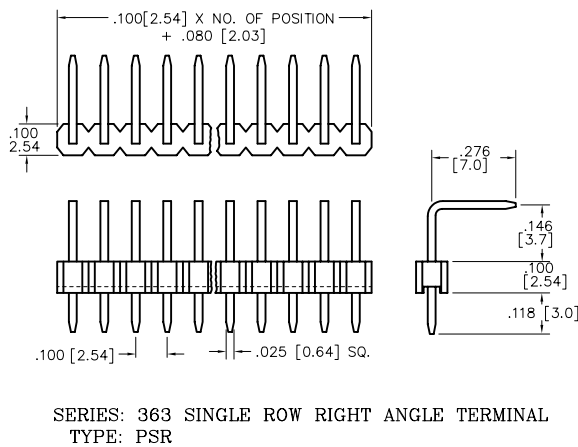
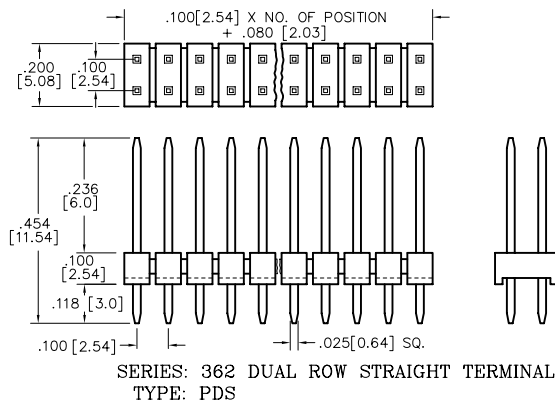
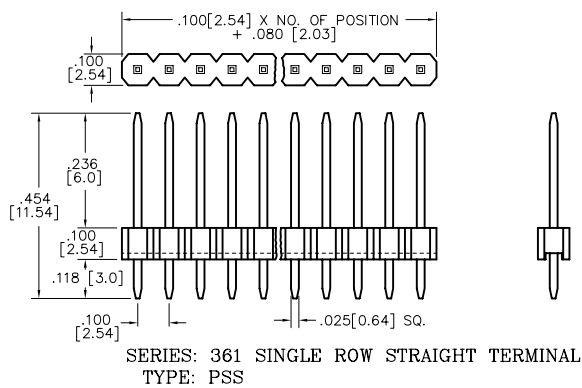
TECHNICAL SPECIFICATIONS

MATERIAL DATA

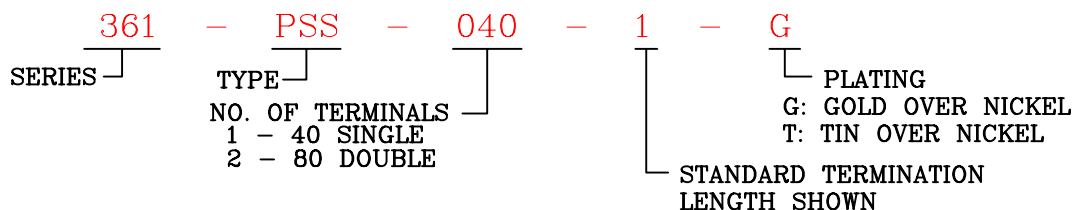
INSULATOR.....GLASS FILLED POLYESTER
UL RATING.....94V-0
TERMINAL.....BRASS
PLATING.....GOLD OVER NICKEL OR TIN

ELECTRICAL DATA

OPERATING TEMPERATURE.....-55°C TO +105°C
VOLTAGE RATING...1000 VAC RMS FOR 1 MIN.
CURRENT RATING 3A
INSULATION RESISTANCE.....1000 MEGOHMS



ORDERING INFORMATION



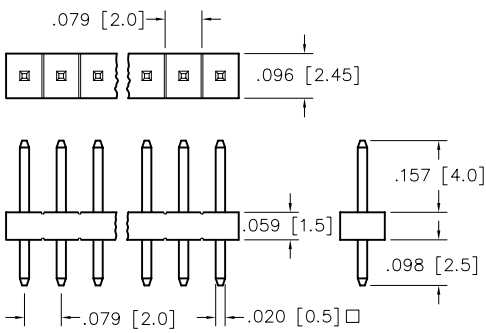


SERIES 380 SINGLE/DUAL ROW HEADERS
 COMMERCIAL-.079 IN.[2,00 MM] PITCH

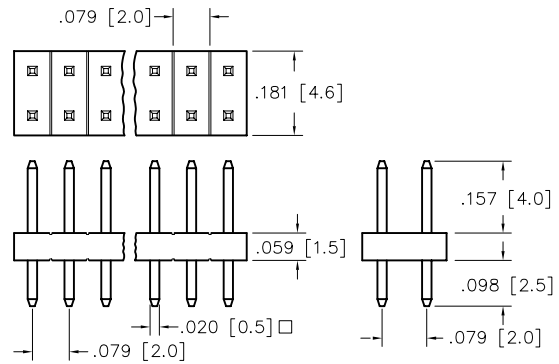
TYPE
 PSS RDS
 PDS PSR
 RSS PDR

- .079 IN.[2,00 MM] CENTERLINE PITCH WITH .020 [0,51] SQUARE POST
- UP TO 40 PIN POSITIONS SINGLE IN LINE AND 80 PIN POSITIONS DUAL IN LINE
- X/Y STACKABLE

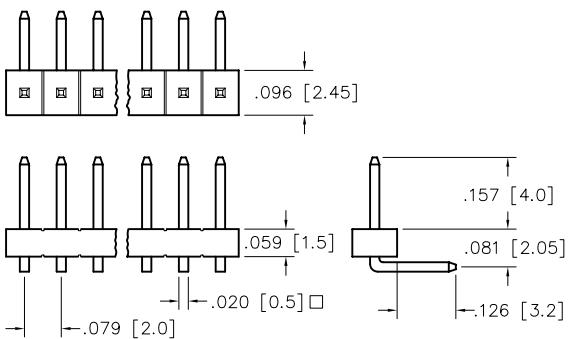
PIN HEADERS



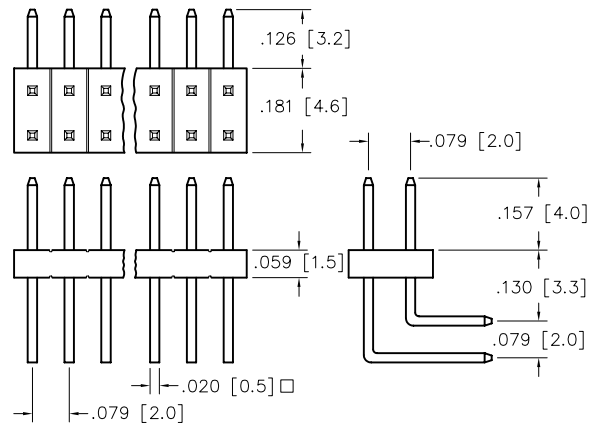
SERIES: 381 SINGLE ROW STRAIGHT TERMINAL
 TYPE: PSS



SERIES: 382 DUAL ROW STRAIGHT TERMINAL
 TYPE: PDS

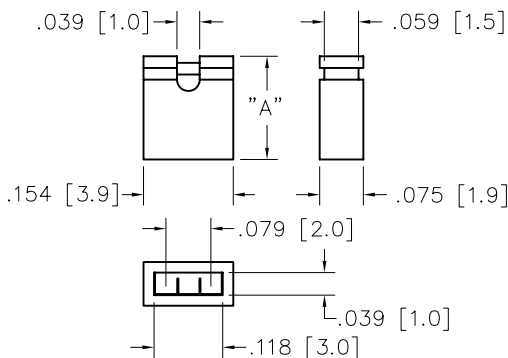


SERIES: 385 SINGLE ROW RIGHT ANGLE TERMINAL
 TYPE: PSR



SERIES: 386 DUAL ROW RIGHT ANGLE TERMINAL
 TYPE: PDR

MINI JUMPER



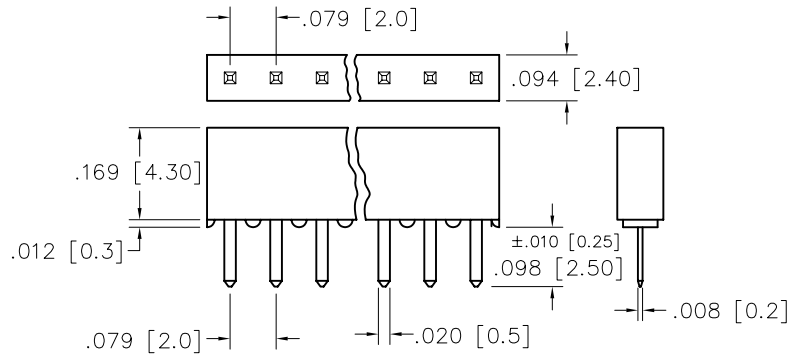
MINI JUMPER P/N	A
392-200-35-G	.138 [3.5]
392-200-45-G	.177 [4.5]
392-200-50-G	.213 [5.4]

© ANDON 2007 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]

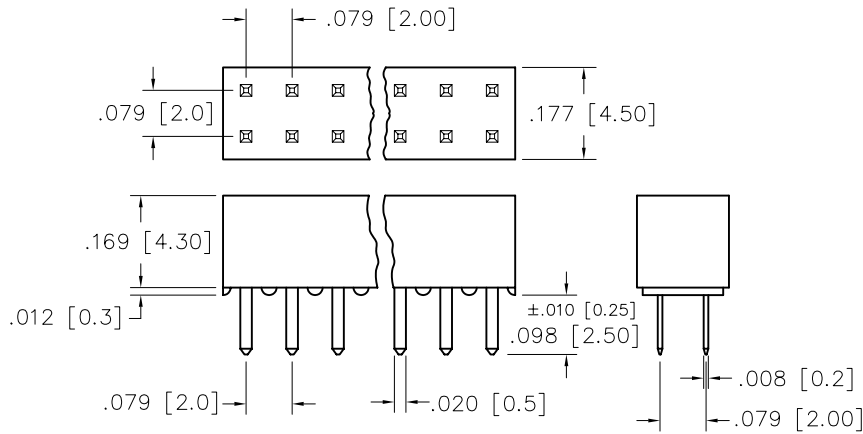
WE RESERVE THE RIGHT TO CHANGE SPECIFICATIONS WITHOUT NOTICE.



SERIES 380 RECEPTACLE HEADERS



SERIES: 383 SINGLE ROW STRAIGHT CONTACTS
TYPE: RSS



SERIES: 384 DUAL ROW STRAIGHT CONTACTS
TYPE: RDS

TECHNICAL SPECIFICATIONS

MATERIAL DATA

INSULATOR.....GLASS FILLED THERMOPLASTIC
UL RATING.....94V-0
CONTACTPHOSPHOR BRONZE
PLATING.....GOLD OVER NICKEL

ELECTRICAL DATA

PIN HEADER ∞
CURRENT RATING.....1 AMP DC
OPERATING
TEMPERATURE -55°C TO +105°C

RECEPTACLE HEADER

CURRENT RATING.....1 AMP DC
CONTACT RESISTANCE.....20 Mohm MAX. AT 6 VDC 0.3A
INSULATION RESISTANCE...1000 Mohms MIN. AT
500 VDC
DIELECTRIC VOLTAGE.....500 VAC FOR 1 MINUTE

ORDERING INFORMATION



CONSULT FACTORY FOR

* OTHER PIN LENGTHS
* .100 [2.54] PIN HEADERS
AND RECEPTACLE HEADERS
NO. OF CONTACTS
1-40 SINGLE
2-80 DOUBLE

© ANDON 2007 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]

WE RESERVE THE RIGHT TO CHANGE SPECIFICATIONS WITHOUT NOTICE.



SERIES 390 MINI-JUMPER/SHORTING CONNECTOR
 PITCH: .100 in. [2.54 mm] and .079 in. [2.00 mm]

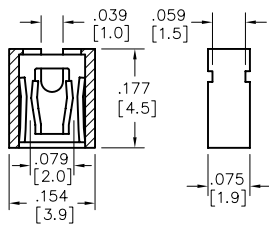
FEATURES

- All Sides Stackable
- Simply Connecting Two Connecting Points Together Or Opposite
- Low Profile
- .079[2.00] Pitch Mates To .020[0.5] Sq. Post
- .100[2.54] Pitch Mates To .025[0.64] Sq. Post

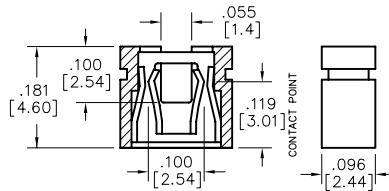
TECHNICAL SPECIFICATIONS

Contact: Phosphor Bronze
 Gold Plating
 Insulator: Glass Filled Polyester (PBT) 94V-0
 Current Rating: 3 AMP max.
 Dielectric Withstanding Voltage: AC 650 VRMS
 Contact Resistance: 20 Milliohms max.
 Insulation Resistance: 1000 Megaohms min.

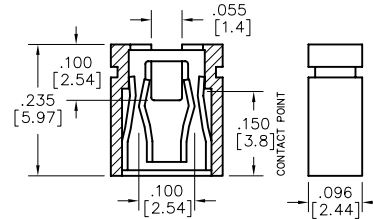
392-200-45-1G



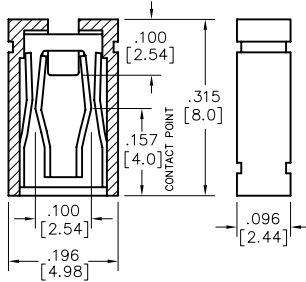
393-254-46-1G



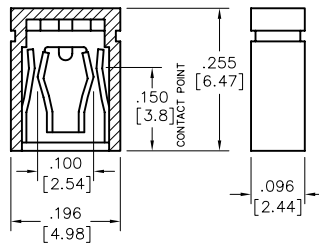
393-254-59-1G



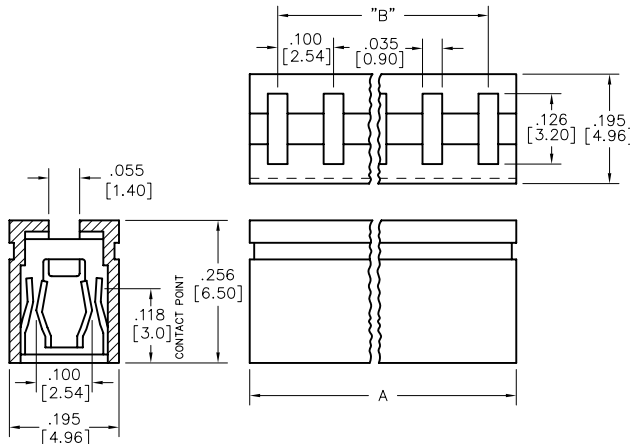
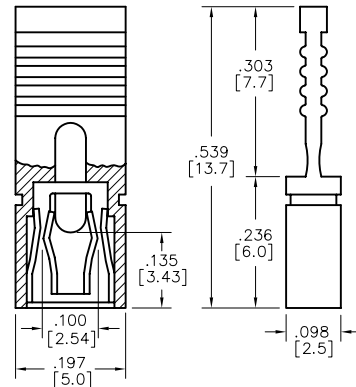
393-254-80-1G



394-254-64-1G



395-254-60-1G

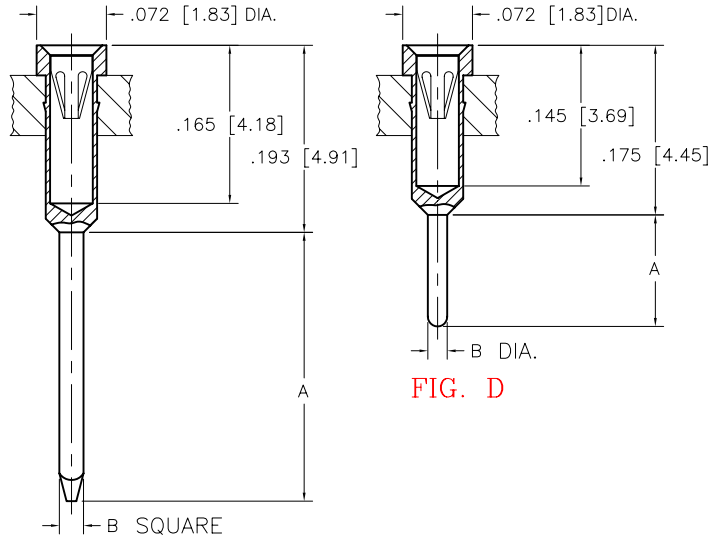
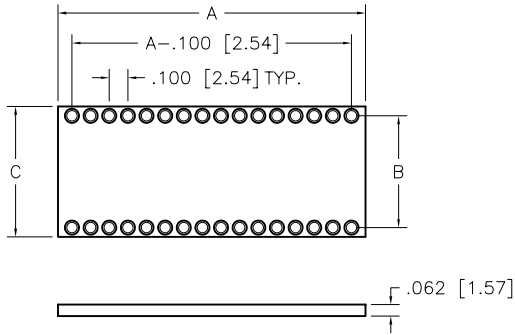


MULTI-JUMPER

PART NO.	NO. OF CONTACTS	"A" ±.004[±0.1]	"B" ±.004[±0.1]
396-254-65-2G	2	.200 [5.08]	.100 [2.54]
396-254-65-3G	3	.300 [7.62]	.200 [5.08]
396-254-65-4G	4	.400 [10.16]	.300 [7.62]
396-254-65-5G	5	.500 [12.70]	.400 [10.16]
396-254-65-6G	6	.600 [15.24]	.500 [12.70]
396-254-65-7G	7	.700 [17.78]	.600 [15.24]
396-254-65-8G	8	.800 [20.32]	.700 [17.78]
396-254-65-9G	9	.900 [22.86]	.800 [20.32]
396-254-65-10G	10	1.000 [25.40]	.900 [22.86]



SERIES 204 DIP SOCKET (LAMINATE WAFER)
(WITHOUT INDEX MARK)



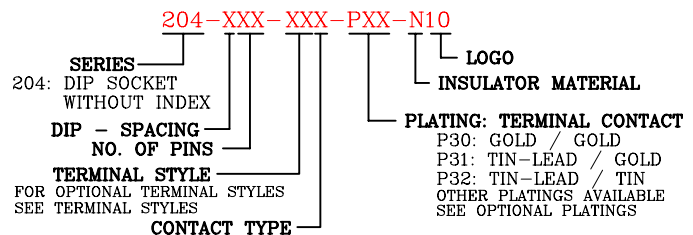
SERIES 402 WAFER CHART						
PIN	DIM "A"	DIM "B"	DIM "C"			
6	.300 [7.62]	.300 [7.62]	.400 [10.16]	306		
8	.400 [10.16]			308		
10	.500 [12.70]			310		
14	.700 [17.78]			314		
16	.800 [20.32]			316		
18	.900 [22.86]			318		
20	1.000 [25.40]			320		
22	1.100 [27.94]			322		
24	1.200 [30.48]			324		
28	1.400 [35.56]			328		
24	1.200 [30.48]	.600 [15.24]	.700 [17.78]	624		
28	1.400 [35.56]			628		
30	1.500 [38.10]			630		
32	1.600 [40.64]			632		
36	1.800 [45.72]			636		
40	2.000 [50.80]			640		
42	2.100 [53.34]			642		
48	2.400 [60.96]			648		
24	1.200 [30.48]			.900 [22.86]	1.000 [25.40]	924
28	1.400 [35.56]					928
32	1.650 [41.91]	932				
50	2.500 [63.05]	950				
52	2.600 [66.04]	952				
64	3.250 [82.55]	964				

TERMINAL CHART			
TERMINAL	FIG.	DIM "A"	DIM "B"
-01	D	.115 [2.92]	.020 [0.51]
-03	C	.510 [12.95]	.025 [0.64]
-08	D	.170 [4.31]	.020 [0.51]
-09	D	.280 [7.11]	.020 [0.51]
-94	D	.125 [3.17]	.018 [0.46]

CONTACT TYPE

S: STANDARD DIP	INSERTION FORCE	9.0 oz. AVG.
	WITHDRAWAL FORCE	2.0 oz. MIN.
M: STANDARD PGA	INSERTION FORCE	1.6 oz. MAX.
	WITHDRAWAL FORCE	0.5 oz. MIN.
L: INTERSTITIAL PGA	INSERTION FORCE	1.0 oz. MAX.
	WITHDRAWAL FORCE	0.3 oz. MIN.
H: HIGH FORCE	INSERTION FORCE	18.3 oz. MAX.
	WITHDRAWAL FORCE	4.2 oz. MIN.

ORDERING INFORMATION



TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR FR-4 EPOXY (LAMINATE)
UL 94V-0 LISTED

TERMINAL CONTACT BRASS PER ASTM-B16
BeCu PER ASTM-B194

OPERATING TEMP. -65°C TO +140°C

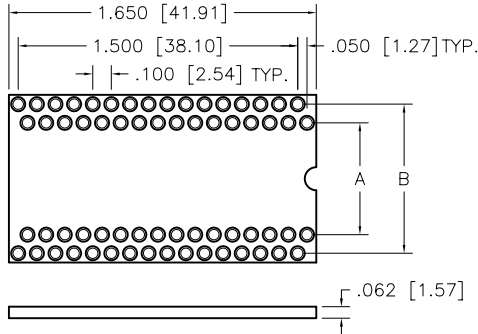
CONTACT FORCES

INSERTION STANDARD 9 oz. AVG.
WITHDRAWAL STANDARD 2 oz. MIN.



SERIES 401 QUAD SOCKET (LAMINATE WAFER)
SERIES 402 DIP SOCKET (LAMINATE WAFER)

SERIES 401 QUAD SOCKET



SERIES 401 WAFER CHART				
P/N	PINS	A	B	
401-764-	64	.750 [19.05]	.950 [24.15]	FOR ROCKWELL & NEC CHIP
401-864-	64	.600 [15.24]	.800 [20.32]	FOR FUJITSU CHIP

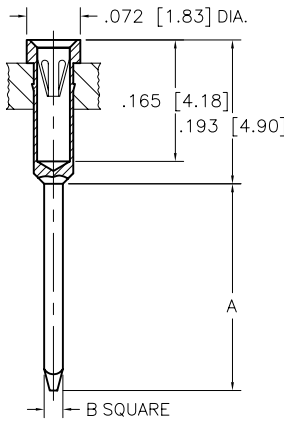


FIG. C

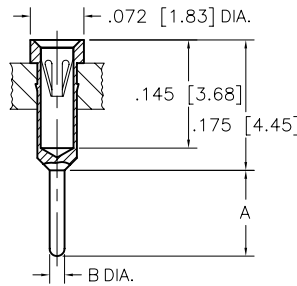


FIG. D

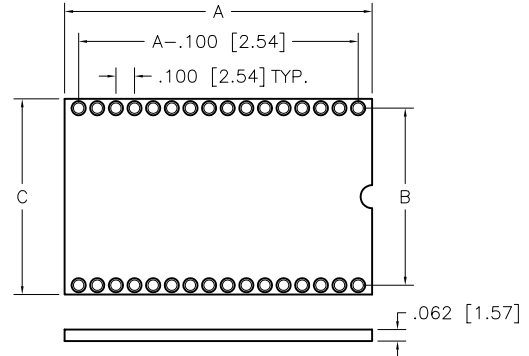
TERMINAL CHART			
TERMINAL	FIG.	DIM "A"	DIM "B"
-01	D	.115 [2.92]	.020 [0.51]
-03	C	.510 [12.95]	.025 [0.64]
-08	D	.170 [4.31]	.020 [0.51]
-09	D	.280 [7.11]	.020 [0.51]
-94	D	.125 [3.17]	.018 [0.46]

TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR FR-4 EPOXY (LAMINATE); UL 94V-0 LISTED
TERMINAL CONTACT BRASS PER ASTM-B16; BeCu PER ASTM-B194
OPERATING TEMP. -65°C TO +140°C

CONTACT FORCES
INSERTION STANDARD 9 oz. AVG.
WITHDRAWAL STANDARD 2 oz. MIN.

SERIES 402 DUAL IN-LINE

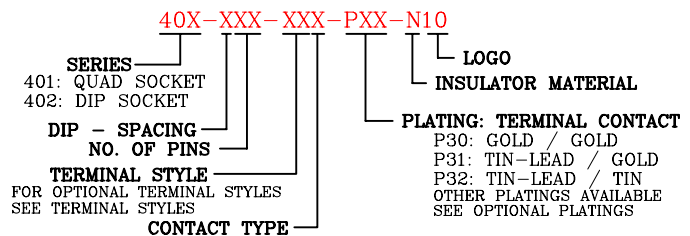


SERIES 402 WAFER CHART				
PIN	DIM "A"	DIM "B"	DIM "C"	
6	.300 [7.62]			306
8	.400 [10.16]			308
10	.500 [12.70]			310
14	.700 [17.78]			314
16	.800 [20.32]			316
18	.900 [22.86]			318
20	1.000 [25.40]			320
22	1.100 [27.94]			322
24	1.200 [30.48]			324
28	1.400 [35.56]			328
24	1.200 [30.48]			624
28	1.400 [35.56]			628
30	1.500 [38.10]			630
32	1.600 [40.64]			632
36	1.800 [45.72]			636
40	2.000 [50.80]			640
48	2.400 [60.96]			648
24	1.200 [30.48]		1.000 [25.40]	924
28	1.400 [35.56]		1.000 [25.40]	928
32	1.650 [41.91]		1.000 [25.40]	932
50	2.500 [63.05]		1.000 [25.40]	950
52	2.600 [66.04]		1.000 [25.40]	952
64	3.250 [82.55]		1.000 [25.40]	964

CONTACT TYPE

S: STANDARD DIP INSERTION FORCE 9.0 oz. AVG.
 WITHDRAWAL FORCE 2.0 oz. MIN.
M: STANDARD PGA INSERTION FORCE 1.6 oz. MAX.
 WITHDRAWAL FORCE 0.5 oz. MIN.
L: INTERSTITIAL PGA INSERTION FORCE 1.0 oz. MAX.
 WITHDRAWAL FORCE 0.3 oz. MIN.
H: HIGH FORCE INSERTION FORCE 18.3 oz. MAX.
 WITHDRAWAL FORCE 4.2 oz. MIN.

ORDERING INFORMATION



© ANDON 2007 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]. WE RESERVE THE RIGHT TO CHANGE SPECIFICATIONS WITHOUT NOTICE.



SERIES 406 DIP SOCKET: POLYIMIDE WITH STANDOFF
407 DIP SOCKET: POLYIMIDE WITHOUT STANDOFF

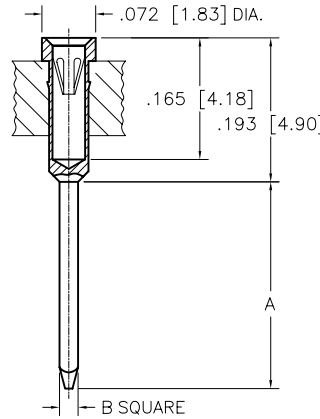
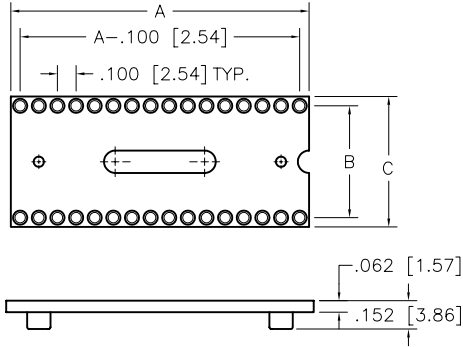


FIG. C

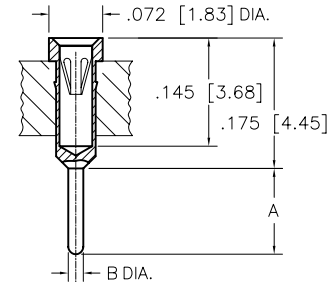


FIG. D

WAFER CHART				
PIN	DIM "A"	DIM "B"	DIM "C"	
6	.300 [7.62]	.300 [7.62]	.400 [10.16]	306
8	.400 [10.16]			308
10	.500 [12.70]			310
14	.700 [17.78]			314
16	.800 [20.32]			316
18	.900 [22.86]			318
20	1.000 [25.40]	.600 [15.24]	.700 [17.78]	320
22	1.100 [27.94]			322
24	1.200 [30.48]			324
28	1.400 [35.56]			328
24	1.200 [30.48]			624
28	1.400 [35.56]			628
30	1.500 [38.10]	.900 [22.86]	1.000 [25.40]	630
32	1.600 [40.64]			632
36	1.800 [45.72]			636
40	2.000 [50.80]			640
48	2.400 [60.96]			648
24	1.200 [30.48]			924
28	1.400 [35.56]	928		
32	1.600 [40.64]	932		
50	2.500 [63.05]	950		
52	2.600 [66.04]	952		
64	3.200 [81.28]	964		

NOTE:
6, 8, AND 10 PIN SOCKETS
DO NOT HAVE A WINDOW

TERMINAL STYLE			
TERMINAL	FIG.	DIM "A"	DIM "B"
-01	D	.115 [2.92]	.020 [0.51]
-03	C	.510 [12.95]	.025 [0.64]
-08	D	.170 [4.31]	.020 [0.51]
-09	D	.280 [7.11]	.020 [0.51]
-94	D	.125 [3.17]	.018 [0.46]

CONTACT TYPE

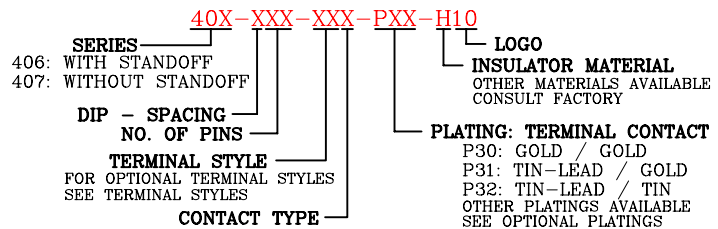
S: STANDARD DIP	INSERTION FORCE	9.0 oz. AVG.
	WITHDRAWAL FORCE	2.0 oz. MIN.
M: STANDARD PGA	INSERTION FORCE	1.6 oz. MAX.
	WITHDRAWAL FORCE	0.5 oz. MIN.
L: INTERSTITIAL PGA	INSERTION FORCE	1.0 oz. MAX.
	WITHDRAWAL FORCE	0.3 oz. MIN.
H: HIGH FORCE	INSERTION FORCE	18.3 oz. MAX.
	WITHDRAWAL FORCE	4.2 oz. MIN.
N: BeNi MATERIAL	INSERTION FORCE	6.70 oz. MAX.
	WITHDRAWAL FORCE	5.29 oz. MIN.

TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR BROWN POLYIMIDE
UL 94V-0 LISTED
TERMINAL CONTACT BRASS PER ASTM-B16
BeCu PER ASTM-B194
OPERATING TEMP. -65°C TO +240°C

CONTACT FORCES
INSERTION STANDARD 9 oz. AVG.
WITHDRAWAL STANDARD 2 oz. MIN.

ORDERING INFORMATION



© ANDON 2007 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]. WE RESERVE THE RIGHT TO CHANGE SPECIFICATIONS WITHOUT NOTICE.



SERIES 451 DECOUPLING CAPACITOR DIP SOCKET (LAMINATE WAFER)

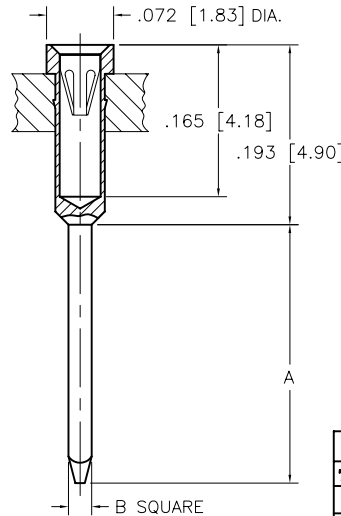
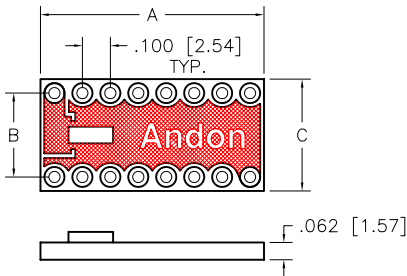


FIG. C

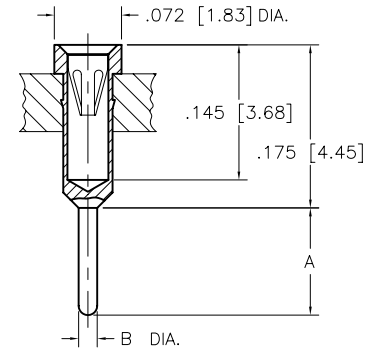
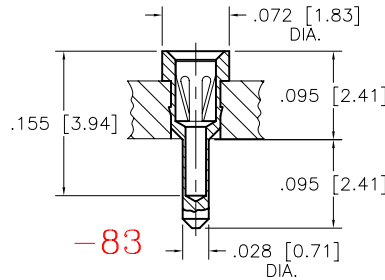


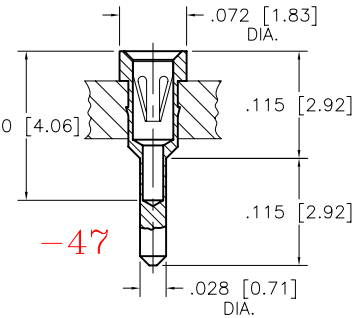
FIG. D

WAFER CHART				
PIN	DIM "A"	"B"	"C"	
6	.300 [7.62]			306
8	.400 [10.16]			308
10	.500 [12.70]			310
14	.700 [17.78]			314
16	.800 [20.32]			316
18	.900 [22.86]	.300 [7.62]	.400 [10.16]	318
20	1.000 [25.40]			320
22	1.100 [27.94]			322
24	1.200 [30.48]			324
28	1.400 [35.56]			328
16	.800 [20.32]	.400 [10.16]	.500 [12.70]	416
22	1.100 [27.94]			422
24	1.200 [30.48]			424
24	1.200 [30.48]			624
28	1.400 [35.56]			628
30	1.500 [38.10]			630
32	1.600 [40.64]	.600 [15.24]	.700 [17.78]	632
36	1.800 [45.72]			636
40	2.000 [50.80]			640
48	2.400 [60.96]			648

TERMINAL CHART			
TERMINAL	FIG.	DIM "A"	DIM "B"
-01	D	.115 [2.92]	.020 [0.51]
-02	C	.370 [9.40]	.025 [0.64]
-03	C	.510 [12.95]	.025 [0.64]
-08	D	.170 [4.31]	.020 [0.51]



-83



-47

CONTACT TYPE

S: STANDARD DIP	INSERTION FORCE	9.0 oz. AVG.
	WITHDRAWAL FORCE	2.0 oz. MIN.
M: STANDARD PGA	INSERTION FORCE	1.6 oz. MAX.
	WITHDRAWAL FORCE	0.5 oz. MIN.
L: INTERSTITIAL PGA	INSERTION FORCE	1.0 oz. MAX.
	WITHDRAWAL FORCE	0.3 oz. MIN.
H: HIGH FORCE	INSERTION FORCE	18.3 oz. MAX.
	WITHDRAWAL FORCE	4.2 oz. MIN.

TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR COPPER CLAD GLASS EPOXY
FR-4 LAMINATE
UL 94V-0 LISTED

TERMINAL CONTACT BRASS PER ASTM-B16
BeCu PER ASTM-B194

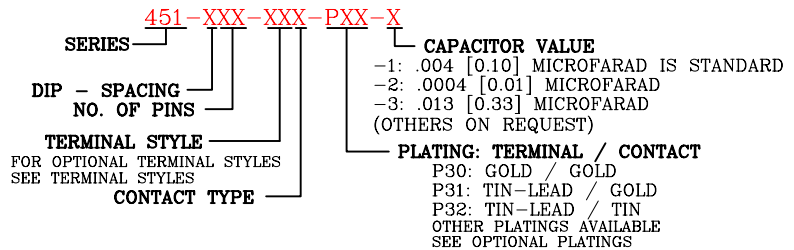
OPERATING TEMP. -65°C TO +140°C

CONTACT FORCES

INSERTION STANDARD 9 oz. AVG.

WITHDRAWAL STANDARD 2 oz. MIN.

ORDERING INFORMATION





7 SERIES CARI-LOC

CARRIER/SOCKET ASSEMBLY WITH RIGID INSULATOR AND CARI-LOC™ PATENTED BALL RELEASE PINS

ANDON'S PULL-OFF CARRIER SOCKETS FEATURE A SPECIALLY DESIGNED CARI-LOC™ BALL RELEASE PIN SYSTEM FOR EASY REMOVAL OF THE RIGID INSULATOR, PROTECTION OF ASSEMBLIES IN TRANSIT, PROTECTION AGAINST CONTAMINATION OF CONTACTS DURING SOLDERING OR CLEANING, PROPER PIN-TO-PIN LOCATION, AND ACCURATE PIN ALIGNMENT. IN ADDITION, MOLDED STANDOFFS HOLD THE BARREL OF THE TERMINAL CLEAR OF THE MOUNTING HOLES TO ASSURE PROPER SOLDER FLOW AND A GOOD SOLDER FILLET ON BOTH SIDES OF THE (PCB) PRINTED CIRCUIT BOARD.

FEATURES AND BENEFITS

RIGID INSULATOR

ALLOWS AUTOMATIC INSTALLATION.
 PROTECT ASSEMBLY IN TRANSIT.
 MAINTAINS PROPER PIN-TO-PIN LOCATION.
 MAINTAINS ACCURATE PIN ALIGNMENT.

REMOVAL OF RIGID INSULATOR

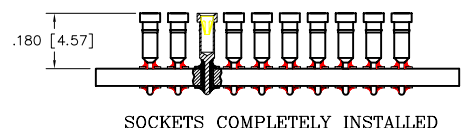
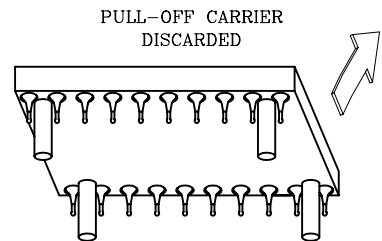
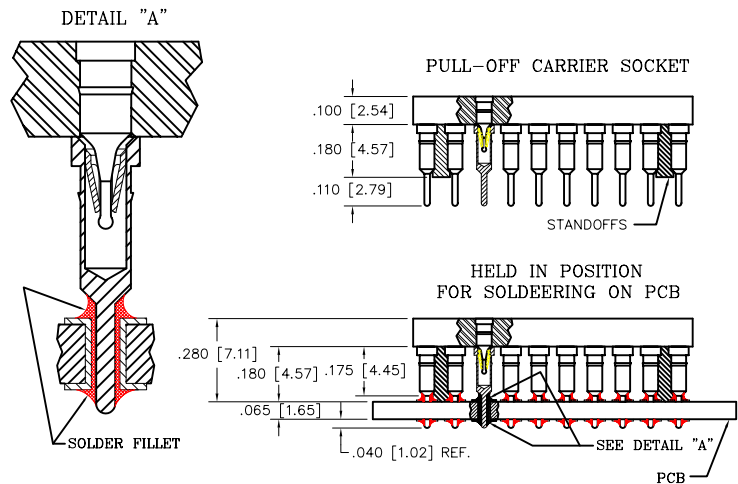
IMPROVES COOLING.
 ELIMINATES IONIC CONTAMINATION OF INSULATING MATERIAL.

MOLDED STANDOFFS

ADD MECHANICAL STRENGTH AND ELECTRICAL INTEGRITY.
 ALLOW ONLY SOLDER TAIL THROUGH PLATED-THRU-HOLE IN PCB.
 ENABLE PROPER SOLDER FLOW THROUGH PLATED-THRU-HOLE.
 INSURE GOOD SOLDER FILLET ON BOTH SIDES OF PCB.

CARI-LOC™ BALL RELEASE PINS

ALLOWS EASY PULL OFF OF RIGID INSULATOR AFTER SOLDERING.
 PREVENTS ACCIDENTAL SEPERATION OF SOCKET ASSEMBLY.
 PREVENTS CONTAMINATION OF CONTACTS DURING SOLDERING OR CLEANING.
 HOLDS TRUE POSITION.
 SYSTEM CAN BE USED ON ANY PGA, DIP, OR SIP FOOTPRINT.



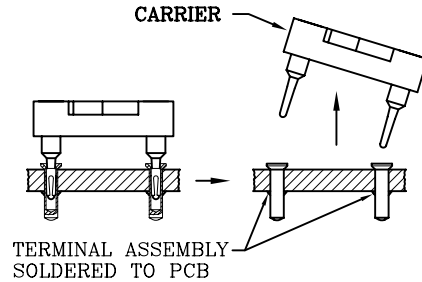


9 SERIES CARRIER ASSEMBLIES ULTRA LOW PROFILE

HI-RELIABILITY ULTRA LOW PROFILE CARRIER SOCKET ASSEMBLIES

- LOW PROFILE ABOVE PCB
- MAINTAINS ACCURATE PIN TO PIN LOCATION
- PREVENTS CONTACT CONTAMINATION DURING SOLDERING
- AVAILABLE IN PGA, DIP, AND SIP CONFIGURATIONS
- RIGID CARRIER EASES PIN INSERTION WITH STANDARD AUTO-INSERTION EQUIPMENT

TYPICAL APPLICATIONS



TECHNICAL SPECIFICATIONS

MATERIALS

CARRIER INSULATOR: GLASS FILLED POLYESTER
UL 94V-0

CARRIER TERMINAL: COPPER ALLOY, NICKEL PLATE

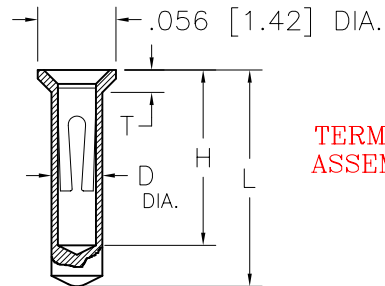
TERMINAL ASSEMBLY:

TERMINAL: BRASS, PER ASTM-B16

CONTACT: BeCu, PER ASTM-B194

CONTACT FORCE:

INSERTION FORCE: 2.8 oz. (MAX.)
WITHDRAWAL FORCE: 0.5 oz. (MIN.)
MOUNTING HOLE DIAMETER .039 [0.99] (MIN.)



TERMINAL ASSEMBLY

PLATING

- P17 TERMINAL: TIN-LEAD
CONTACT: GOLD 30 μ INCH
- P29 TERMINAL: TIN-LEAD
CONTACT: GOLD 10 μ INCH
- P32 TERMINAL: TIN-LEAD
CONTACT: TIN 200 μ INCH

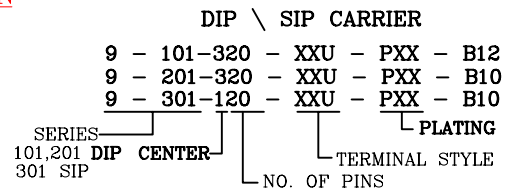
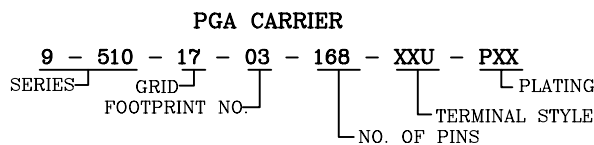
TYPE	H	L	D	T
-52U	.120[3.05]	.136[3.45]	.038[.97]	.016[.41]
-54U	.138[3.51]	.155[3.94]	.034[.86]	.031[.79]

* ALL DIMENSIONS ARE FOR REFERENCE ONLY

PGA DEVICE	ANDON P\N
INTEL™ 80386	9-510-14-21-132-XXU-PXX-S10
INTEL™ 80486	9-510-17-03-168-XXU-PXX-S10
INTEL OVERDRIVE READY™	9-510-19-09-238-XXU-PXX-S10
INTEL PENTIUM™	9-510-21-04-273-XXU-PXX-S10

* PENTIUM™ AND OVERDRIVE READY™ ARE TRADEMARKS OF INTEL CORP.
INTEL® IS A REGISTERED TRADEMARK OF INTEL CORPORATION

ORDERING INFORMATION



* CONSULT FACTORY FOR AVAILABLE SOCKET AND TERMINAL OPTIONS

© ANDON 2007

DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]

WE RESERVE THE RIGHT TO CHANGE THE DIMENSIONS WITHOUT NOTICE.



SERIES 120 ALUMINUM CARRIER FRAME

ALUMINUM CARRIER CHART			
	PIN	DIM "A"	
FIG. 1	6	.200 [5.08]	306
	8	.300 [7.62]	308
	10	.400 [10.16]	310
	14	.600 [15.24]	314
	16	.700 [17.78]	316
	18	.800 [20.32]	318
	20	.900 [22.86]	320
	22	1.000 [25.40]	322
	24	1.100 [27.94]	324
	FIG. 2	24	1.100 [27.94]
28		1.300 [33.02]	628
30		1.400 [35.56]	630
32		1.500 [38.10]	632
36		1.700 [43.18]	636
40		1.900 [48.26]	640
48		2.300 [58.42]	648

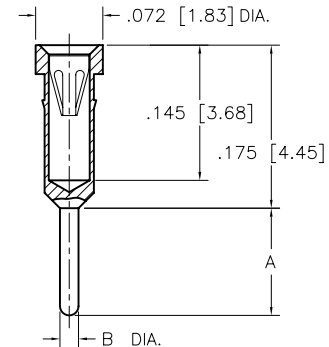
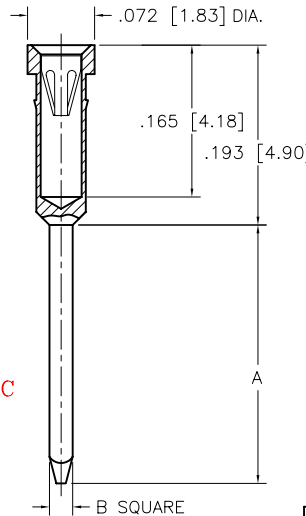


FIG. C

FIG. D

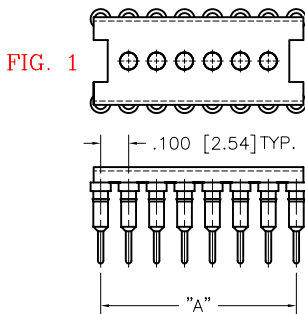
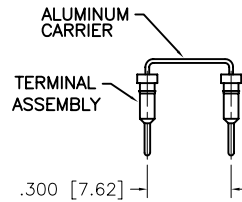


FIG. 1



TERMINAL STYLE			
TERMINAL	FIG.	DIM "A"	DIM "B"
-01	D	.115 [2.92]	.020 [0.51]
-02	C	.370 [9.40]	.025 [0.64]
-03	C	.510 [12.95]	.025 [0.64]
-08	D	.170 [4.31]	.020 [0.51]
-09	D	.280 [7.11]	.020 [0.51]
-11	D	.135 [3.43]	.020 [0.51]
-94	D	.125 [3.17]	.018 [0.46]

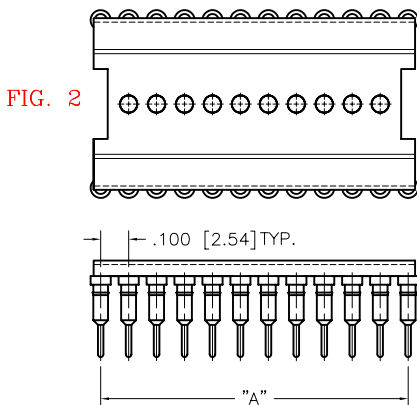
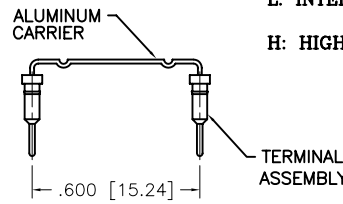


FIG. 2



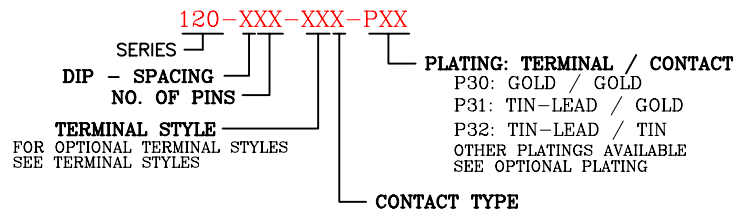
CONTACT TYPE

- S: STANDARD DIP** INSERTION FORCE 9.0 oz. AVG.
WITHDRAWAL FORCE 2.0 oz. MIN.
- M: STANDARD PGA** INSERTION FORCE 1.6 oz. MAX.
WITHDRAWAL FORCE 0.5 oz. MIN.
- L: INTERSTITIAL PGA** INSERTION FORCE 1.0 oz. MAX.
WITHDRAWAL FORCE 0.3 oz. MIN.
- H: HIGH FORCE** INSERTION FORCE 18.3 oz. MAX.
WITHDRAWAL FORCE 4.2 oz. MIN.

TECHNICAL SPECIFICATIONS

- MATERIAL CARRIER** ALUMINUM
- TERMINAL CONTACT** BRASS PER ASTM-B16
BeCu PER ASTM-B194
- CONTACT FORCES**
- INSERTION** STANDARD 9 oz. AVG.
- WITHDRAWAL** STANDARD 2 oz. MIN.

ORDERING INFORMATION

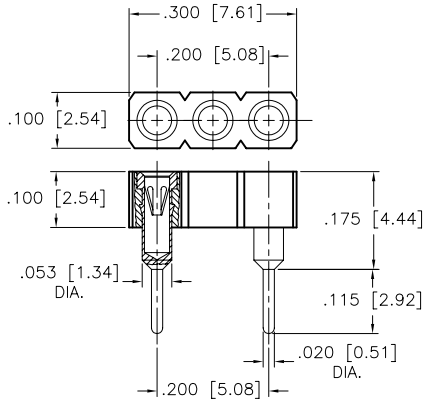




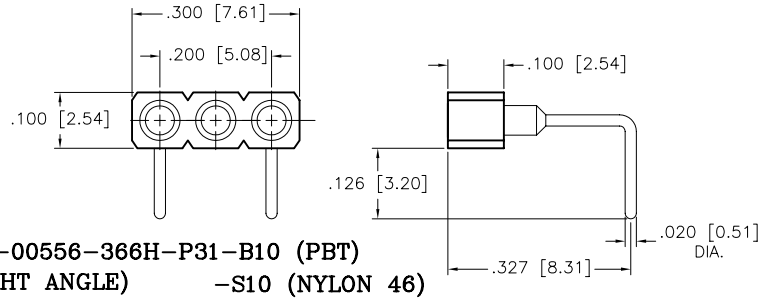
FUSE SOCKETS

TIN-LEAD AND LEAD FREE
QUICK AND EASY FUSE REPLACEMENT
WITHOUT POST SOLDERING / DESOLDERING

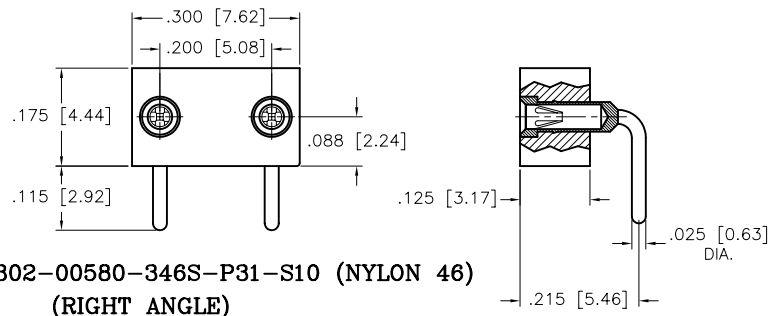
ISO 9001:2000
CERTIFIED



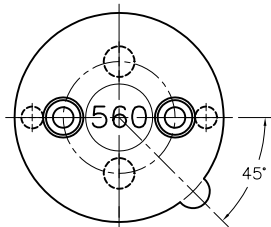
303-00556-01S-P29-S10 (NYLON 46)
(THRU HOLE)
UL LISTED FILE NO. E208521



303-00556-366H-P31-B10 (PBT)
(RIGHT ANGLE) -S10 (NYLON 46)

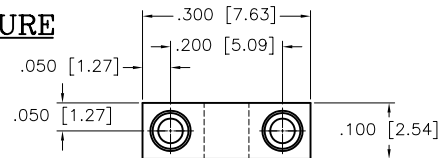


302-00580-346S-P31-S10 (NYLON 46)
(RIGHT ANGLE)

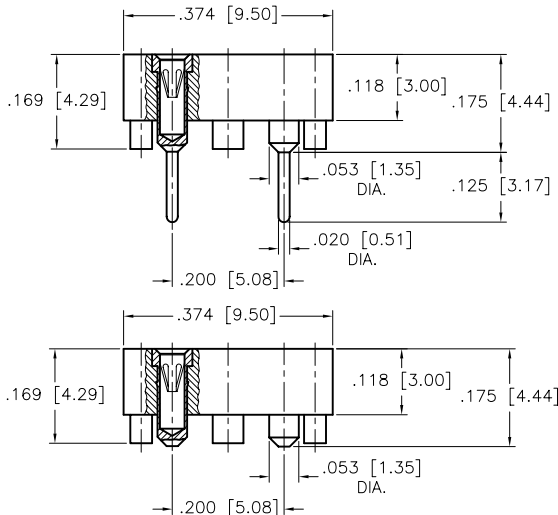


560-02-229S-P31-S18 (NYLON 46)
(THRU HOLE)
UL LISTED FILE NO. E208521

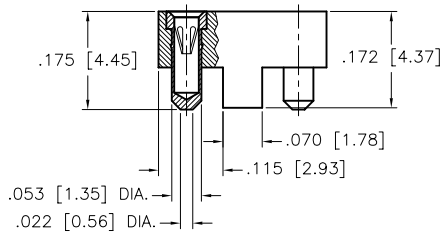
**HIGH TEMPERATURE
NYLON 46**



302-00567-93S-P31-S10 (NYLON 46)
(SURFACE MOUNT)
UL LISTED FILE NO. E208521



560-02-93S-P31-S18 (NYLON 46)
(SURFACE MOUNT)
UL LISTED FILE NO. E208521



TECHNICAL SPECIFICATIONS

MATERIAL

INSULATOR: B10: PBT GLASS FILLED, UL 94V-0
S10 AND S18: HIGH TEMP. NYLON 46
GLASS FILLED, UL 94V-0

TERMINAL: BRASS, TIN-LEAD PLATED } P31 AND P29 = TIN-LEAD PLATING *

TERMINAL: BRASS, TIN PLATED } R31 = LEAD FREE PLATING *

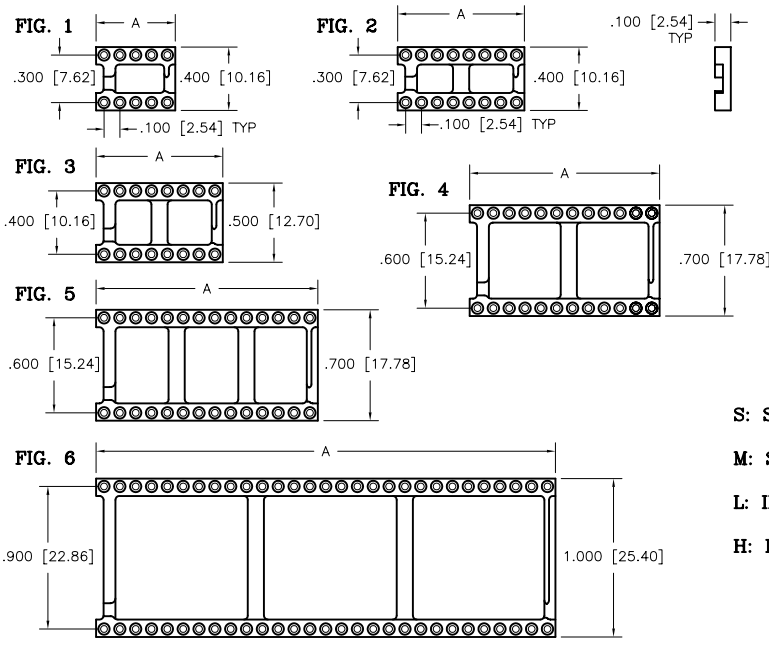
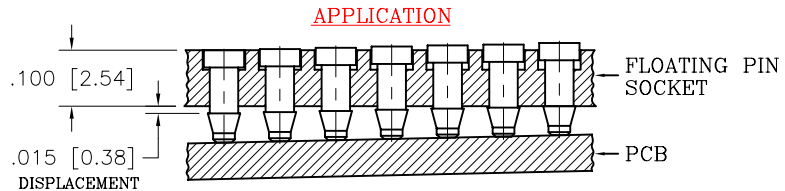
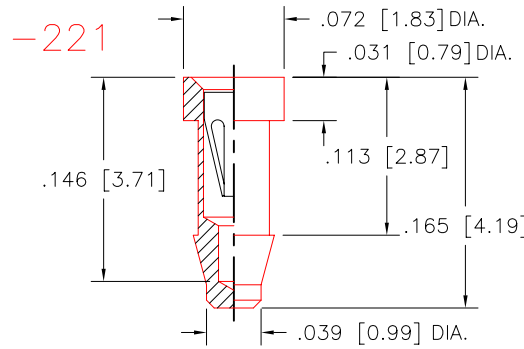
CONTACT: BeCu, GOLD PLATED } R29 = PLATING *

* OTHER PLATINGS AVAILABLE



FLOATING TERMINAL SOCKETS (OPEN FRAME)

WAFER CHART			
	PIN	DIM "A"	
FIG. 1	6	.300 [7.62]	306
	8	.400 [10.16]	308
	10	.500 [12.70]	310
FIG. 2	14	.700 [17.78]	314
	16	.800 [20.32]	316
	18	.900 [22.86]	318
	20	1.000 [25.40]	320
	22	1.100 [27.94]	322
	24	1.200 [30.48]	324
FIG. 3	28	1.400 [35.56]	328
	16	.800 [20.32]	416
FIG. 4	22	1.100 [27.94]	422
	24	1.200 [30.48]	424
FIG. 5	24	1.200 [30.48]	624
	28	1.400 [35.56]	628
	30	1.500 [38.10]	630
	32	1.600 [40.64]	632
	36	1.800 [45.72]	636
	40	2.000 [50.80]	640
FIG. 6	48	2.400 [60.96]	648
	50	2.500 [63.50]	950
	52	2.600 [66.04]	952
	64	3.200 [81.28]	964



CONTACT TYPE

S: STANDARD DIP	INSERTION FORCE	9.0 oz. AVG.
	WITHDRAWAL FORCE	2.0 oz. MIN.
M: STANDARD PGA	INSERTION FORCE	1.6 oz. MAX.
	WITHDRAWAL FORCE	0.5 oz. MIN.
L: INTERSTITIAL PGA	INSERTION FORCE	1.0 oz. MAX.
	WITHDRAWAL FORCE	0.3 oz. MIN.
H: HIGH FORCE	INSERTION FORCE	18.3 oz. MAX.
	WITHDRAWAL FORCE	4.2 oz. MIN.

TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR HIGH TEMP. GREY NYLON 46
UL 94V-0 LISTED

TERMINAL CONTACT BRASS PER ASTM-B16
BeCu PER ASTM-B194

OPERATING TEMP. -65°C TO +150°C

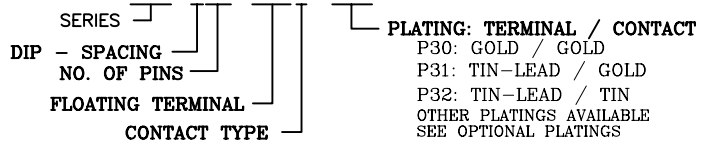
CONTACT FORCES

INSERTION STANDARD 9 oz. AVG.

WITHDRAWAL STANDARD 2 oz. MIN.

ORDERING INFORMATION

101-XXX-221S-PXX-Y12

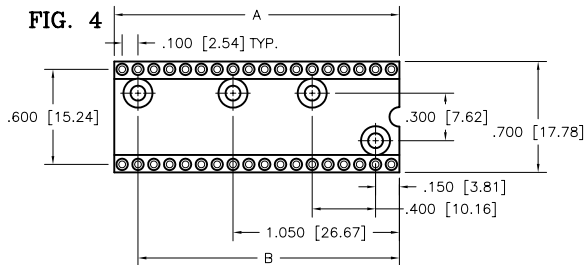
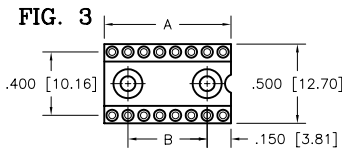
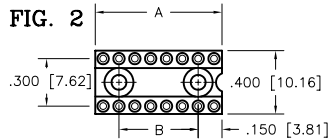
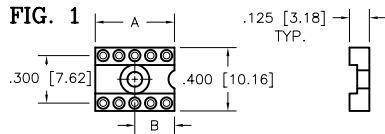
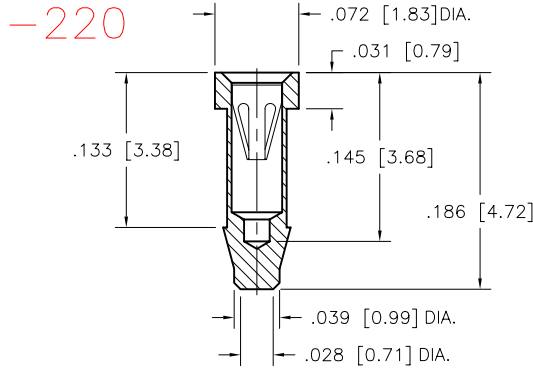




FLOATING TERMINAL SOCKETS (SOLID FRAME)

AVAILABLE WITH AND WITHOUT MOUNTING HOLES

WAFER CHART				
	PIN	DIM "A"	DIM "B"	
FIG. 1	6	.300 [7.62]	.150 [3.81]	306
	8	.400 [10.16]	.200 [5.08]	308
	10	.500 [12.70]	.250 [6.35]	310
FIG. 2	14	.700 [17.78]	.400 [10.16]	314
	16	.800 [20.32]	.500 [12.70]	316
	18	.900 [22.86]	.600 [15.24]	318
	20	1.000 [25.40]	.700 [17.78]	320
FIG. 3	24	1.200 [30.48]	.900 [22.86]	324
	24	.800 [20.32]	.500 [12.70]	416
	22	1.100 [27.94]	.800 [20.32]	422
	24	1.200 [30.48]	.900 [22.86]	424
FIG. 4	24	1.200 [30.48]		624
	28	1.400 [35.56]		628
	30	1.500 [38.10]		630
	32	1.600 [40.64]		632
	36	1.800 [45.72]	1.650 [41.91]	636
	40	2.000 [50.80]	1.650 [41.91]	640

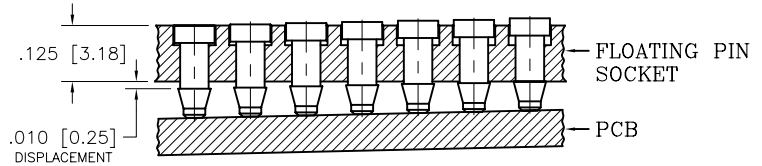


TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR GLASS FILLED NYLON 46
UL 94V-0 LISTED
TERMINAL CONTACT BRASS PER ASTM-B16
BeCu PER ASTM-B194
OPERATING TEMP. -65°C TO +150°C

CONTACT FORCES
INSERTION STANDARD 9 oz. AVG.
WITHDRAWAL STANDARD 2 oz. MIN.

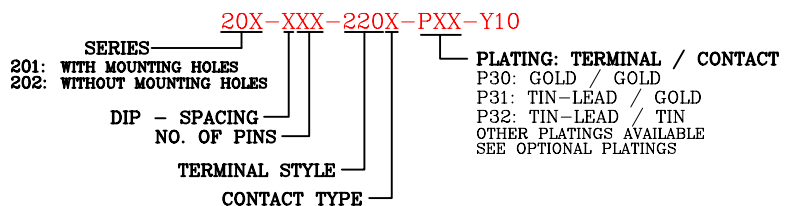
APPLICATION



CONTACT TYPE

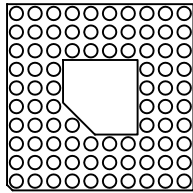
S: STANDARD DIP	INSERTION FORCE	9.0 oz. AVG.
	WITHDRAWAL FORCE	2.0 oz. MIN.
M: STANDARD PGA	INSERTION FORCE	1.6 oz. MAX.
	WITHDRAWAL FORCE	0.5 oz. MIN.
L: INTERSTITIAL PGA	INSERTION FORCE	1.0 oz. MAX.
	WITHDRAWAL FORCE	0.3 oz. MIN.
H: HIGH FORCE	INSERTION FORCE	18.3 oz. MAX.
	WITHDRAWAL FORCE	4.2 oz. MIN.

ORDERING INFORMATION

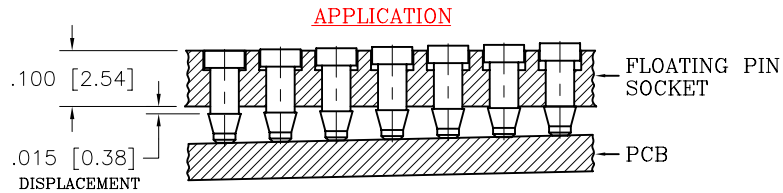
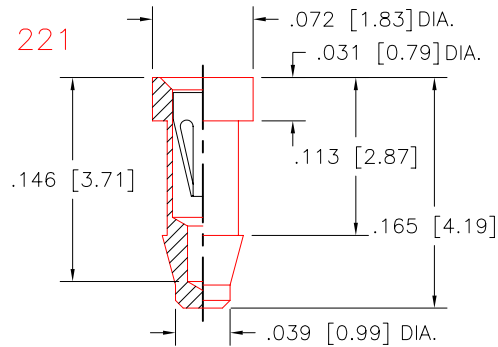




FLOATING TERMINAL SOCKETS (PIN GRID ARRAY)



REFER TO FOOTPRINTS FOR AVAILABLE PATTERNS



CONTACT TYPE

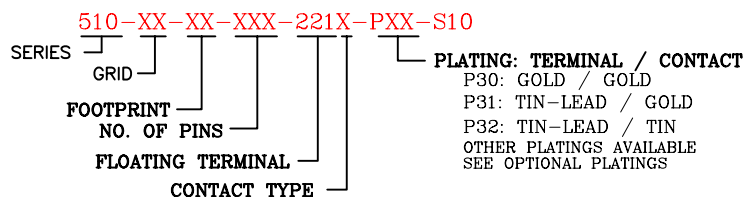
S: STANDARD DIP	INSERTION FORCE	9.0 oz. AVG.
	WITHDRAWAL FORCE	2.0 oz. MIN.
M: STANDARD PGA	INSERTION FORCE	1.6 oz. MAX.
	WITHDRAWAL FORCE	0.5 oz. MIN.
L: INTERSTITIAL PGA	INSERTION FORCE	1.0 oz. MAX.
	WITHDRAWAL FORCE	0.3 oz. MIN.
H: HIGH FORCE	INSERTION FORCE	18.3 oz. MAX.
	WITHDRAWAL FORCE	4.2 oz. MIN.

TECHNICAL SPECIFICATIONS

MATERIAL INSULATOR	HIGH TEMP. BLACK NYLON 46 UL 94V-0 LISTED
TERMINAL CONTACT	BRASS PER ASTM-B16 BeCu PER ASTM-B194
OPERATING TEMP.	-65°C TO +150°C

CONTACT FORCES	
INSERTION	STANDARD 1.6 oz. MAX.
WITHDRAWAL	STANDARD 0.5 oz. MIN.

ORDERING INFORMATION





TERMINAL STYLES

THE FOLLOWING PAGES SHOW OUR STANDARD RANGE OF TERMINAL STYLES. THESE ARE AVAILABLE EITHER MOUNTED IN A SOCKET BODY OR AS LOOSE PARTS. IF LOOSE PIECE PARTS ARE REQUIRED PLEASE REFER TO THE PART NUMBERS LISTED. SHOULD YOU HAVE ANY SPECIAL REQUIREMENTS PLEASE CONTACT OUR SALES OFFICE.

ANDON ELECTRONICS CORPORATION OFFERS A VARIETY OF TERMINALS FOR MOUNTING INTO DIFFERENT SOCKET INSULATORS. ON THE FOLLOWING PAGES YOU WILL FIND SPECIFICATIONS FOR OUR STANDARD TERMINALS FROM WHICH YOU MAY CHOOSE THE REQUIRED TYPE.

DESIGN AND ENGINEERING ASSISTANCE AVAILABLE TO SUIT YOUR SPECIFIC REQUIREMENTS.

FROM THE RAW MATERIAL TO THE FINISHED PRODUCT OUR QUALITY CONTROL FACILITIES ENSURE THE HIGHEST QUALITY PRODUCTS.

MATERIAL

TERMINAL: BRASS PER ASTM-B16
CONTACT: BeCu, PER ASTM-B194

PLATING CHART

-P29	TERMINAL	TIN-LEAD
	CONTACT	GOLD 10 μ INCHES
-P30	TERMINAL	GOLD 4 μ INCHES
	CONTACT	GOLD 4 μ INCHES
-P31	TERMINAL	TIN-LEAD
	CONTACT	GOLD 4 μ INCHES
-P32	TERMINAL	TIN-LEAD
	CONTACT	TIN

NOTE: OTHER PLATINGS AVAILABLE

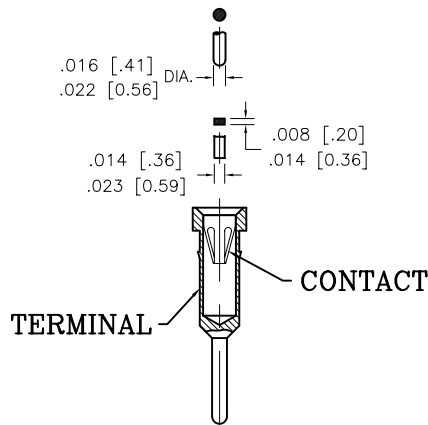
CONTACT TYPE

S: STANDARD DIP	INSERTION FORCE	9.0 oz. AVG.
	WITHDRAWAL FORCE	2.0 oz. MIN.
M: STANDARD PGA	INSERTION FORCE	1.6 oz. MAX.
	WITHDRAWAL FORCE	0.5 oz. MIN.
H: HIGH FORCE	INSERTION FORCE	18.3 oz. MAX.
	WITHDRAWAL FORCE	4.2 oz. MIN.
N: BeNi MATERIAL	INSERTION FORCE	6.70 oz. MAX.
	WITHDRAWAL FORCE	5.29 oz. MIN.
U: ULTRA MINI (SMALLER DIAMETER)	INSERTION FORCE	2.8 oz. MAX.
	WITHDRAWAL FORCE	0.5 oz. MIN.

NOTE: EXCEPT FOR "U" CONTACT, S, M, L, H CAN BE USED IN ANY TERMINAL ASSEMBLY

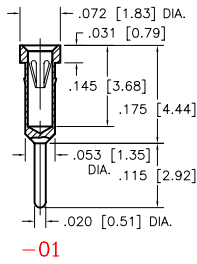
TEST PROBE DIMENSION

DIN 41870, IEC 191
FOR RECTANGULAR IC-LEADS

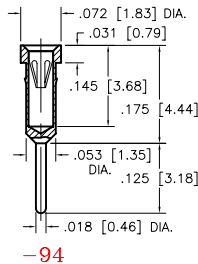




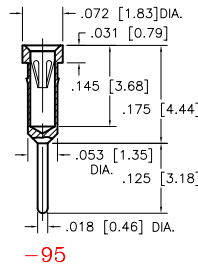
TERMINAL STYLES



-01

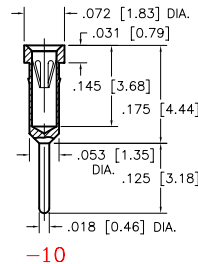


-94



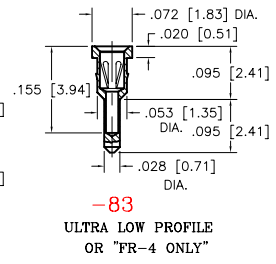
-95

TERMINAL MATERIAL
SOFT BRASS



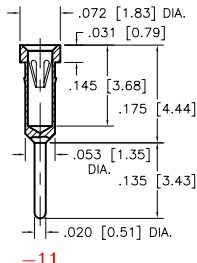
-10

TERMINAL MATERIAL
PHOSPHOR BRONZE

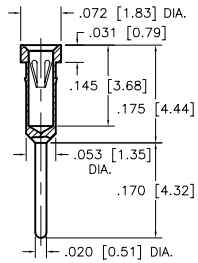


-83

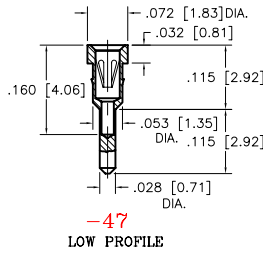
ULTRA LOW PROFILE
OR "FR-4 ONLY"



-11

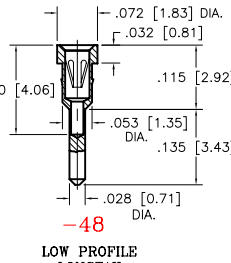


-08



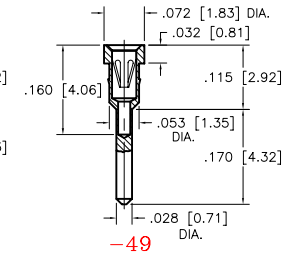
-47

LOW PROFILE



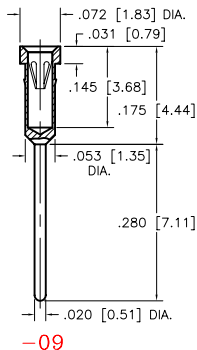
-48

LOW PROFILE
LONGTAIL

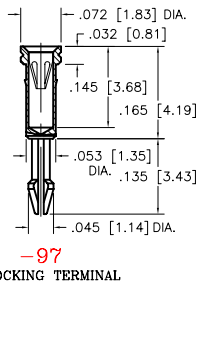


-49

LOW PROFILE
LONGTAIL



-09



-97

LOCKING TERMINAL

ORDERING INFORMATION

XXX-PXX

TERMINAL STYLE | PLATING
| CONTACT TYPE

CONTACT TYPE

S: STANDARD DIP	INSERTION FORCE	9.0 oz. AVG.
	WITHDRAWAL FORCE	2.0 oz. MIN.
M: STANDARD PGA	INSERTION FORCE	1.6 oz. MAX.
	WITHDRAWAL FORCE	0.5 oz. MIN.
L: INTERSTITIAL PGA	INSERTION FORCE	1.0 oz. MAX.
	WITHDRAWAL FORCE	0.3 oz. MIN.
H: HIGH FORCE	INSERTION FORCE	18.3 oz. MAX.
	WITHDRAWAL FORCE	4.2 oz. MIN.

PLATING CHART

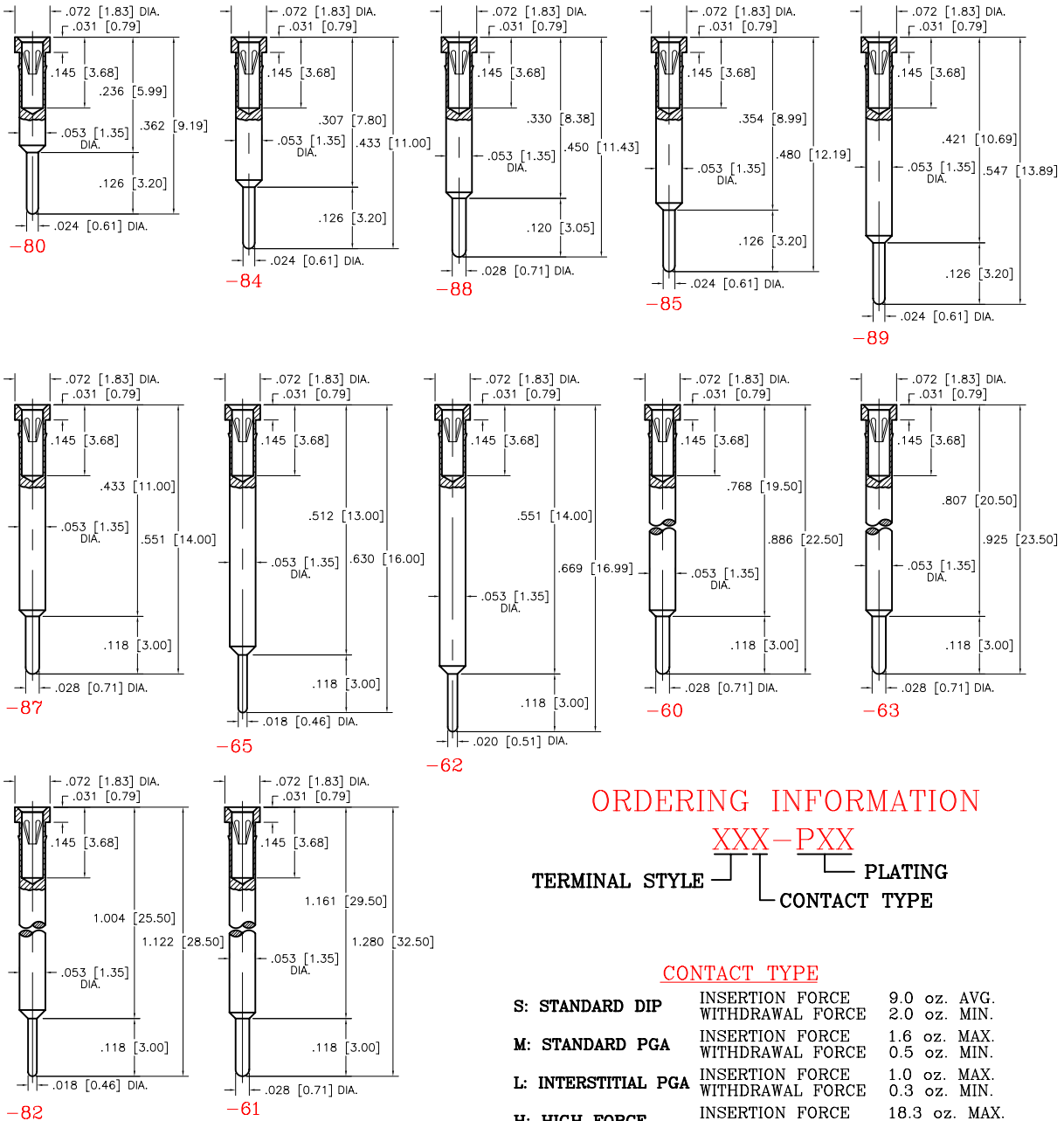
-P29	TERMINAL CONTACT	TIN-LEAD GOLD 10 μ INCHES
-P30	TERMINAL CONTACT	GOLD 4 μ INCHES GOLD 4 μ INCHES
-P31	TERMINAL CONTACT	TIN-LEAD GOLD 4 μ INCHES
-P32	TERMINAL CONTACT	TIN-LEAD TIN

TECHNICAL SPECIFICATIONS

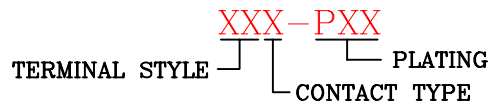
MATERIAL	
• TERMINAL	BRASS PER ASTM-B16
• CONTACT	BeCu PER ASTM-B194
MECHANICAL DATA	
• SOLDERABILITY	EXCEED MIL-STD-202 METHOD 208



TERMINAL STYLES RAISED INTERCONNECTORS



ORDERING INFORMATION



CONTACT TYPE

CONTACT TYPE	INSERTION FORCE	WITHDRAWAL FORCE
S: STANDARD DIP	9.0 oz. AVG.	2.0 oz. MIN.
M: STANDARD PGA	1.6 oz. MAX.	0.5 oz. MIN.
L: INTERSTITIAL PGA	1.0 oz. MAX.	0.3 oz. MIN.
H: HIGH FORCE	18.3 oz. MAX.	4.2 oz. MIN.

TECHNICAL SPECIFICATIONS

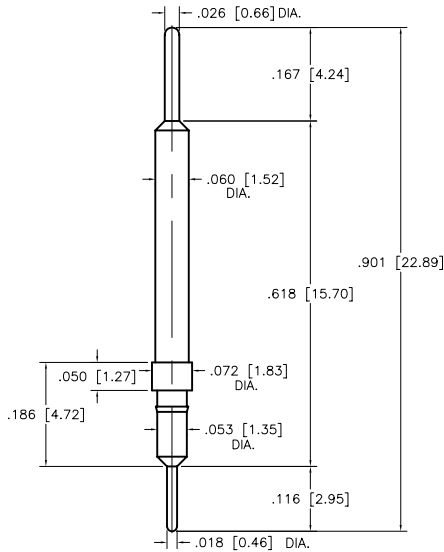
MATERIAL	
• TERMINAL	BRASS, PER ASTM-B16
• CONTACT	BeCu, PER ASTM-B194
MECHANICAL DATA	
• SOLDERABILITY	EXCEED MIL-STD-202 METHOD 208

PLATING CHART

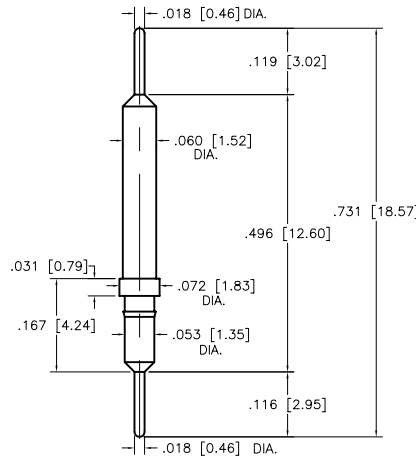
-P29	TERMINAL CONTACT	TIN-LEAD GOLD 10 μ INCHES
-P30	TERMINAL CONTACT	GOLD 4 μ INCHES GOLD 4 μ INCHES
-P31	TERMINAL CONTACT	TIN-LEAD GOLD 4 μ INCHES
-P32	TERMINAL CONTACT	TIN-LEAD TIN



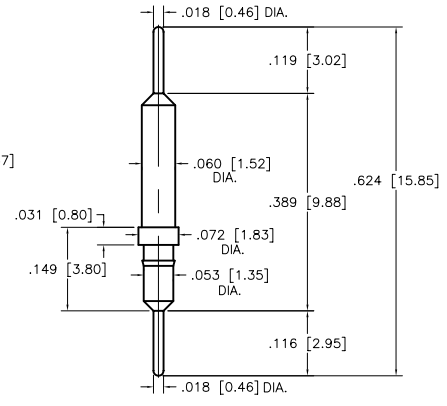
TERMINAL STYLES BOARD TO BOARD



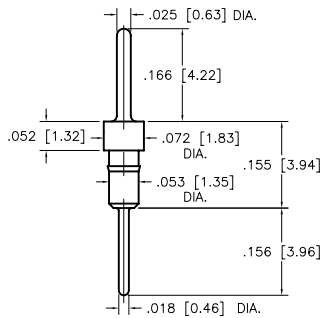
-56



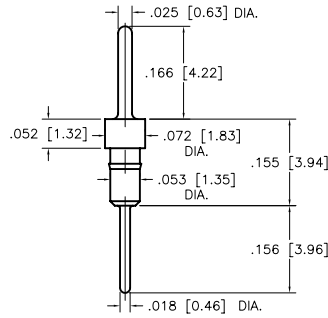
-59



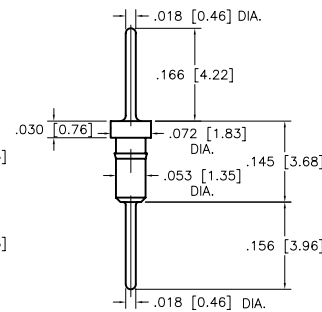
-58



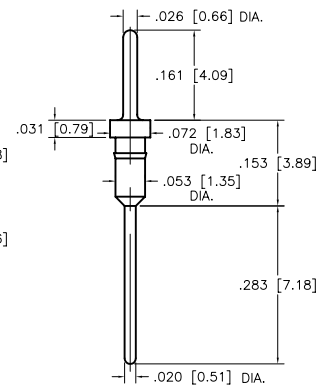
-37



-04
MATERIAL
PHOSPHOR BRONZE



-77
MATERIAL
PHOSPHOR BRONZE



-57

ORDERING INFORMATION

XX-XXX

TERMINAL STYLE PLATING

TECHNICAL SPECIFICATIONS

- TERMINAL MATERIAL BRASS PER ASTM-B16
- SOLDERABILITY EXCEED MIL-STD-202 METHOD 208

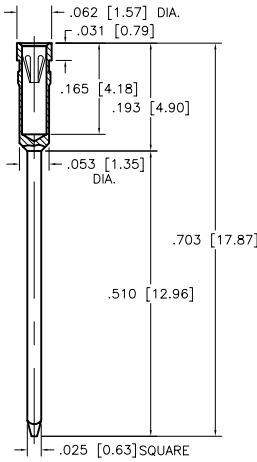
PLATING CHART

- T TIN
- TL TIN-LEAD
- G04 GOLD 4 μ INCHES
- G10 GOLD 10 μ INCHES
- G15 GOLD 15 μ INCHES

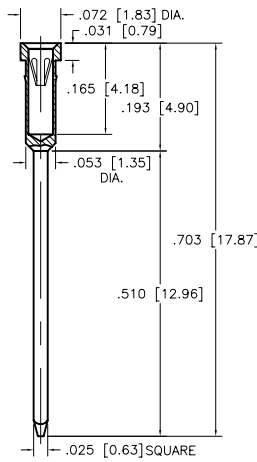


TERMINAL STYLES

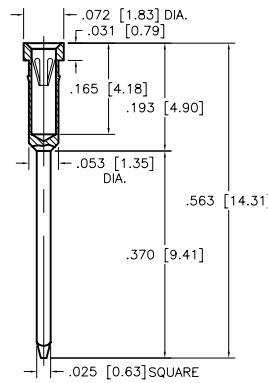
WIRE WRAP



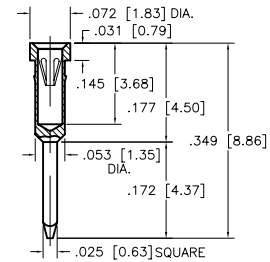
-81
.070 [1.78] SPACING



-03



-02



-44

PLATING CHART

-P29	TERMINAL CONTACT	TIN-LEAD GOLD 10 μ INCHES
-P30	TERMINAL CONTACT	GOLD 4 μ INCHES GOLD 4 μ INCHES
-P31	TERMINAL CONTACT	TIN-LEAD GOLD 4 μ INCHES
-P32	TERMINAL CONTACT	TIN-LEAD TIN

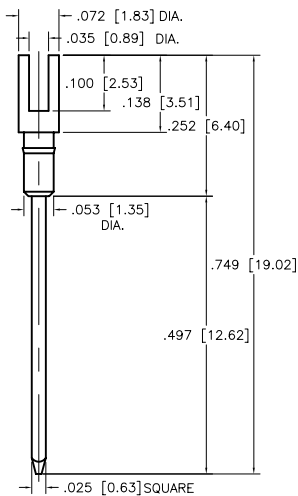
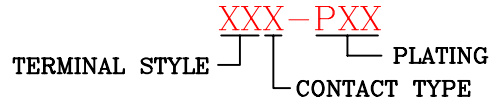
TECHNICAL SPECIFICATIONS

MATERIAL	
• TERMINAL	BRASS PER ASTM-B16
• CONTACT	BeCu PER ASTM-B194
MECHANICAL DATA	
• SOLDERABILITY	EXCEED MIL-STD-202 METHOD 208

CONTACT TYPE

S: STANDARD DIP	INSERTION FORCE	9.0 oz. AVG.
	WITHDRAWAL FORCE	2.0 oz. MIN.
M: STANDARD PGA	INSERTION FORCE	1.6 oz. MAX.
	WITHDRAWAL FORCE	0.5 oz. MIN.
L: INTERSTITIAL PGA	INSERTION FORCE	1.0 oz. MAX.
	WITHDRAWAL FORCE	0.3 oz. MIN.
H: HIGH FORCE	INSERTION FORCE	18.3 oz. MAX.
	WITHDRAWAL FORCE	4.2 oz. MIN.

ORDERING INFORMATION



-38

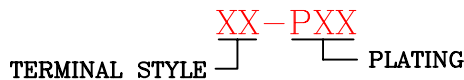
TECHNICAL SPECIFICATIONS

MATERIAL	
• TERMINAL	BRASS PER ASTM-B16
MECHANICAL DATA	
• SOLDERABILITY	EXCEED MIL-STD-202 METHOD 208

PLATING CHART

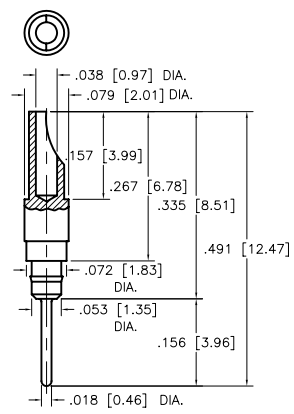
-T	TIN
-TL	TIN-LEAD
-G04	GOLD 4 μ INCHES
-G10	GOLD 10 μ INCHES
-G15	GOLD 15 μ INCHES

ORDERING INFORMATION



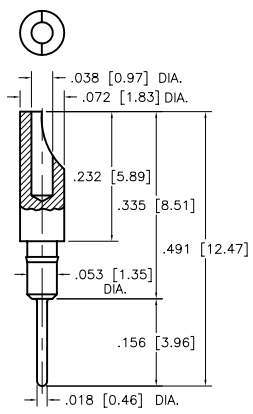


TERMINAL STYLES

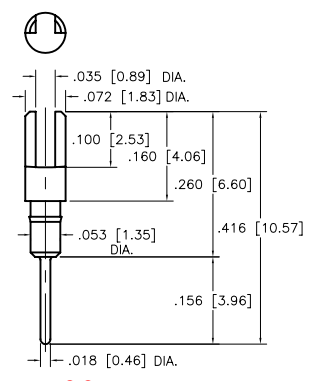


-36

OPEN FRAME AND LAMINATE APPLICATIONS

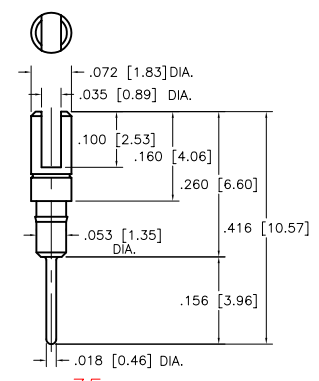


-05



-06

PHOSPHOR BRONZE



-35

TECHNICAL SPECIFICATIONS

MATERIAL

TERMINAL • BRASS PER ASTM-B16
CONTACT • BeCu PER ASTM-B194

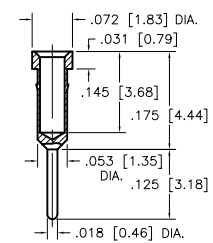
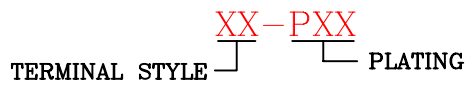
MECHANICAL DATA

SOLDERABILITY EXCEED MIL-STD-202 METHOD 208

PLATING CHART

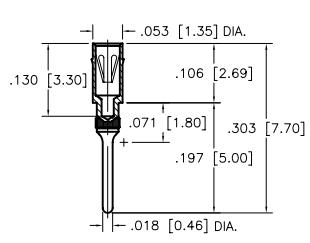
- T TIN
- TL TIN-LEAD
- G04 GOLD 4 μ INCHES
- G10 GOLD 10 μ INCHES
- G15 GOLD 15 μ INCHES

ORDERING INFORMATION

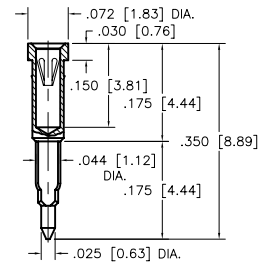


-07

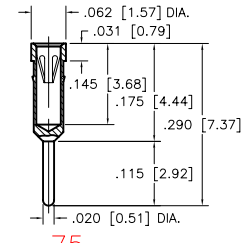
HOLLOW PHOSPHOR BRONZE



-128
TRANSPUTER

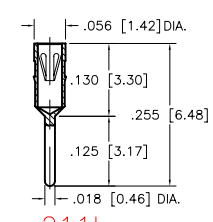


-477
PRESS-FIT



-75

.070 [1.78] SPACING



-211L

INTERSTITIAL APPLICATIONS

TECHNICAL SPECIFICATIONS

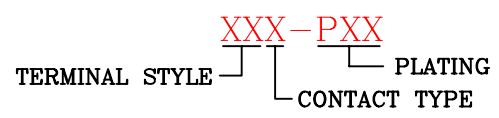
MATERIAL

TERMINAL • BRASS PER ASTM-B16
CONTACT • BeCu PER ASTM-B194

MECHANICAL DATA

SOLDERABILITY EXCEED MIL-STD-202 METHOD 208

ORDERING INFORMATION



PLATING CHART

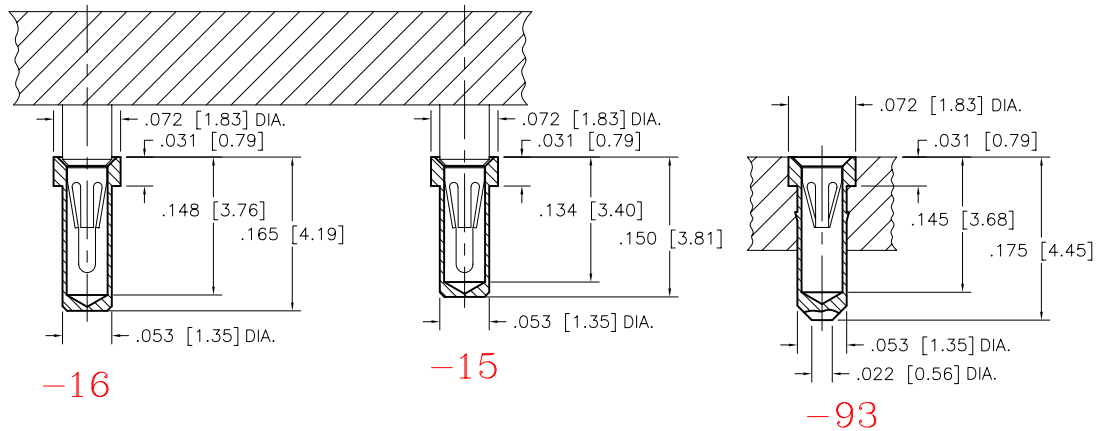
- P29 TERMINAL TIN-LEAD
CONTACT GOLD 10 μ INCHES
- P30 TERMINAL GOLD 4 μ INCHES
CONTACT GOLD 4 μ INCHES
- P31 TERMINAL TIN-LEAD
CONTACT GOLD 4 μ INCHES
- P32 TERMINAL TIN-LEAD
CONTACT TIN

CONTACT TYPE

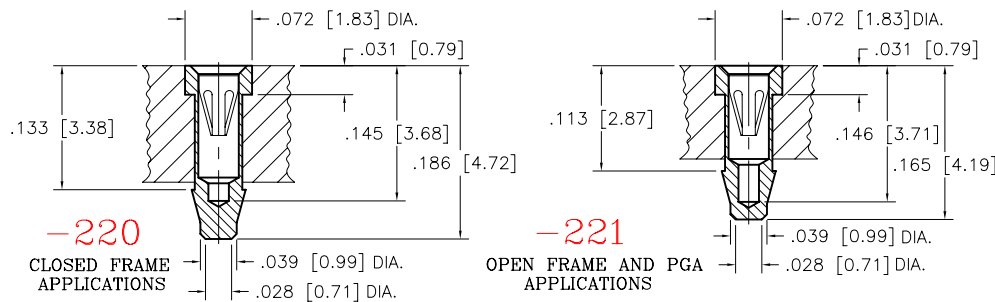
- S: STANDARD DIP INSERTION FORCE 9.0 oz. AVG.
WITHDRAWAL FORCE 2.0 oz. MIN.
- M: STANDARD PGA INSERTION FORCE 1.6 oz. MAX.
WITHDRAWAL FORCE 0.5 oz. MIN.
- L: INTERSTITIAL PGA INSERTION FORCE 1.0 oz. MAX.
WITHDRAWAL FORCE 0.3 oz. MIN.
- H: HIGH FORCE INSERTION FORCE 18.3 oz. MAX.
WITHDRAWAL FORCE 4.2 oz. MIN.



TERMINAL STYLES SURFACE MOUNT TERMINALS

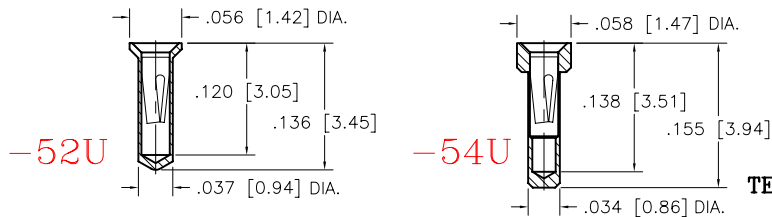


FLOATING TERMINALS



ULTRA-MINI TERMINALS

FOR .100 AND .070 PITCH APPLICATIONS



ORDERING INFORMATION

XXX-PXX

TERMINAL STYLE | PLATING
| CONTACT TYPE

TECHNICAL SPECIFICATIONS

MATERIAL
• TERMINAL BRASS PER ASTM-B16
• CONTACT BeCu PER ASTM-B194

MECHANICAL DATA
• SOLDERABILITY EXCEED MIL-STD-202 METHOD 208

PLATING CHART

-P29 TERMINAL CONTACT TIN-LEAD
-P30 TERMINAL CONTACT GOLD 10 μ INCHES
-P31 TERMINAL CONTACT TIN-LEAD
-P32 TERMINAL CONTACT GOLD 4 μ INCHES
-P32 TERMINAL CONTACT TIN-LEAD
-P32 TERMINAL CONTACT TIN

CONTACT TYPE

S: STANDARD DIP INSERTION FORCE 9.0 oz. AVG.
WITHDRAWAL FORCE 2.0 oz. MIN.

M: STANDARD PGA INSERTION FORCE 1.6 oz. MAX.
WITHDRAWAL FORCE 0.5 oz. MIN.

L: INTERSTITIAL PGA INSERTION FORCE 1.0 oz. MAX.
WITHDRAWAL FORCE 0.3 oz. MIN.

H: HIGH FORCE INSERTION FORCE 18.3 oz. MAX.
WITHDRAWAL FORCE 4.2 oz. MIN.

U: ULTRA MINI (SMALLER DIAMETER) INSERTION FORCE 2.8 oz. MAX.
WITHDRAWAL FORCE 0.5 oz. MIN.

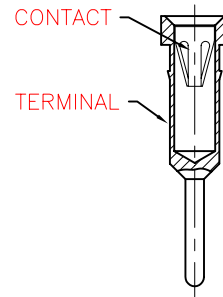
NOTE: EXCEPT FOR "U" CONTACT, S, M, L, H CAN BE USED IN ANY TERMINAL ASSEMBLY



OPTIONAL PLATINGS

TERMINAL ASSEMBLY PLATING:

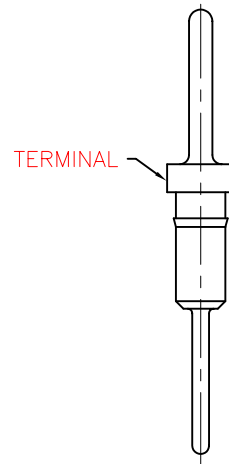
-P15	TERMINAL	GOLD 10 μ INCH MIN.
	CONTACT	GOLD 30 μ INCH MIN.
-P17	TERMINAL	TIN-LEAD 150 - 250 μ INCH
		TIN-LEAD RATIO 90/10
	CONTACT	GOLD 30 μ INCH MIN.
-P29	TERMINAL	TIN-LEAD 150 - 250 μ INCH
		TIN-LEAD RATIO 90/10
	CONTACT	GOLD 10 μ INCH MIN.
-P31	TERMINAL	TIN-LEAD 150 - 250 μ INCH
		TIN-LEAD RATIO 90/10
	CONTACT	GOLD 4 μ INCH MIN.
-P32	TERMINAL	TIN-LEAD 150 - 250 μ INCH
		TIN-LEAD RATIO 90/10
	CONTACT	TIN 200 - 300 μ INCH MIN.



CONSULT FACTORY FOR OTHER AVAILABLE PLATINGS

TERMINAL PLATING:

-G04	TERMINAL	GOLD 4 μ INCH MIN.
-G10	TERMINAL	GOLD 10 μ INCH MIN.
-G15	TERMINAL	GOLD 15 μ INCH MIN.
-G30	TERMINAL	GOLD 30 μ INCH MIN.
-TL	TERMINAL	TIN-LEAD 150 - 250 μ INCH
		TIN-LEAD RATIO 90/10
-T	TERMINAL	TIN 200 - 300 μ INCH MIN.



CONSULT FACTORY FOR OTHER AVAILABLE PLATINGS



PIN GRID ARRAY SOCKETS
(PGA)
HI-TEMP • 150°C INSULATION

HI-REL PGA SOCKETS WITH A VARIETY OF CONTACT FORCES
TO SUIT YOUR SPECIFIC REQUIREMENTS

We developed the first precision in-house manufactured contacts under strict quality control.

PGA sockets are used to accept microprocessors and PGA adapters which are also produced by Andon.

Over (200??) footprints available.

Modular mold tooling to quickly provide you with your own configurations. Standard PGA sockets and ASIC sockets made-to-order.

Series 510 Standard PGA Sockets Molded Insulators

Series 575 Custom PGA Sockets (FR-4 and Polyimide, Hi-Temp, 240°C)

Easy to specify drawing format to fax to our factory for fast response.

Large variety of terminals to suit your specific application.

Let us submit our value engineered analysis of your requirements for Product Improvement and Cost Reduction.

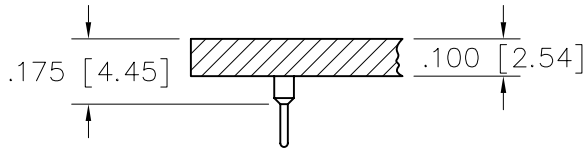
Consult our factory for design and specification assistance.

We are the industry innovators.



PIN GRID ARRAY SOCKETS (PGA)

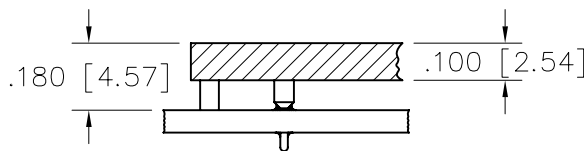
SERIES 510



STANDARD OFF THE SHELF

-S10= HIGH TEMP NYLON 46, 150°C
SUITABLE FOR INFRARED SOLDERING
OTHER MATERIALS AVAILABLE

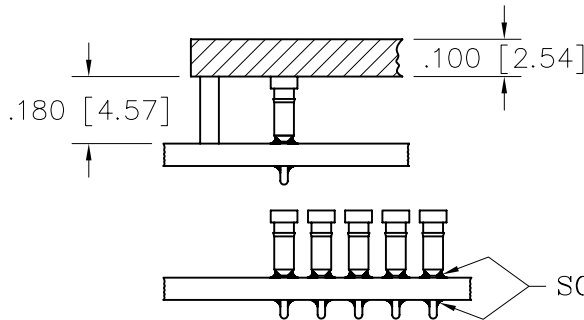
SERIES 540



INSULATOR WITH STANDOFFS FOR SOLDER FILLET TOP AND BOTTOM OF PCB

-S10= HIGH TEMP NYLON 46, 150°C
SUITABLE FOR INFRARED SOLDERING
OTHER MATERIALS AVAILABLE

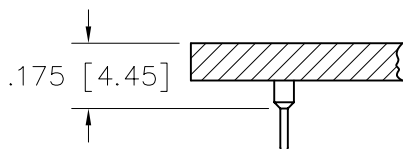
SERIES 550



PULL-OFF CARRIER SOCKET DISCARDABLE INSULATOR WITH STANDOFFS FOR SOLDER FILLET TOP AND BOTTOM OF PCB

-S10= HIGH TEMP NYLON 46, 150°C
SUITABLE FOR INFRARED SOLDERING
(DISCARD PLASTIC WAFER AFTER SOLDERING)
OTHER MATERIALS AVAILABLE

SERIES 575

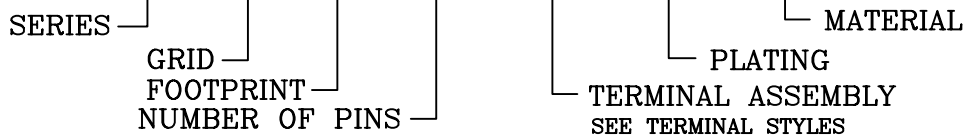


MATERIAL FOR CUSTOM DESIGN

-N10=.062[1.57] THICK GLASS EPOXY, FR4 140°C
-L10=.050[1.27] THICK GLASS EPOXY, FR4 140°C
-H10=.062[1.57] THICK POLYIMIDE HI-TEMP, 240°C

ORDERING INFORMATION

5XX-XX-XX-XXX-XXX-PXX-S10
575-XX-XX-XXX-XXX-PXX-XXX



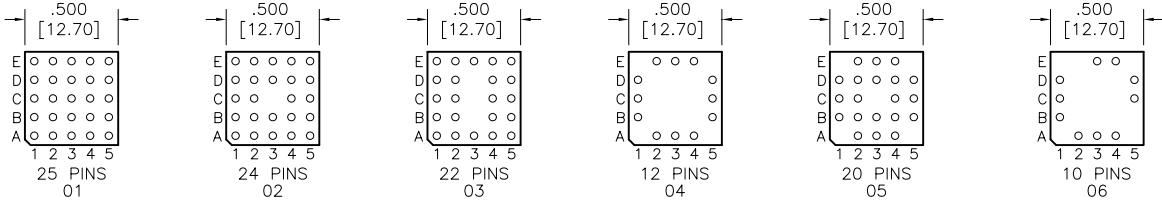
© ANDON 2007 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]

WE RESERVE THE RIGHT TO CHANGE SPECIFICATIONS WITHOUT NOTICE.

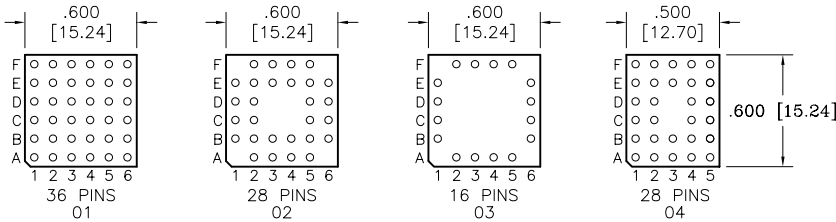


PGA SOCKET FOOTPRINTS

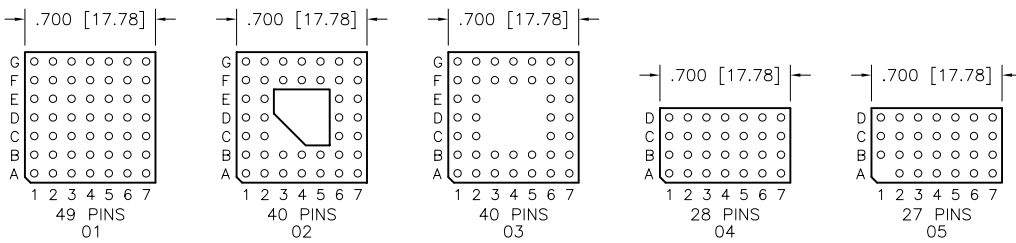
5 X 5



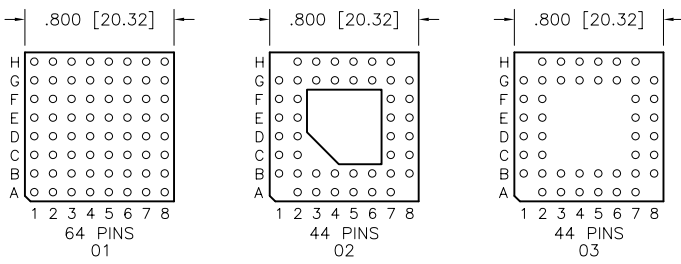
6 X 6



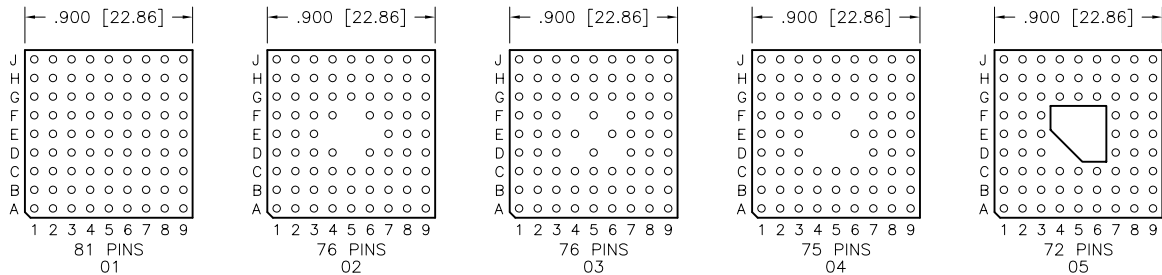
7 X 7



8 X 8



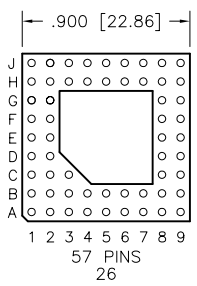
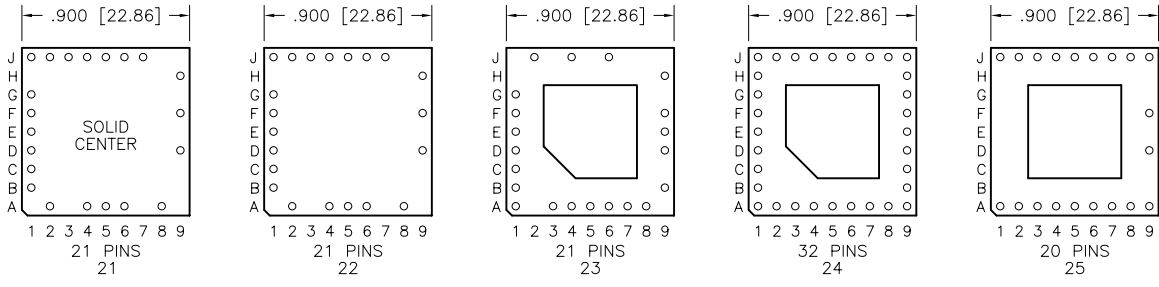
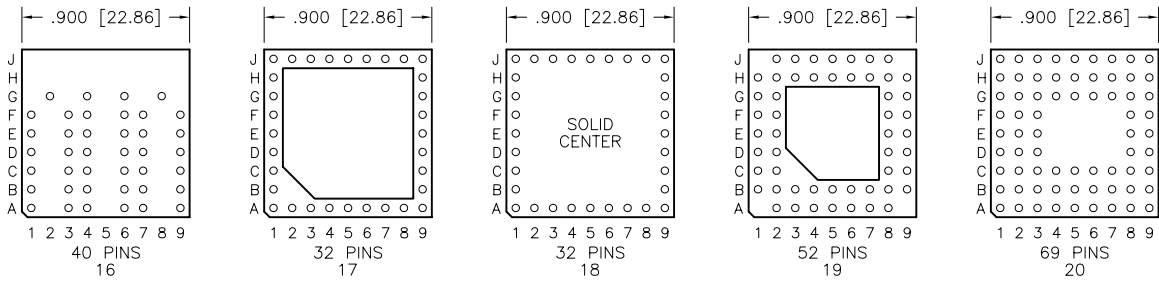
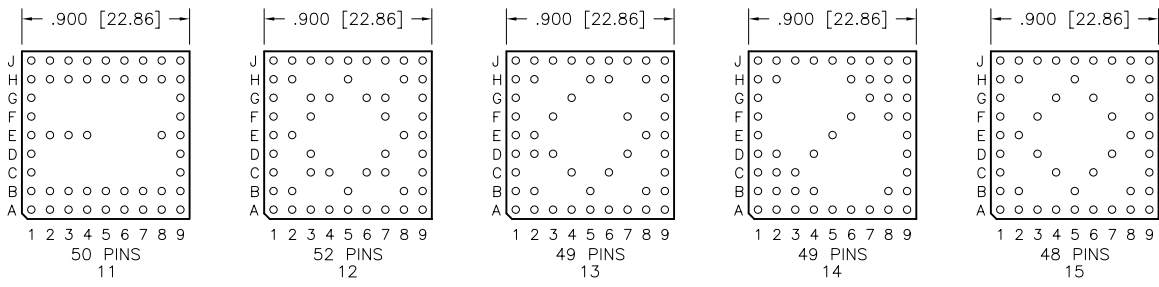
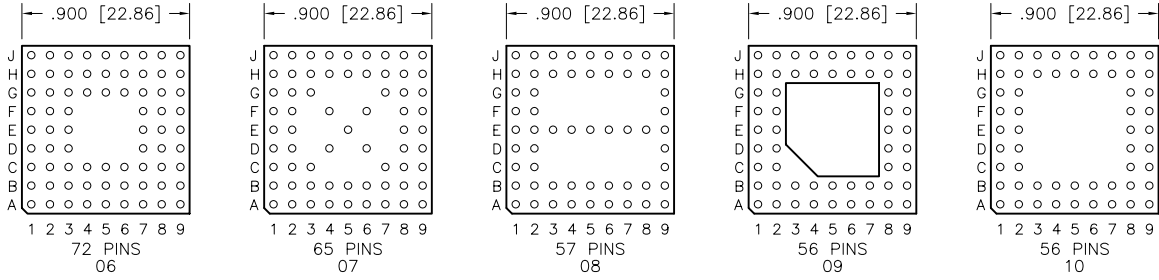
9 X 9





PGA SOCKET FOOTPRINTS

9 X 9



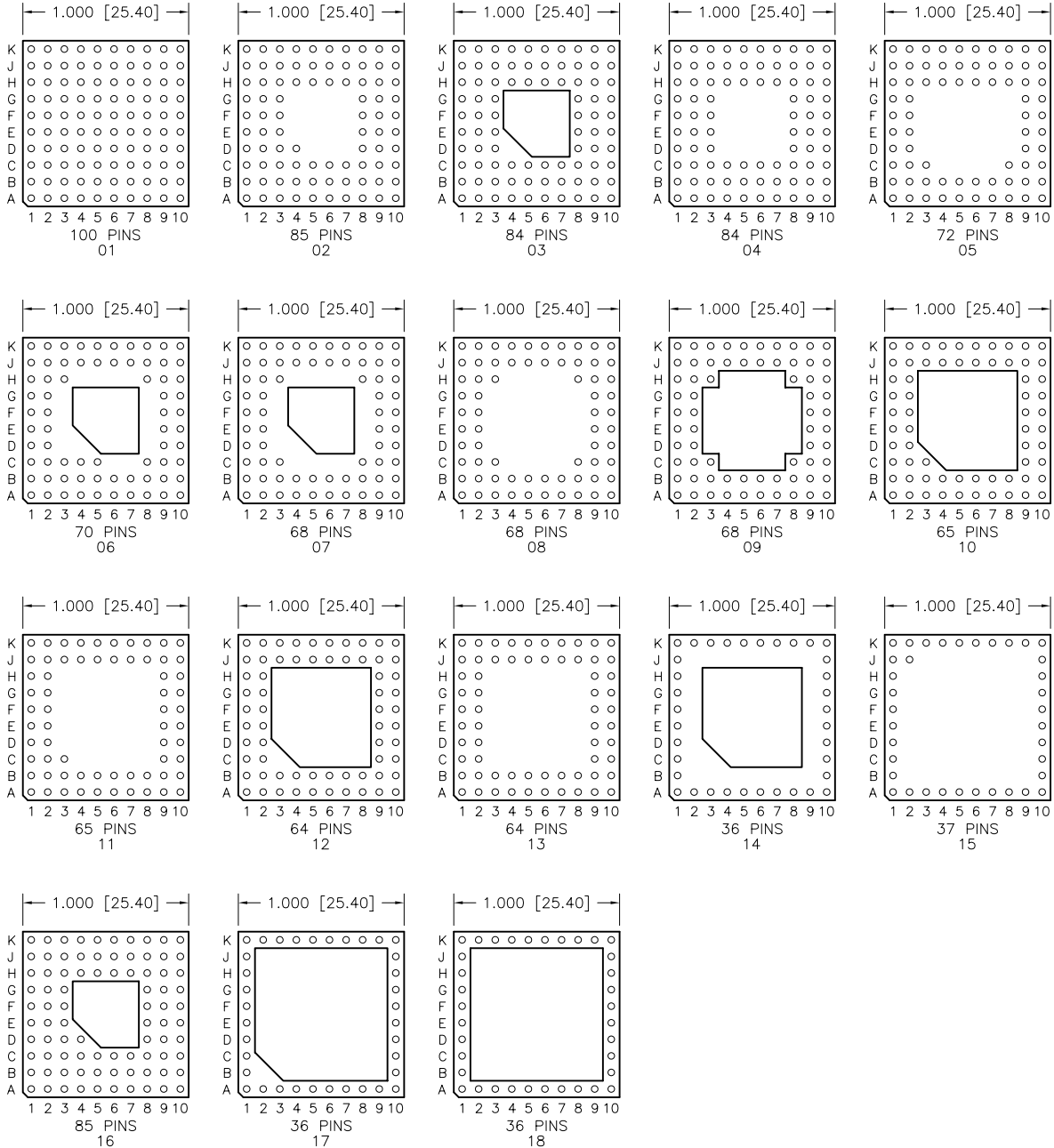
© ANDON 2007 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]

WE RESERVE THE RIGHT TO CHANGE SPECIFICATIONS WITHOUT NOTICE.



PGA SOCKET FOOTPRINTS

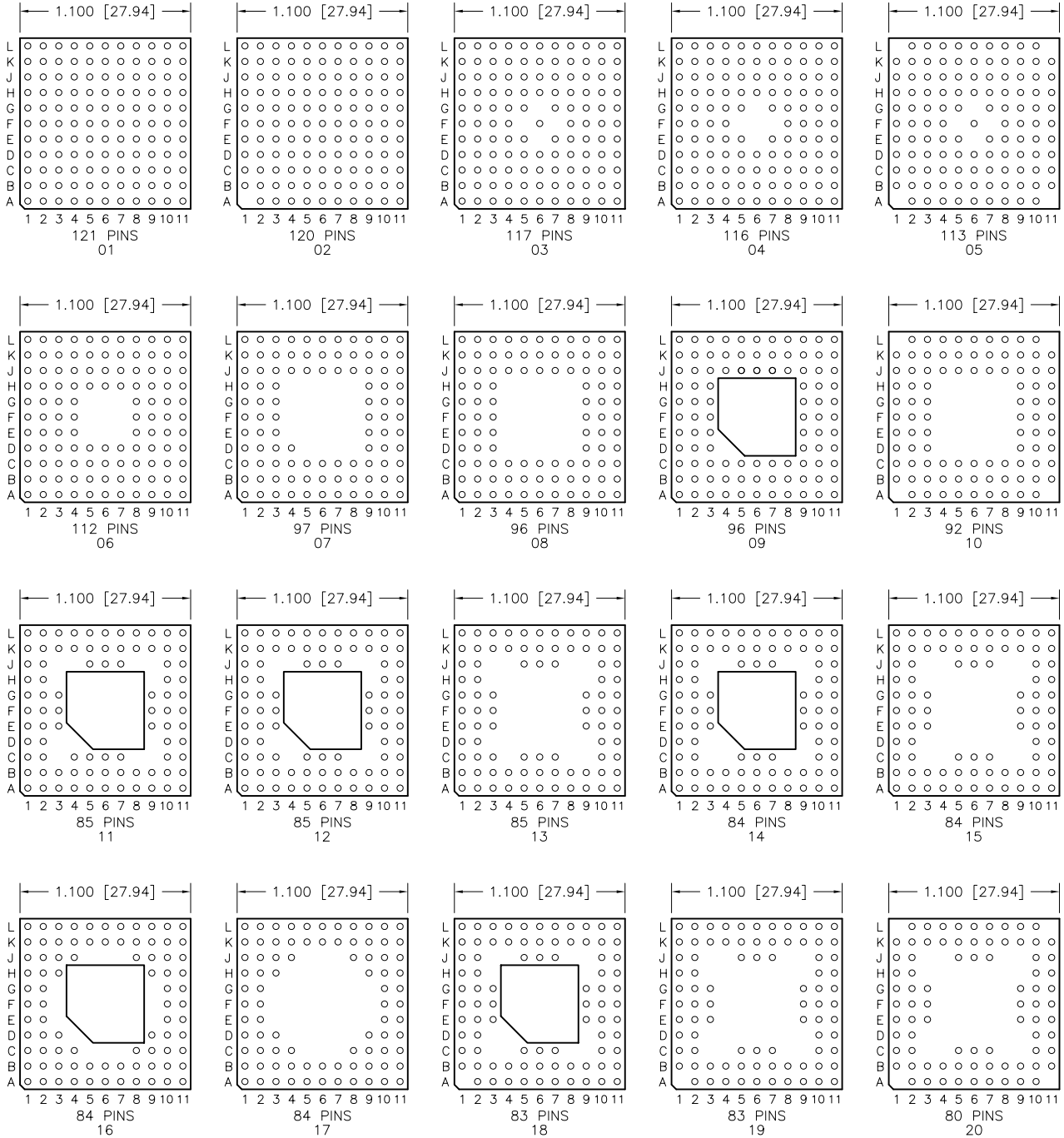
10 X 10





PGA SOCKET FOOTPRINTS

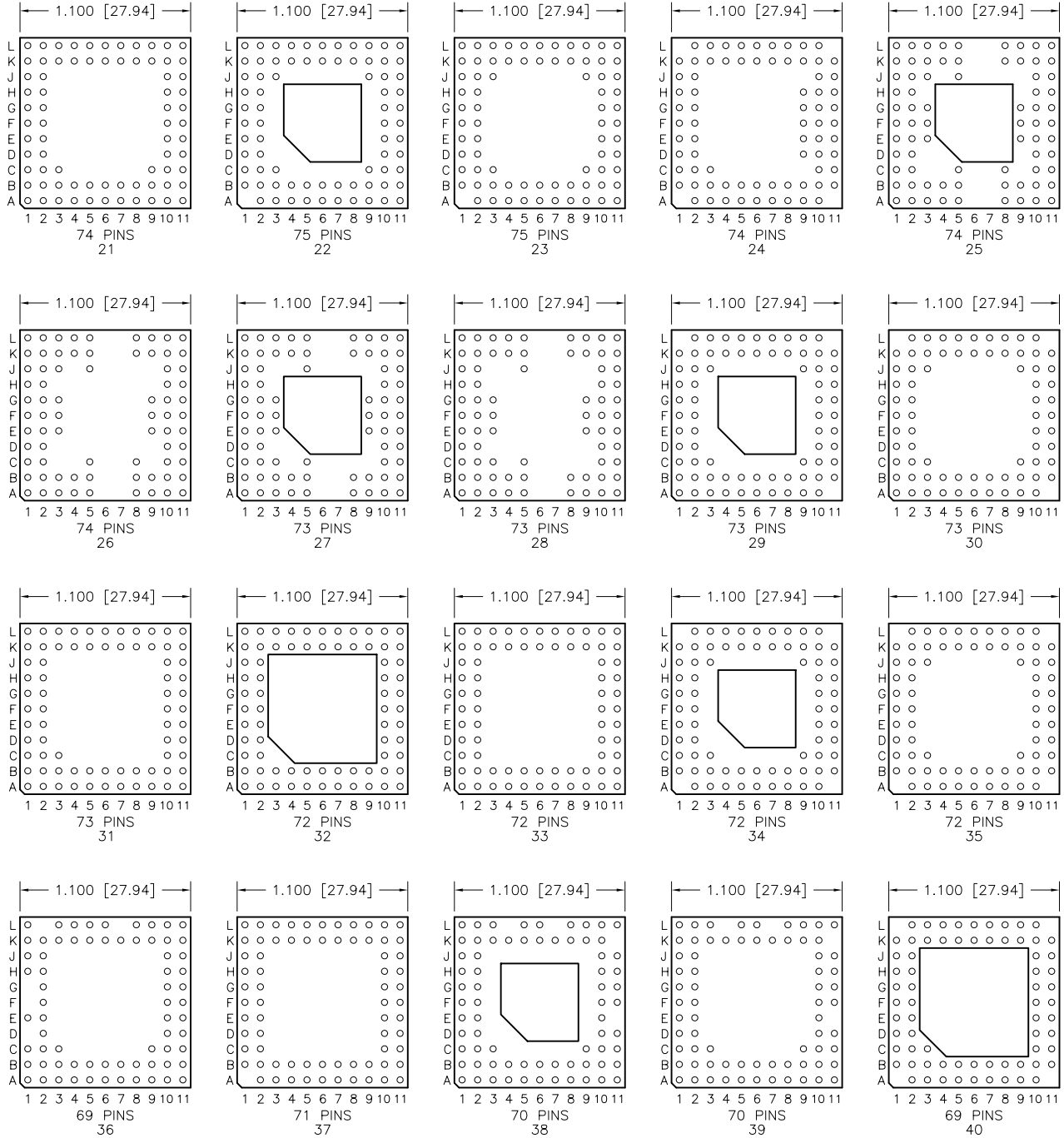
11 X 11





PGA SOCKET FOOTPRINTS

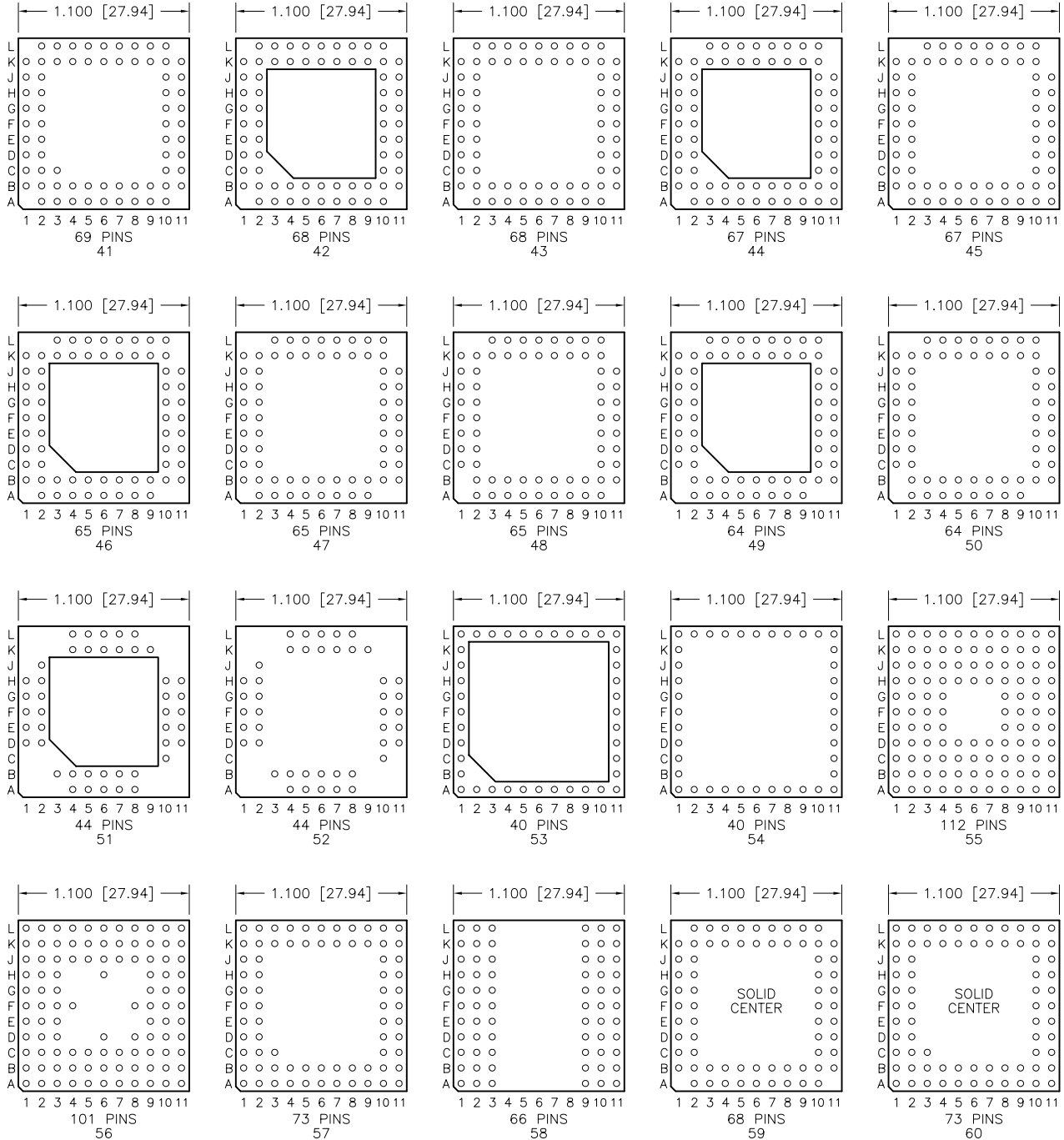
11 X 11





PGA SOCKET FOOTPRINTS

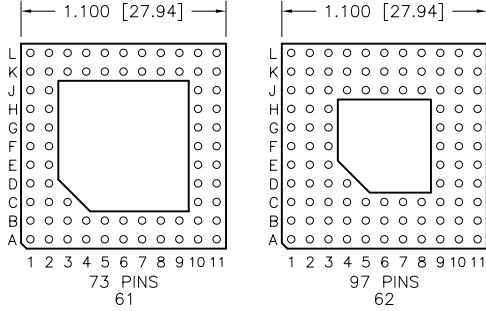
11 X 11



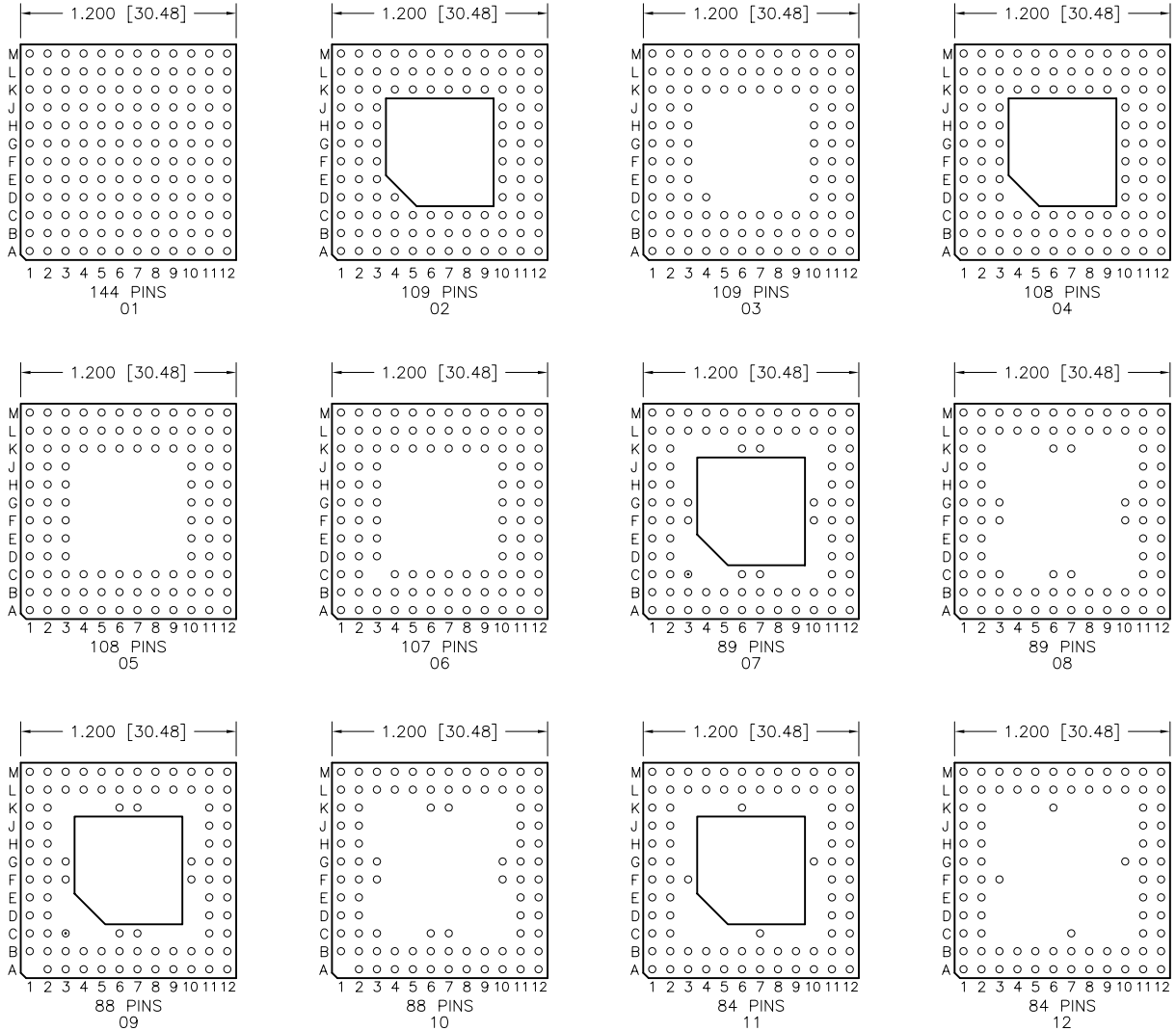


PGA SOCKET FOOTPRINTS

11 X 11



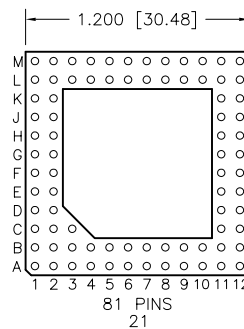
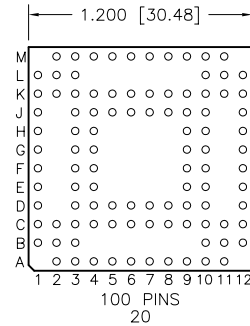
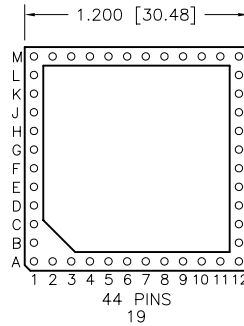
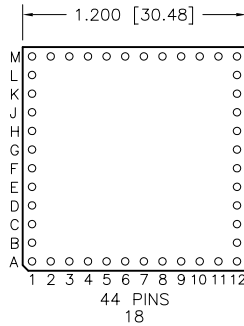
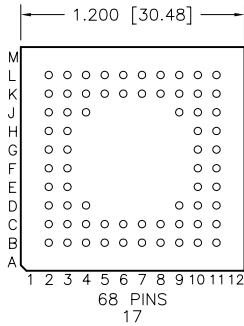
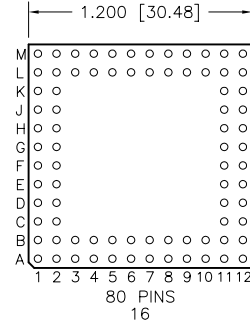
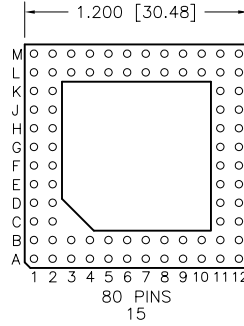
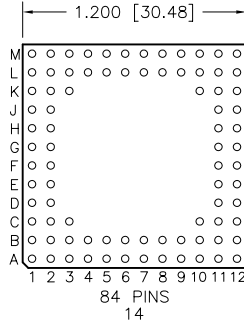
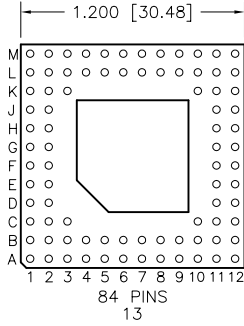
12 X 12





PGA SOCKET FOOTPRINTS

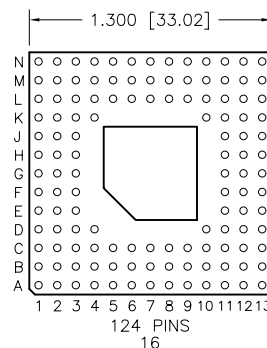
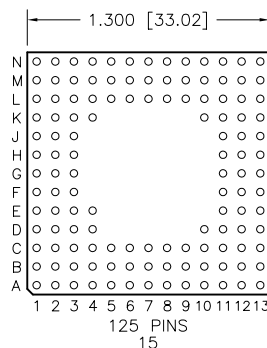
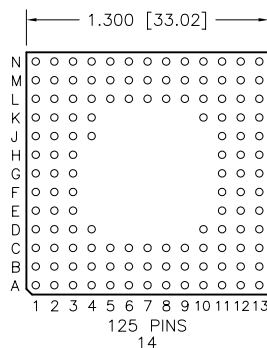
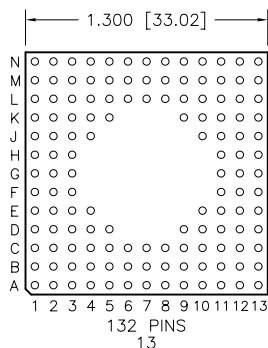
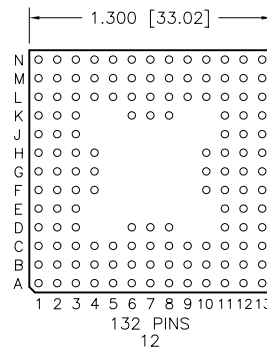
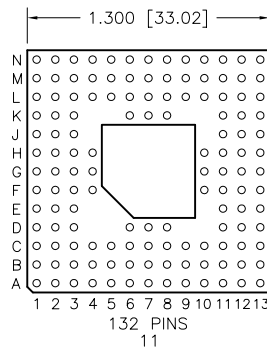
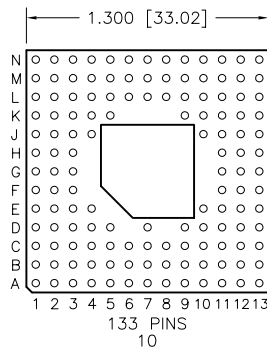
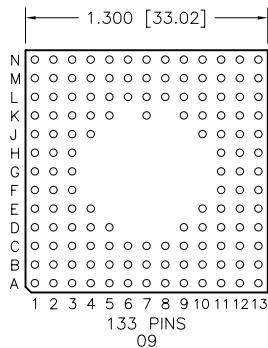
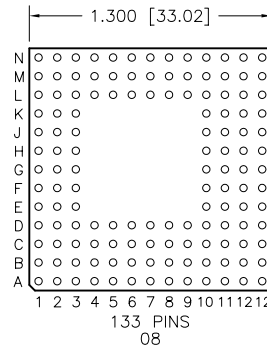
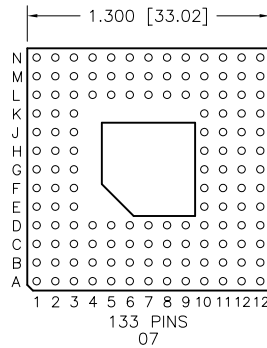
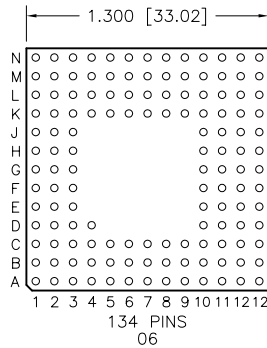
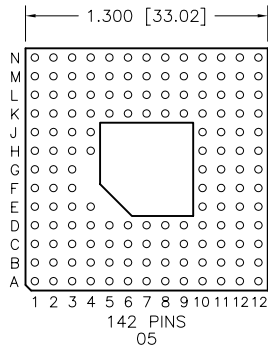
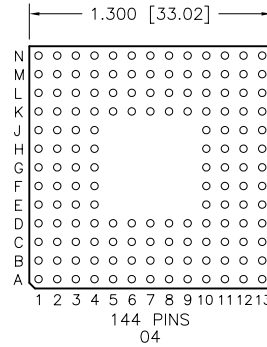
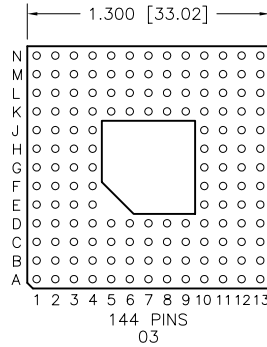
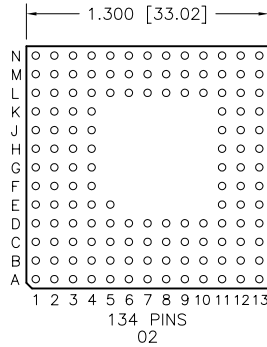
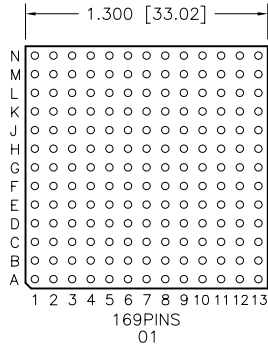
12 X 12





PGA SOCKET FOOTPRINTS

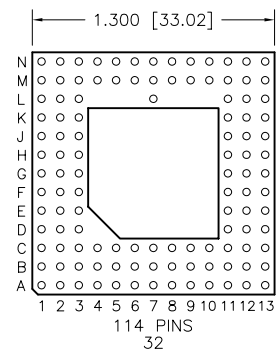
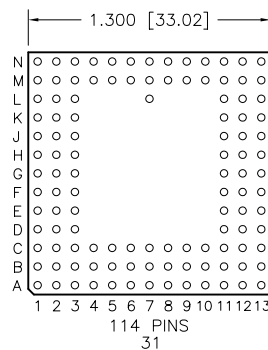
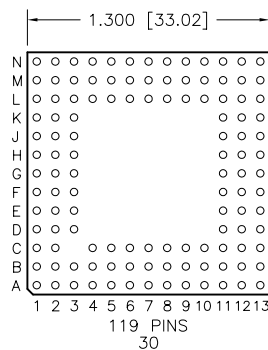
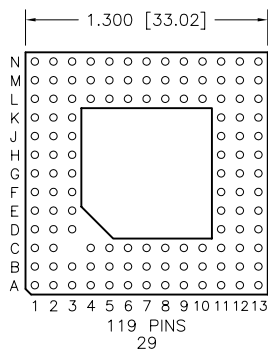
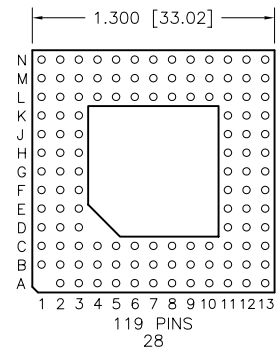
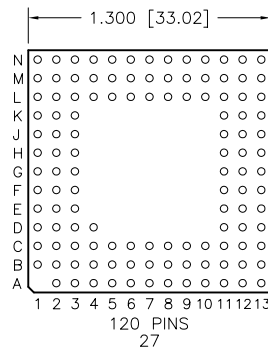
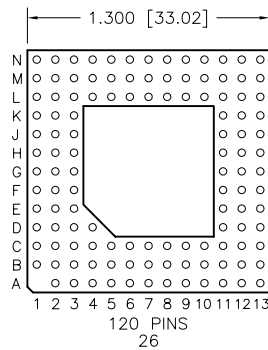
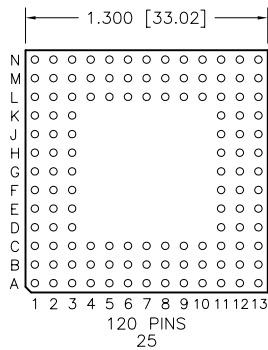
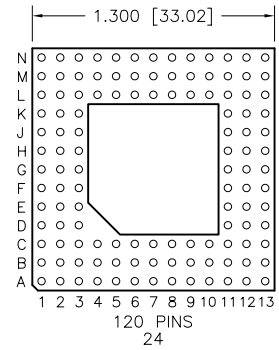
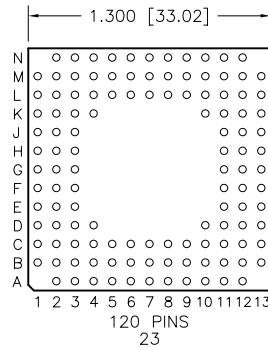
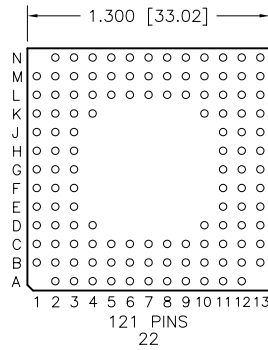
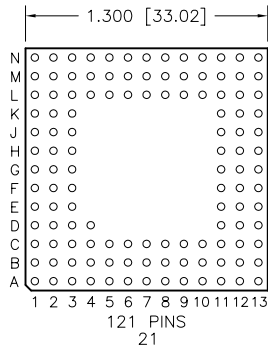
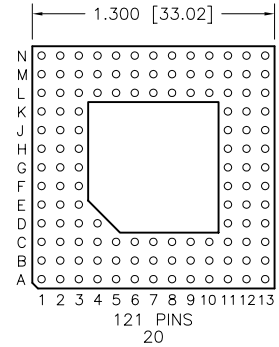
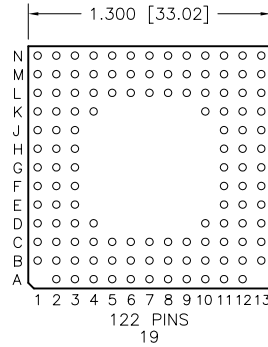
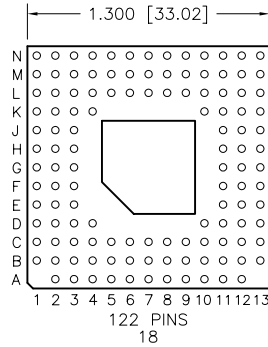
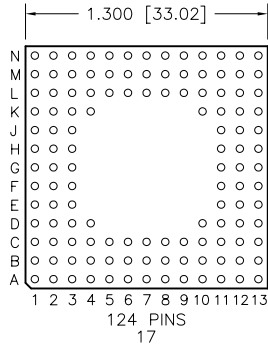
13 X 13





PGA SOCKET FOOTPRINTS

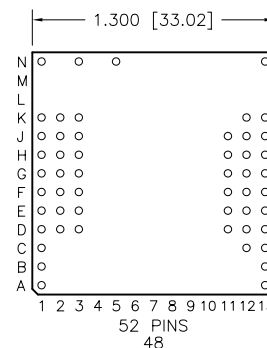
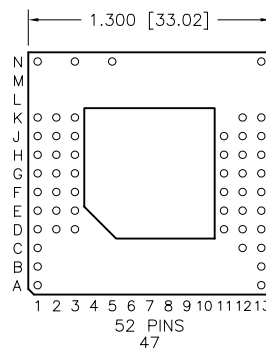
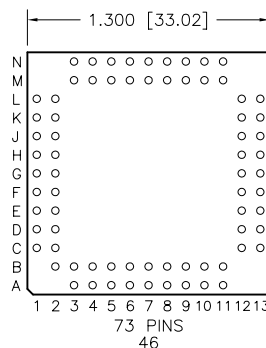
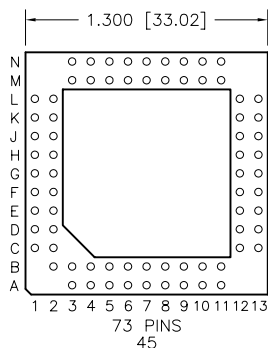
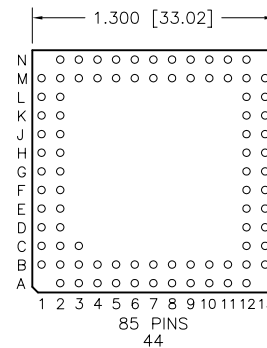
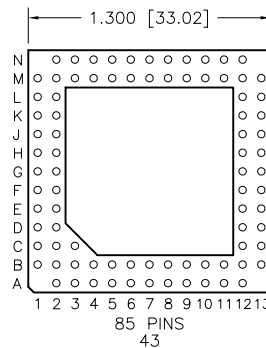
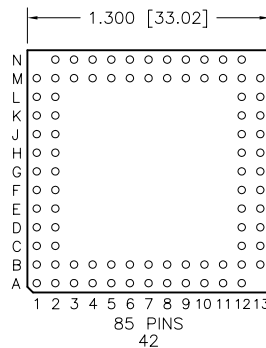
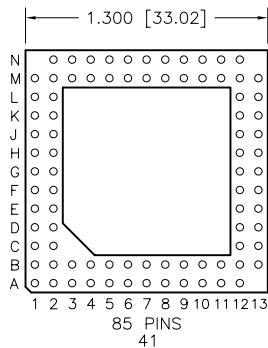
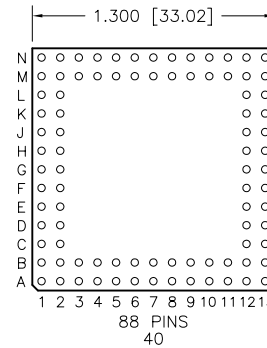
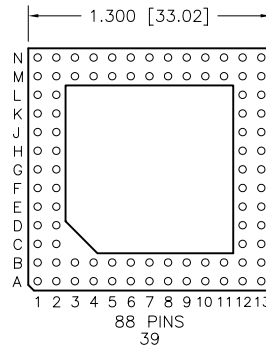
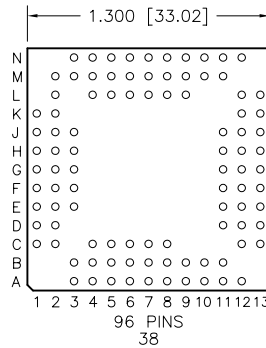
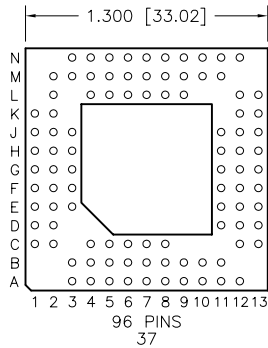
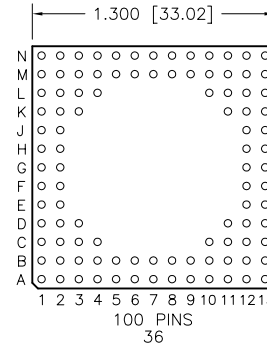
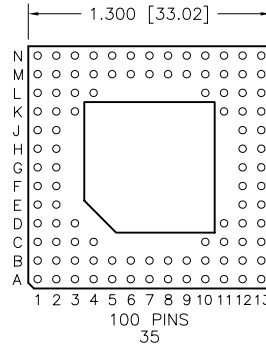
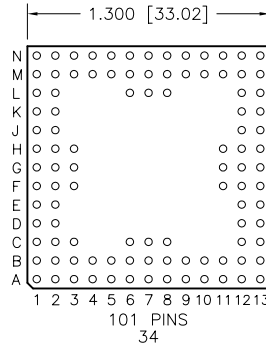
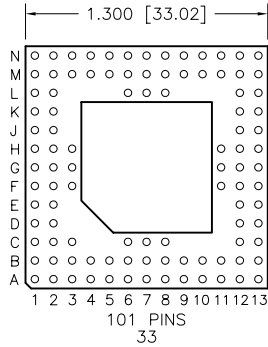
13 X 13





PGA SOCKET FOOTPRINTS

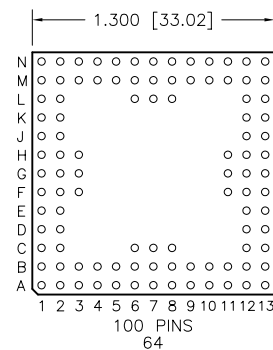
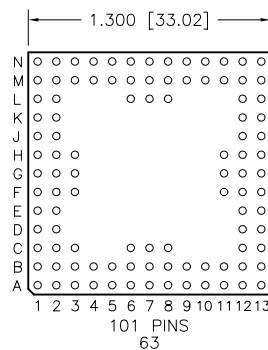
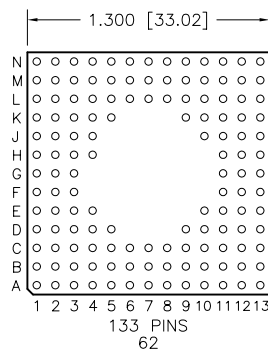
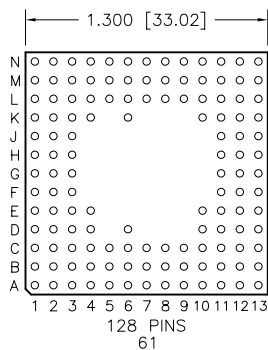
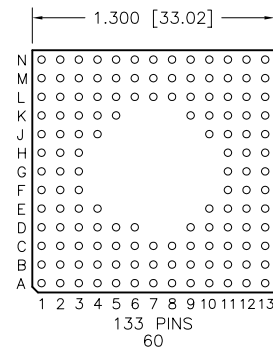
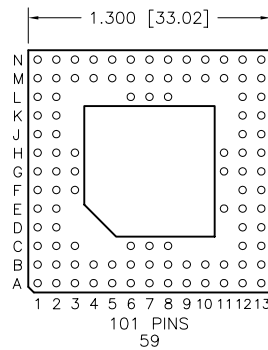
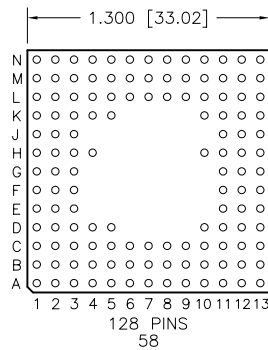
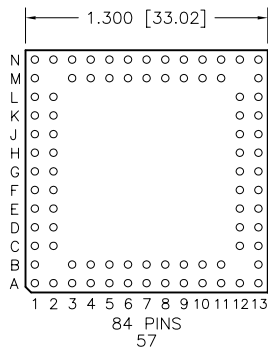
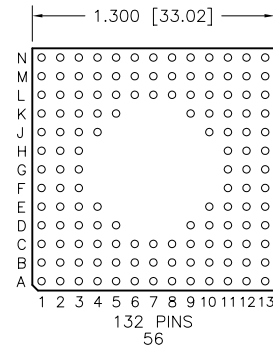
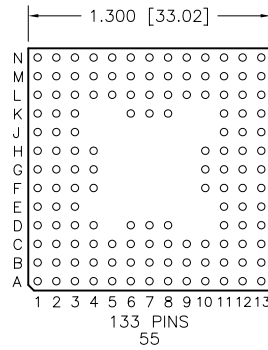
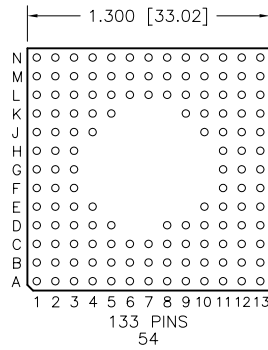
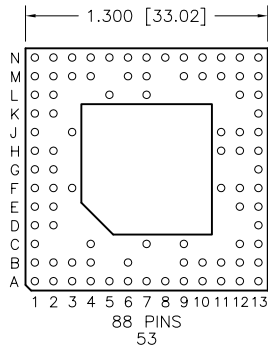
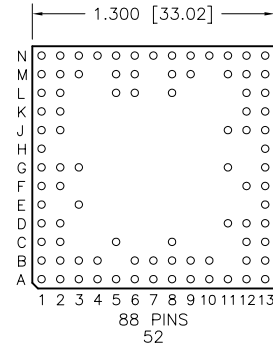
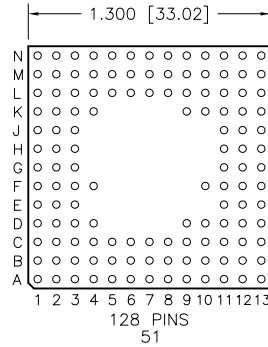
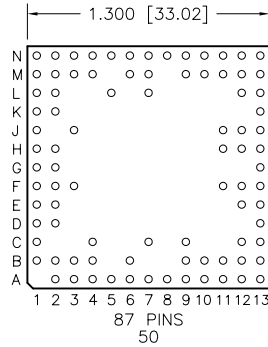
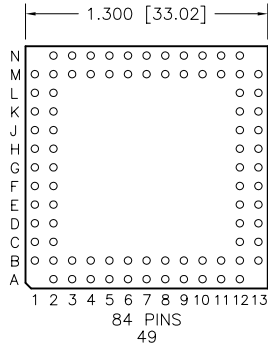
13 X 13





PGA SOCKET FOOTPRINTS

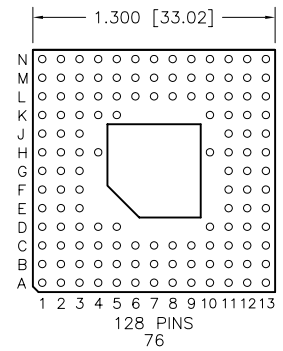
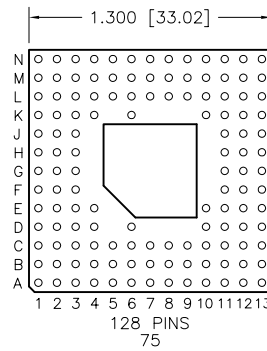
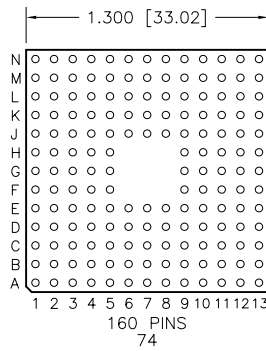
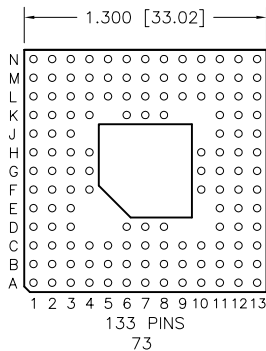
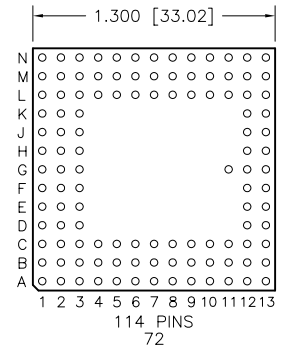
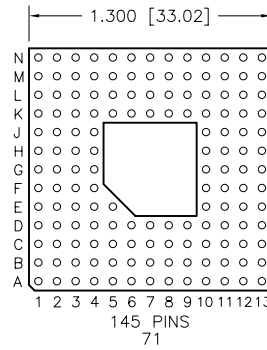
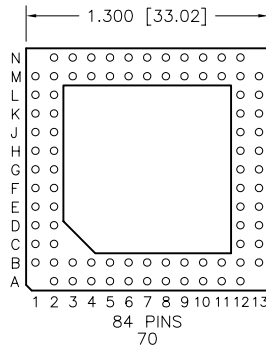
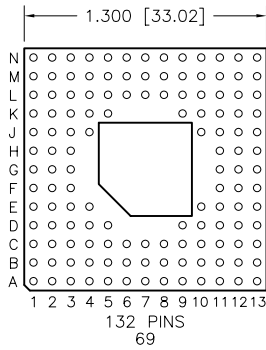
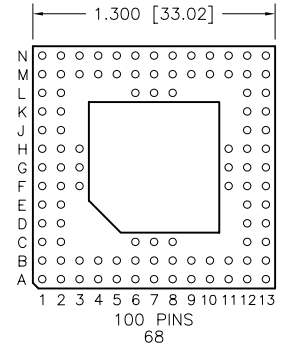
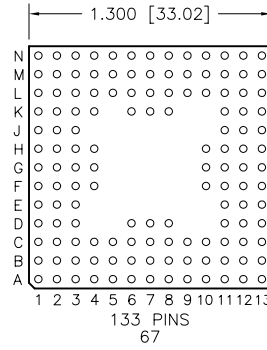
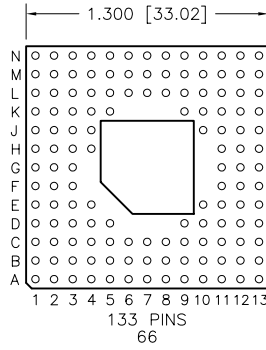
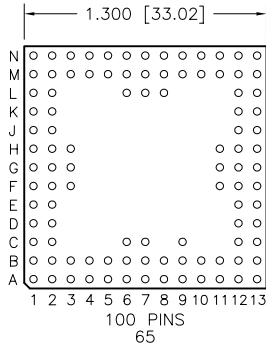
13 X 13



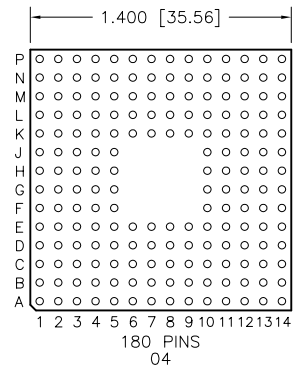
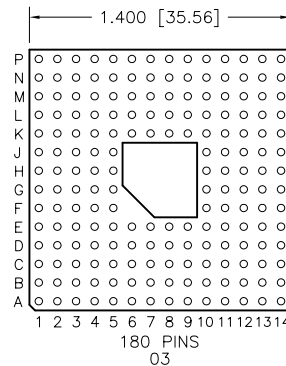
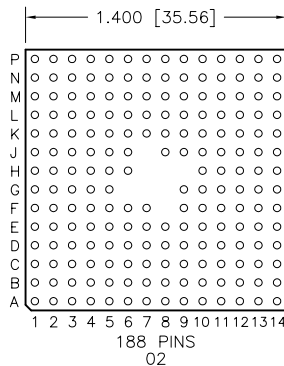
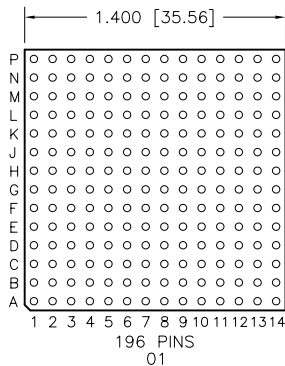


PGA SOCKET FOOTPRINTS

13 X 13



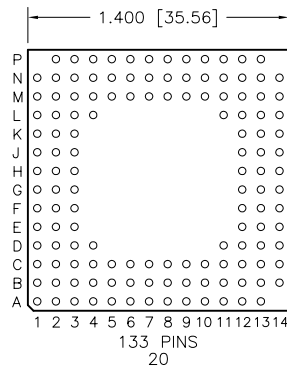
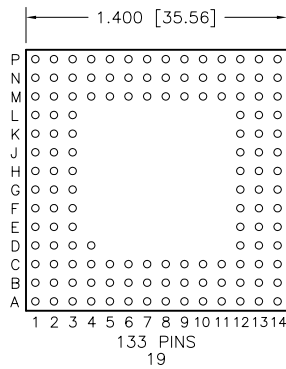
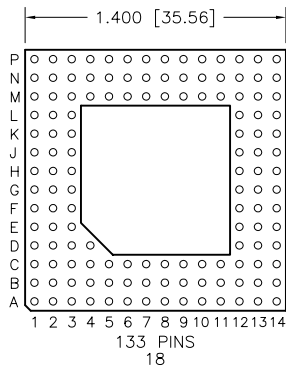
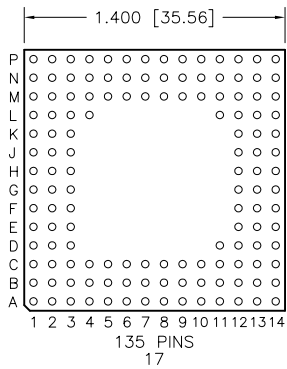
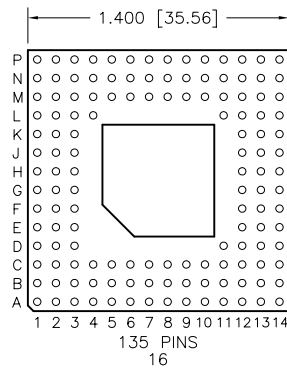
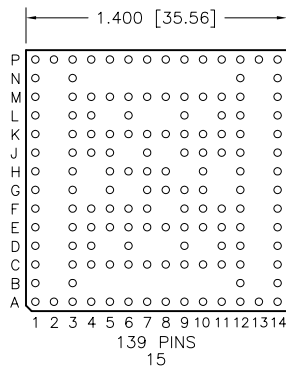
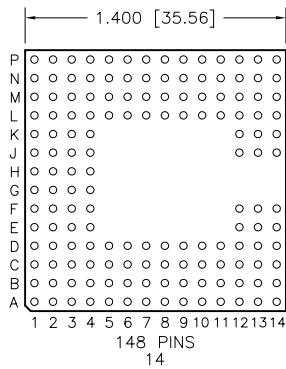
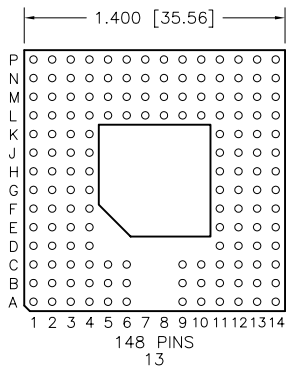
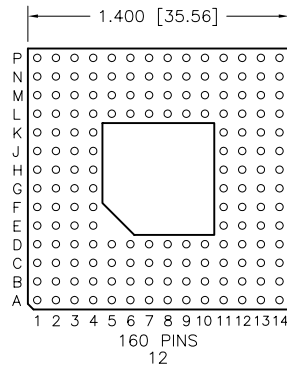
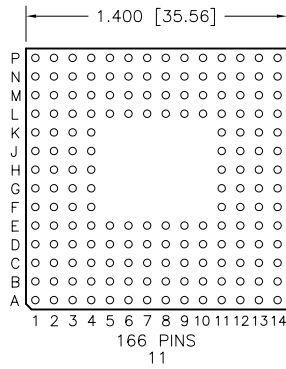
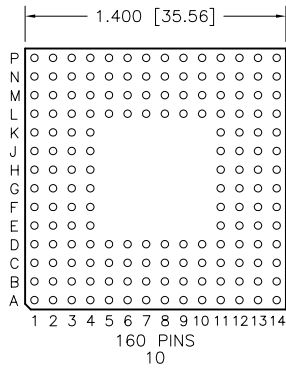
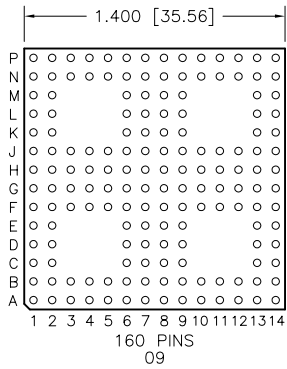
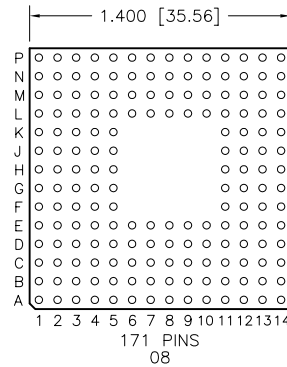
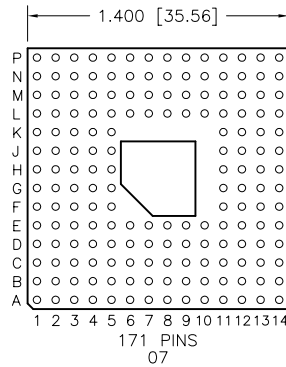
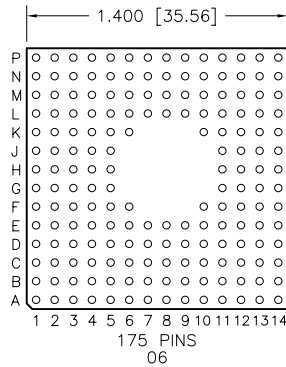
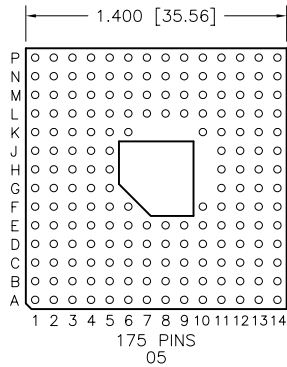
14 X 14





PGA SOCKET FOOTPRINTS

14 X 14



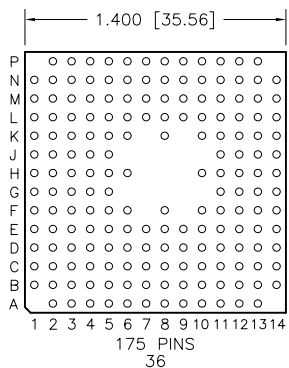
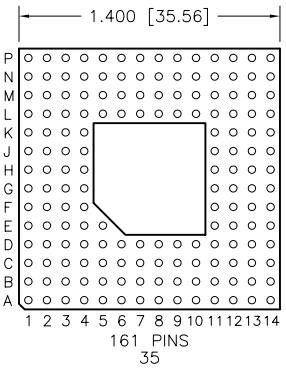
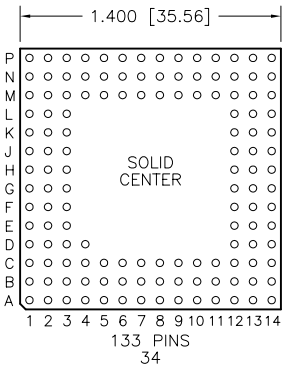
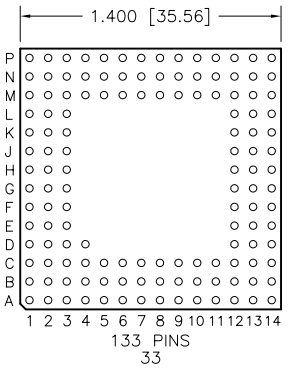
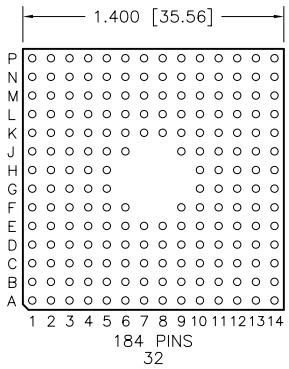
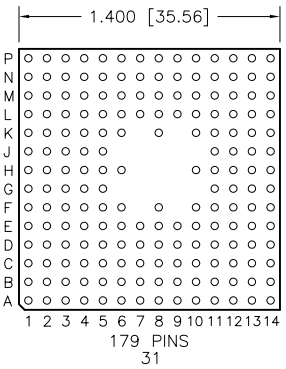
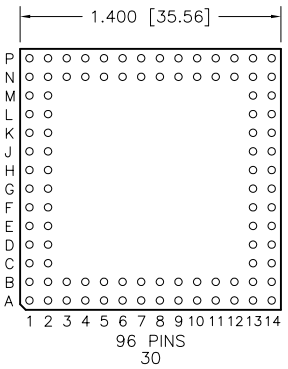
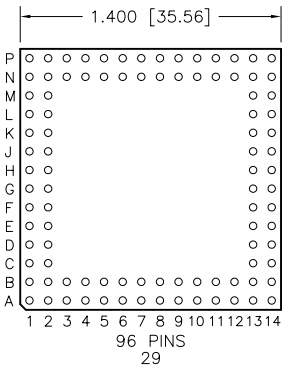
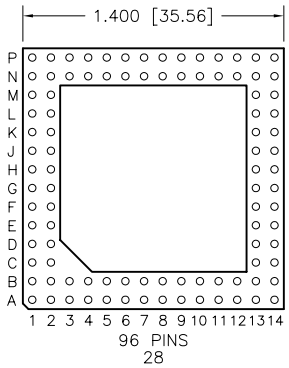
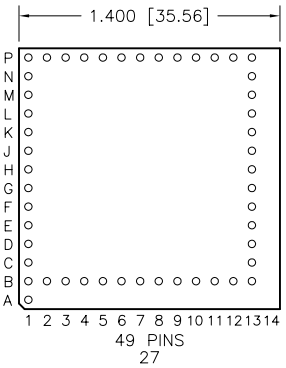
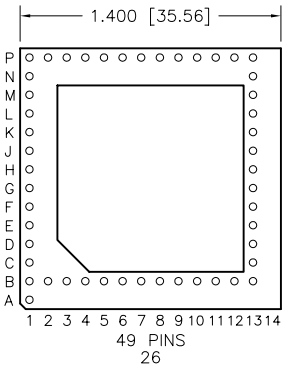
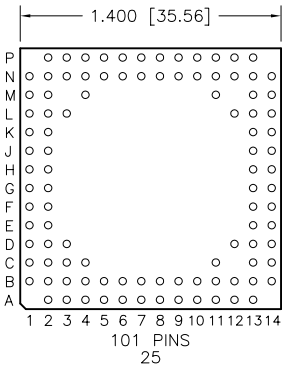
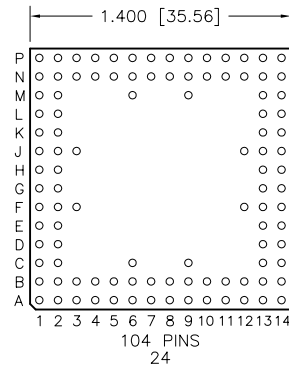
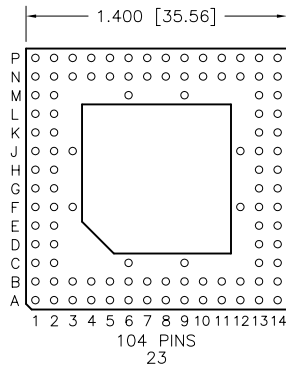
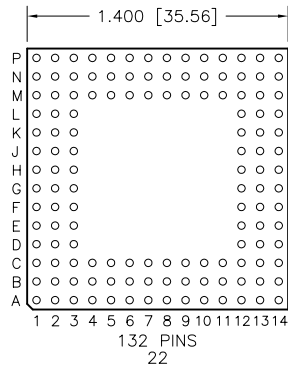
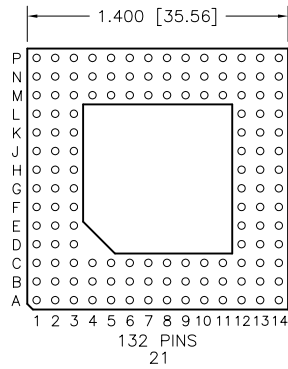
© ANDON 2007 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]

WE RESERVE THE RIGHT TO CHANGE SPECIFICATIONS WITHOUT NOTICE.



PGA SOCKET FOOTPRINTS

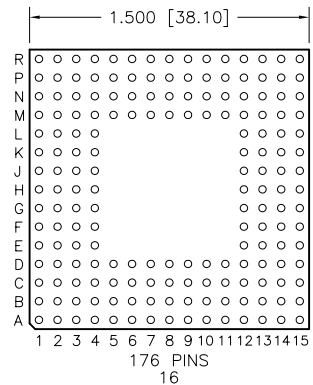
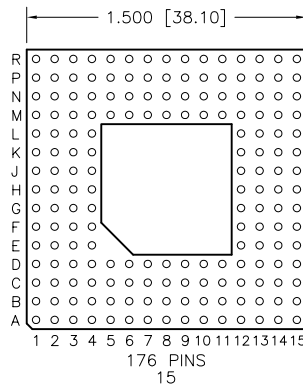
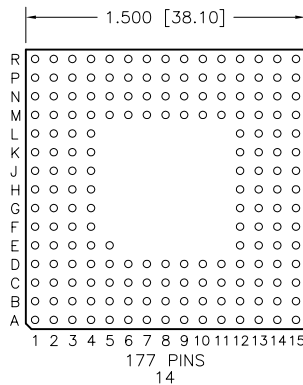
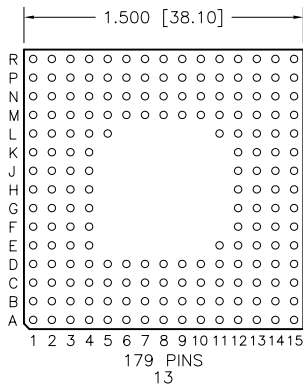
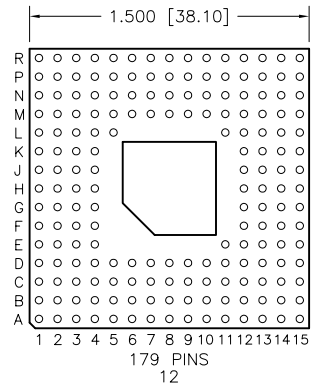
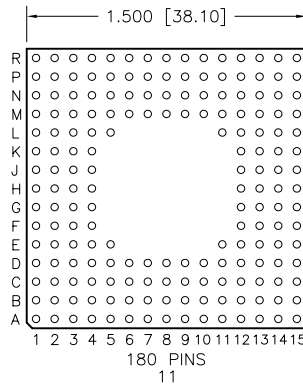
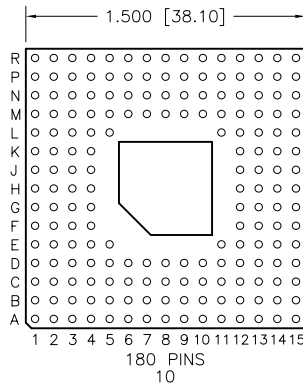
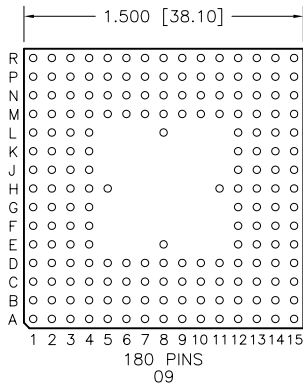
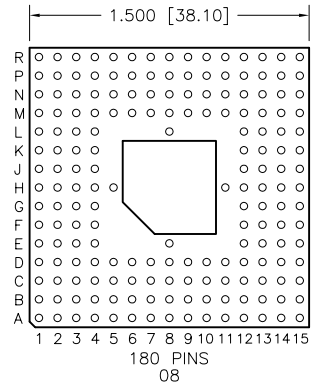
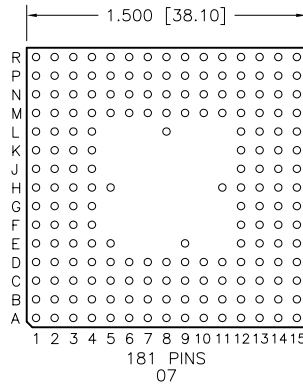
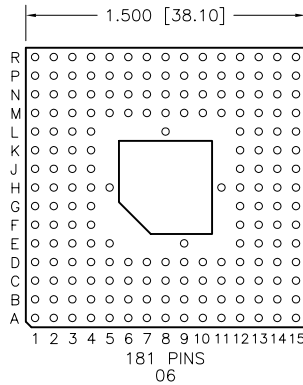
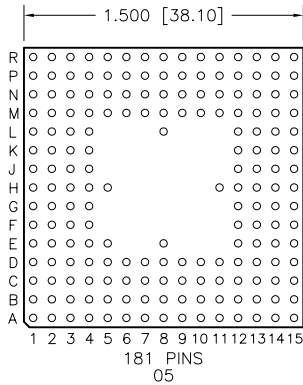
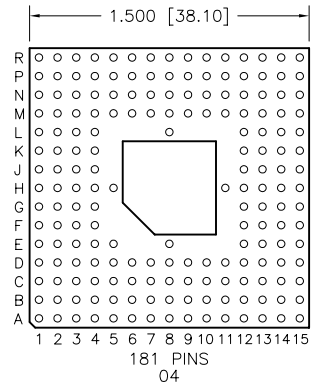
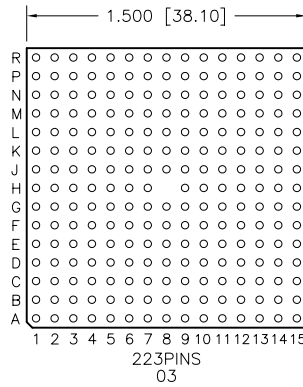
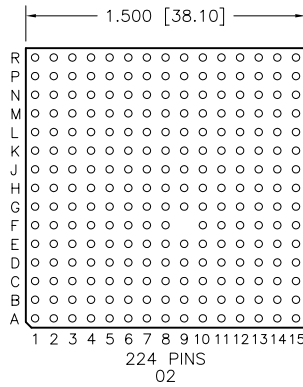
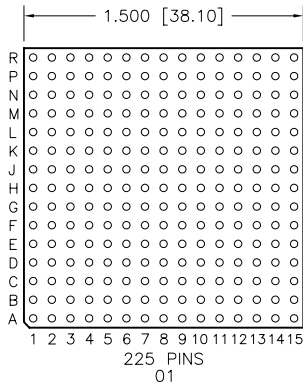
14 X 14





PGA SOCKET FOOTPRINTS

15 X 15



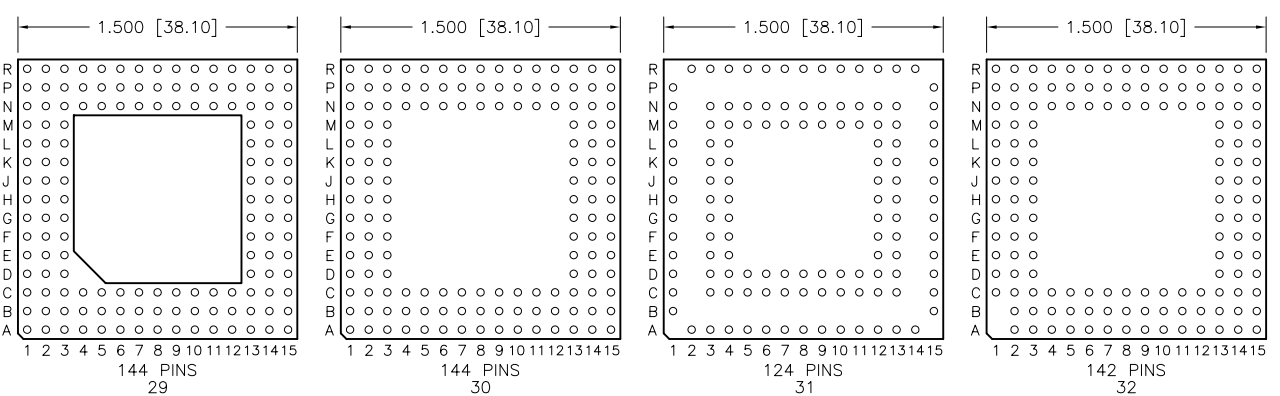
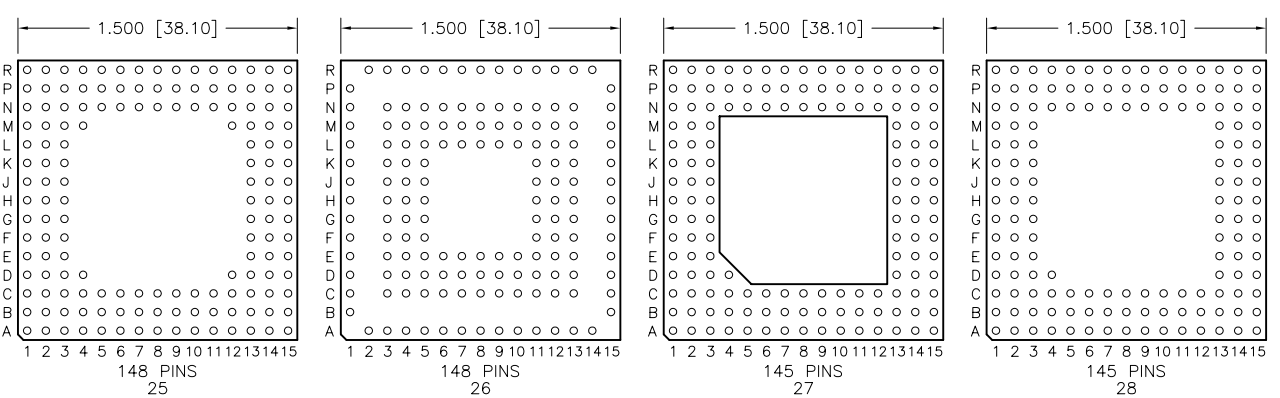
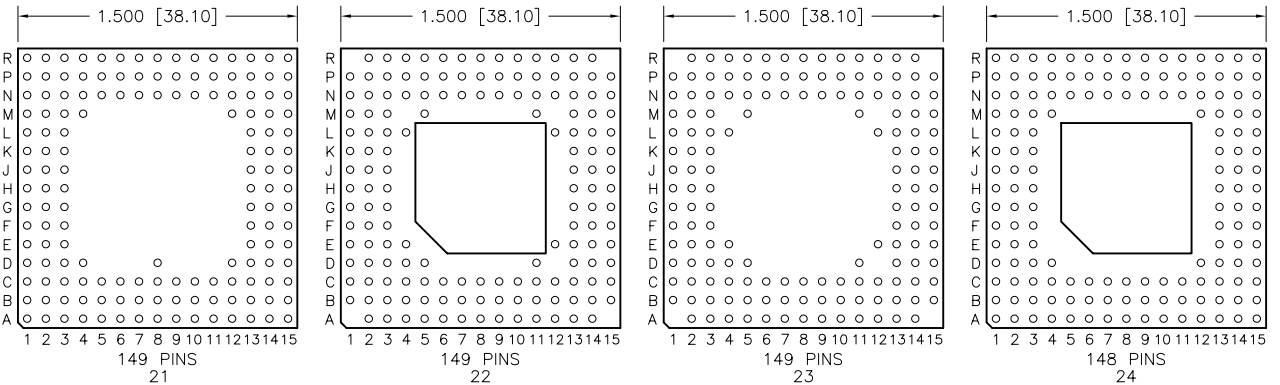
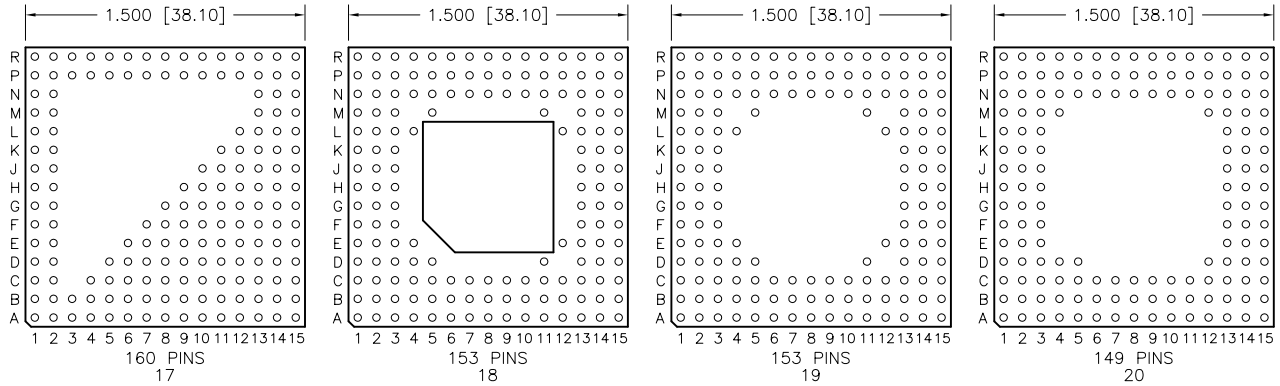
© ANDON 2007 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]

WE RESERVE THE RIGHT TO CHANGE SPECIFICATIONS WITHOUT NOTICE.



PGA SOCKET FOOTPRINTS

15 X 15



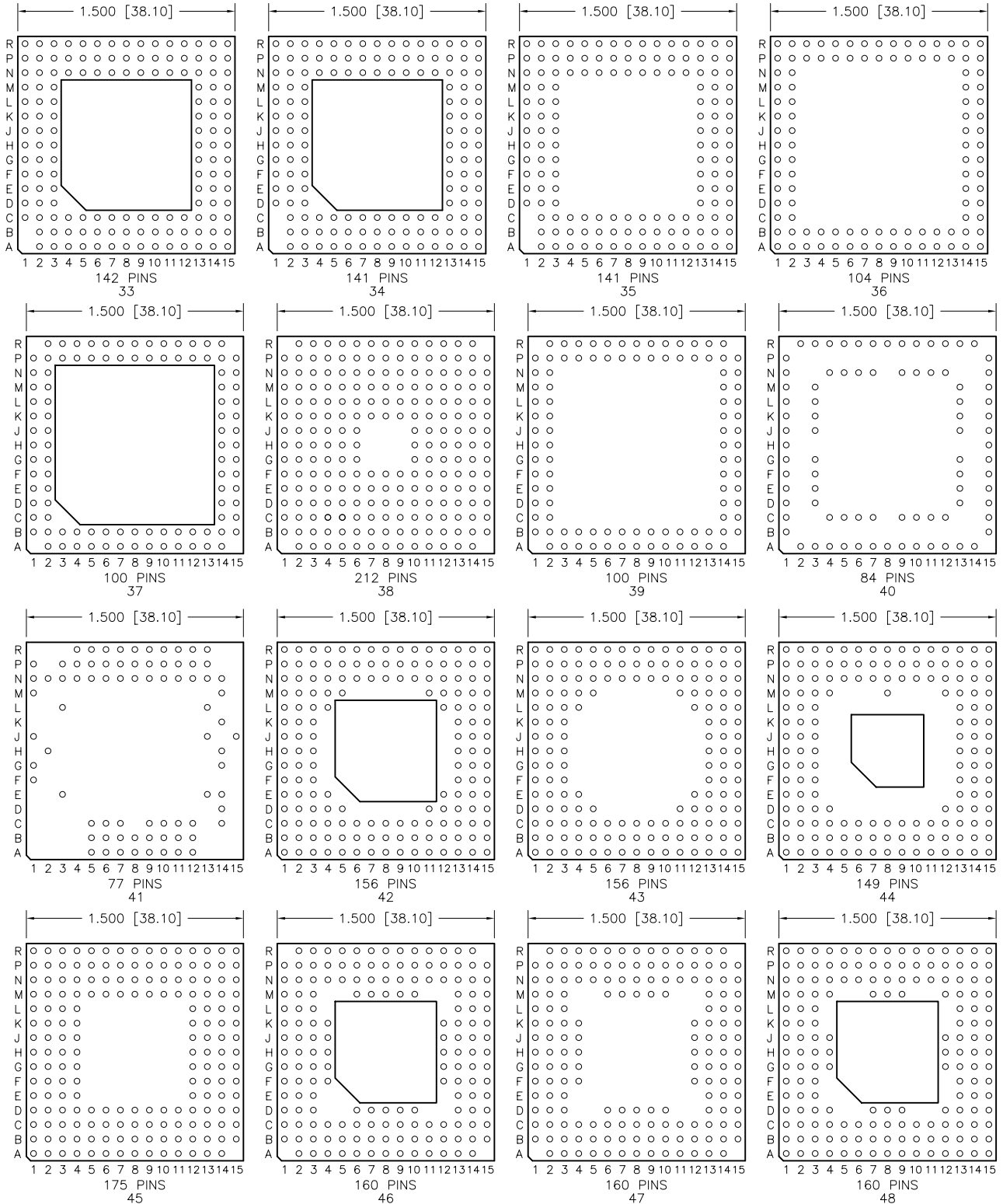
© ANDON 2007 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]

WE RESERVE THE RIGHT TO CHANGE SPECIFICATIONS WITHOUT NOTICE.



PGA SOCKET FOOTPRINTS

15 X 15



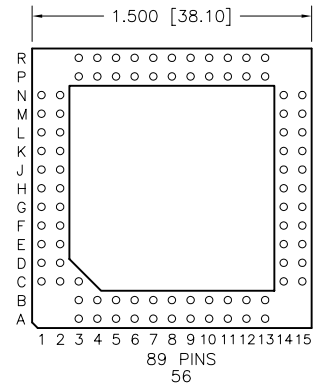
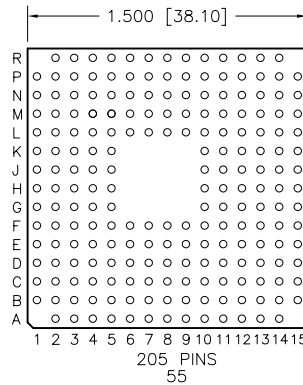
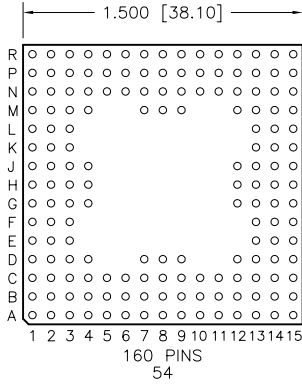
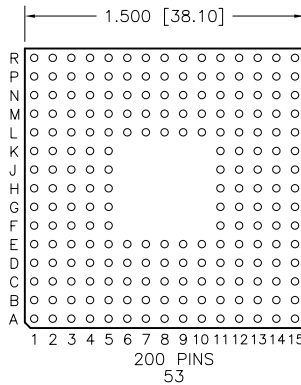
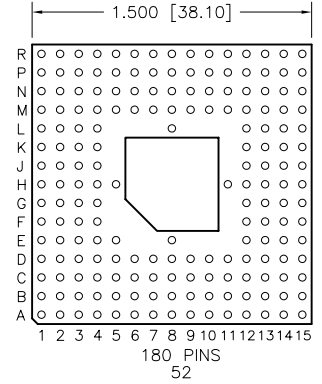
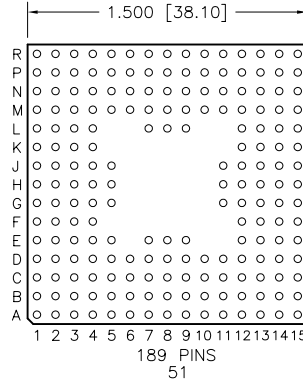
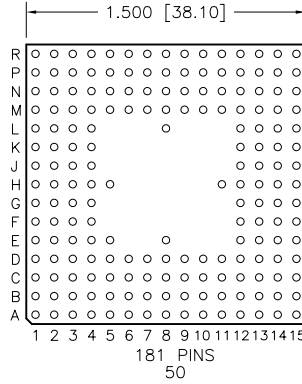
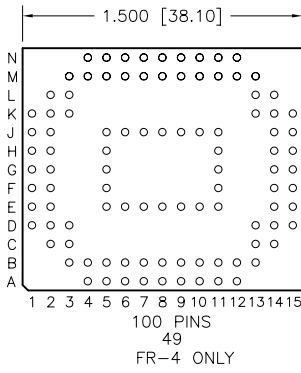
© ANDON 2007 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]

WE RESERVE THE RIGHT TO CHANGE SPECIFICATIONS WITHOUT NOTICE.



PGA SOCKET FOOTPRINTS

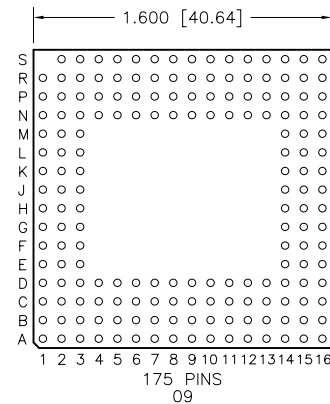
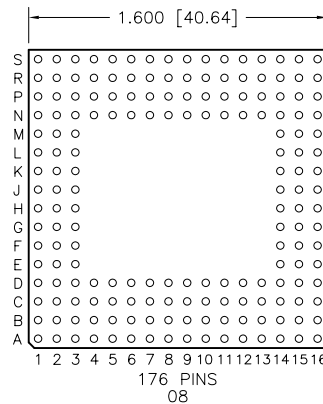
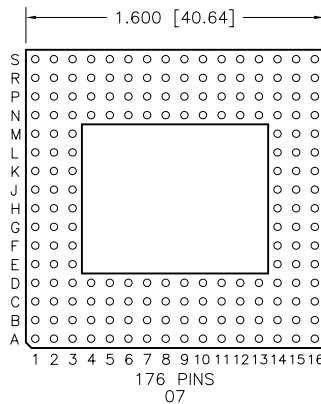
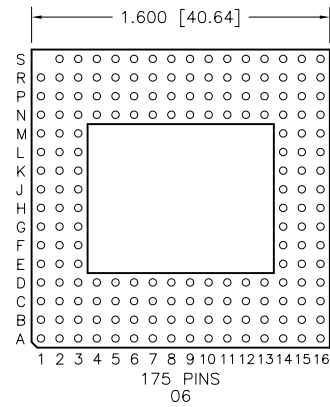
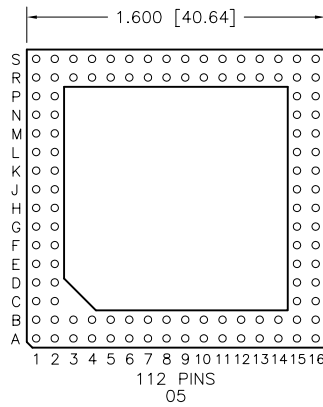
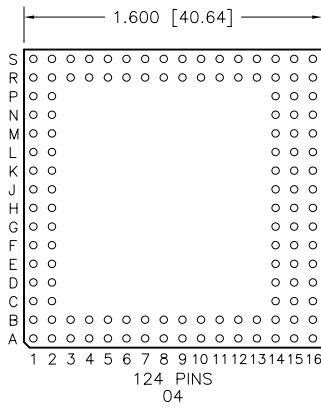
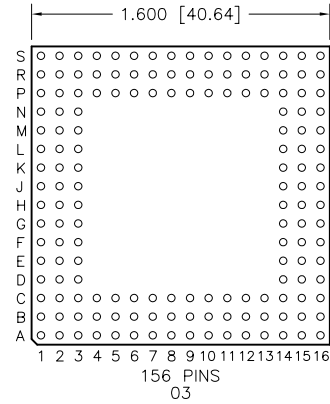
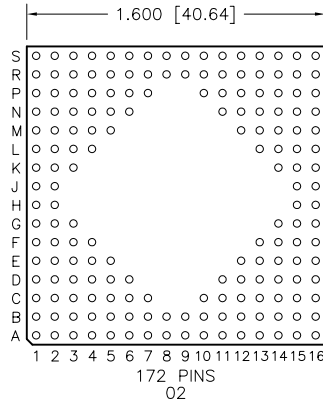
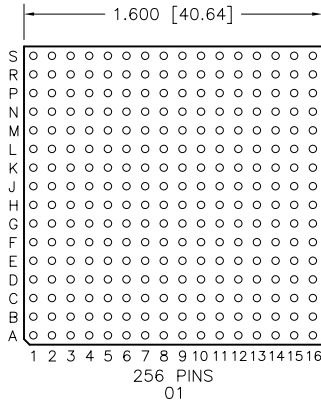
15 X 15





PGA SOCKET FOOTPRINTS

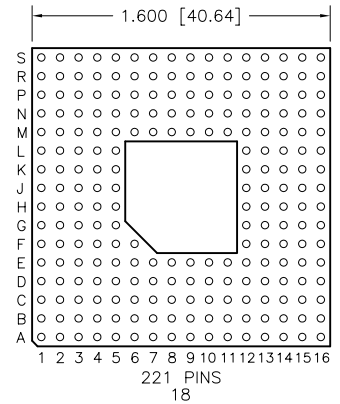
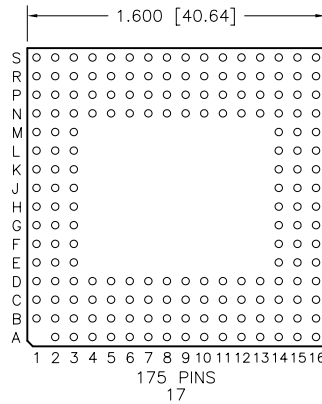
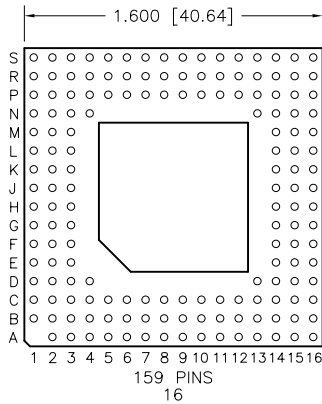
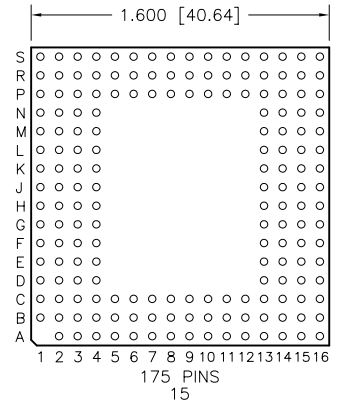
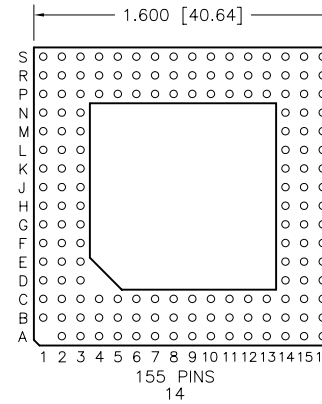
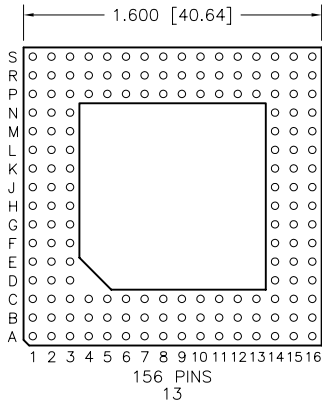
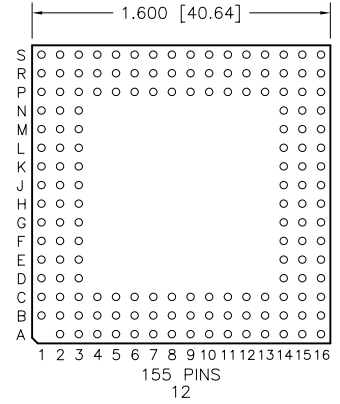
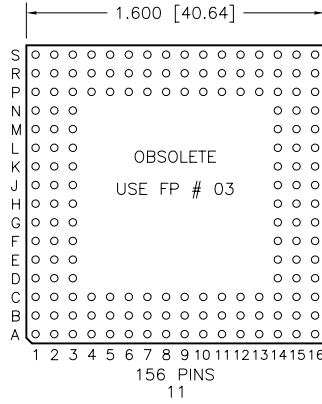
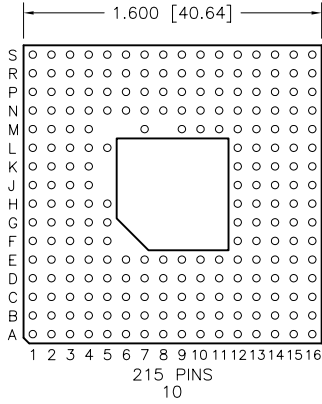
16 X 16





PGA SOCKET FOOTPRINTS

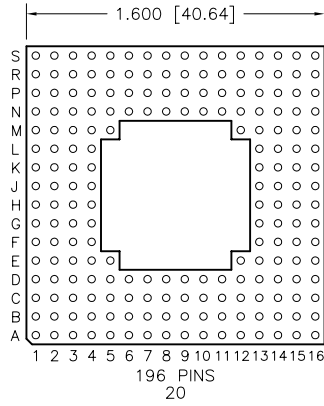
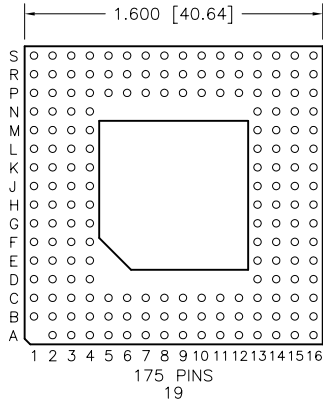
16 X 16



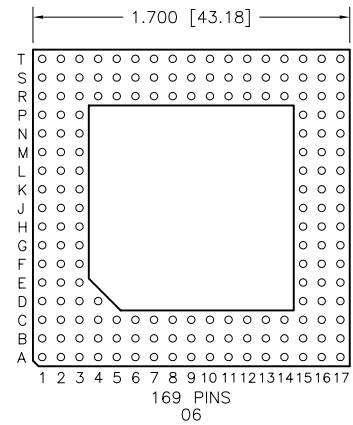
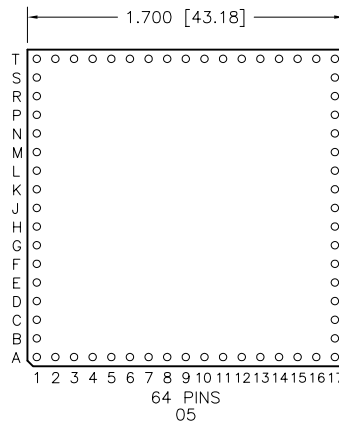
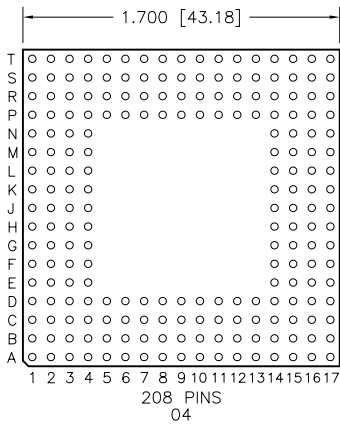
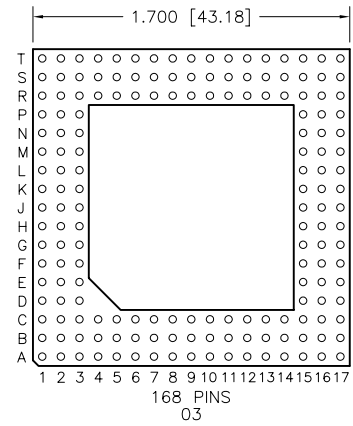
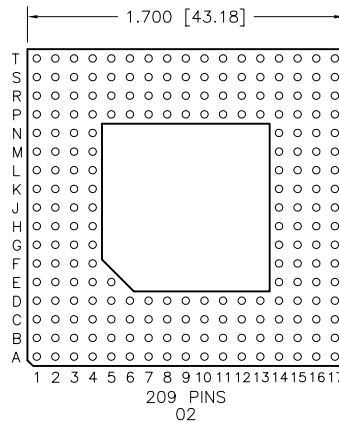
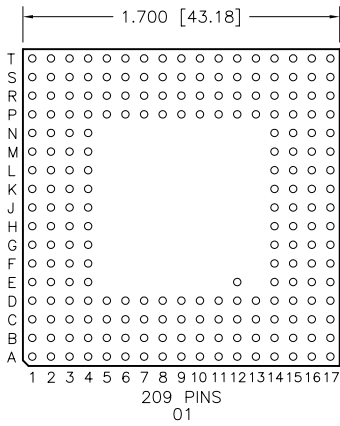


PGA SOCKET FOOTPRINTS

16 X 16



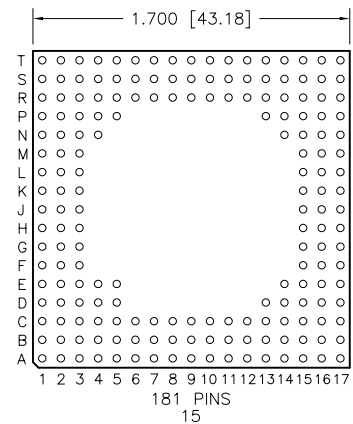
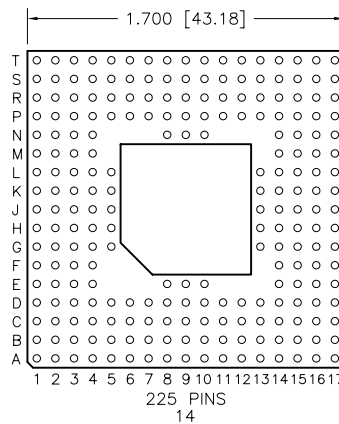
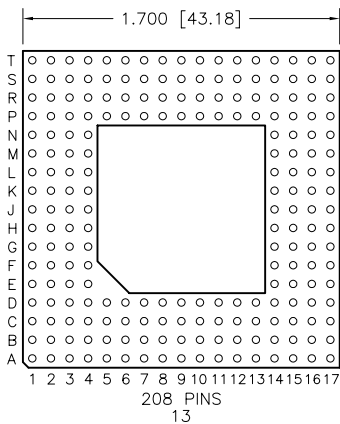
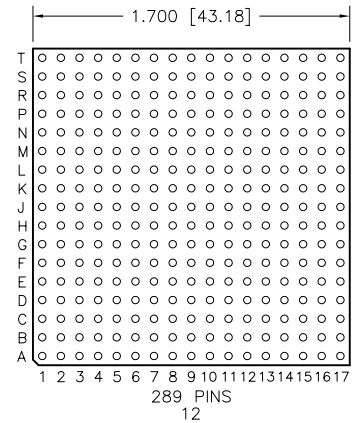
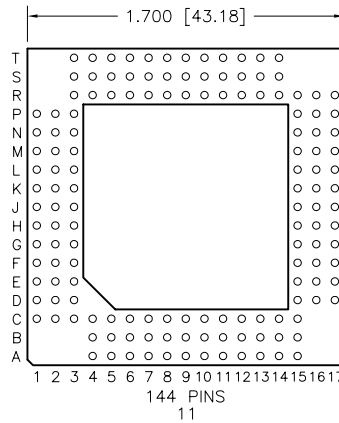
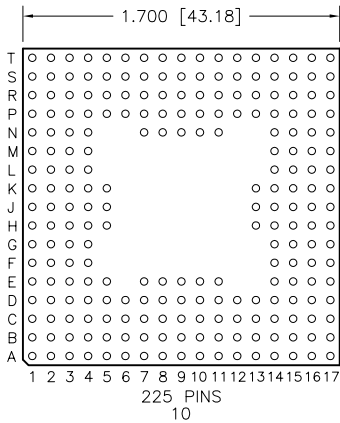
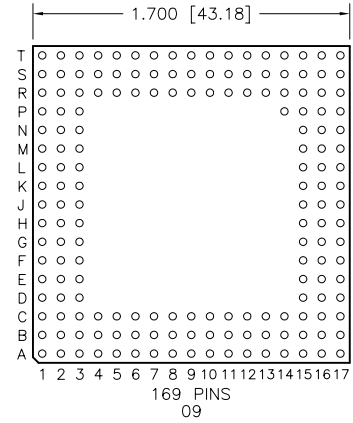
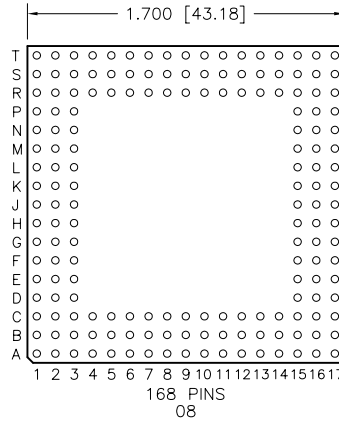
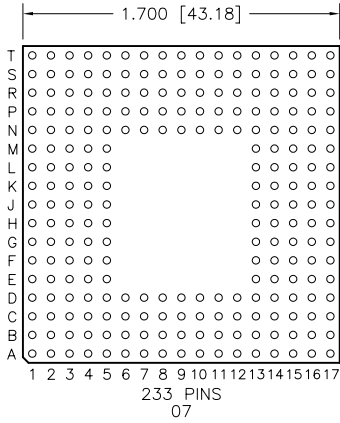
17 X 17





PGA SOCKET FOOTPRINTS

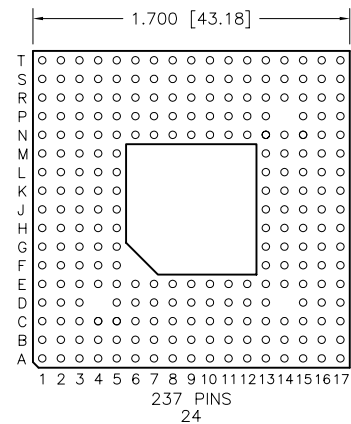
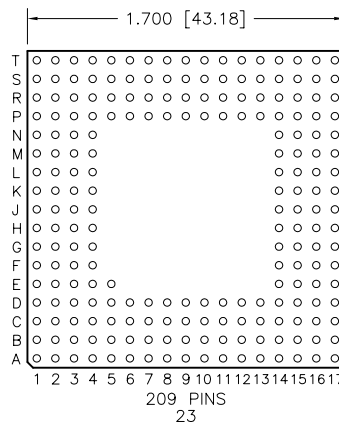
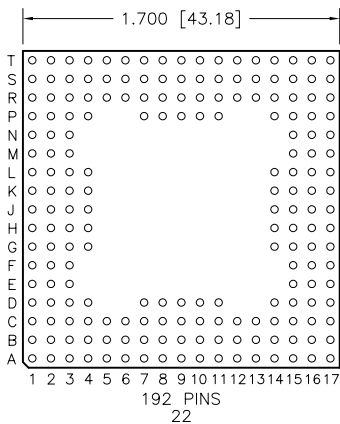
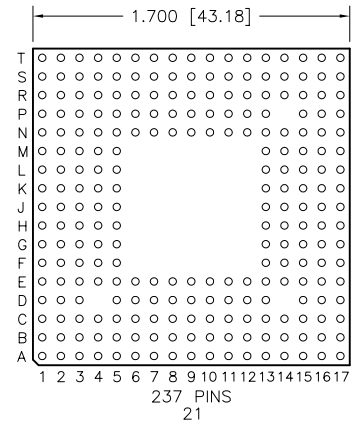
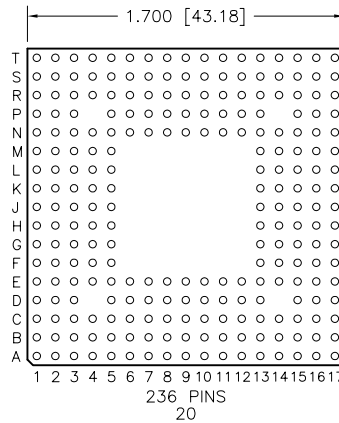
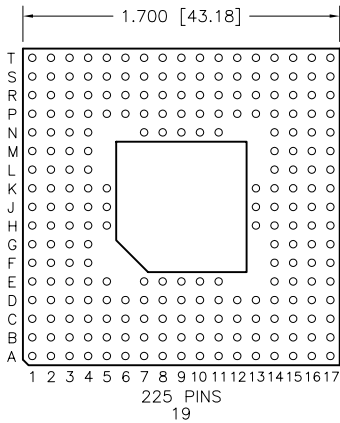
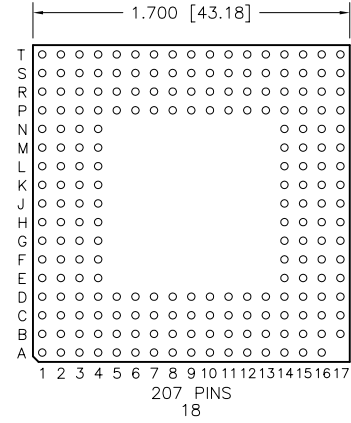
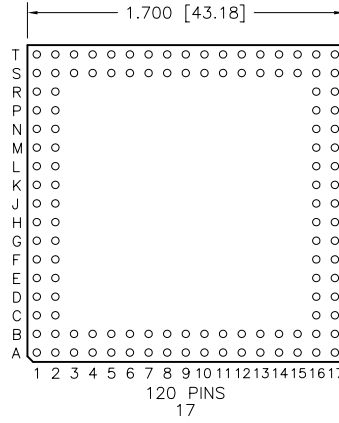
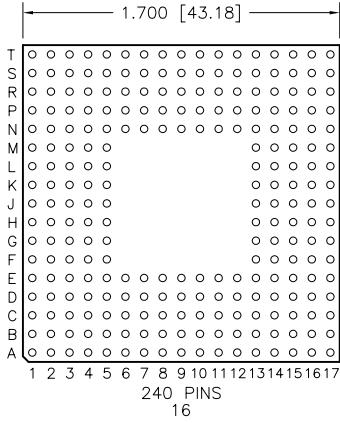
17 X 17





PGA SOCKET FOOTPRINTS

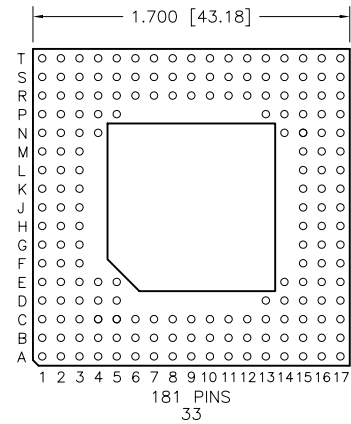
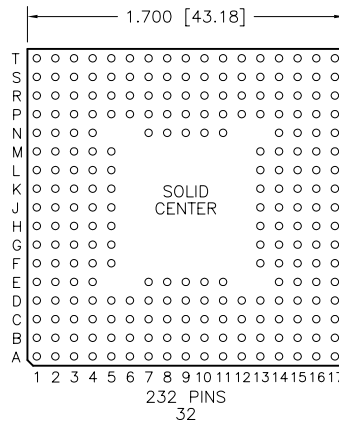
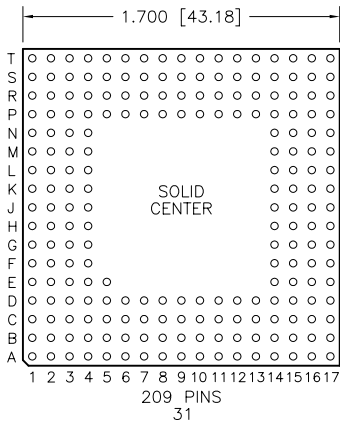
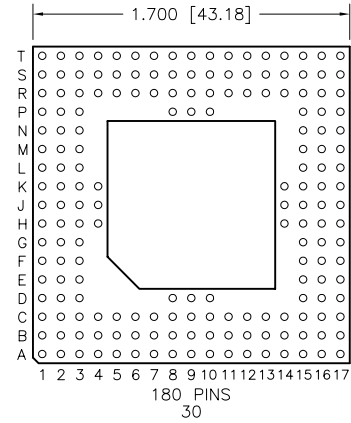
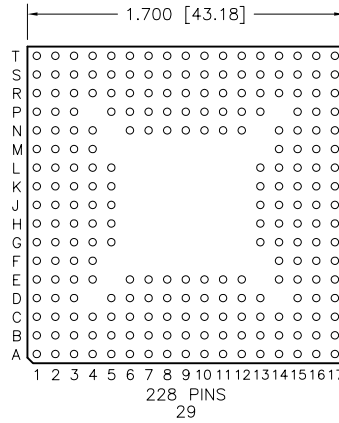
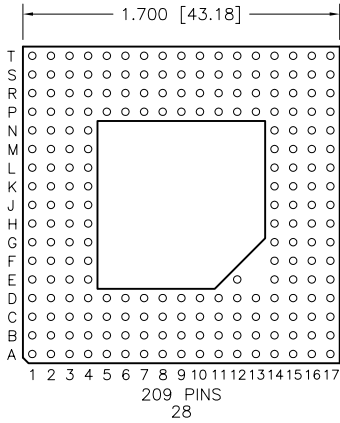
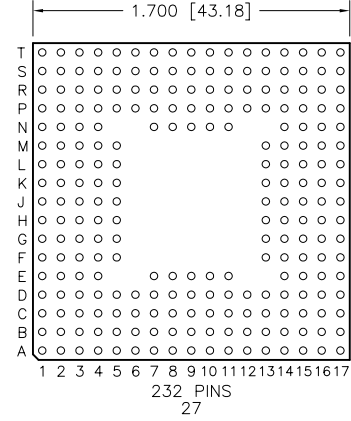
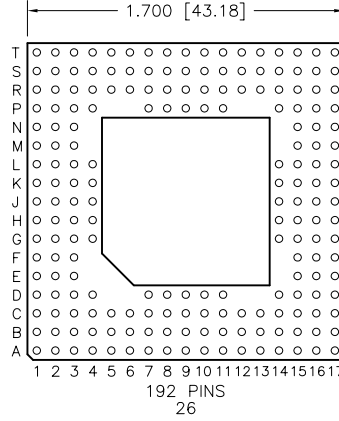
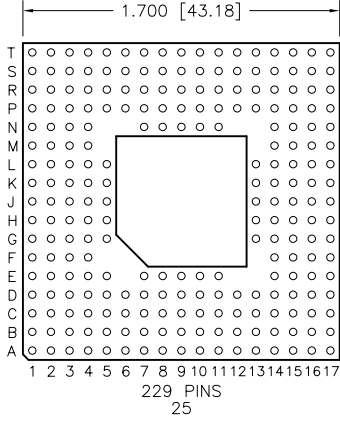
17 X 17





PGA SOCKET FOOTPRINTS

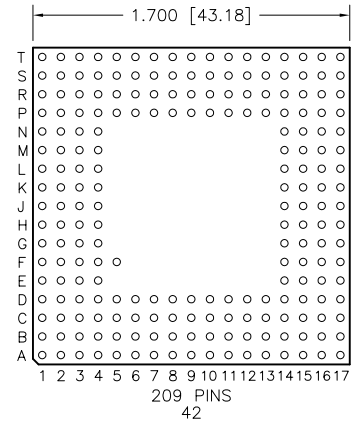
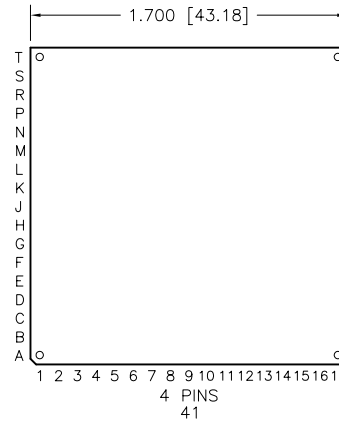
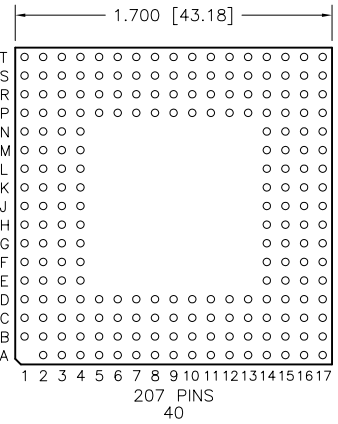
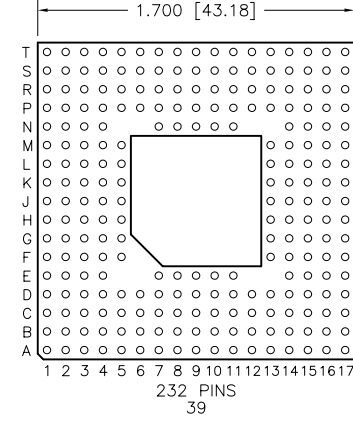
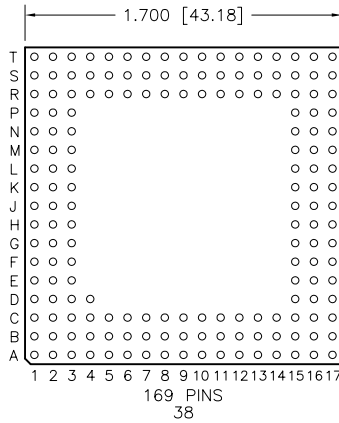
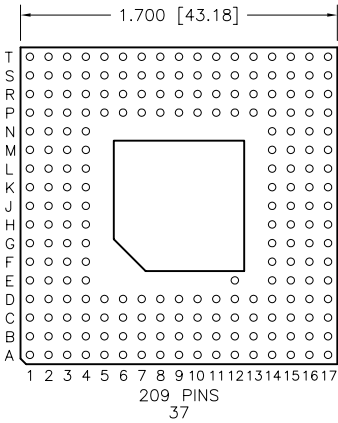
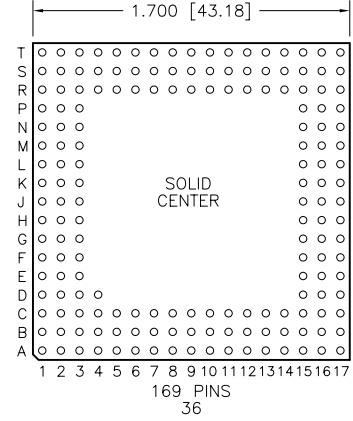
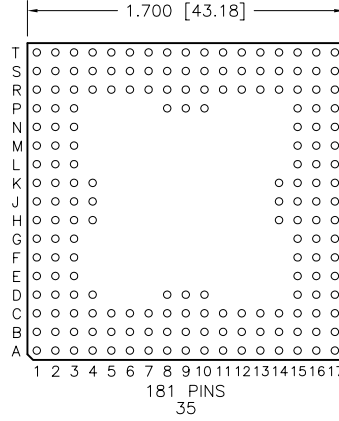
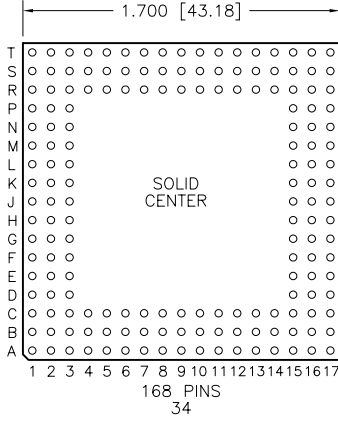
17 X 17





PGA SOCKET FOOTPRINTS

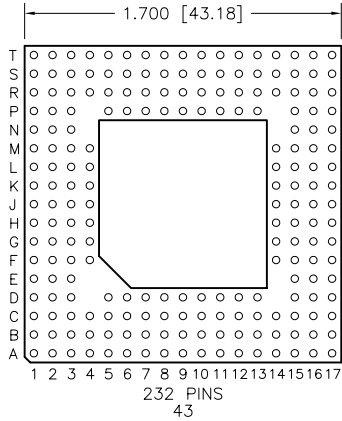
17 X 17



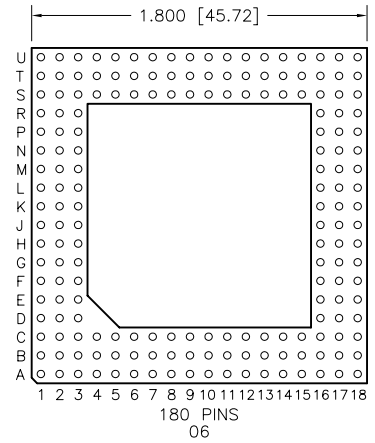
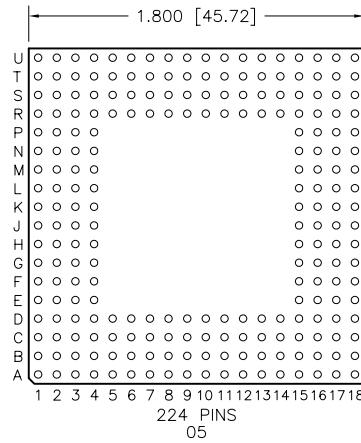
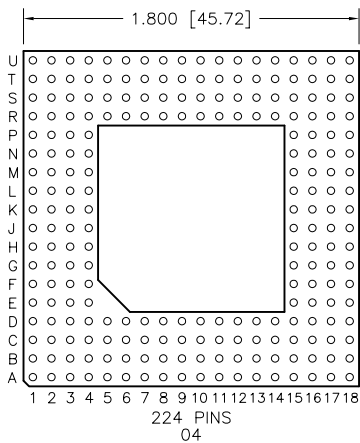
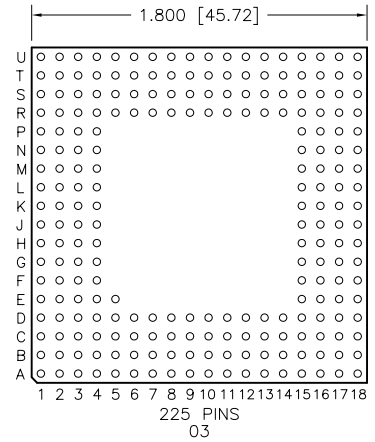
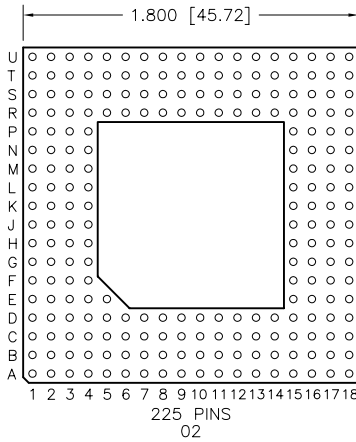
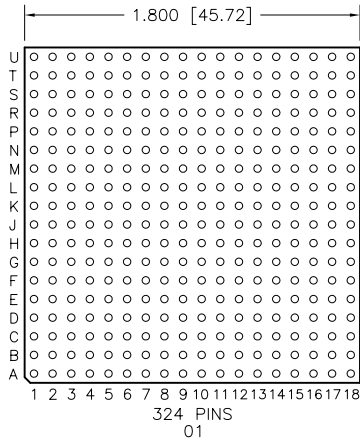


PGA SOCKET FOOTPRINTS

17 X 17



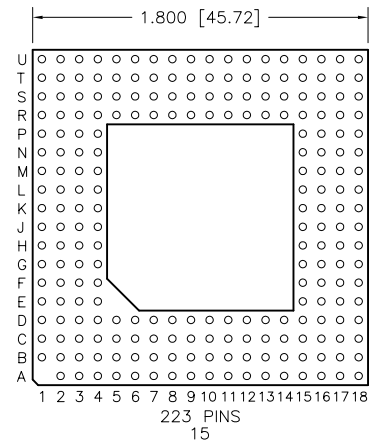
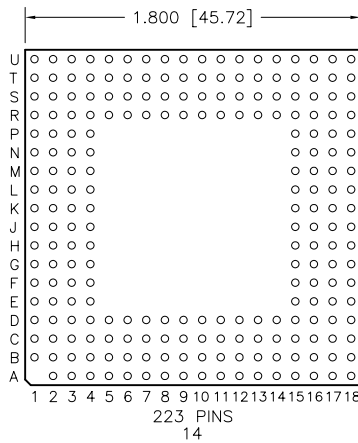
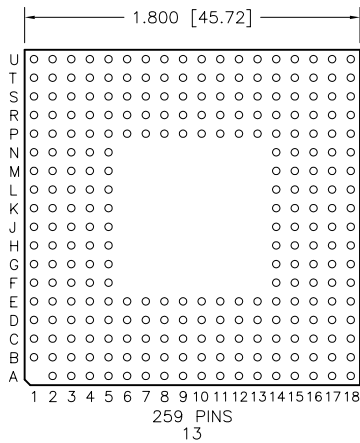
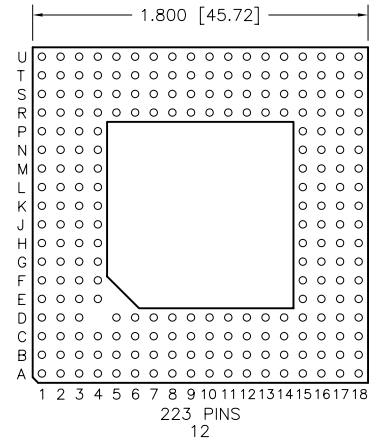
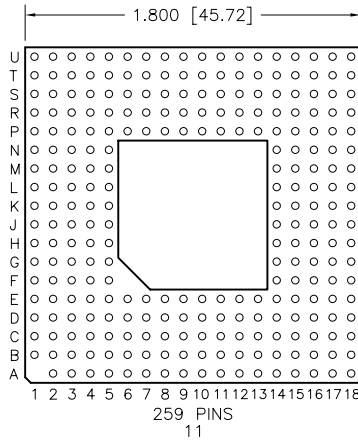
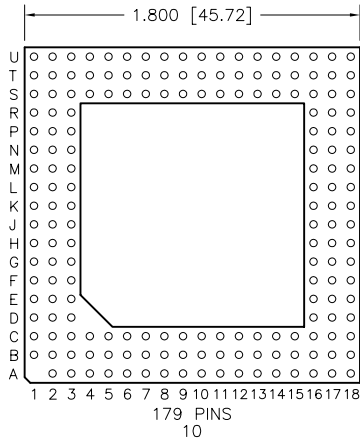
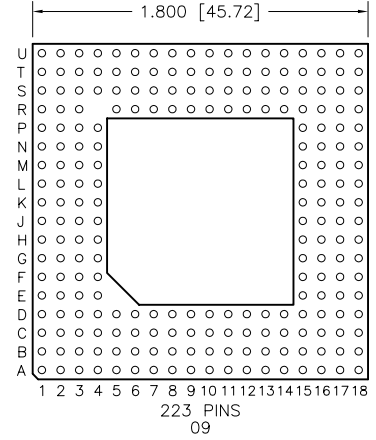
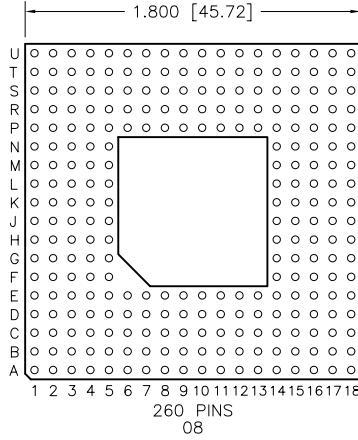
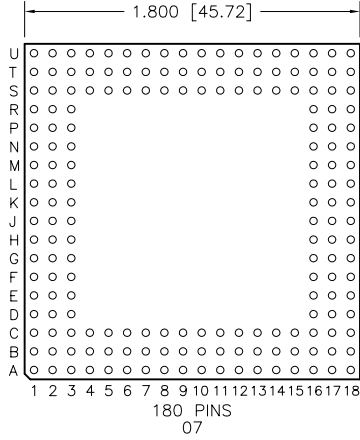
18 X 18





PGA SOCKET FOOTPRINTS

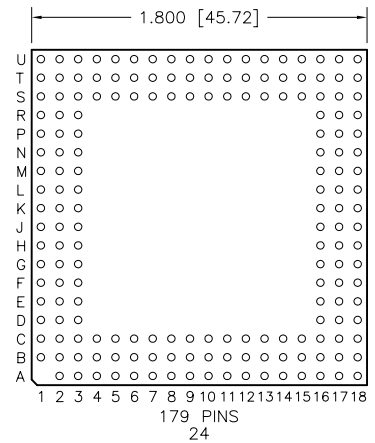
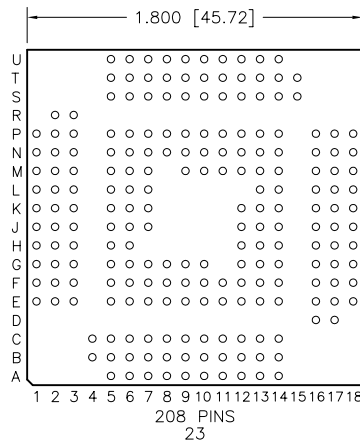
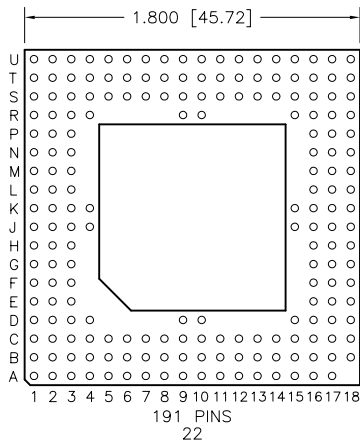
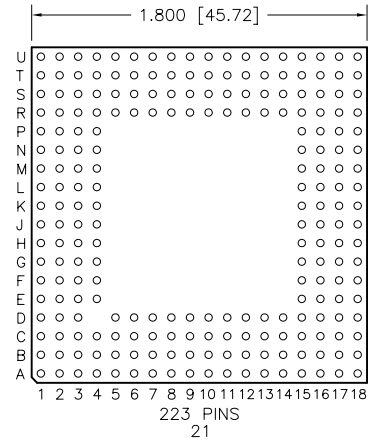
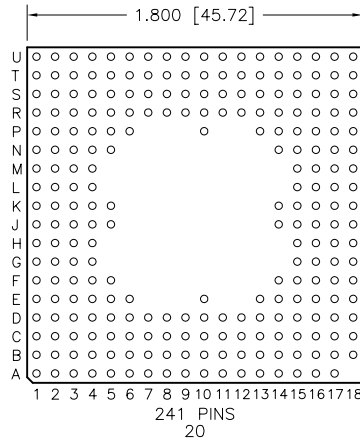
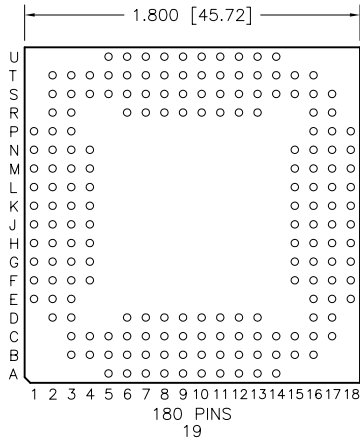
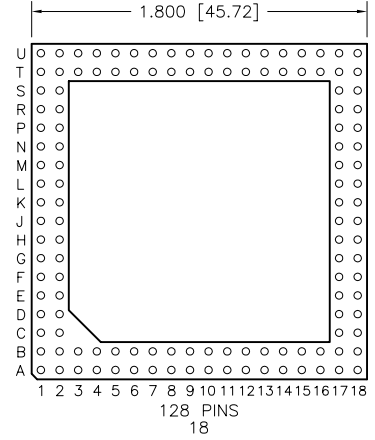
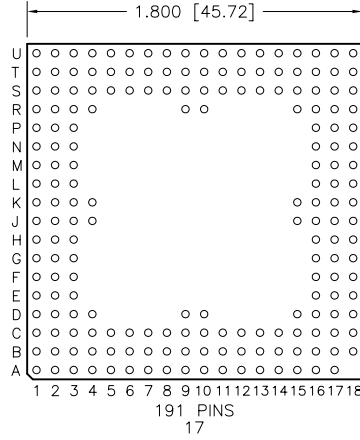
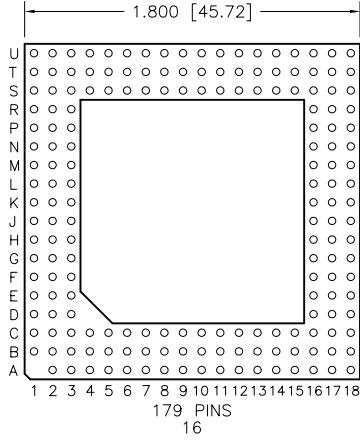
18 X 18





PGA SOCKET FOOTPRINTS

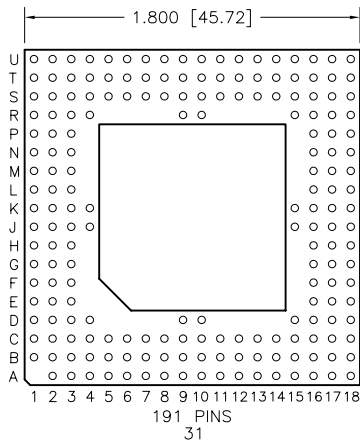
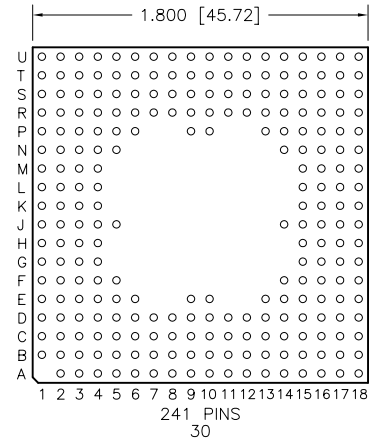
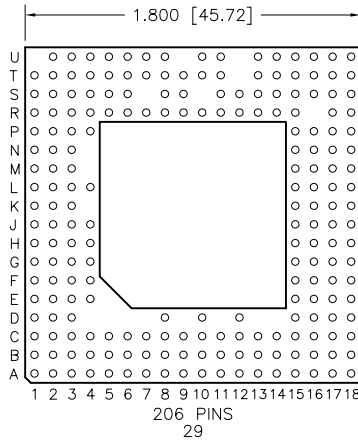
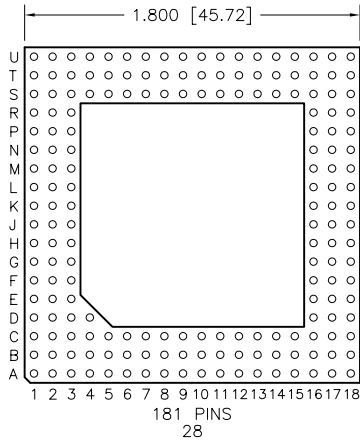
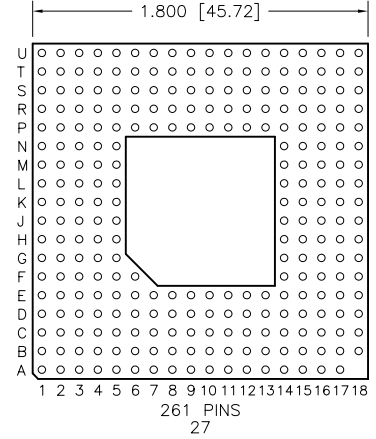
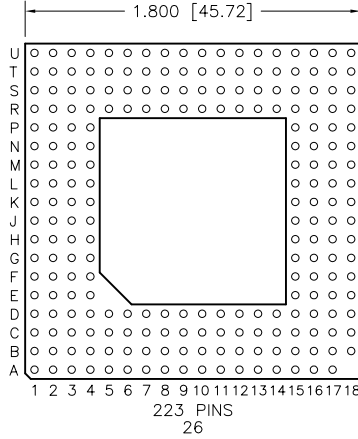
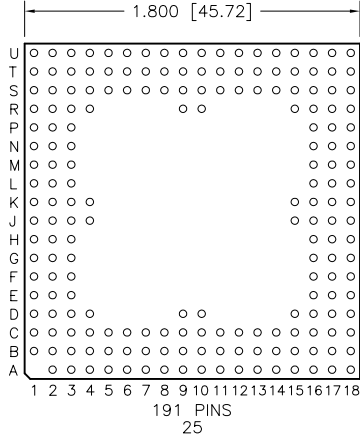
18 X 18





PGA SOCKET FOOTPRINTS

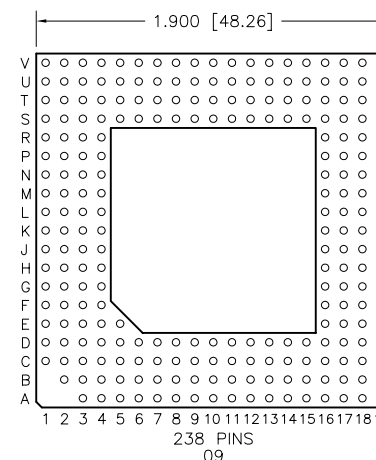
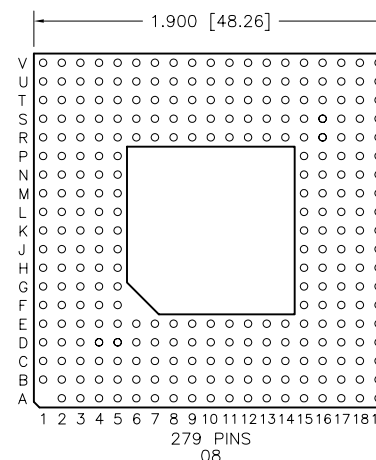
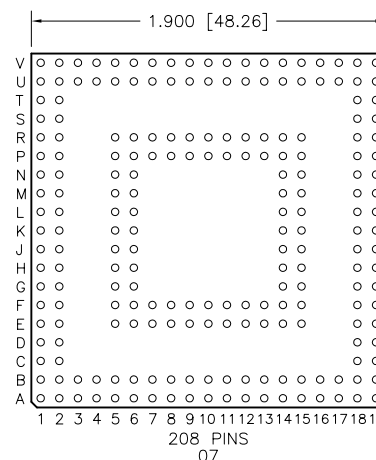
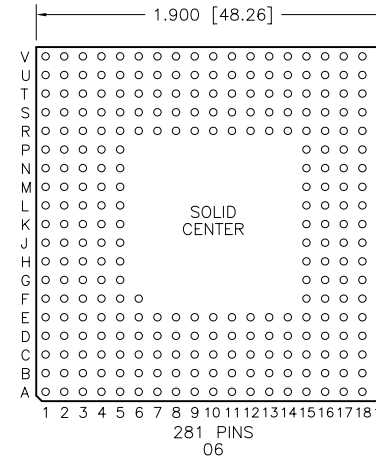
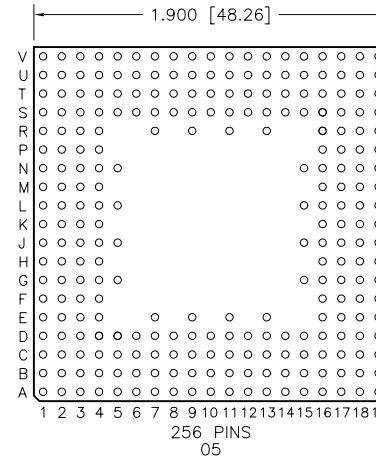
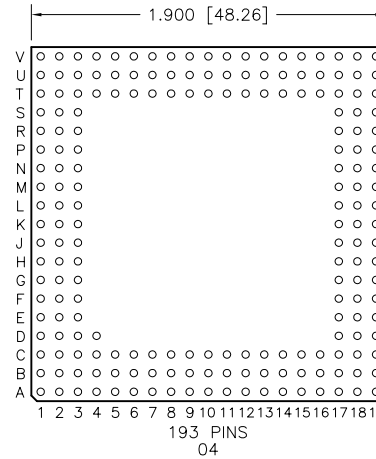
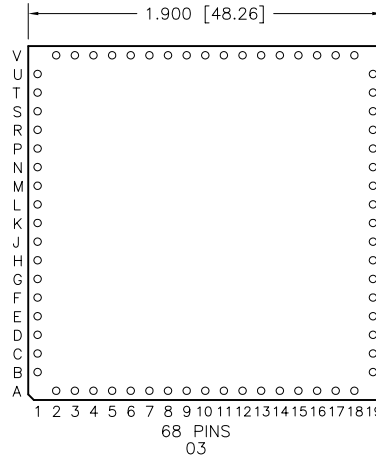
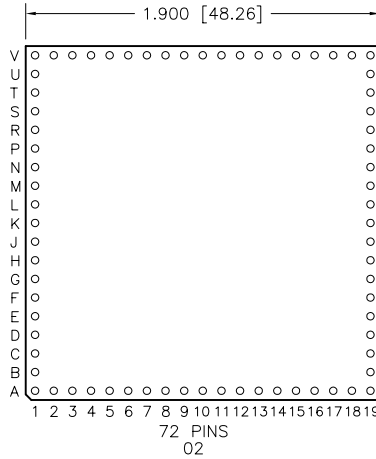
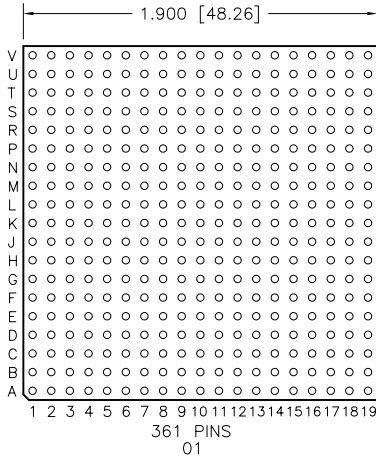
18 X 18





PGA SOCKET FOOTPRINTS

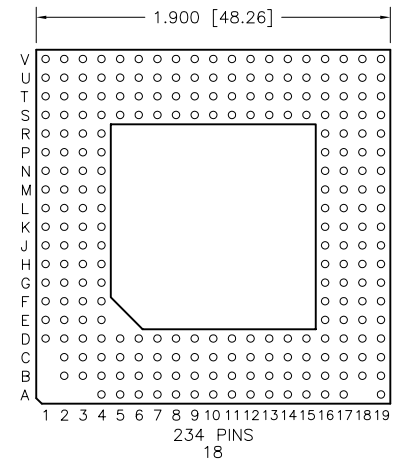
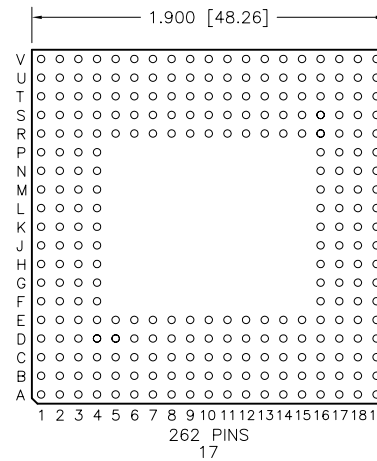
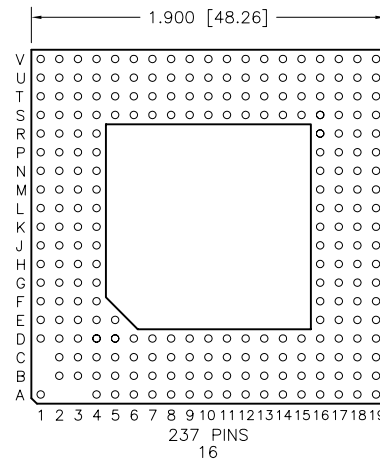
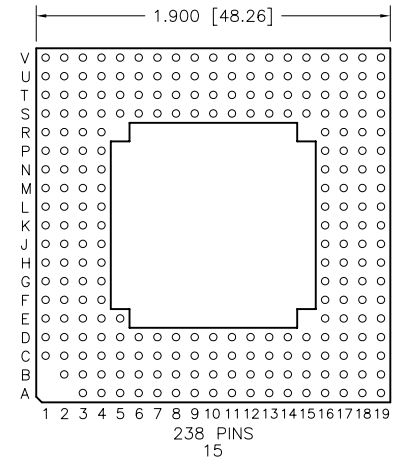
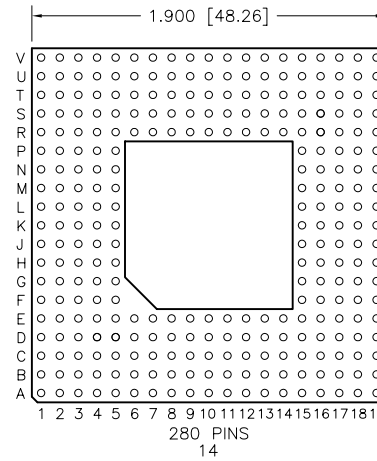
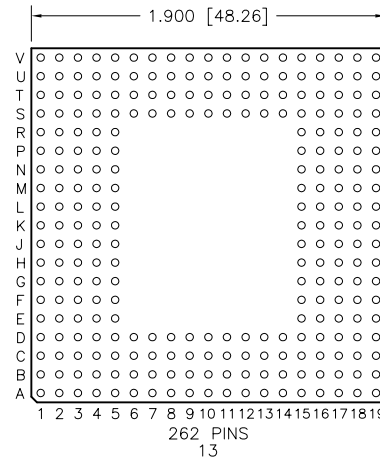
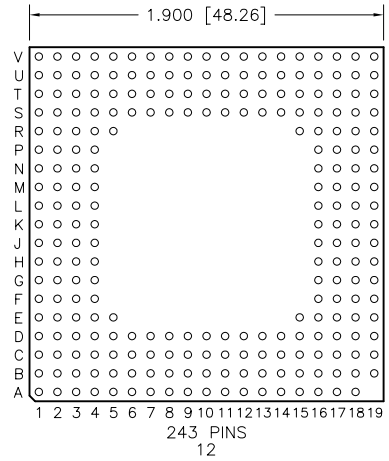
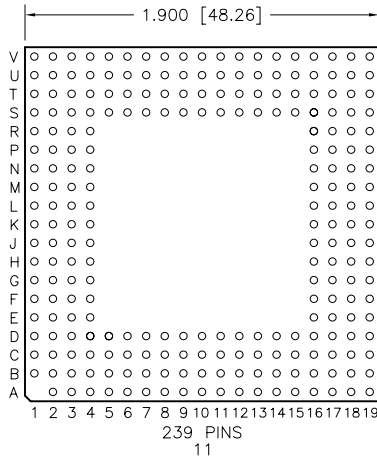
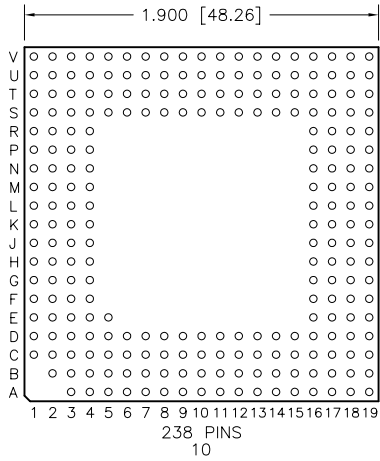
19 X 19





PGA SOCKET FOOTPRINTS

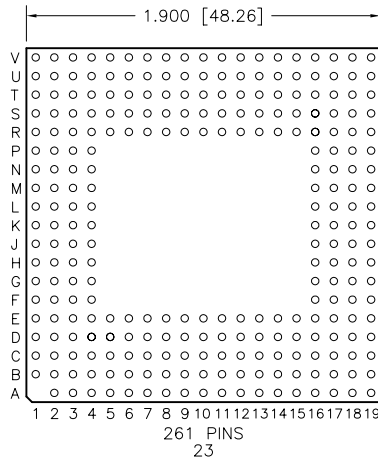
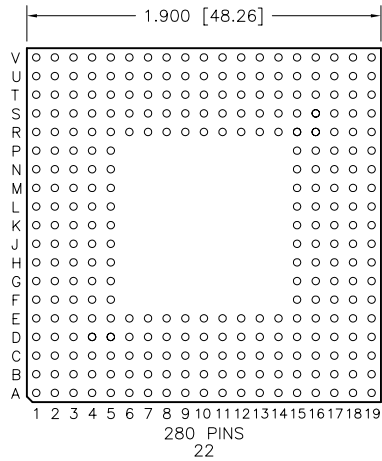
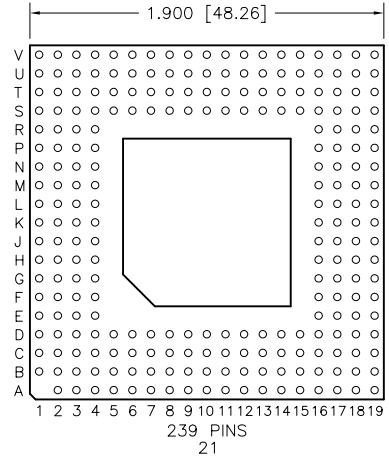
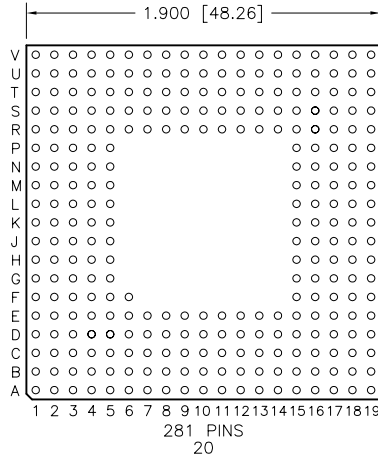
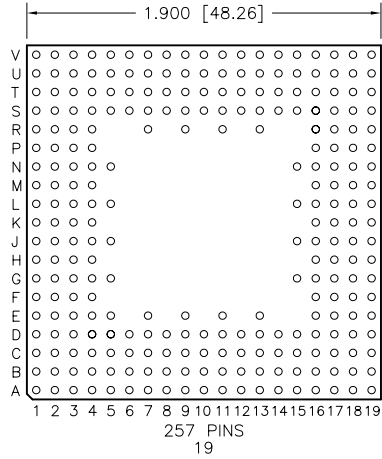
19 X 19





PGA SOCKET FOOTPRINTS

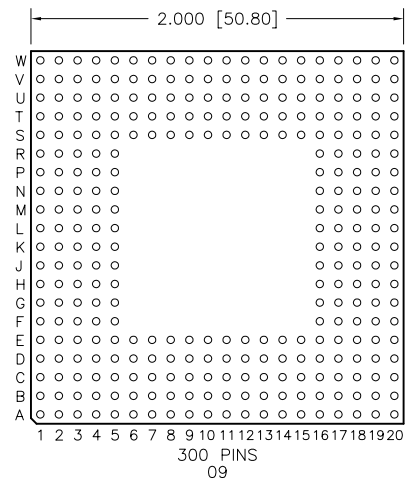
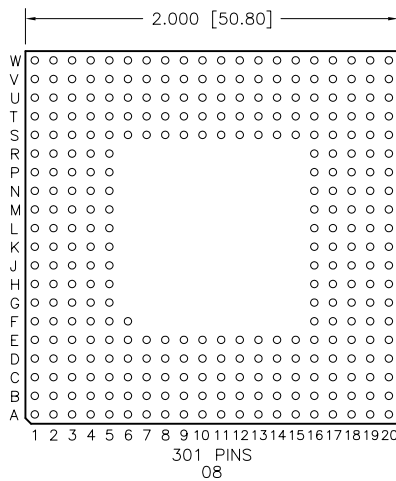
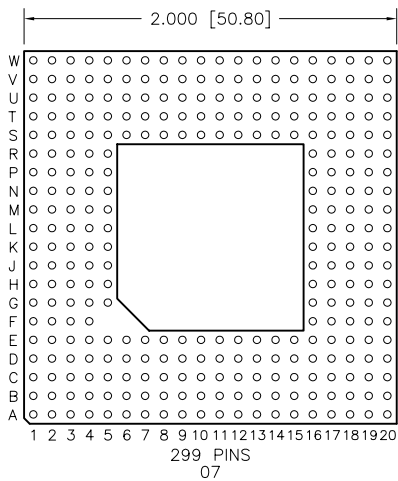
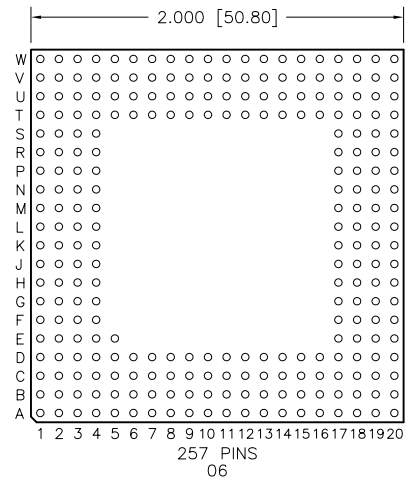
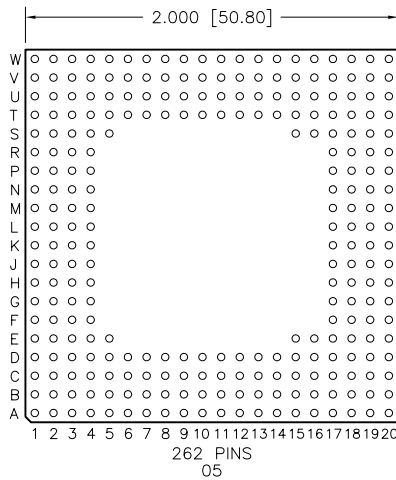
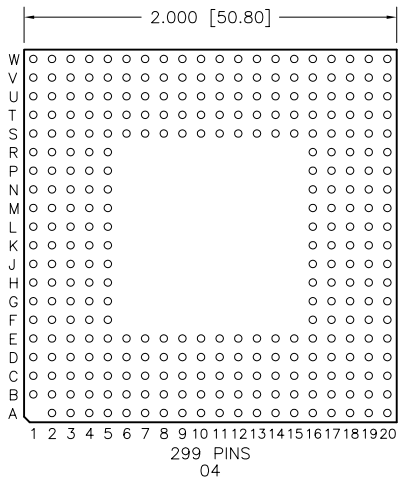
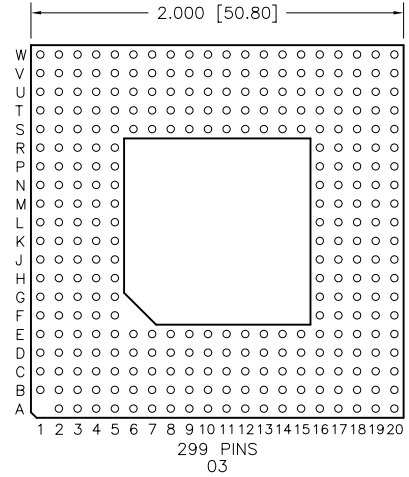
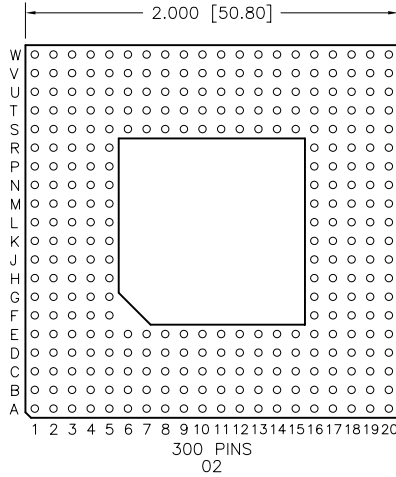
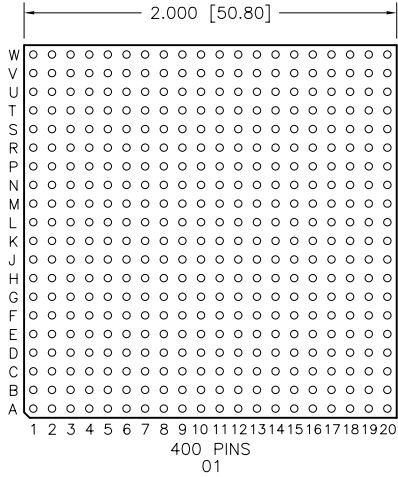
19 X 19





PGA SOCKET FOOTPRINTS

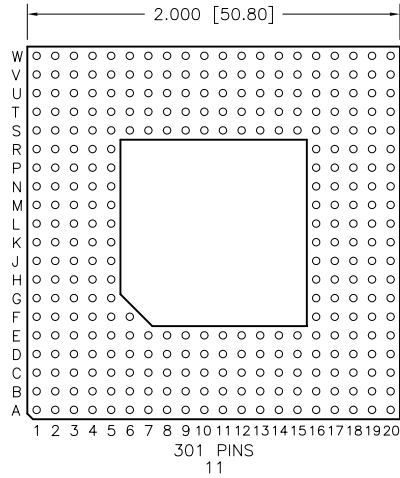
20 X 20



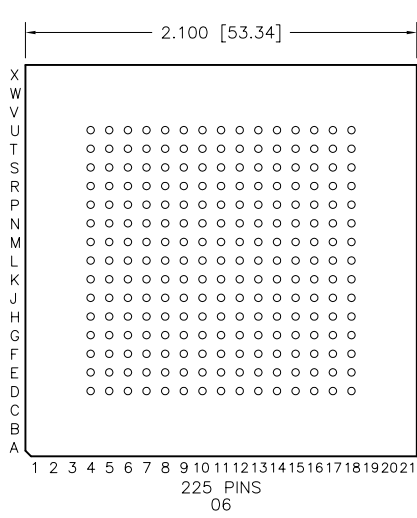
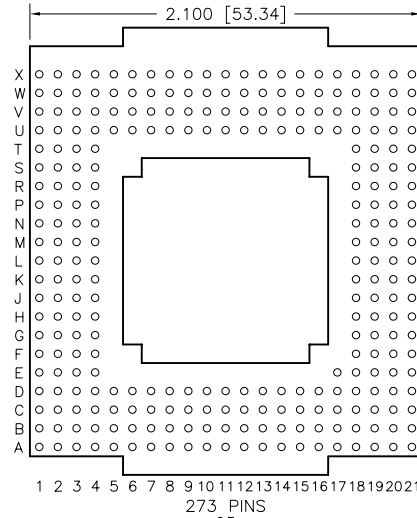
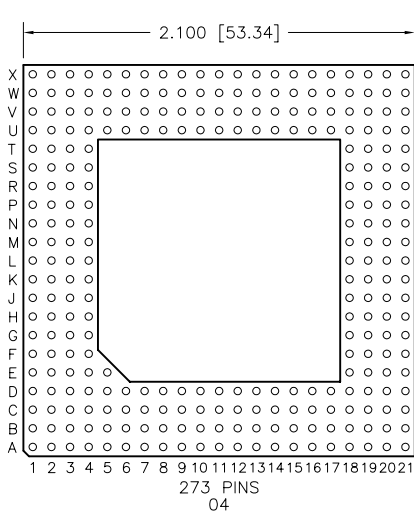
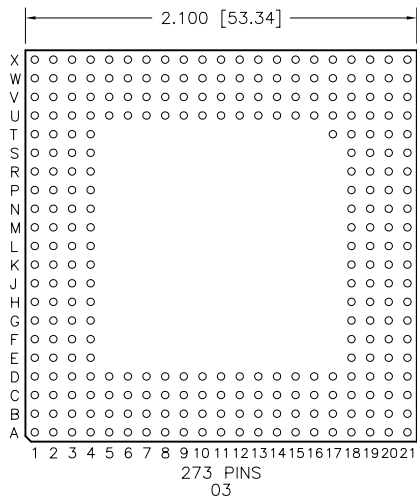
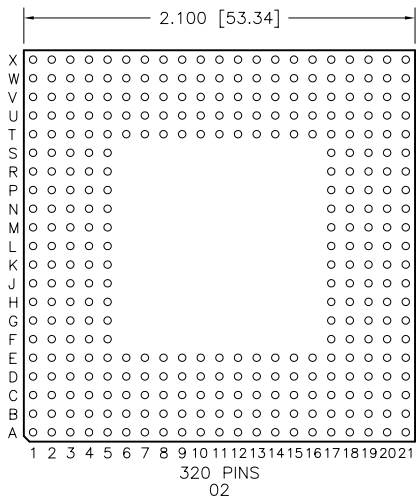
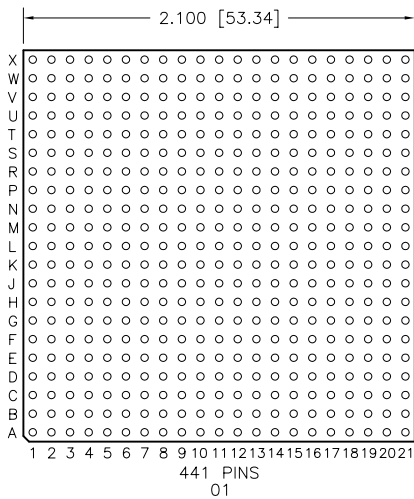


PGA SOCKET FOOTPRINTS

20 X 20



21 X 21



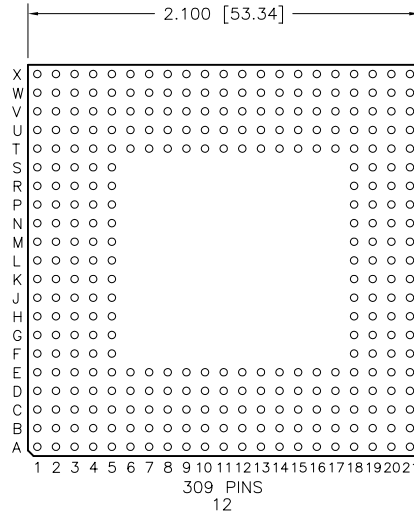
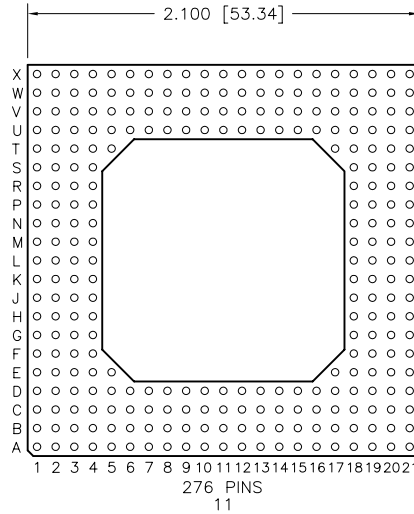
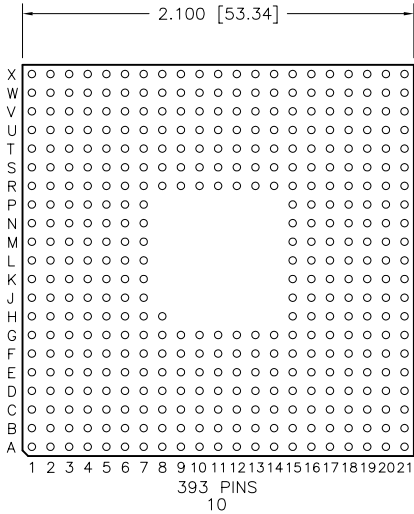
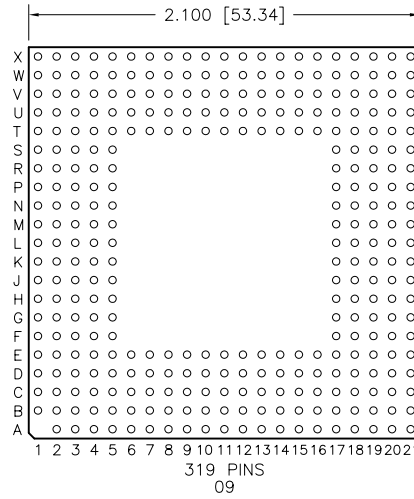
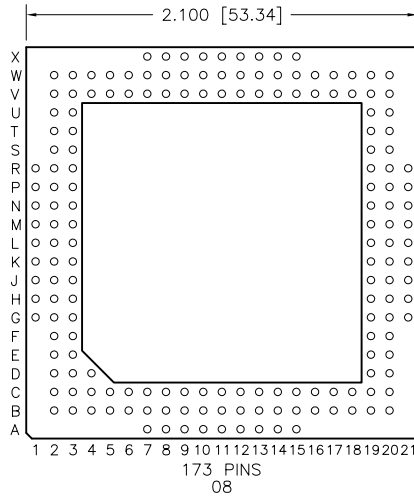
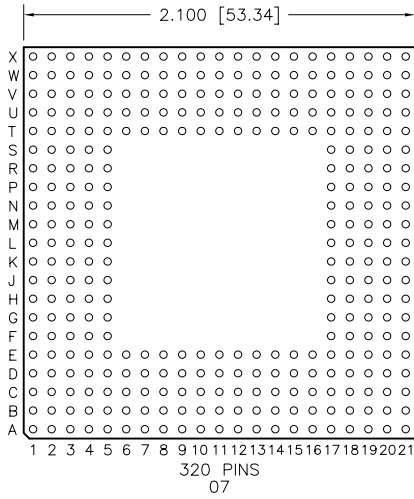
© ANDON 2007 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]

WE RESERVE THE RIGHT TO CHANGE SPECIFICATIONS WITHOUT NOTICE.

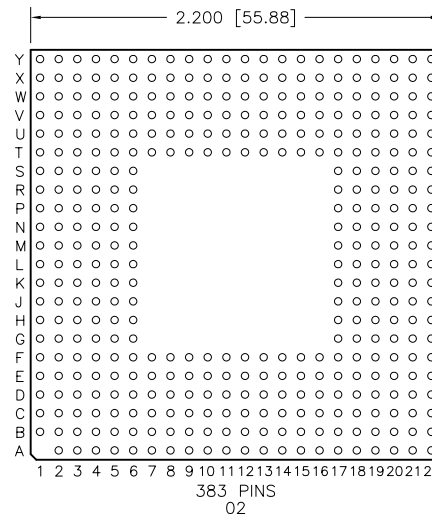
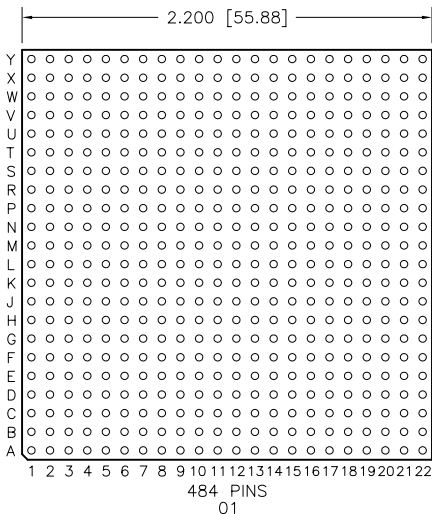


PGA SOCKET FOOTPRINTS

21 X 21



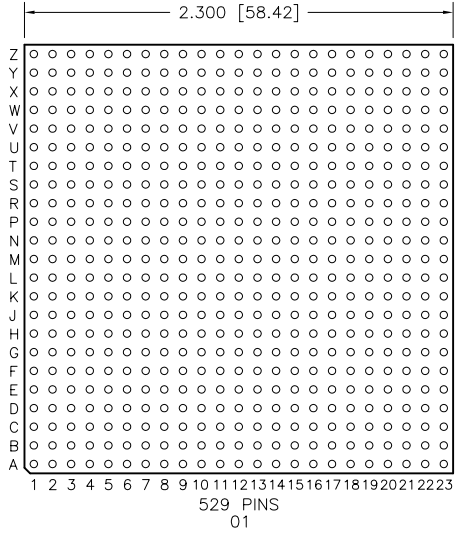
22 X 22



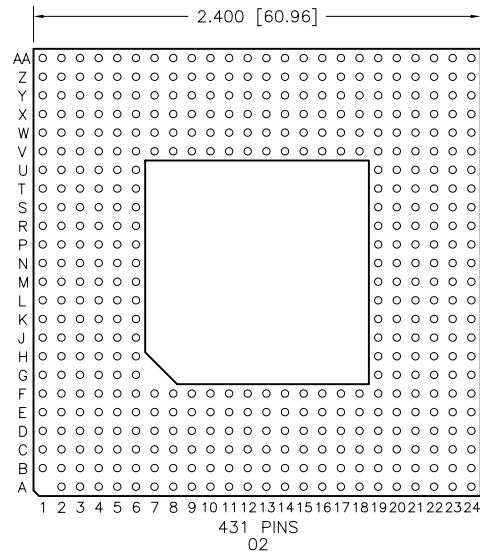
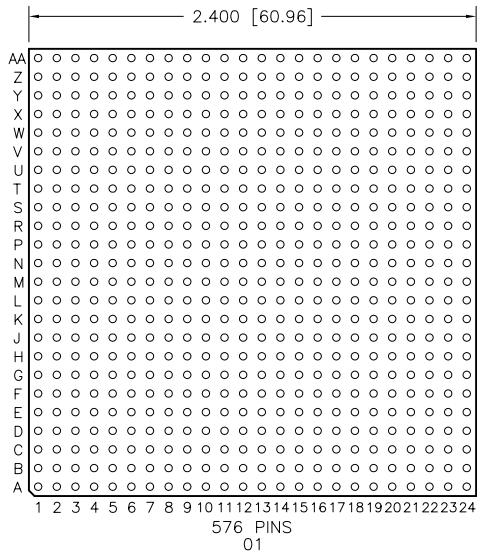


PGA SOCKET FOOTPRINTS

23 X 23



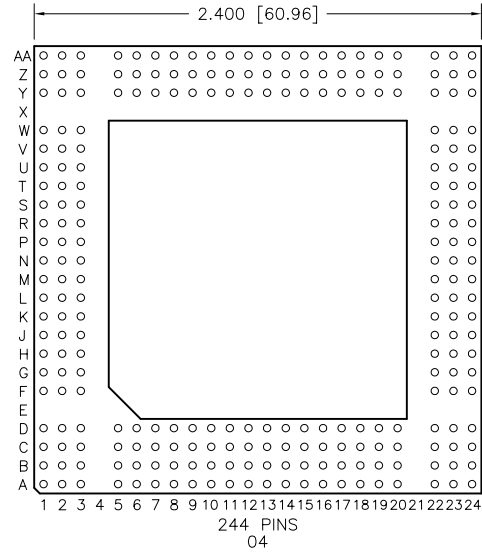
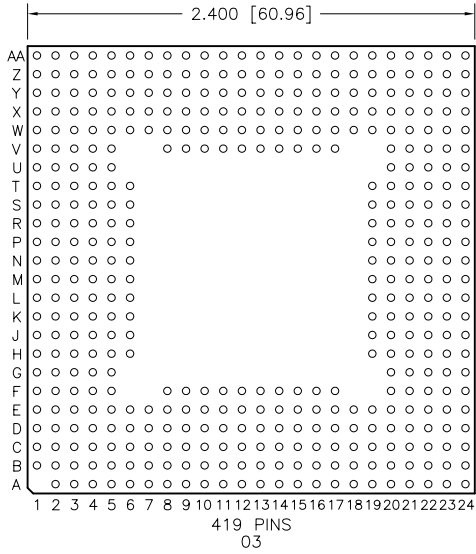
24 X 24



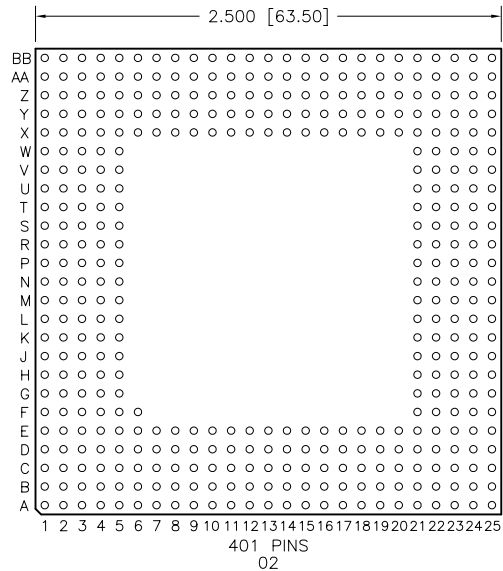
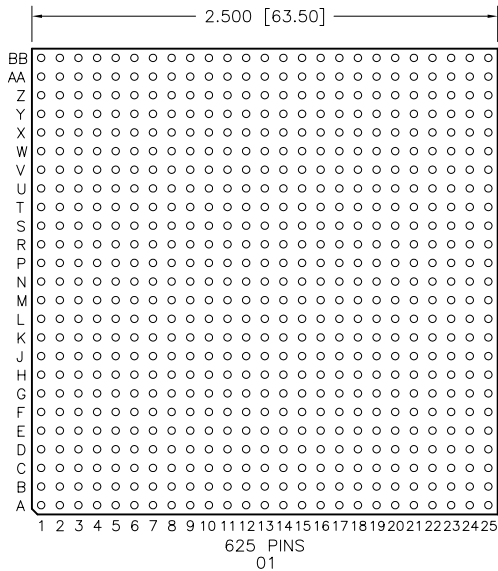


PGA SOCKET FOOTPRINTS

24 X 24



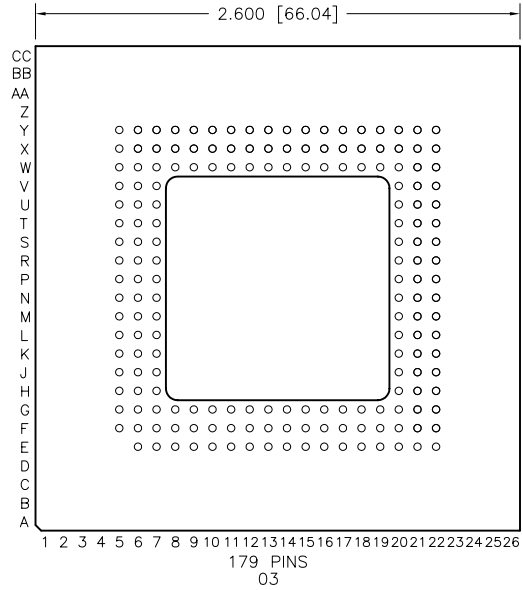
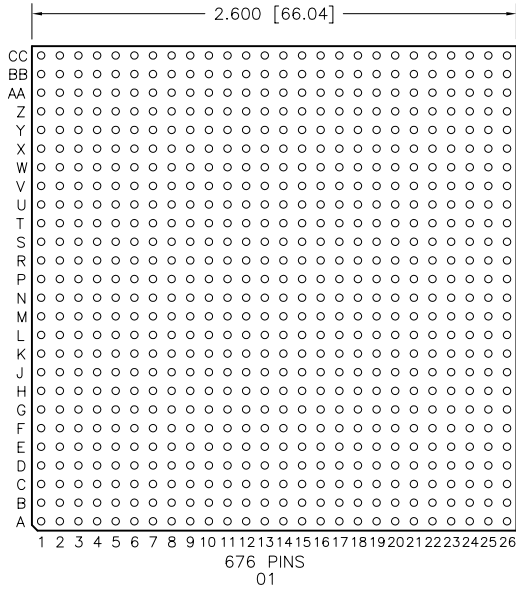
25 X 25





PGA SOCKET FOOTPRINTS

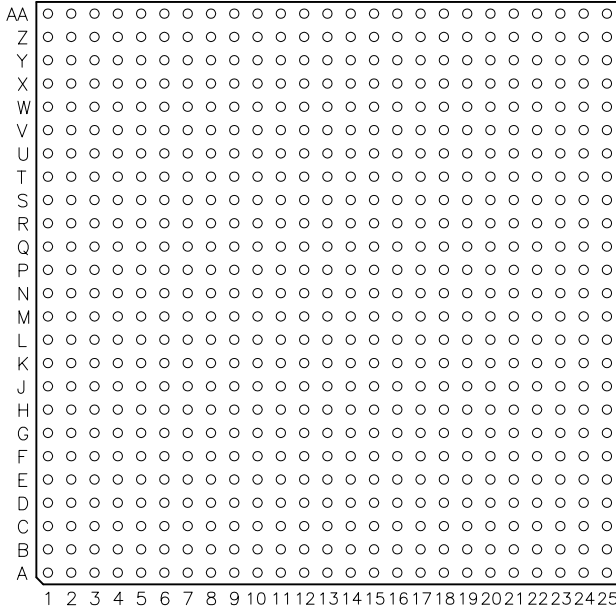
26 X 26



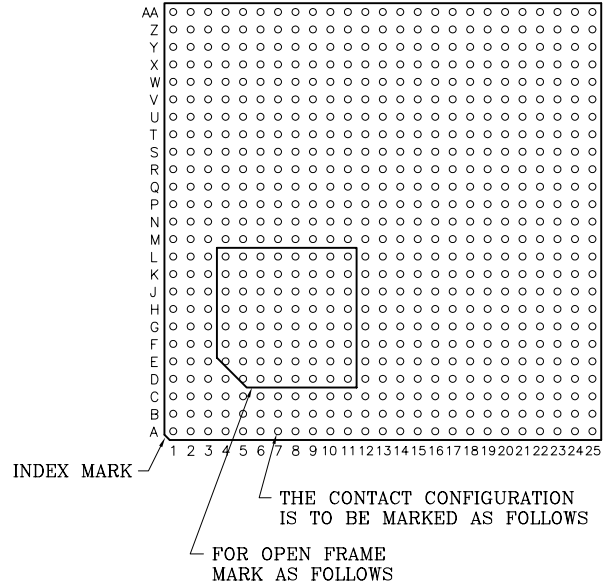


PGA SOCKET FOOTPRINTS

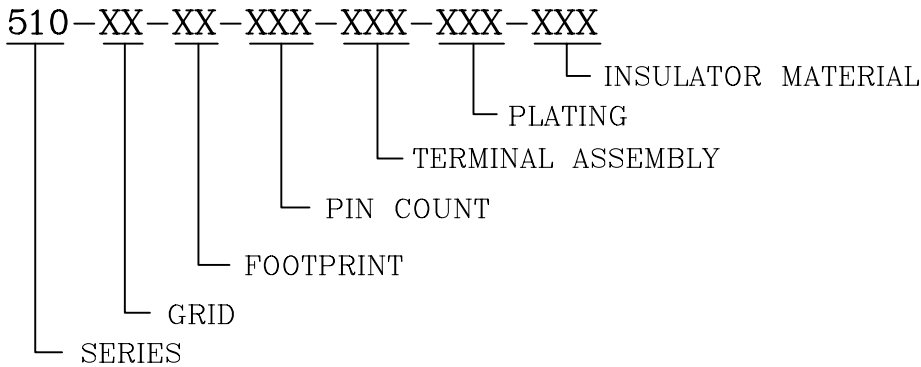
THE PIN GRID ARRAY FOOTPRINTS SHOWN IN THIS CATALOG REPRESENT OUR STANDARD CONFIGURATIONS. IF YOU REQUIRE A CUSTOM CONFIGURATION, PLEASE USE THE CUSTOM GRID PATTERN BELOW TO INDICATE YOUR SPECIFIC REQUIREMENTS BY MARKING THE CIRCLES AT THE DESIRED LOCATION OF EACH CONTACT (SEE EXAMPLE BELOW). ONCE COMPLETED, FILL OUT THE REST OF THE REQUIRED INFORMATION AND SEND A COPY. ANDON WILL RESPOND TO YOUR REQUEST AS SOON AS WE RECEIVE IT.



CUSTOM PGA TOP VIEW



PART NUMBER ORDERING INFORMATION



CUSTOM GRID PATTERN SIZE

NUMBER OF PINS: _____ PGA PIN DIAMETER: _____ PIN LENGTH: _____
 REQUIRED SOCKET QUANTITY: _____

YOUR NAME AND ADDRESS

COMPANY: _____
 NAME: _____ DIVISION: _____
 ADDRESS 1: _____ ADDRESS 2: _____
 CITY: _____ STATE: _____ ZIP: _____
 PHONE: _____ FAX: _____

© ANDON 2007 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS] WE RESERVE THE RIGHT TO CHANGE SPECIFICATIONS WITHOUT NOTICE.



INTERSTITIAL PGA SOCKETS (IPGA)

HI-REL EXCLUSIVE SOCKET CONTACT DESIGN
(1.0 Ounce [28 Gram] Insertion)
(0.5 Ounces [14 Gram] Withdrawal)

ONLY FROM ANDON

This unique 4-finger, stamped and formed contact design solves an industry microprocessor to socket tolerance problem. Contacts produced in-house, under strict quality control. A larger entrance diameter to provide tolerance correction and to reduce microprocessor insertion forces. Reduces damage to microprocessor pins and substrate. Any pin configuration or footprint can be provided. Prototypes in FR-4 insulators for fast delivery of ASICS. Production quantities in Hi-Temp insulators suitable for SMD.

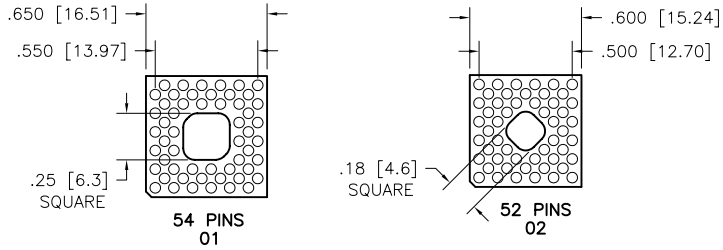
Series 585 Hi-Reliability IPGA Sockets (FR-4 insulator)
Series 586 Hi-Reliability IPGA Sockets (Hi-temp Molded)

Certified Test Reports Available.
Consult our factory for design and specification assistance.

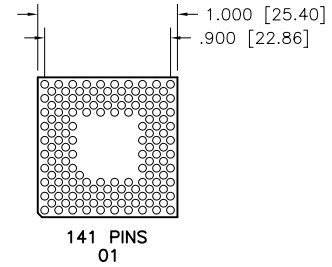


INTERSTITIAL PGA FOOTPRINTS
.050 IN. [1.27 MM] X .100 IN. [2.54 MM] GRID

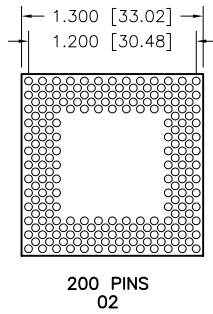
6 X 6



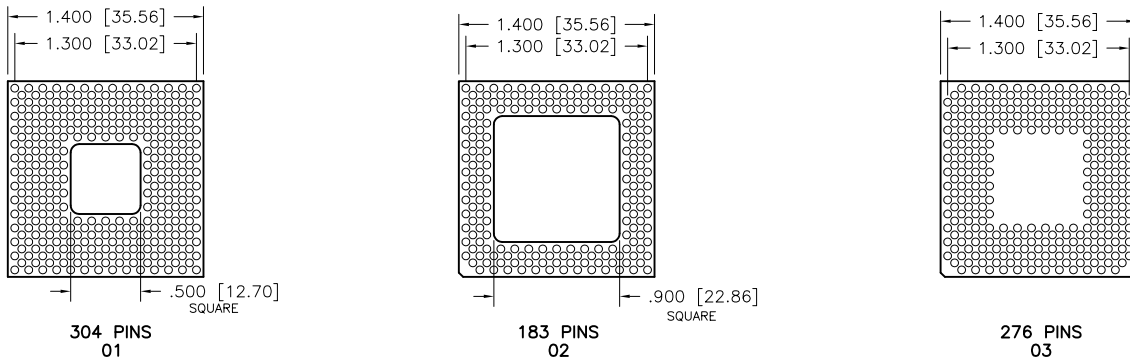
10 X 10



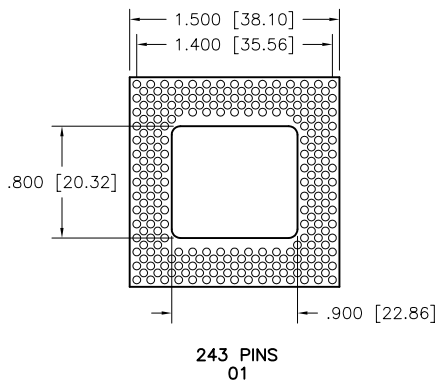
13 X 13



14 X 14



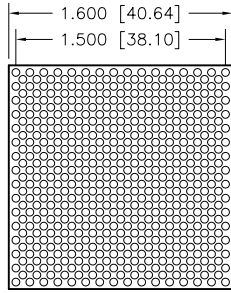
15 X 15





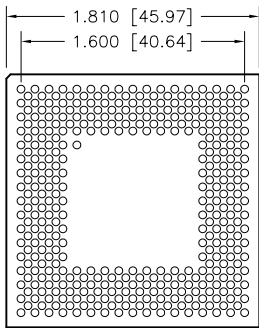
INTERSTITIAL PGA FOOTPRINTS
.050 IN. [1.27 MM] X .100 IN. [2.54 MM] GRID

16 X 16

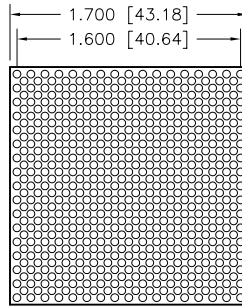


481 PINS
01

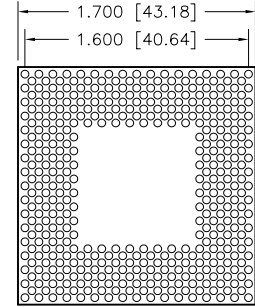
17 X 17



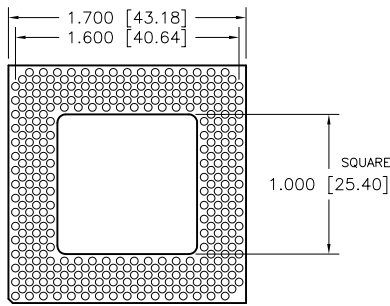
365 PINS
01



545 PINS
02

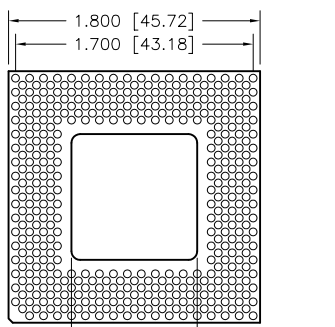


400 PINS
03

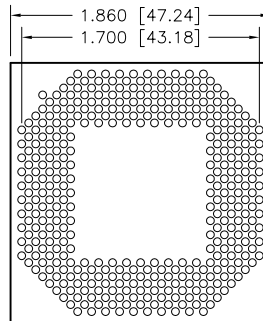


321 PINS
04

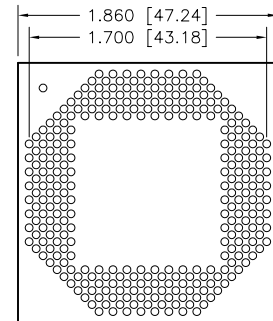
18 X 18



391 PINS
01



369 PINS
02

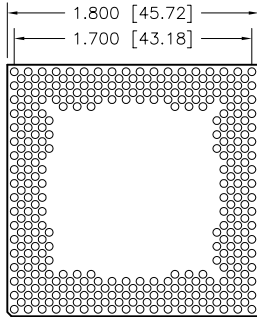


293 PINS
03

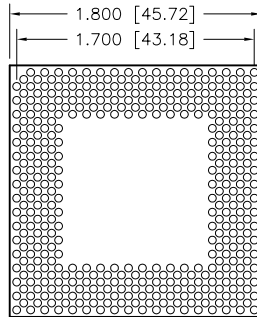


INTERSTITIAL PGA FOOTPRINTS
 .050 IN. [1.27 MM] X .100 IN. [2.54 MM] GRID

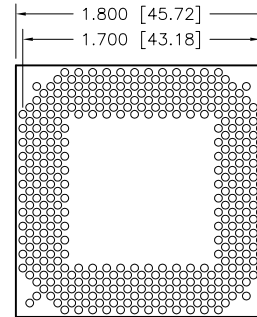
18 X 18



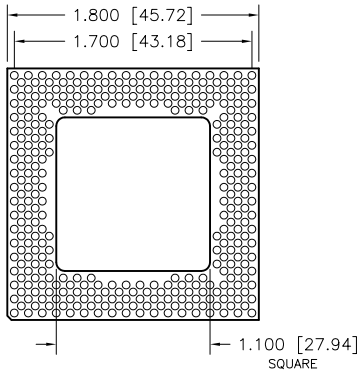
325 PINS
04



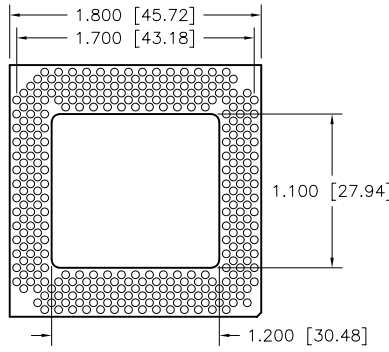
391 PINS
05



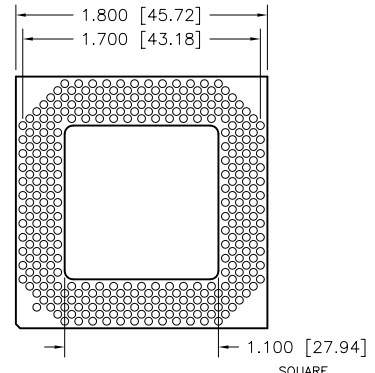
361 PINS
06



325 PINS
07

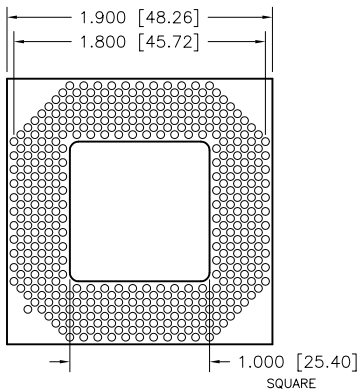


305 PINS
08

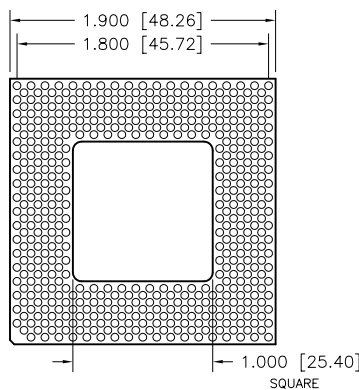


313 PINS
09

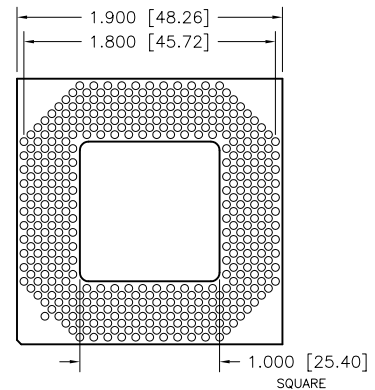
19 X 19



401 PINS
01



463 PINS
02

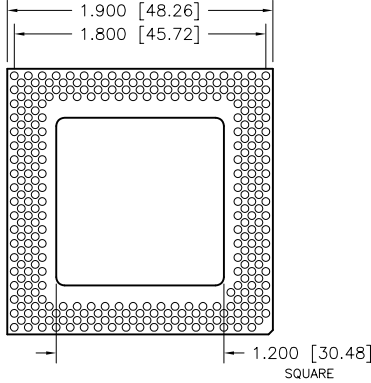


401 PINS
03

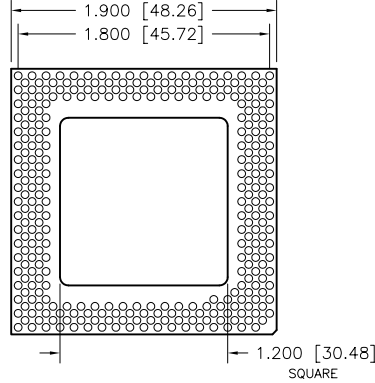


INTERSTITIAL PGA FOOTPRINTS
.050 IN. [1.27 MM] X .100 IN. [2.54 MM] GRID

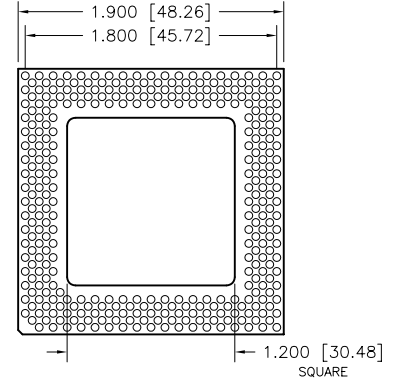
19 X 19



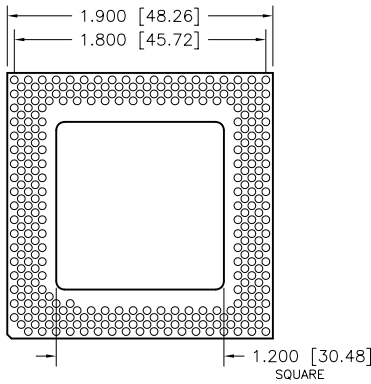
294 PINS
04



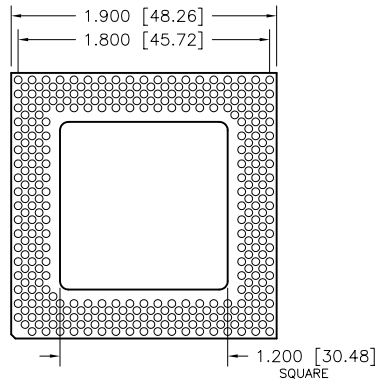
296 PINS
05



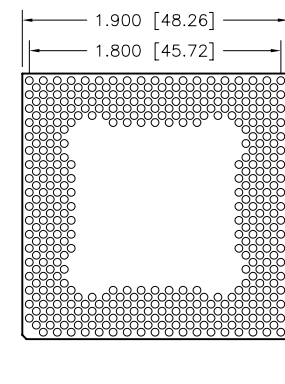
320 PINS
06



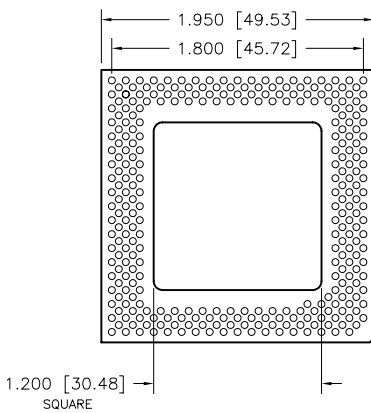
296 PINS
07



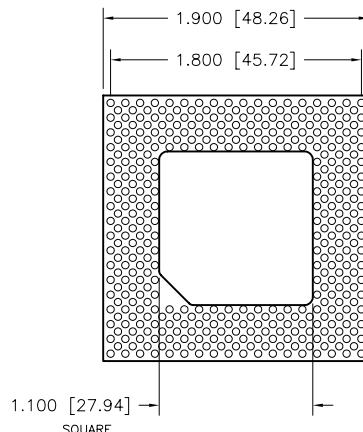
321 PINS
08



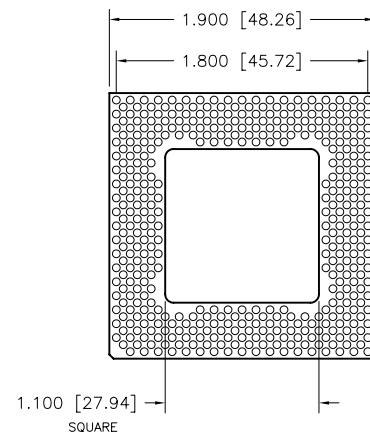
403 PINS
09



296 PINS
10



504 PINS
11

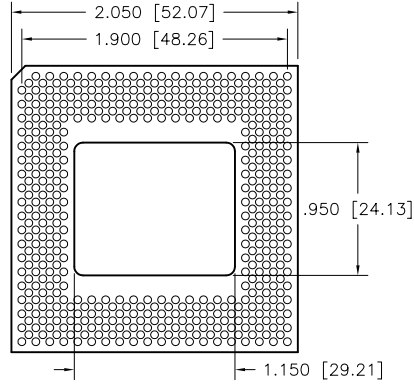


403 PINS
12

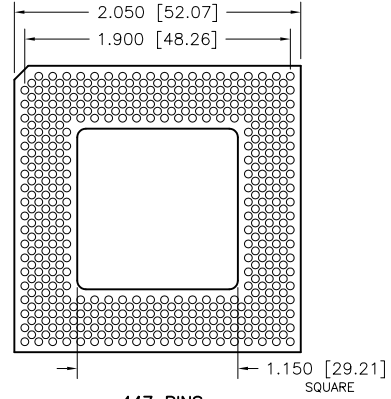


INTERSTITIAL PGA FOOTPRINTS
 .050 IN. [1.27 MM] X .100 IN. [2.54 MM] GRID

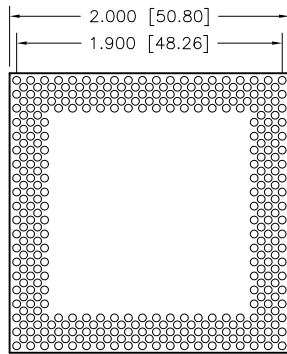
20 X 20



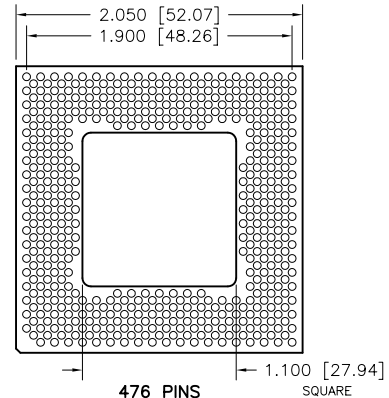
447 PINS
01



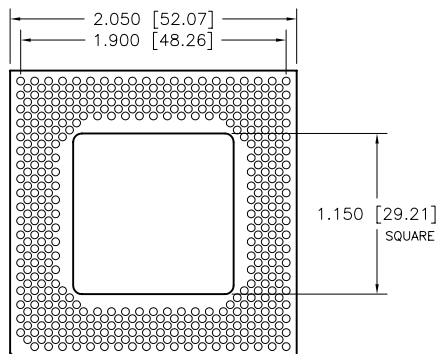
447 PINS
02



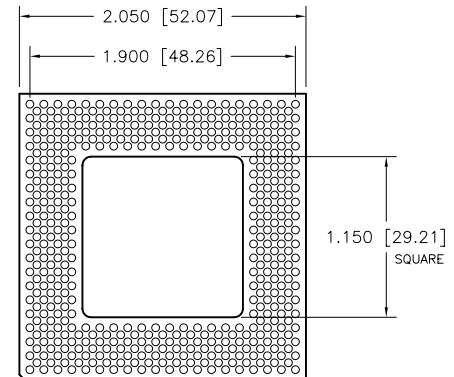
340 PINS
03



476 PINS
04



411 PINS
05

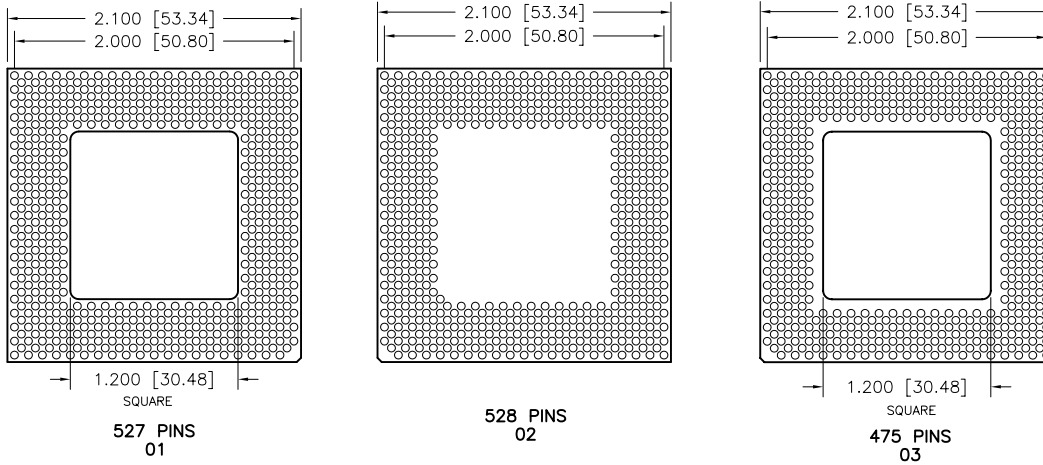


448 PINS
06

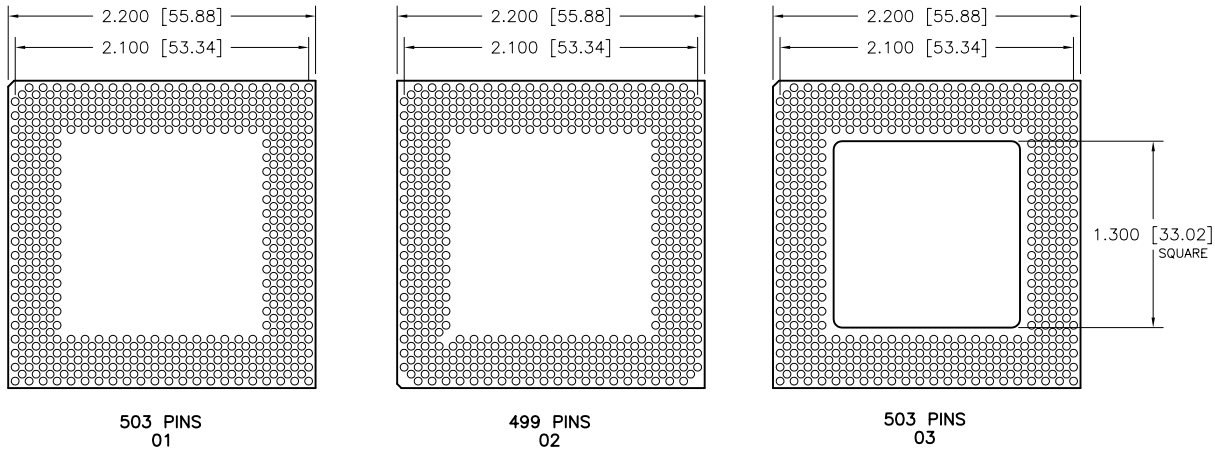


INTERSTITIAL PGA FOOTPRINTS
 .050 IN. [1.27 MM] X .100 IN. [2.54 MM] GRID

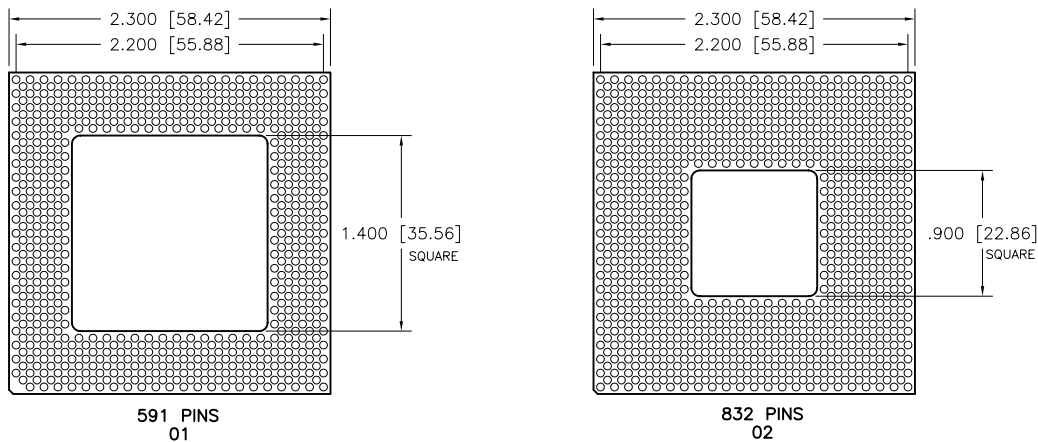
21 X 21



22 X 22



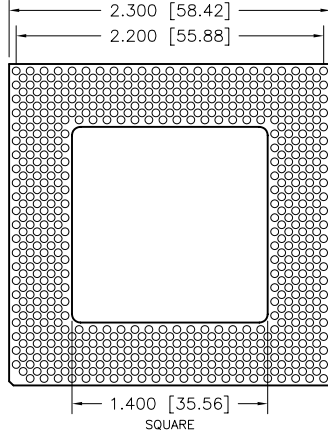
23 X 23



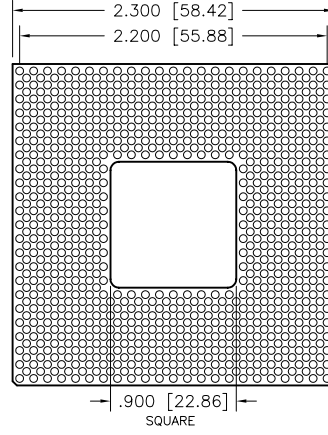


INTERSTITIAL PGA FOOTPRINTS
.050 IN. [1.27 MM] X .100 IN. [2.54 MM] GRID

23 X 23



591 PINS
01

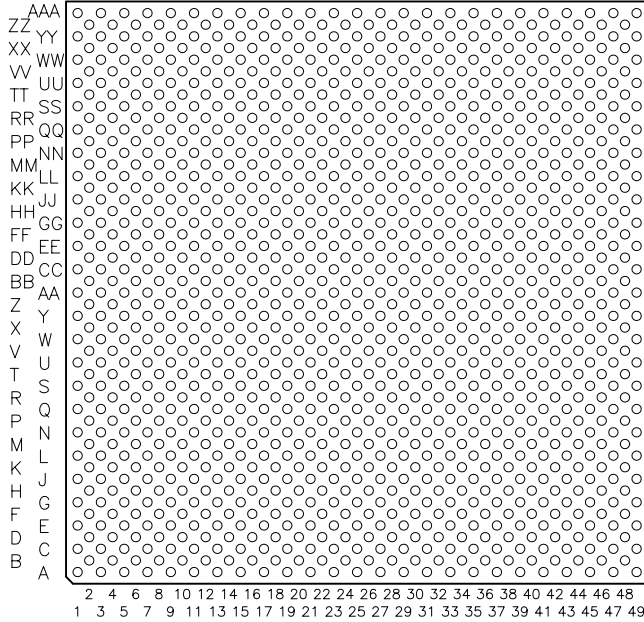


832 PINS
02

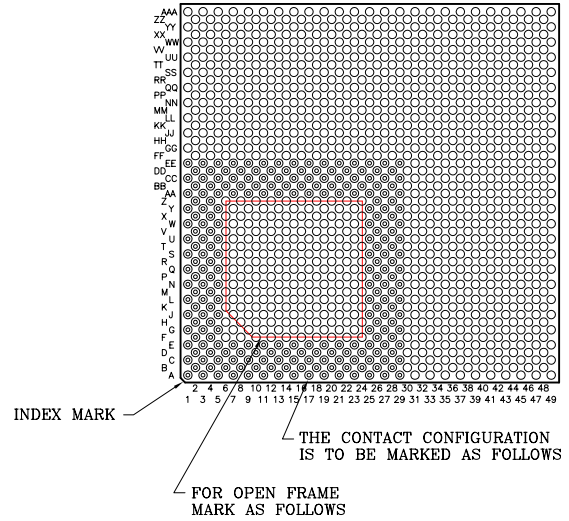


IPGA SOCKET FOOTPRINTS

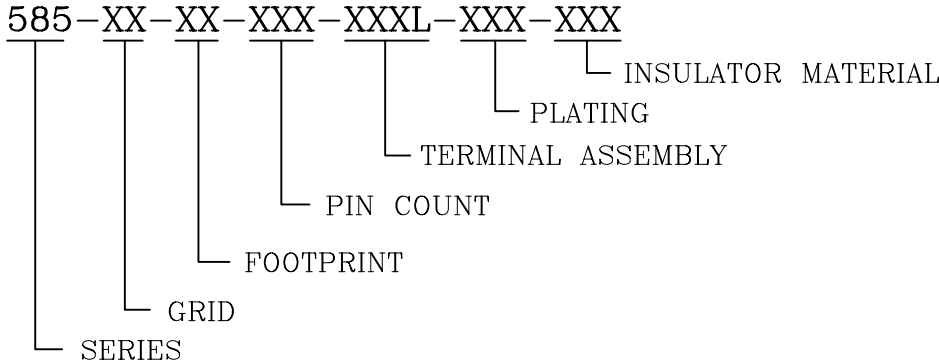
THE PIN GRID ARRAY FOOTPRINTS SHOWN IN THIS CATALOG REPRESENT OUR STANDARD CONFIGURATIONS. IF YOU REQUIRE A CUSTOM CONFIGURATION, PLEASE USE THE CUSTOM GRID PATTERN BELOW TO INDICATE YOUR SPECIFIC REQUIREMENTS BY MARKING THE CIRCLES AT THE DESIRED LOCATION OF EACH CONTACT (SEE EXAMPLE BELOW). ONCE COMPLETED, FILL OUT THE REST OF THE REQUIRED INFORMATION AND SEND A COPY. ANDON WILL RESPOND TO YOUR REQUEST AS SOON AS WE RECEIVE IT.



CUSTOM IPGA TOP VIEW



PART NUMBER ORDERING INFORMATION



CUSTOM GRID PATTERN SIZE

NUMBER OF PINS: _____ PGA PIN DIAMETER: _____ PIN LENGTH: _____

REQUIRED SOCKET QUANTITY: _____

YOUR NAME AND ADDRESS

COMPANY: _____

NAME: _____ DIVISION: _____

ADDRESS 1: _____ ADDRESS 2: _____

CITY: _____ STATE: _____ ZIP: _____

PHONE: _____ FAX: _____



BGA BALL GRID ARRAY SOCKETS AND ADAPTERS

Andon's new BGA Socket and Adapter System can efficiently replace semiconductors without any risk of damaging the expensive PCB which has many other expensive components already assembled.

There is a solution to the inherent BGA assembly problems.

A BGA can be soldered onto an adapter with pins for plugging into a socket. The socket is mounted onto a PCB with thru-hole pins or surface-mount pins soldered in the conventional manner.

The adapter is approximately the same size as the BGA. Soldering the BGA to a smaller surface area of the adapter as compared to soldering to a large area of a PCB is more efficient and cost effective. Any re-work can be better facilitated as the de-soldering of a smaller surface area will reduce any risk of damage to an expensive BGA, or multi-layer PGA.

The BGA adapter socket has a reduced height and minimum length pins to improve electrical characteristics of the interconnection as compared to the larger PGA's.

The manufacturing process control in the assembly of like size BGA's and adapters will reduce rework costs and risk of damage to expensive PCB's and BGA's. Also, assuring better definable production output with less down time.

Andon has developed the capability to provide users of BGA's with adapters and sockets in any footprint and terminal/socket configuration.

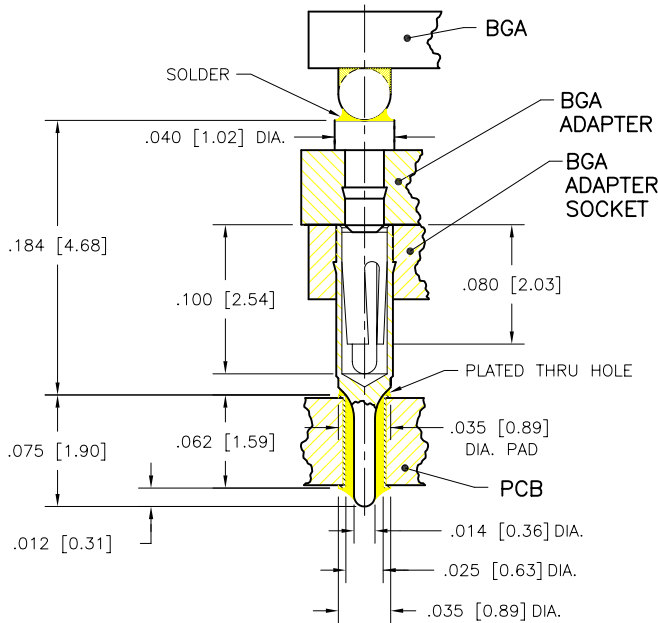
Socket contacts are produced in-house under strict Quality Control to provide specific contact forces.



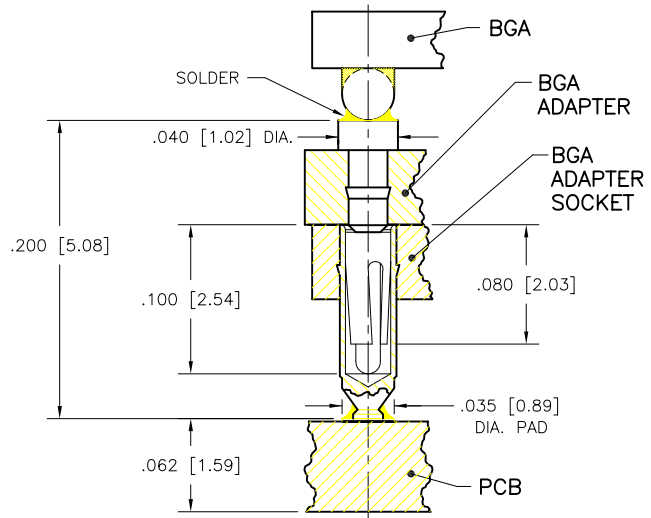
SERIES 10

BGA SOCKETS/ADAPTERS BALL GRID ARRAY SOCKETING SYSTEM

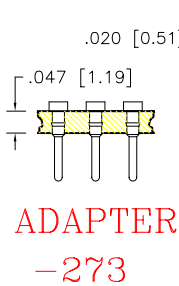
BALL GRID ARRAY SOCKETING ASSEMBLY



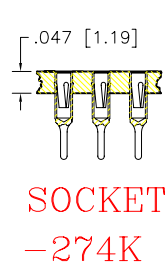
THRU HOLE



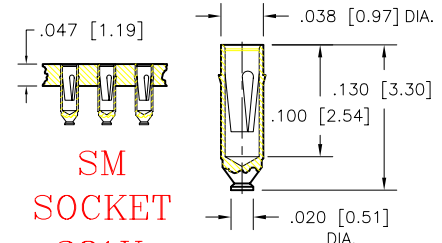
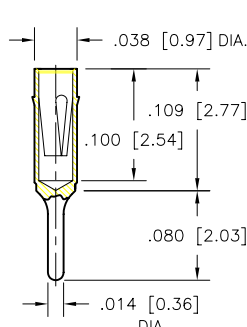
SURFACE MOUNT



**ADAPTER
-273**



**SOCKET
-274K**



**SM
SOCKET
-281K**

TECHNICAL SPECIFICATIONS

MATERIAL:	FR-4 LAMINATE U.L. RATED 94V-0
INSULATOR:	FR-4 LAMINATE U.L. RATED 94V-0
TERMINAL:	BRASS PLATED TIN-LEAD
CONTACT:	BeCu PLATED GOLD
ADAPTER:	BRASS PLATED TIN-LEAD OR GOLD

ORDERING INFORMATION

10-XX-XX-XXX-XXX-XXX-N10

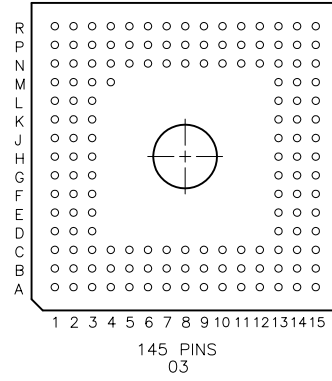
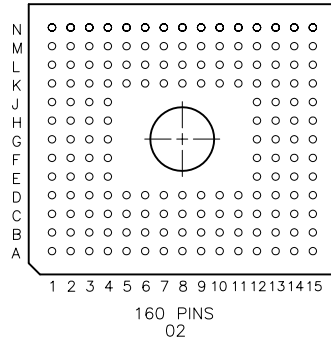
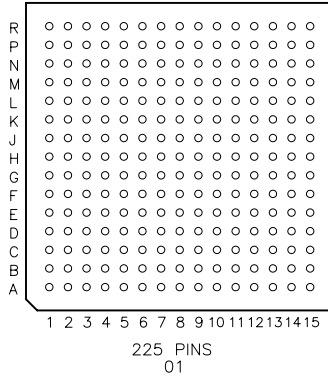
SERIES	GRID	FOOTPRINT	NO. OF PINS	PLATING:
				P31 SOCKET
				TL ADAPTER
				G04 GOLD ADAPTER
				OTHER PLATINGS AVAILABLE
				273 ADAPTER
				274K SOCKET
				281K SOCKET



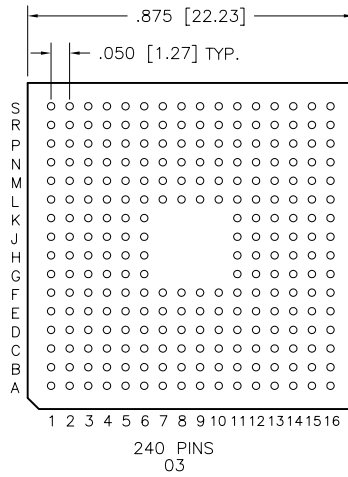
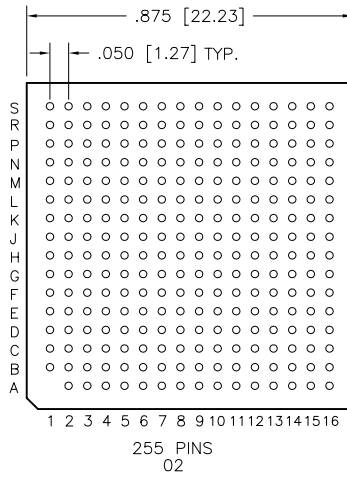
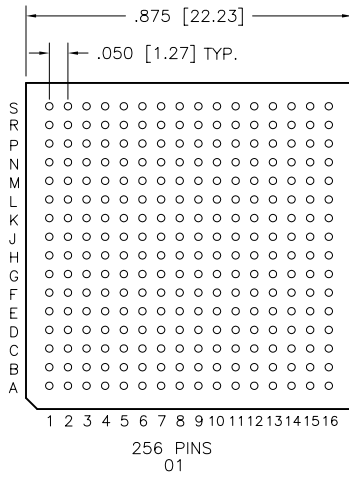
BGA ADAPTOR & SOCKET FOOTPRINTS

.050 [1.27] PITCH BGA SOCKET AND ADAPTOR FOOTPRINTS

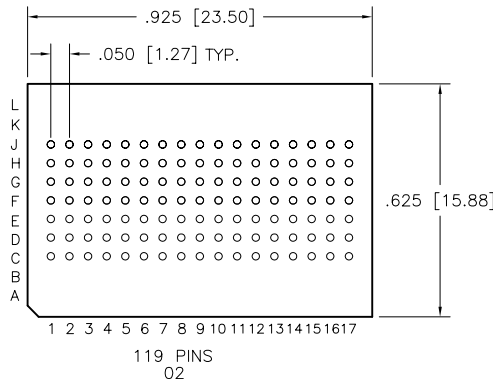
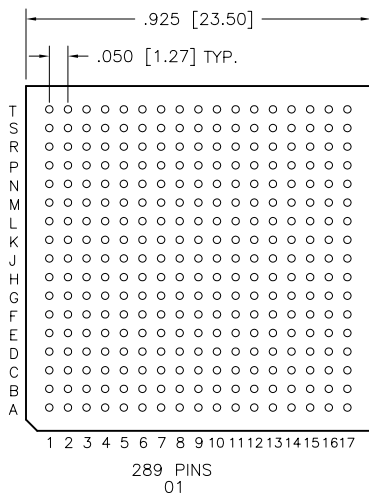
15 X 15



16 X 16



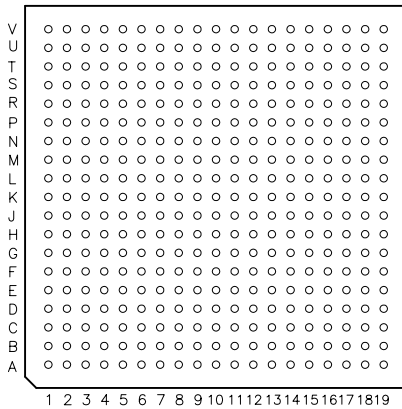
17 X 17



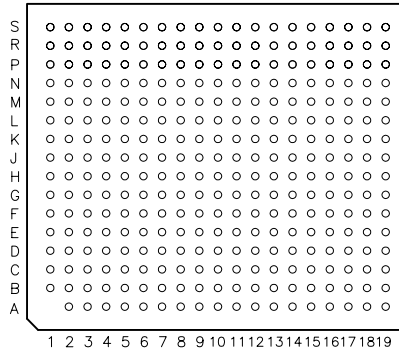


BGA ADAPTOR & SOCKET FOOTPRINTS
 .050 [1.27] PITCH BGA SOCKET AND ADAPTOR FOOTPRINTS

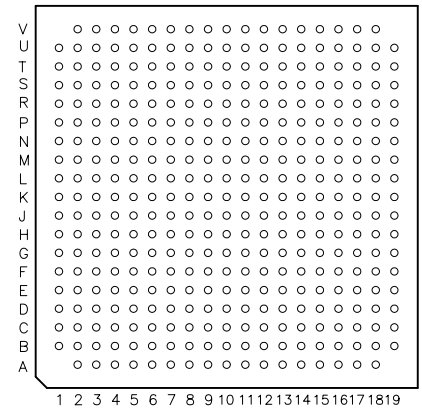
19 X 19



361 PINS
01

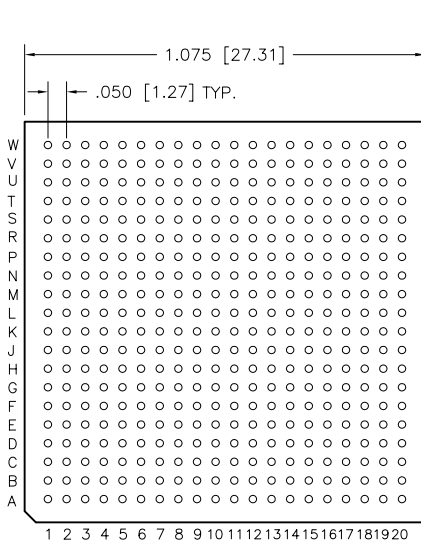


303 PINS
02

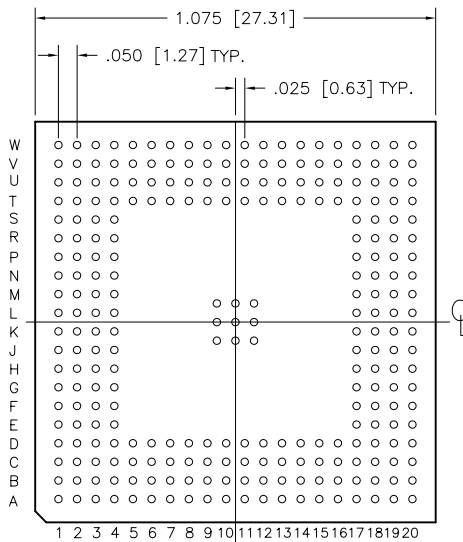


357 PINS
03

20 X 20



400 PINS
01

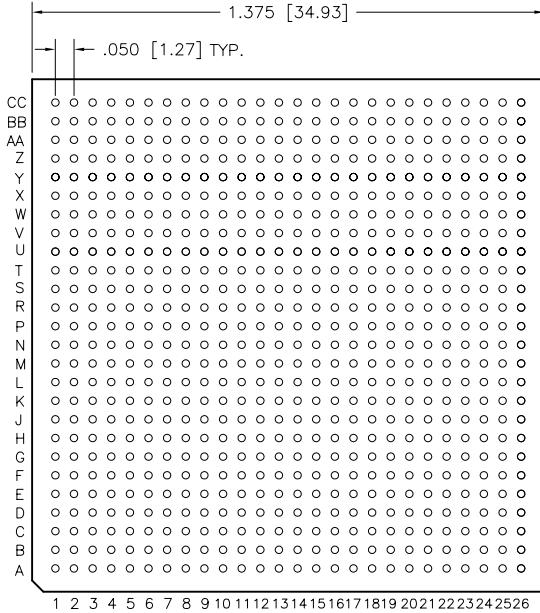


265 PINS
02

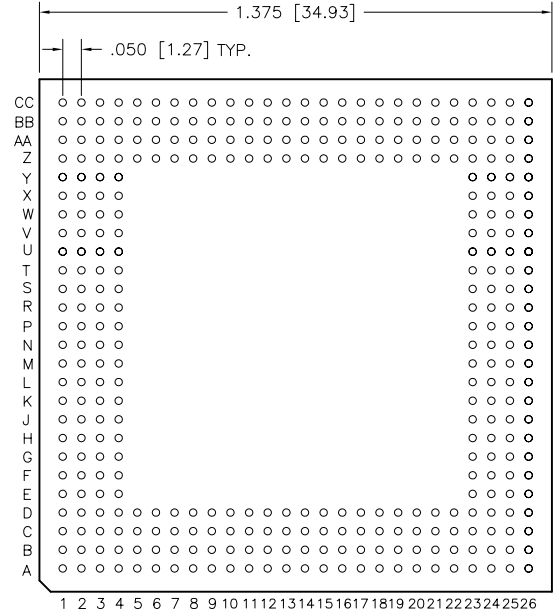


BGA ADAPTOR & SOCKET FOOTPRINTS
.050 [1.27] PITCH BGA SOCKET AND ADAPTOR FOOTPRINTS

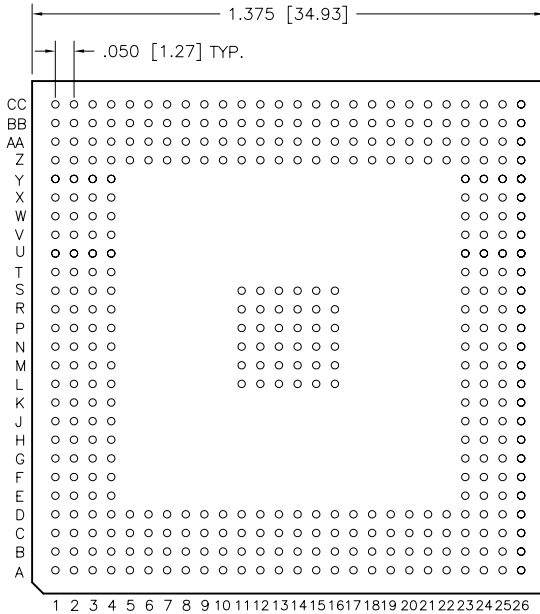
26 X 26



676 PINS
01



352 PINS
02

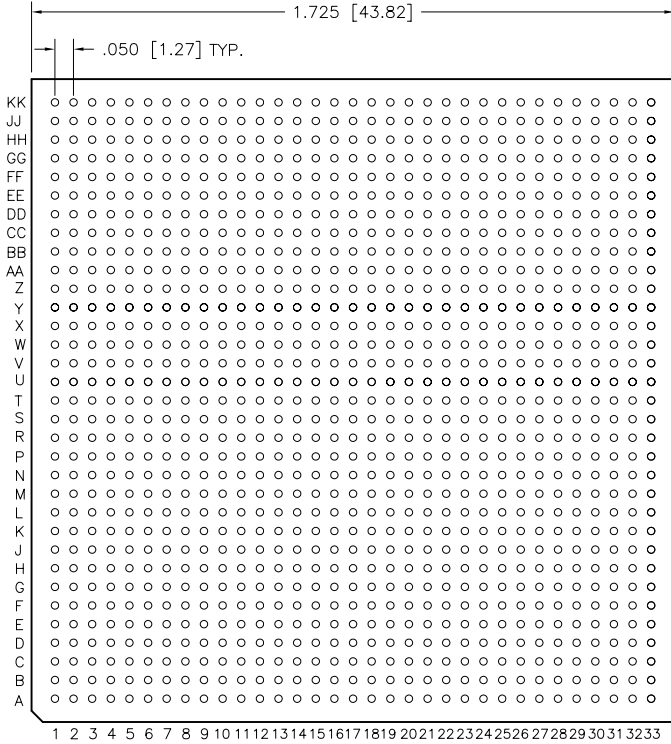


388 PINS
03

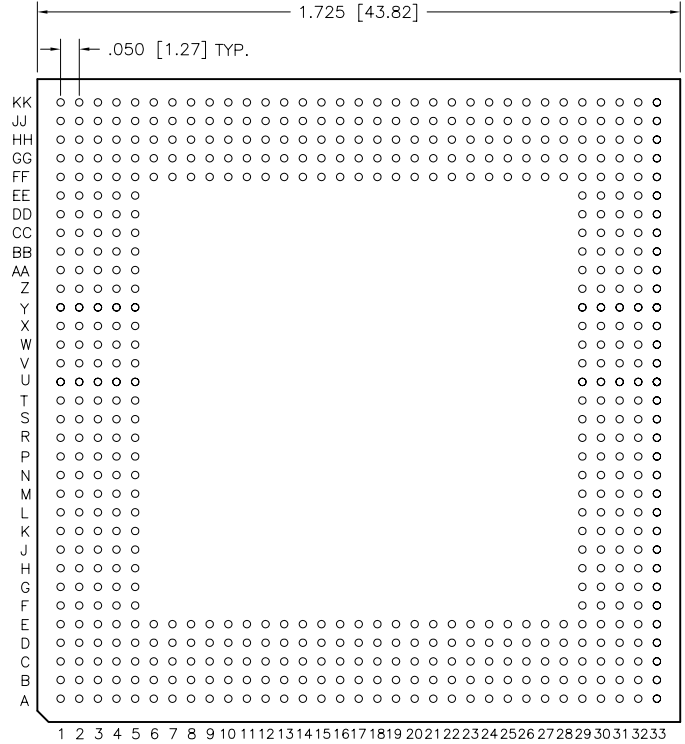


BGA ADAPTOR & SOCKET FOOTPRINTS
 .050 [1.27] PITCH BGA SOCKET AND ADAPTOR FOOTPRINTS

33 x 33



1089 PINS
01

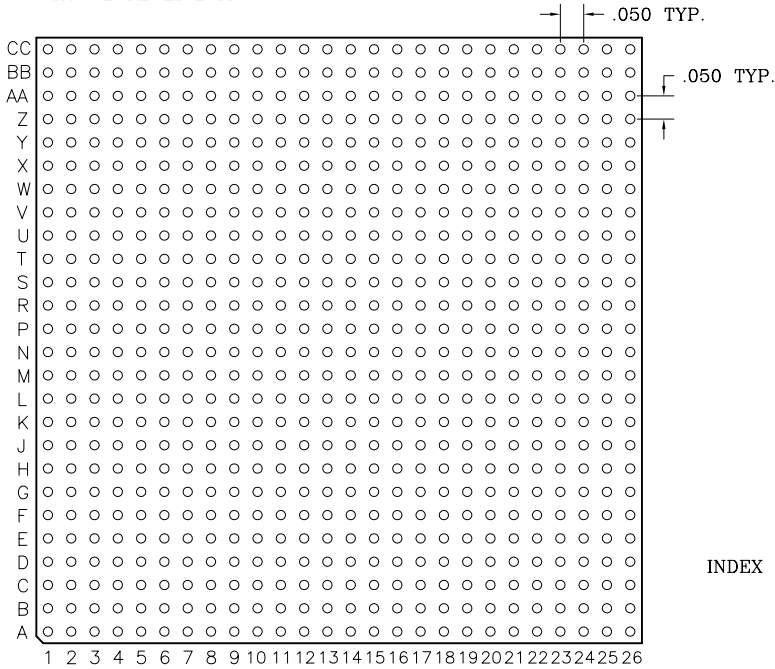


560 PINS
02

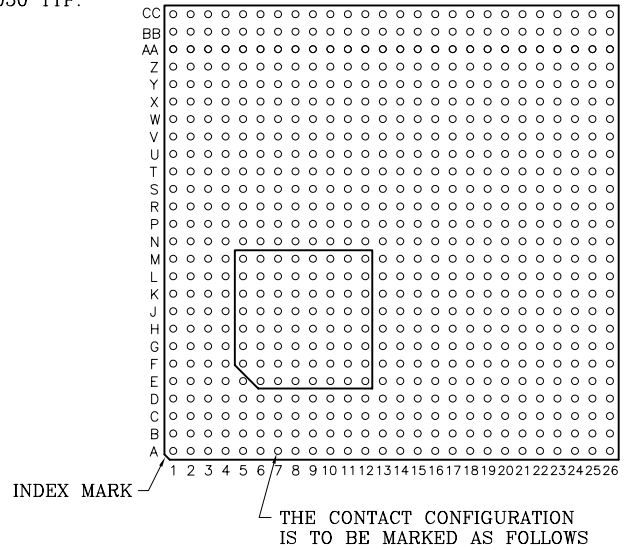


BGA – MPGA SOCKET/ADAPTOR FOOTPRINTS

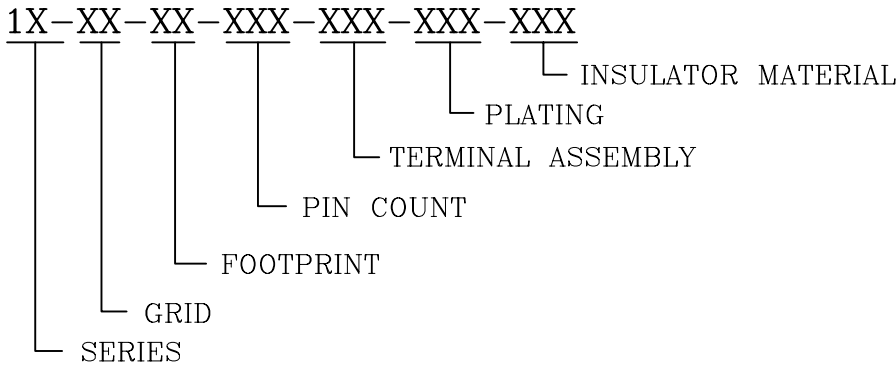
THE PIN GRID ARRAY FOOTPRINTS SHOWN IN THIS CATALOG REPRESENT OUR STANDARD CONFIGURATIONS. IF YOU REQUIRE A CUSTOM CONFIGURATION, PLEASE USE THE CUSTOM GRID PATTERN BELOW TO INDICATE YOUR SPECIFIC REQUIREMENTS BY MARKING THE CIRCLES AT THE DESIRED LOCATION OF EACH CONTACT (SEE EXAMPLE BELOW). ONCE COMPLETED, FILL OUT THE REST OF THE REQUIRED INFORMATION AND SEND A COPY. ANDON WILL RESPOND TO YOUR REQUEST AS SOON AS WE RECEIVE IT.



CUSTOM BGA TOP VIEW



PART NUMBER ORDERING INFORMATION



CUSTOM GRID PATTERN SIZE

NUMBER OF PINS: _____ BGA PIN DIAMETER: _____ PIN LENGTH: _____
 REQUIRED SOCKET/ADAPTOR QUANTITY: _____

YOUR NAME AND ADDRESS

COMPANY: _____
 NAME: _____ DIVISION: _____
 ADDRESS 1: _____ ADDRESS 2: _____
 CITY: _____ STATE: _____ ZIP: _____
 PHONE: _____ FAX: _____

© ANDON 2007 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS] WE RESERVE THE RIGHT TO CHANGE SPECIFICATIONS WITHOUT NOTICE.



LCC SOCKETS
FOR SMD
JEDEC TYPE C DEVICES

(Typical Cellular Telephone Application)

PATENTED

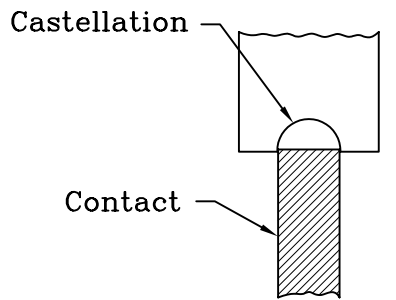
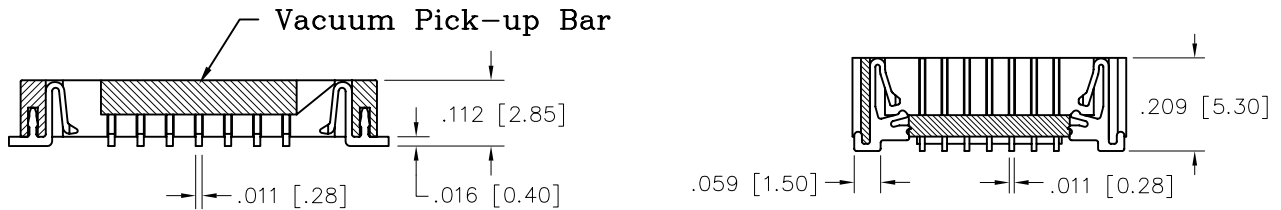
Andon has developed a leadless ceramic chip socket contact providing excellent electrical conductivity and excellent mechanical security. The height of the socket is the same as the mounted height of the chip, 2.85 mm. Great space savings!

The unique tapered end of the contact fits securely into the ceramic chip castellations to compensate for a wide variety of castellation tolerances. For additional mechanical security there is a 2-way clip and a 4-way clip to suit the most demanding shock and vibration environments.

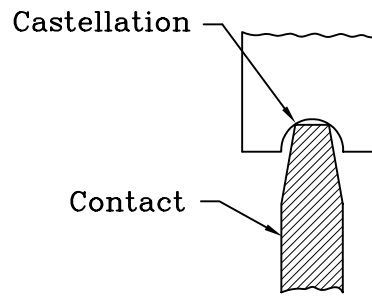
The 620 series socket is designed for automatic pick and place equipment from specially designed trays supplied by Andon. This socket has a molded-in "Vacuum Pick-up Bar" to facilitate assembly. After assembly, the "Vacuum Pick-up Bar" is removed by a slight twist-off.

For hand assembly, the 621 series has the "Vacuum Pick-up Bar" already removed.

This socket is a highly reliable, side action, low profile socket with easily accessible contacts for testing circuits and solder joint inspection. High temperature molded insulation withstands SMD soldering temperature without distortion.



Competition



Andon



SERIES 610 LCC SOCKET, 5.4 mm
FOR JEDEC TYPE C DEVICE
SMD
HI-REL SURFACE MOUNT 32 PIN
LEADLESS CHIP CARRIER SOCKETS

PATENTED

TECHNICAL SPECIFICATIONS

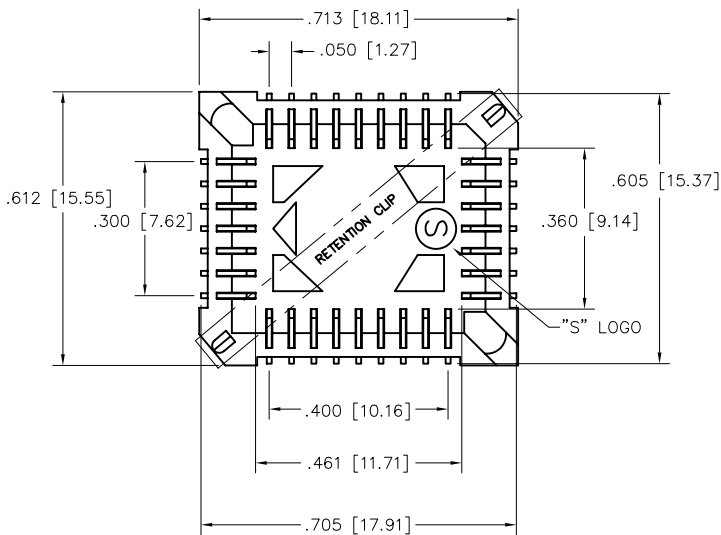
ELECTRICAL DATA

CONTACT RESISTANCE 30 MILLIOHMS
CURRENT RATING 1.0 AMP
INSULATION RESISTANCE . . . 1000 MEGAOHMS
DIELECTRIC VOLTAGE 500 VAC

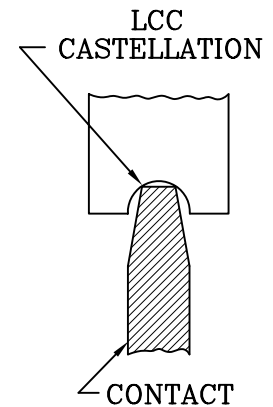
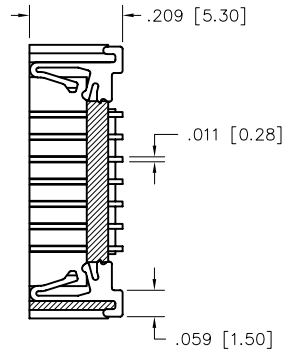
MATERIAL DATA

INSULATOR PPS; UL 94 V-0
CONTACT BERYLLIUM COPPER
FINISH -G10 GOLD OVER NICKEL

TOP VIEW

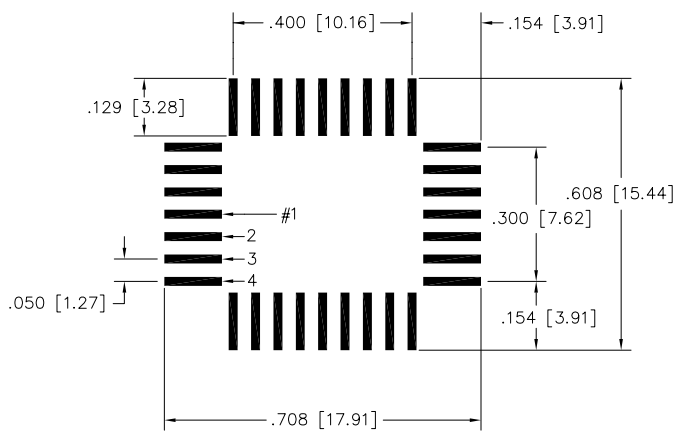


SIDE VIEW



PATENT No. 5,588,847

PC BOARD FOOTPRINT

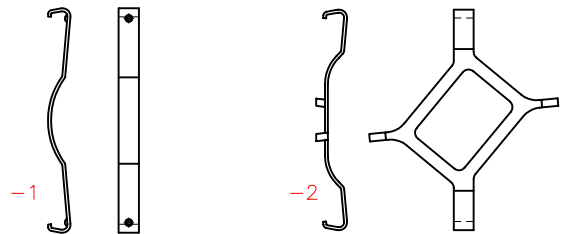


ORDERING INFORMATION

610-32-SM-G10-R12-X

SERIES 610-32-SM-G10-R12-X
NO. OF CONTACTS 32
TYPE SURFACE MOUNT
WHEN ORDERING WITH OPTIONAL RETENTION CLIP MATERIAL AND LOGO
CONTACT PLATING GOLD OVER NICKEL

OPTIONAL RETENTION CLIP



P/N: CLL-32
WHEN ORDERING SEPERATELY

P/N: CLL-32-4
WHEN ORDERING SEPERATELY



SERIES 620 LCC SOCKET, 2.85mm
AUTOMATIC ASSEMBLY

621 LCC SOCKET, 2.85mm
MANUAL ASSEMBLY

FOR JEDEC TYPE C DEVICE

PATENTED

SMD

HI-REL SURFACE MOUNT 32 PIN
ULTRA LOW PROFILE LEADLESS CHIP CARRIER SOCKET

PATENT No.
5,588,847

FEATURES

- .112 in [2.85 mm] HEIGHT ABOVE BOARD
SAME HEIGHT AS UNSOCKETED DEVICE
- ACCEPTS JEDEC TYPE C DEVICES
.050 in [1.27 mm] PITCH, MOUNTS ON EXISTING
FOOT-PRINT
- DESIGNED FOR HIGH DENSITY APPLICATIONS WHERE
SPACE ON & ABOVE PCB IS CRITICAL
- 220°C INSULATOR MATERIAL WITHSTANDS HIGH
TEMPERATURE SOLDER PROCESS
- UNIQUE BeCu CONTACT DESIGN ALLOWS SECURE
RETENTION OF DEVICE
- OPTIONAL RETENTION CLIP AVAILABLE FOR HIGH
SHOCK APPLICATIONS
- SPECIFICALLY DESIGNED FOR MOBILE/CELLULAR PHONE
AND DISK DRIVE APPLICATIONS

NOTE: VACUUM PICKUP BAR IS DESIGNED TO BE
TWISTED OFF BY HAND AFTER SOLDERING

TECHNICAL SPECIFICATIONS

ELECTRICAL DATA

CONTACT RESISTANCE: 30 MILLIOHMS MAX.
CURRENT RATING: 1.0 AMP
INSULATION RESISTANCE: 1000 MEGAOHMS MIN.
DIELECTRIC VOLTAGE: 500 VAC

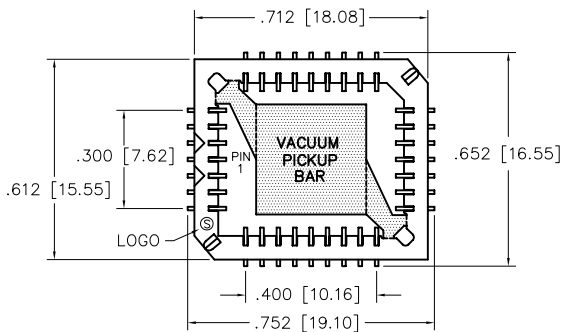
MATERIAL DATA

INSULATOR: HIGH TEMP NYLON 46, UL94V-0
CONTACT: BERYLLIUM COPPER
PLATING: GOLD OVER NICKEL

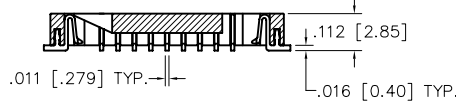
WILL ACCEPT THE FOLLOWING DEVICES	
AMD #	M27C010-155LC
ATMEL #	AT27C010
CATALYST #	CAT27C2000EI-25
FUJITSU #	276512-15
WSI #	WS272561-90

620 SERIES

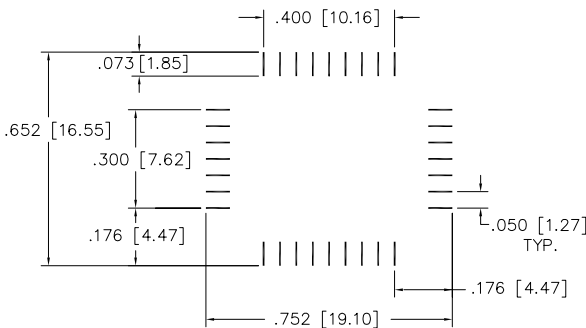
TOP VIEW



SIDE VIEW

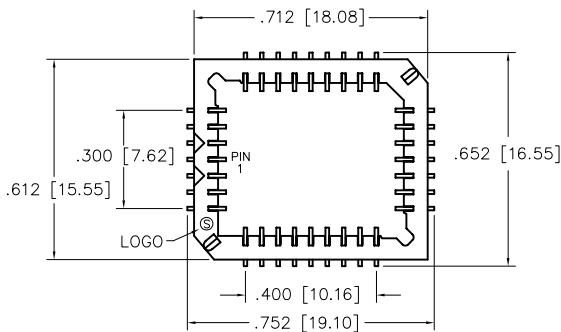


PC BOARD FOOTPRINT

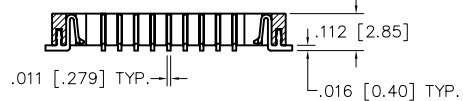


621 SERIES

TOP VIEW



SIDE VIEW

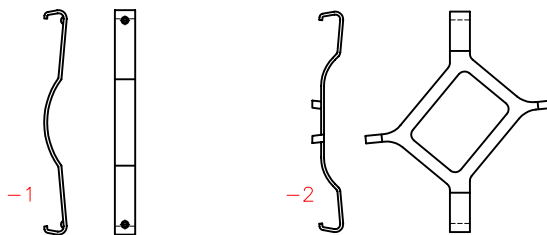


ORDERING INFORMATION

62X-32-SM-G10-S12-X



OPTIONAL RETENTION CLIP



P/N: CLL-32
WHEN ORDERING SEPARATELY

P/N: CLL-32-4
WHEN ORDERING SEPARATELY

© ANDON 2007

DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]

WE RESERVE THE RIGHT TO CHANGE SPECIFICATIONS WITHOUT NOTICE.



PLCC SOCKETS WITH HIGH TEMPERATURE INSULATION

HIGH-REL • HIGH SHOCK • HIGH VIBRATION

SERIES 651-STO PLCC THRU HOLE SOCKETS

SERIES 651-SMO PLCC SURFACE MOUNT SOCKETS

Contact design is with flat heavy gage copper alloy.

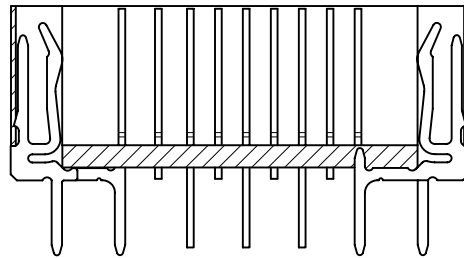
Contact area is EDGE WIPE, Beryllium Copper.

High Redundancy

Excellent for Military-Mobile-Medical-Long Life Application

Contact Feature.

651-STO



LOW COST COMPUTER APPLICATIONS

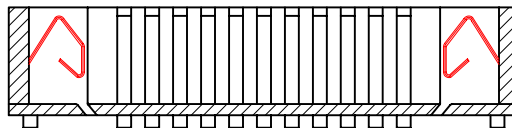
SERIES 654-STO PLCC THRU HOLE SOCKETS

SERIES 654-SMO PLCC SURFACE MOUNT SOCKETS

Contact design with rolled-leaf copper alloy

Contact area is FACE WIPE.

654-SMO





**SERIES 651 HI-REL PLCC
LEADED CHIP CARRIER SOCKETS**

TECHNICAL SPECIFICATIONS

INSULATOR: PPS, UL 94 V-0
CONTACT MATERIAL: PHOSPHOR BRONZE

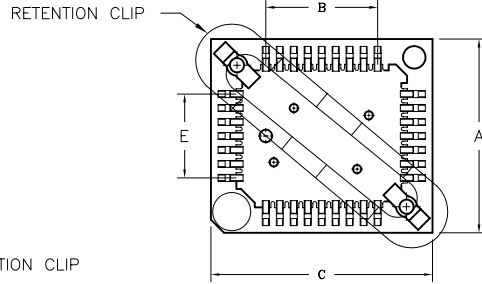
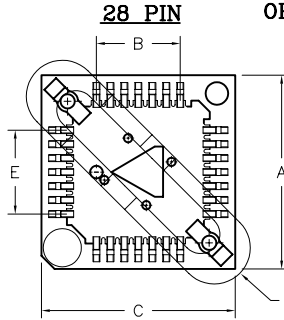
CONTACT FINISH: Sn OVER Ni
(Au OVER Ni ON REQUEST)

CONTACT SPACING: .050 IN. [1.27 MM]

OPERATING TEMP.: -65°C TO +220°C

	NO. OF PINS	
	28	32
A	.693 [17.60]	.693 [17.60]
B	.300 [7.62]	.400 [10.16]
C	.693 [17.60]	.793 [20.14]
D	.500 [12.70]	.500 [12.70]
E	.300 [7.62]	.300 [7.62]

THE 32 PIN SOCKET IS RECTANGULAR

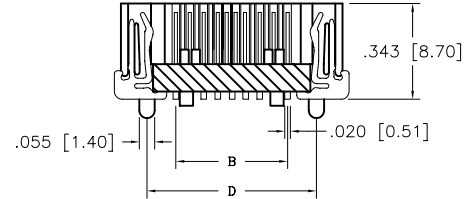
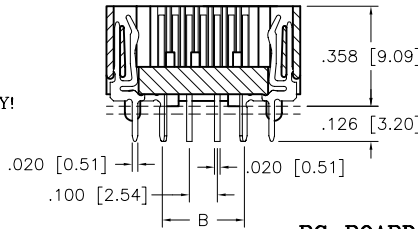


SOLDERTAIL-TYPE
P/N: 651-28STO-455
P/N: 651-32STO-455

SURFACE MOUNT-TYPE
P/N: 651-28SMC-455
P/N: 651-32SMC-455

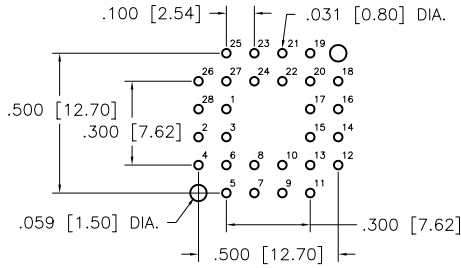
RETENTION CLIP	
28 PIN	CLP-28
32 PIN	CLP-32

PLEASE ORDER SEPARATELY!

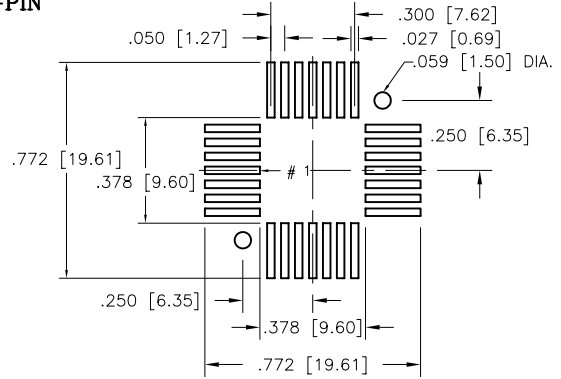


**PC-BOARD LAYOUT
28-PIN**

SOLDERTAIL-TYPE

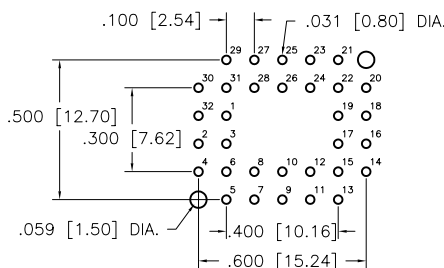


SURFACE MOUNT-TYPE

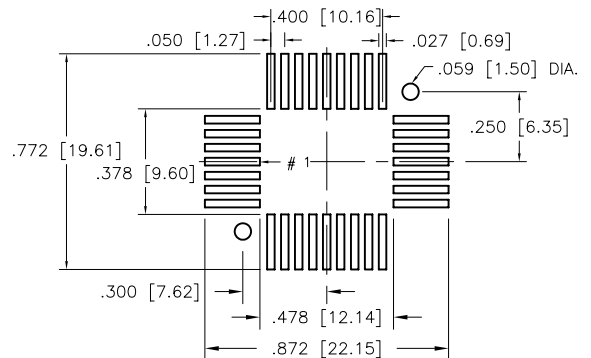


**PC-BOARD LAYOUT
32-PIN**

SOLDERTAIL-TYPE

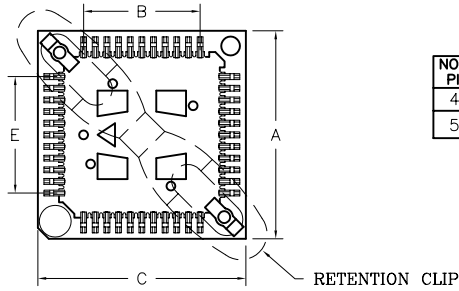


SURFACE MOUNT-TYPE





**SERIES 651 HI-REL
LEADED CHIP CARRIER SOCKETS**



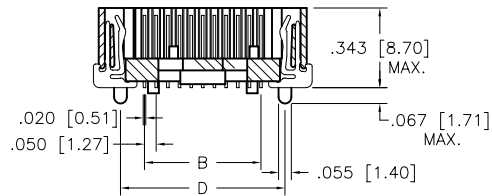
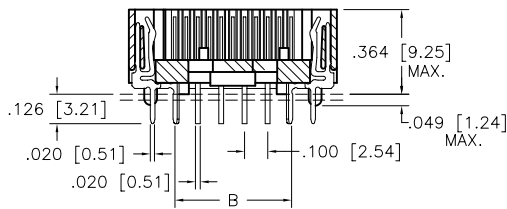
NO. OF PINS	A & C	B & E	D
44	.893 [22.68]	.500 [12.70]	.700 [17.78]
52	.993 [25.22]	.600 [15.24]	.800 [20.32]

RETENTION CLIP	
44 PIN	CLP-44
52 PIN	CLP-52

PLEASE ORDER SEPARATELY!

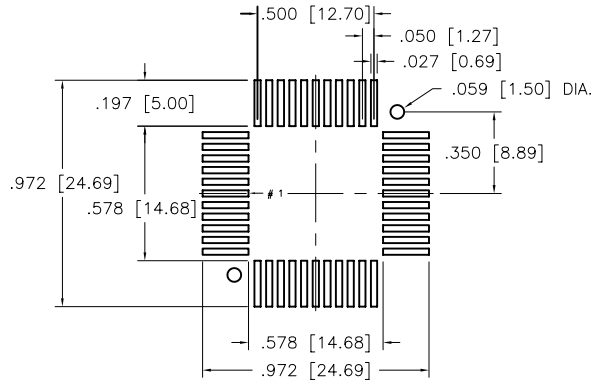
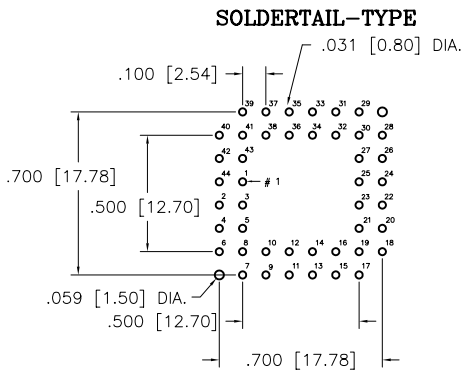
SOLDERTAIL-TYPE
P/N: 651-44STO-455
P/N: 651-52STO-455

SURFACE MOUNT-TYPE
P/N: 651-44SMC-455
P/N: 651-52SMC-455



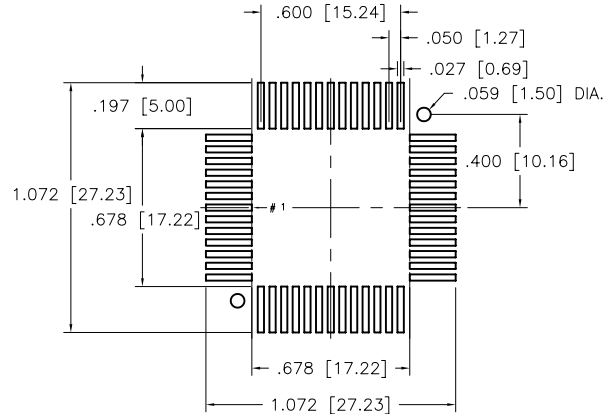
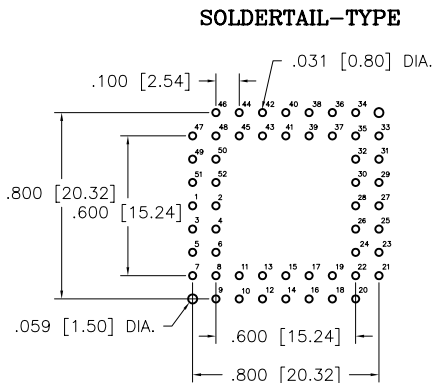
**PC-BOARD LAYOUT
44-PIN**

SURFACE MOUNT-TYPE



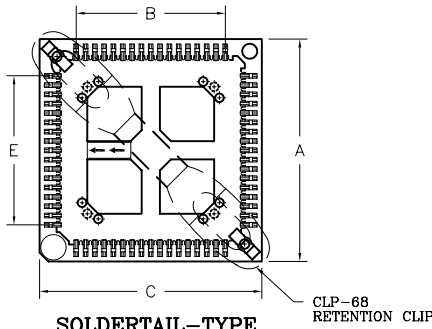
**PC-BOARD LAYOUT
52-PIN**

SURFACE MOUNT-TYPE





SERIES 651 HI-REL PLCC
LEADED CHIP CARRIER SOCKETS



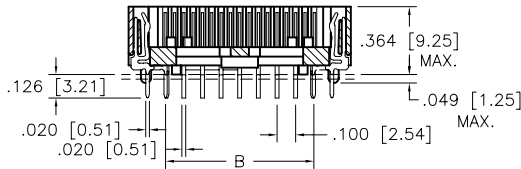
NO. OF PINS	A & C	B & E	D
68	1.193 [30.30]	.800 [20.32]	1.000 [25.40]
84	1.393 [35.38]	1.000 [25.40]	1.200 [30.48]

RETENTION CLIP	
68 PIN	CLP-68
84 PIN	CLP-84

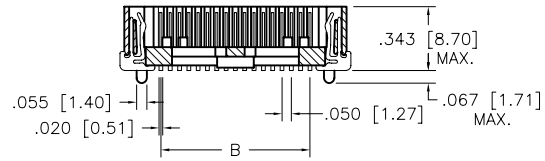
PLEASE ORDER SEPARATELY!

SOLDERTAIL-TYPE
P/N: 651-68STO-455
P/N: 651-84STO-455

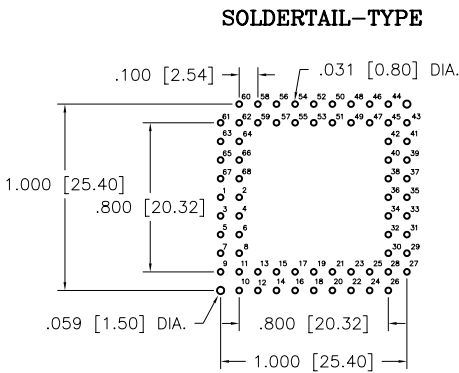
SURFACE MOUNT-TYPE
P/N: 651-68SMC-455
P/N: 651-84SMC-455



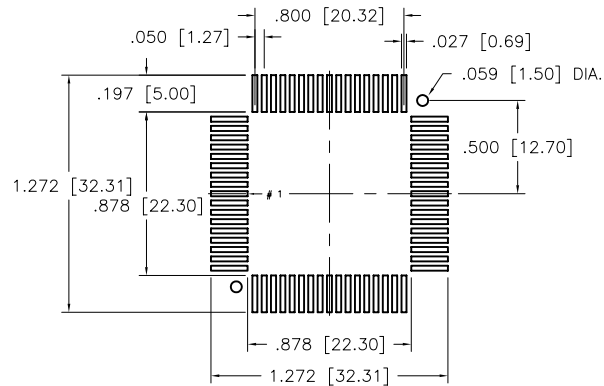
PC-BOARD LAYOUT
68-PIN



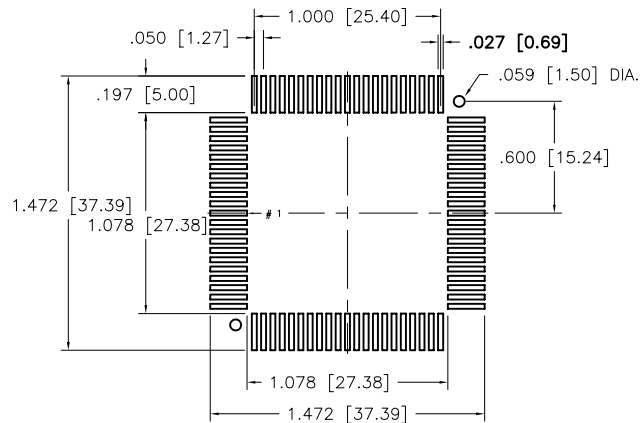
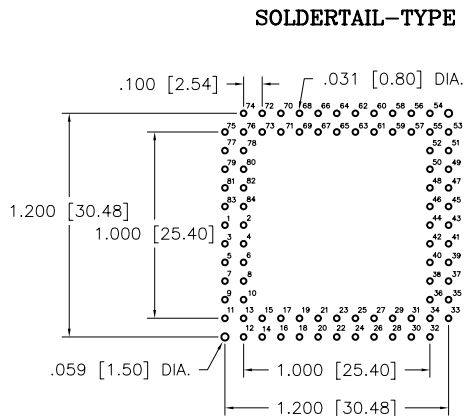
SURFACE MOUNT-TYPE



PC-BOARD LAYOUT
84-PIN



SURFACE MOUNT-TYPE



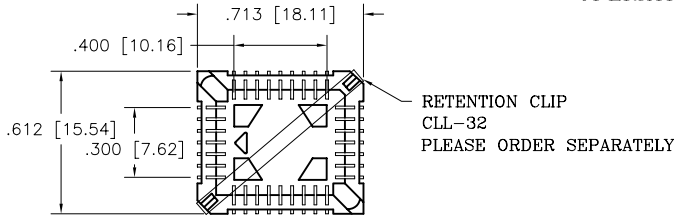


SERIES 652 HI-REL LCC
LEADLESS CHIP CARRIER SOCKETS

TECHNICAL SPECIFICATIONS

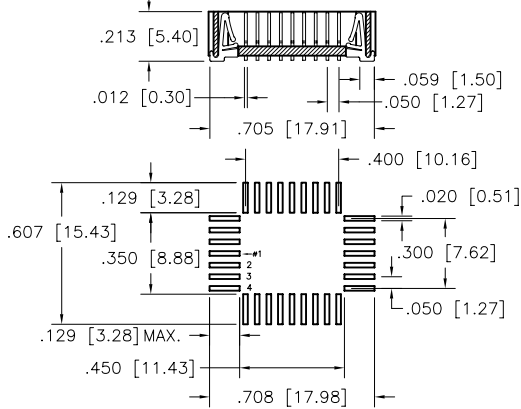
INSULATOR: PPS; UL 94 V-0
CONTACT MATERIAL: BERYLLIUM COPPER

CONTACT FINISH: -451 Au OVER Ni
-455 Sn OVER Ni
CONTACT SPACING: .050 IN [1.27 MM]
OPERATING TEMP.: -65°C TO +220°C

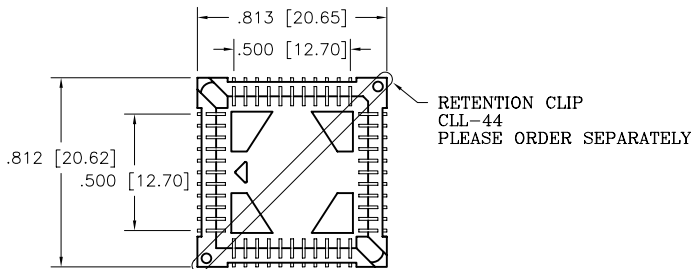
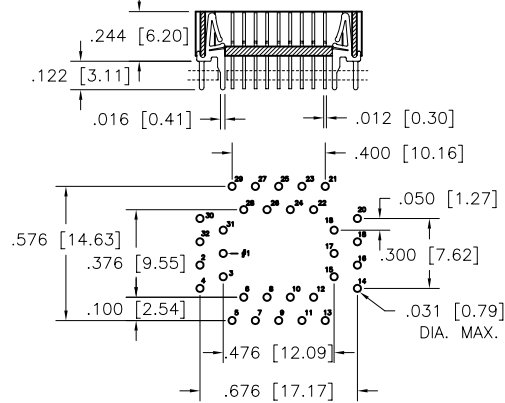


ORDERING INFORMATION
652-XX-XXX-XXX
SERIES | CONTACT COUNT | TYPE | CONTACT FINISH

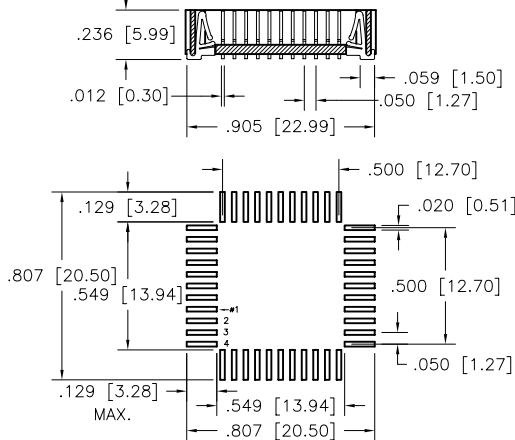
652-32-SMC-XXX



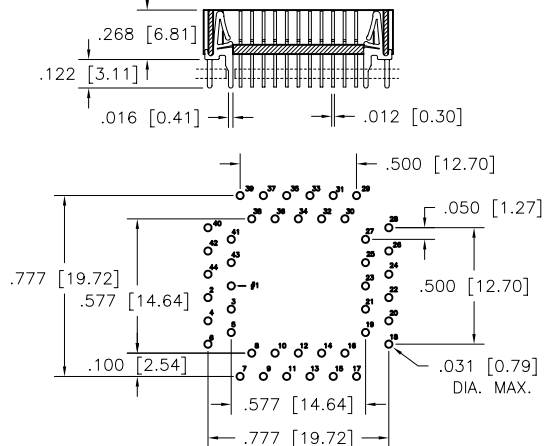
652-32-STC-XXX



652-44-SMC-XXX



652-44-STC-XXX





SERIES 654-STO
654-SMO

HI-TEMP, LOW COST PLCC THRU HOLE SOCKET
HI-TEMP, LOW COST PLCC SURFACE MOUNT SOCKET

SERIES 654-STO HI-TEMP PLCC THRU HOLE SOCKET

FEATURES

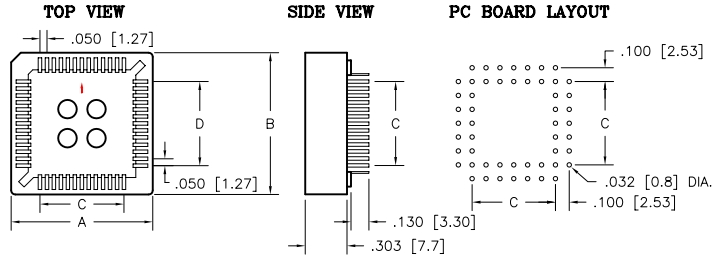
- ACCEPTS JEDEC MO-47 & MO-52 LEADED PLASTIC CHIP CARRIER PACKAGES
- SOLDER TERMINATIONS ON .100 [2.54] GRID
- LOW PROFILE HI-TEMP INSULATOR
- ANTI-SHORTING CONTACTS
- HIGH VISIBILITY PIN ONE INDICATOR

MATERIAL DATA

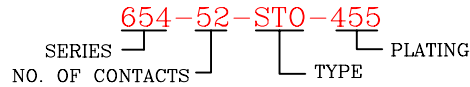
INSULATOR..... PPS
UL RATING..... 94V-0
CONTACTS..... PHOSPHOR BRONZE
PLATINGTIN
MOUNTING......100 IN. [2.54 MM] GRID

ELECTRICAL DATA

CONTACT RESISTANCE (MAX.)...30 MILLIOHMS
CURRENT RATING1.0 AMP MIN.
INSULATION RESISTANCE1000 MEGOHMS
WITHSTANDING VOLTAGE500 VAC



DIMENSIONAL FEATURES				
PART NUMBER	A ±.008 [0.2]	B ±.008 [0.2]	C ±.008 [0.2]	D ±.008 [0.2]
654-20-STO	.610 [15.50]	.610 [15.50]	.200 [5.08]	.200 [5.08]
654-28-STO	.720 [18.30]	.720 [18.30]	.300 [7.62]	.300 [7.62]
654-32-STO	.704 [17.90]	.807 [20.50]	.300 [7.62]	.400 [10.16]
654-44-STO	.923 [23.45]	.923 [23.45]	.500 [12.70]	.500 [12.70]
654-52-STO	1.018 [25.85]	1.018 [25.85]	.600 [15.24]	.600 [15.24]
654-68-STO	1.214 [30.85]	1.214 [30.85]	.800 [20.32]	.800 [20.32]
654-84-STO	1.417 [36.00]	1.417 [36.00]	1.000 [25.40]	1.000 [25.40]
654-100-STO	1.654 [42.00]	1.654 [42.00]	1.000 [25.40]	1.000 [25.40]



SERIES 654-SMO HI-TEMP PLCC SURFACE MOUNT SOCKET

FEATURES

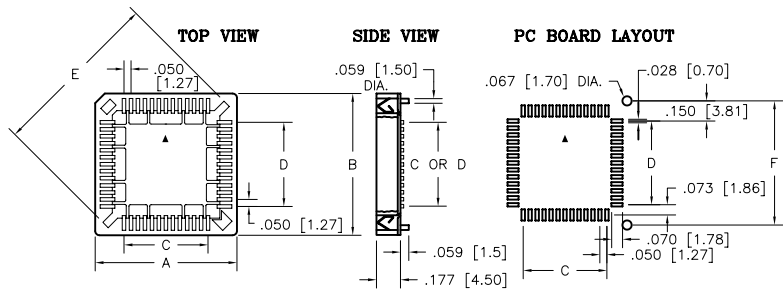
- ACCEPTS JEDEC MO-47 & MO-52 LEADED PLASTIC CHIP CARRIER PACKAGES
- HIGH TEMPERATURE INSULATOR - GOOD FOR VAPORPHASE AND IR SOLDERING
- LOW PROFILE INSULATOR
- UNIVERSAL MOUNTING FOOTPRINT
- VIEW PORTS FOR INSPECTING SOLDER TERMINATIONS
- HIGH VISIBILITY PIN ONE INDICATOR

MATERIAL DATA

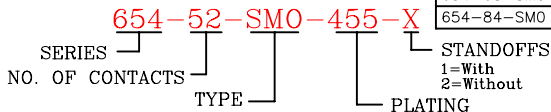
INSULATOR..... PPS
UL RATING..... 94V-0
CONTACTS..... PHOSPHOR BRONZE
PLATINGTIN
MOUNTING......050 [1.27] GRID

ELECTRICAL DATA

CONTACT RESISTANCE (MAX.)...15 MILLIOHMS
INSULATION RESISTANCE10,000 MEGOHMS
DIELECTRIC STRENGTH.....1000 VAC CONTINUOUS FOR 1 MINUTE



DIMENSIONAL FEATURES						
PART NUMBER	A ±.008 [0.2]	B ±.008 [0.2]	C ±.004 [0.1]	D ±.004 [0.1]	E ±.008 [0.2]	F ±.008 [0.2]
654-20-SMO	.616 [15.65]	.616 [15.65]	.200 [5.08]	.200 [5.08]	.673 [17.10]	.500 [12.70]
654-28-SMO	.716 [18.18]	.716 [18.18]	.300 [7.62]	.300 [7.62]	.814 [20.68]	.600 [15.24]
654-32-SMO	.716 [18.18]	.817 [20.75]	.300 [7.62]	.400 [10.16]	.882 [22.40]	.700 [17.78]
654-44-SMO	.917 [23.28]	.917 [23.28]	.500 [12.70]	.500 [12.70]	1.096 [27.85]	.800 [20.32]
654-52-SMO	1.017 [25.84]	1.017 [25.84]	.600 [15.24]	.600 [15.24]	1.242 [31.54]	.900 [22.86]
654-68-SMO	1.219 [30.95]	1.219 [30.95]	.800 [20.32]	.800 [20.32]	1.524 [38.70]	1.100 [27.94]
654-84-SMO	1.417 [36.00]	1.417 [36.00]	1.000 [25.40]	1.000 [25.40]	1.809 [45.95]	1.500 [38.10]



© ANDON 2007 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]

WE RESERVE THE RIGHT TO CHANGE SPECIFICATIONS WITHOUT NOTICE.

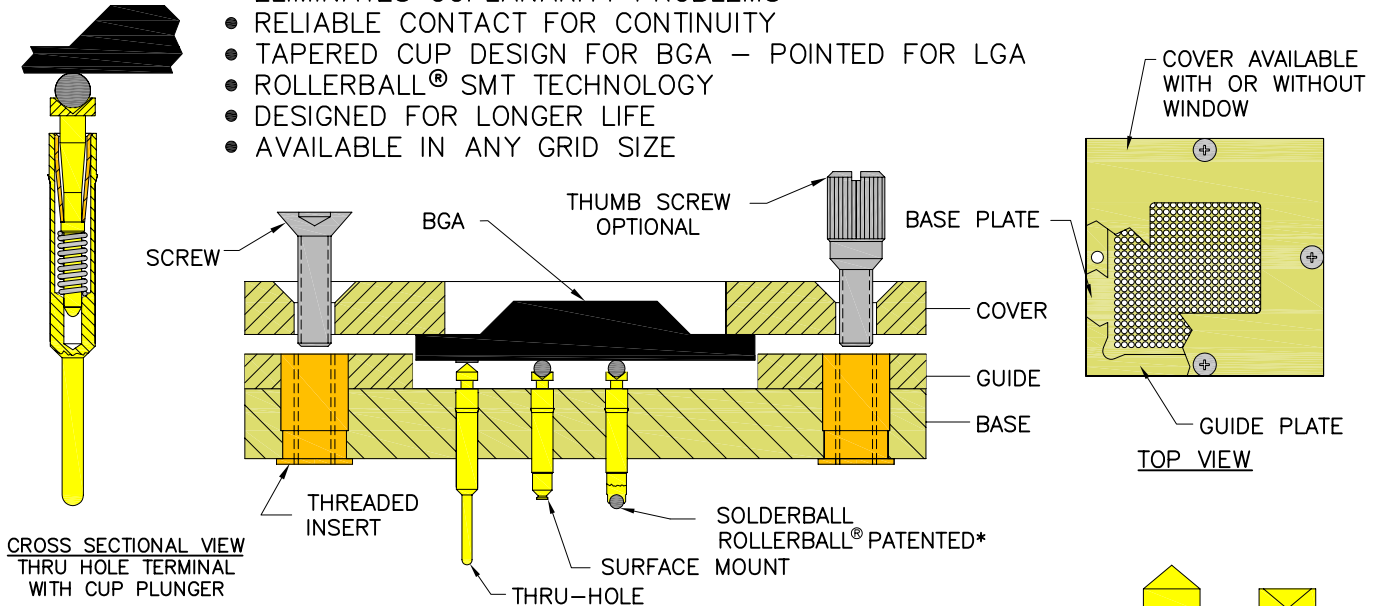


ISO 9001:2000
CERTIFIED

HI REL BGA & LGA TEST SOCKETS

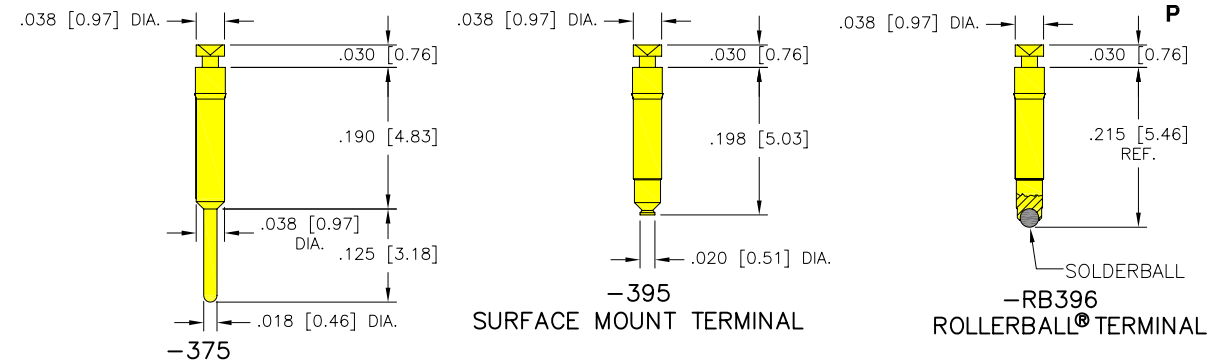
1.5mm [.059 in] and 1.27mm [.050 in] Pitch **LEAD FREE AVAILABLE**

- CONTACT PLUNGER & SPRING MAINTAINS PERPENDICULARITY
- ELIMINATES COPLANARITY PROBLEMS
- RELIABLE CONTACT FOR CONTINUITY
- TAPERED CUP DESIGN FOR BGA – POINTED FOR LGA
- ROLLERBALL® SMT TECHNOLOGY
- DESIGNED FOR LONGER LIFE
- AVAILABLE IN ANY GRID SIZE



CROSS SECTIONAL VIEW
THRU HOLE TERMINAL
WITH CUP PLUNGER

AVAILABLE IN THREE TERMINAL STYLES WITH 2 PLUNGER STYLES (POINTED OR CUP)



THRU HOLE TERMINAL

OTHER TERMINALS AND CUSTOM DESIGNS AVAILABLE

TECHNICAL SPECIFICATIONS

MECHANICAL DATA

INDIVIDUAL CONTACT FORCE... 60 grs AVG.
CONTACT LIFE 10,000 CYCLES MIN.
DURABILITY..... > 100 CYCLES

ELECTRICAL DATA

CONTACT RESISTANCE..... < 30 MILLIOHMS
CURRENT RATING..... 1.0 AMP MAX.
INSULATION RESISTANCE @ 500VDC... 10,000 MEGAOHMS

LEAD FREE AVAILABLE

MATERIAL DATA

INSULATOR .. HIGH TEMP. 94V-0
CONTACT ... BERYLLIUM COPPER
PLATING ... GOLD OVER NICKEL
TERMINAL BRASS
PLATING ... GOLD OVER NICKEL
PLUNGER C = BERYLLIUM COPPER
 B = BRASS
 T = TOOL STEEL
 S = STAINLESS STEEL
PLATING ... GOLD OVER NICKEL

ORDERING INFORMATION

SEND PRINT OF THE DEVICE AND WE WILL SUPPLY THE PART NUMBER.
EVERY FOOTPRINT AVAILABLE

* U.S. PAT. No. 6,352,437
* U.S. PAT. No. 6,861,862

© ANDON 2007 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS]

WE RESERVE THE RIGHT TO CHANGE SPECIFICATIONS WITHOUT NOTICE.

ANDON ELECTRONICS CORPORATION
4 COURT DRIVE, LINCOLN, R.I. 02865, USA

TEL. (401) 333-0388 / FAX (401) 333-0287
E-MAIL: info@andonelect.com
WEB SITE: http://www.andonelect.com

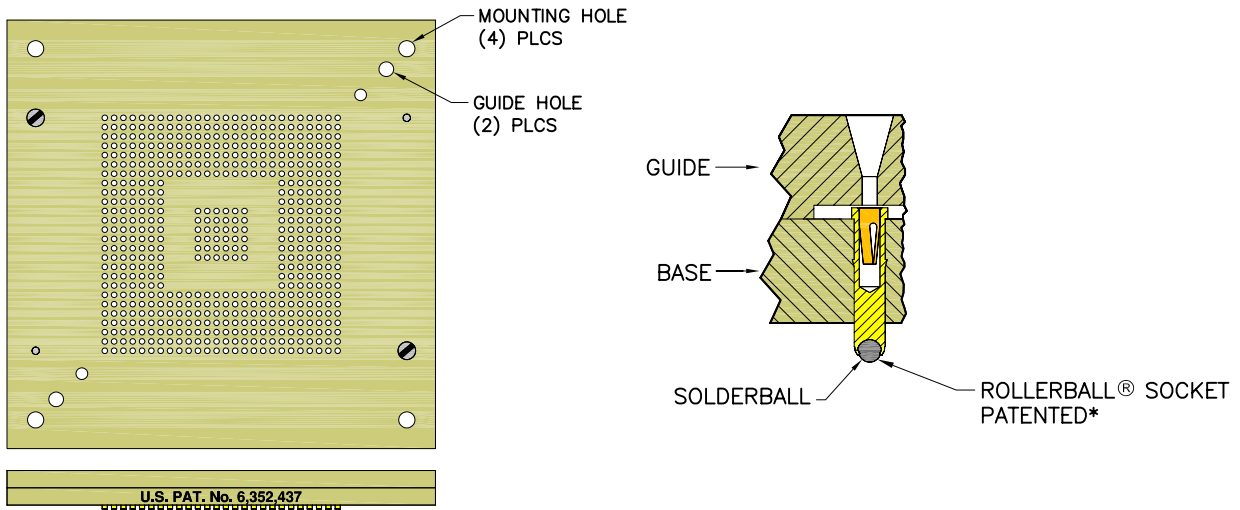


ISO 9001:2000
CERTIFIED

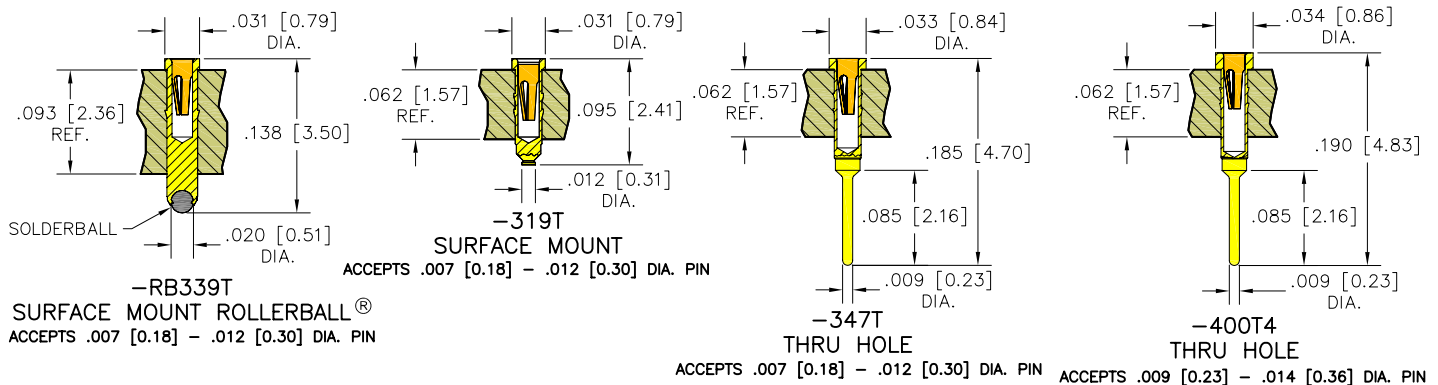
TEST SOCKET RECEPTACLE

AVAILABLE ON 1.27mm [.050 in], 1.0mm [.0394 in], 0.8mm [.0315 in] & 0.75mm [.0295] PITCH

RECEPTACLE SHOWN IS 26 X 26 568 PIN ROLLERBALL® SOCKET .050 [1.27] PITCH
OTHER SOCKETS AVAILABLE – CONSULT FACTORY



AVAILABLE IN THREE TERMINAL STYLES ROLLERBALL®, SURFACE MOUNT & THRU-HOLE.



OTHER TERMINALS AND CUSTOM DESIGNS AVAILABLE

TECHNICAL INFORMATION

- INSULATORS:** LAMINATE HI-TEMP, 94V-0
- TERMINAL:** BRASS, PER ASTM-B16
- CONTACT:** BeCu, PER ASTM-B194
- PLATING:** TERMINAL: GOLD PLATED
CONTACT: GOLD PLATED
- SOLDERBALL:** 63% TIN, 37% LEAD

ORDERING INFORMATION

- CONTACT FACTORY FOR ORDERING INFORMATION
- SEND PRINT OF THE DEVICE AND WE WILL SUPPLY THE PART NUMBER
- EVERY FOOTPRINT AVAILABLE

* U.S. PAT. No. 6,352,437

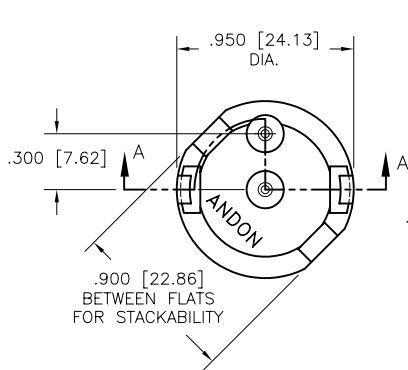


TADIRAN BATTERY SOCKETS

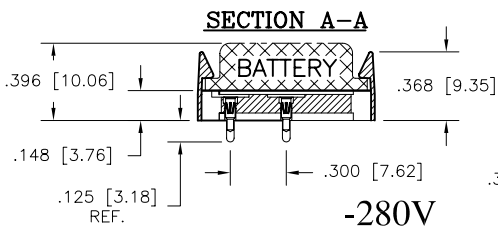


ISO 9001:2000
CERTIFIED

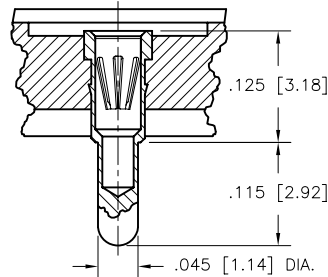
RoHS COMPLIANT



ACCEPTS TADIRAN®
TL-5186
(# TL-2186 & TL-4986)



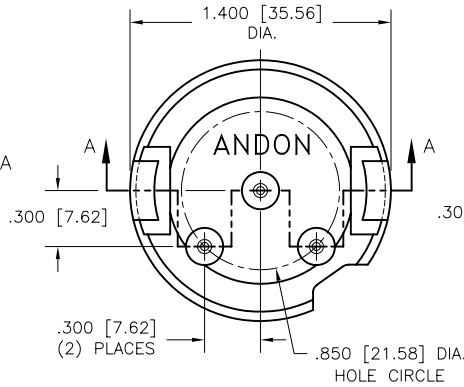
-280V
SOCKET ASSEMBLY



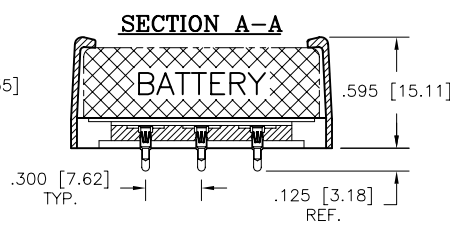
MOUNTING HOLE ϕ
.055 [1.40] / .065 [1.65] DIA.
ACCEPTS BATTERY TAIL LENGTH
.135 [3.43] / .210 [5.33]
ACCEPTS TAIL DIA.
.025 [2.64] / .037 [0.94]

TECHNICAL SPECIFICATIONS

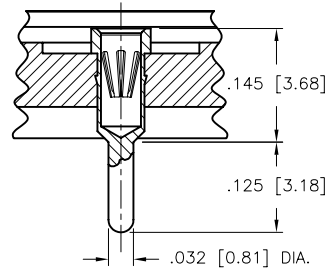
MATERIALS:
INSULATOR: UL 94V-0
TERMINAL: BRASS, PER ASTM-B16
PLATED TIN- LEAD OR
PLATED GOLD
OR PLATED TIN (RoHS COMPLIANT)
CONTACT: BeCu, PER ASTM-B194
PLATED TIN OR
PLATED GOLD



ACCEPTS TADIRAN®
TL-5135
(# TL-2135 & TL-4935)



-295V
SOCKET ASSEMBLY



MOUNTING HOLE ϕ
.042 [1.07] / .052 [1.32] DIA.
ACCEPTS BATTERY TAIL LENGTH
.115 [2.92] / .132 [3.35]
ACCEPTS TAIL DIA.
.025 [2.64] / .037 [0.94]

ORDERING INFORMATION

BS-XXXX-XX-2XXV-PXX-D14

SERIES ———— INSULATOR UL 94V-0
BATTERY TYPE ———— PLATING: TERMINAL / CONTACT
5186 ———— P27: GOLD / GOLD
5135 ———— P32: TIN-LEAD / TIN
5134 ————
NO. OF PINS ————
TERMINAL ASSEMBLY NO. ————
280V ————
295V ————
R (RoHS COMPLIANT)
TERMINAL: TIN PLATING



SPECIFICATIONS

TYPICAL INSULATOR SPECIFICATIONS

1. **PBT** POLYESTER 30% GLASS REINFORCED POLYBUTYLENE TEREPHTHALATE
 U.L. RATED: 94V-0
 HEAT DEFLECTION TEMPERATURE (@ 264 PSI): 403°F/206°C
 MAX. OPERATING TEMPERATURE: 284°F/140°C
2. **NYLON 46** HIGH TEMPERATURE 30% GLASS REINFORCED POLYTETRAMETHYLENE - ADIPAMIDE
 U.L. RATED: 94V-0
 HEAT DEFLECTION TEMPERATURE (@ 264 PSI): 534°F/279°C
 MAX. OPERATING TEMPERATURE: 302°F/150°C
3. **PPS** 30% GLASS REINFORCED POLYPHENYLENE SULFIDE
 U.L. RATED: 94V-0
 HEAT DEFLECTION TEMPERATURE (@ 264 PSI): >500°F/260°C
 MAX. OPERATING TEMPERATURE: 428°F/220°C
4. **FR-4** GLASS EPOXY LAMINATE
 U.L. RATED: 94V-0
 MAX. OPERATING TEMPERATURE: 284°F/140°C
5. **POLYIMIDE** LAMINATE
 U.L. RATED: 94V-0
 MAX. OPERATING TEMPERATURE: 464°F/240°C

CONTACT SPECIFICATIONS

CONTACT TYPE	RECOMMENDED MINIMUM PIN DIA.	RECOMMENDED MAXIMUM PIN DIA.	SPRING MATERIAL	INSERTION PIN DIA.	WITHDRAWAL PIN DIA.
U	.015 [0.38]	.021 [0.53]	BeCu	$\frac{2.8 \text{ oz. MAX.}}{.018 [0.46]}$	$\frac{0.5 \text{ oz. MIN.}}{.018 [0.46]}$
K	.015 [0.38]	.022 [0.56]	BeCu	$\frac{1.0 \text{ oz. MAX.}}{.017 [0.43]}$	$\frac{0.4 \text{ oz. MIN.}}{.017 [0.43]}$
L	.015 [0.38]	.022 [0.56]	BeCu	$\frac{1.0 \text{ oz. MAX.}}{.018 [0.46]}$	$\frac{0.3 \text{ oz. MIN.}}{.018 [0.46]}$
S	.016 [0.41]	.022 [0.56]	BeCu	$\frac{9.0 \text{ oz. AVG.}}{.018 [0.46]}$	$\frac{2.0 \text{ oz. MIN.}}{.018 [0.46]}$
H	.015 [0.38]	.022 [0.56]	BeCu	$\frac{18.3 \text{ oz. MAX.}}{.018 [0.46]}$	$\frac{4.2 \text{ oz. MIN.}}{.018 [0.46]}$
M	.015 [0.38]	.025 [0.64]	BeCu	$\frac{1.6 \text{ oz. MAX.}}{.018 [0.46]}$	$\frac{0.5 \text{ oz. MIN.}}{.018 [0.46]}$
N	.015 [0.38]	.025 [0.64]	BeNi	$\frac{6.7 \text{ oz. AVG.}}{.017 [0.43]}$	$\frac{5.3 \text{ oz. MIN.}}{.017 [0.43]}$
V	.025 [0.64]	.037 [0.94]	BeCu	$\frac{4.4 \text{ oz. MAX.}}{.026 [0.66]}$	$\frac{1.41 \text{ oz. MIN.}}{.026 [0.66]}$



NOTICE:

THE SELLER DOES NOT GUARANTEE THE ACCURACY, COMPLETENESS OR THE SUITABILITY OF THE PRODUCT FOR THE INTENDED USE OR APPLICATION.

THERE ARE NO WARRANTIES EXPRESSED OR IMPLIED, INCLUDING BUT NOT LIMITED TO THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR THE INTENDED USE WHICH WARRANTIES ARE HEREBY EXPRESSLY DISCLAIMED. THE SELLER SHALL NOT BE LIABLE TO THE USER OR ANYONE FOR ANY INJURY, NEGLIGENCE OR ANY DIRECT OR CONSEQUENTIAL DAMAGE SUSTAINED OR INCURRED AS A RESULT OF THE USE OF ANY OF THE SELLER PRODUCTS THAT ARE OR ARE NOT DEFECTIVE.

THE USER HAS THE RIGHT TO INSPECT, ACCEPT OR REJECT THE SELLERS PRODUCTS AT THE TIME OF RECEIPT. ONCE THE SELLERS PRODUCTS ARE ACCEPTED, USED, OR INCORPORATED INTO THE USERS PRODUCTS OR PROCESSED IN ANY MANNER BY THE USER, THE USER ASSUMES ALL RISKS AND LIABILITY.



B.C.E. s.r.l.

Via Regina Pacis, 54/c - 41049 SASSUOLO (MO) Italy
Tel. +39 0536 811.616 r.a. - Fax +39 0536 811.500
www.bce.it - E-mail: bce@bce.it

